

Application of Plasma Phenomena



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Lecture 11

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Tuesday 9:10-12:00

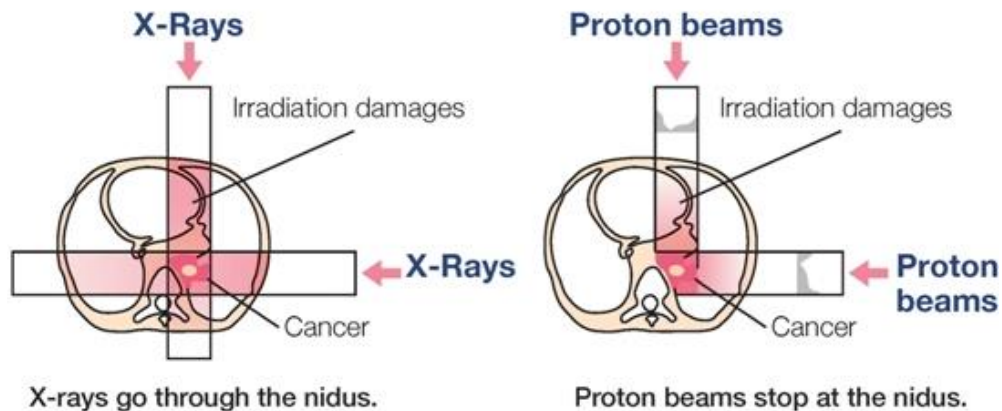
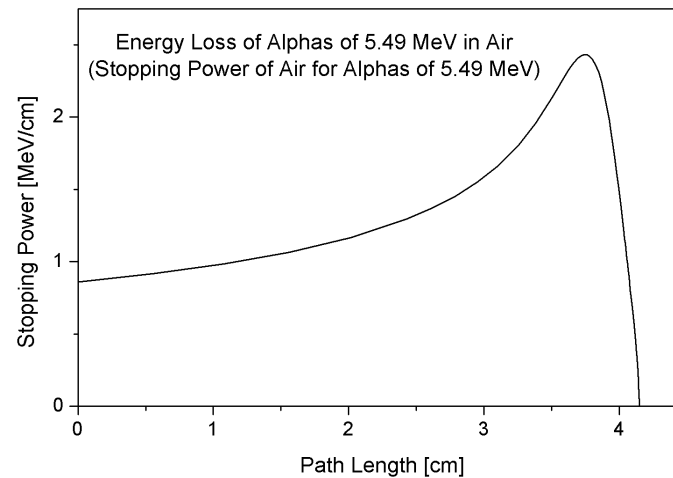
Materials:

<https://capst.ncku.edu.tw/PGS/index.php/teaching/>

Online courses:

<https://nckucc.webex.com/nckucc/j.php?MTID=m2a52f2d8ea616f434b6ec3053ef0ebd2>

Proton therapy takes the advantage of using Bragg peak



Saha equation gives the relative proportions of atoms of a certain species that are in two different states of ionization in thermal equilibrium



$$\frac{n_{r+1}n_e}{n_r} = \frac{G_{r+1}g_e}{G_r} \frac{(2\pi m_e KT)^{3/2}}{h^3} \exp\left(-\frac{\chi_r}{KT}\right)$$

- n_{r+1} , n_r : Density of atoms in ionization state $r+1$, r (m^{-3})
- n_e : Density of electrons (m^{-3})
- G_{r+1} , G_r : Partition function of ionization state $r+1$, r
- $g_e=2$: Statistical weight of the electron
- m_e : Mass of the electron
- χ_r : Ionization potential of ground level of state r to reach to the ground level of state $r+1$
- T : Temperature
- h : Planck's constant
- K : Boltzmann constant

Saha equation is derived using the transition between different ionization states



- Photoionization:

$$R_{pi} = n_{r,k} u(\nu) B_{r,k \rightarrow r+1,j}$$

- Induced radiation:

$$R_{ir} = n_{r+1,j} n_{e,p}(\rho) u(\nu) B_{r+1,j \rightarrow r,k}$$

- Spontaneous emission:

$$R_{sr} = n_{r+1,j} n_{e,p}(\rho) A_{r+1,j \rightarrow r,k}$$

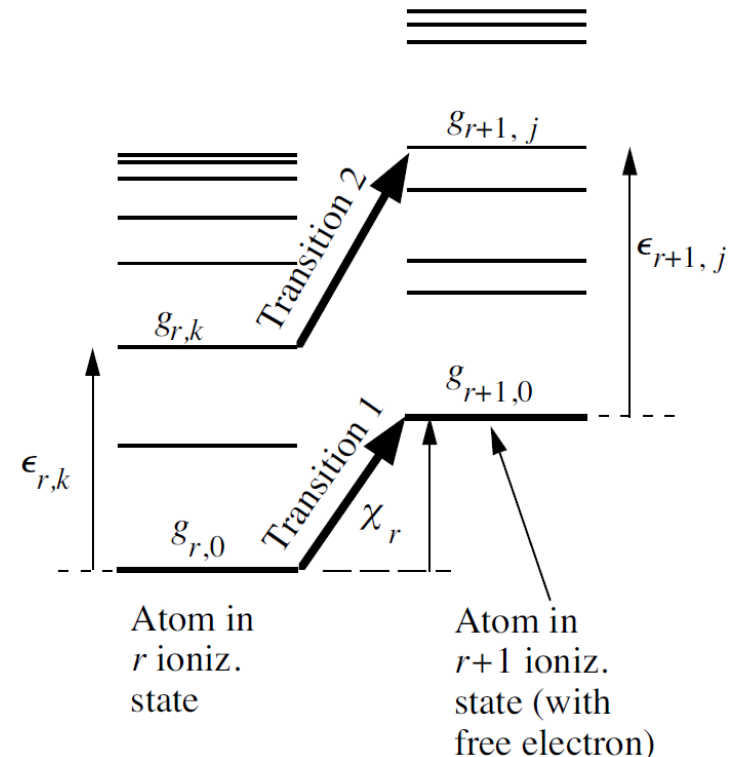
- In thermal equilibrium:

$$\begin{aligned} n_{r+1,j} n_{e,p} A_{r+1,j \rightarrow r,k} + n_{r+1,j} n_{e,p} u B_{r+1,j \rightarrow r,k} \\ = n_{r,k} u B_{r,k \rightarrow r+1,j} \end{aligned}$$

- Einstein coefficients:

$$\frac{B_{r,k \rightarrow r+1,j}}{B_{r+1,j \rightarrow r,k}} = \frac{g_{r+1,j}}{g_{r,k}} \frac{g_e 4\pi p^2}{h^3}$$

$$\frac{A_{r+1,j \rightarrow r,k}}{B_{r+1,j \rightarrow r,k}} = \frac{8\pi h \nu^3}{c^3}$$



Saha equation – example: hydrogen plasma of the sun



- Photosphere of the sun – hydrogen atoms in an optically thick gas in thermal equilibrium at temperature $T=6400$ K.

- Neutral hydrogen (r state / ground state)

$$G_r = \sum g_{r,k} = g_{r,0} + g_{r,1} \exp\left(-\frac{\epsilon_{r,1}}{KT}\right) + \dots = 2 + 8 \exp\left(-\frac{10.2\text{eV}}{0.56\text{eV}}\right) + \dots \\ = 2 + 9.8 \times 10^{-8} + \dots \approx 2$$

- Ionized state (r+1 state)

$$G_{r+1} = \sum g_{r+1,j} = g_{r+1,0} + g_{r+1,1} \exp\left(-\frac{\epsilon_{r+1,1}}{KT}\right) + \dots \approx 1$$

- Other information: $g_e = 2$ $\chi_r = 13.6\text{eV}$; $kT = 0.56\text{eV}$ $n_{r+1} = n_e$

$$\frac{n_{r+1}^2}{n_r} = 2.41 \times 10^{21} \frac{1 \times 2}{2} (6400)^{3/2} \exp\left(-\frac{13.6}{0.56}\right) = 3.5 \times 10^{16} m^{-3}$$

It is mostly neutral in the photosphere of the sun



- Assuming 50 % ionization:

$$n_{r+1} = n_r = 3.5 \times 10^{16} m^{-3} \quad n = n_{r+1} + n_r = 7 \times 10^{16} m^{-3}$$

- In the photosphere of the sun:

$$\rho \sim 3 \times 10^{-4} \text{ kg}/m^3 \rightarrow n = 2 \times 10^{23} m^{-3} \gg 7 \times 10^{16} m^{-3}$$

- At higher densities n at the same temperature, there should be more collisions leading to higher recombination rate and thus the plasma is less than 50 % ionization.

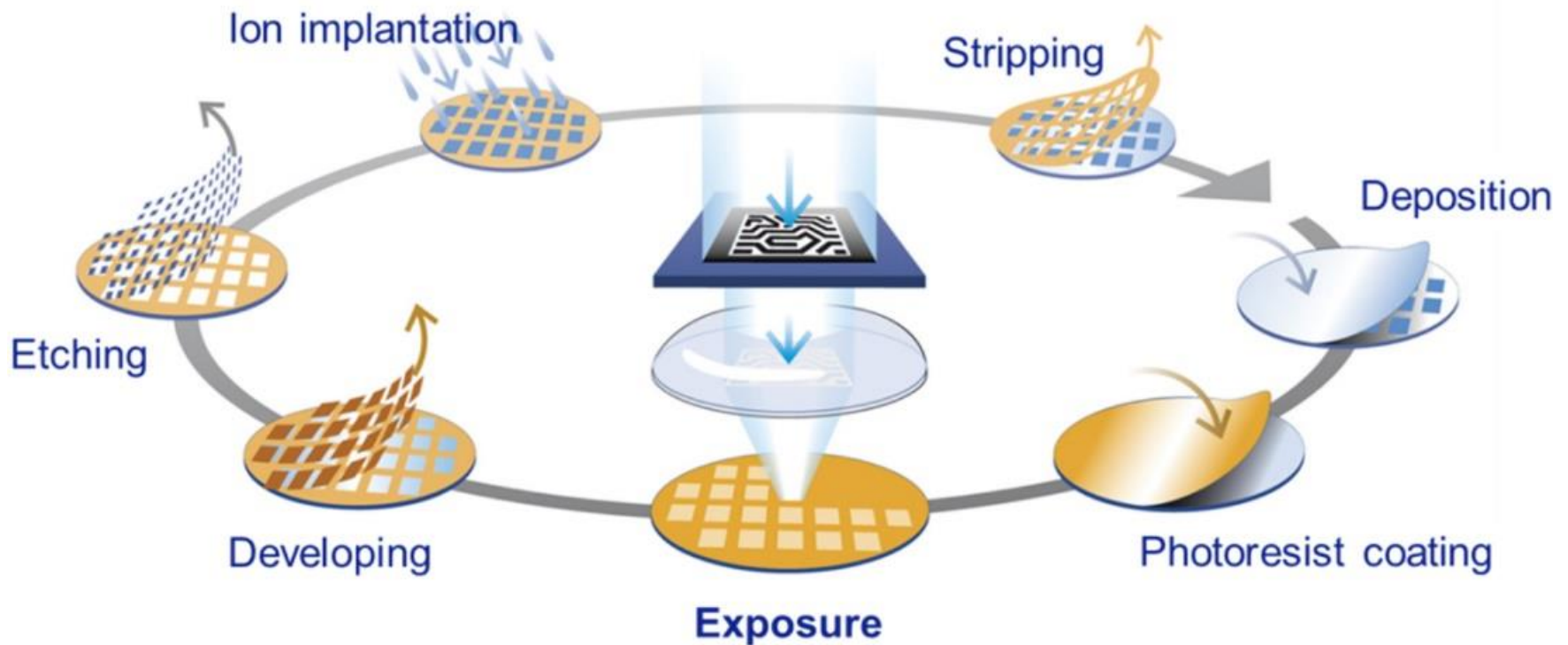
⇒ Less than 50 % ionization

- Use the total number density to estimate the ionization percentage:

$$n_{r+1} + n_r = 2 \times 10^{23}$$

$$\frac{n_{r+1}}{n_r} = 4 \times 10^{-4} @ 6400K$$

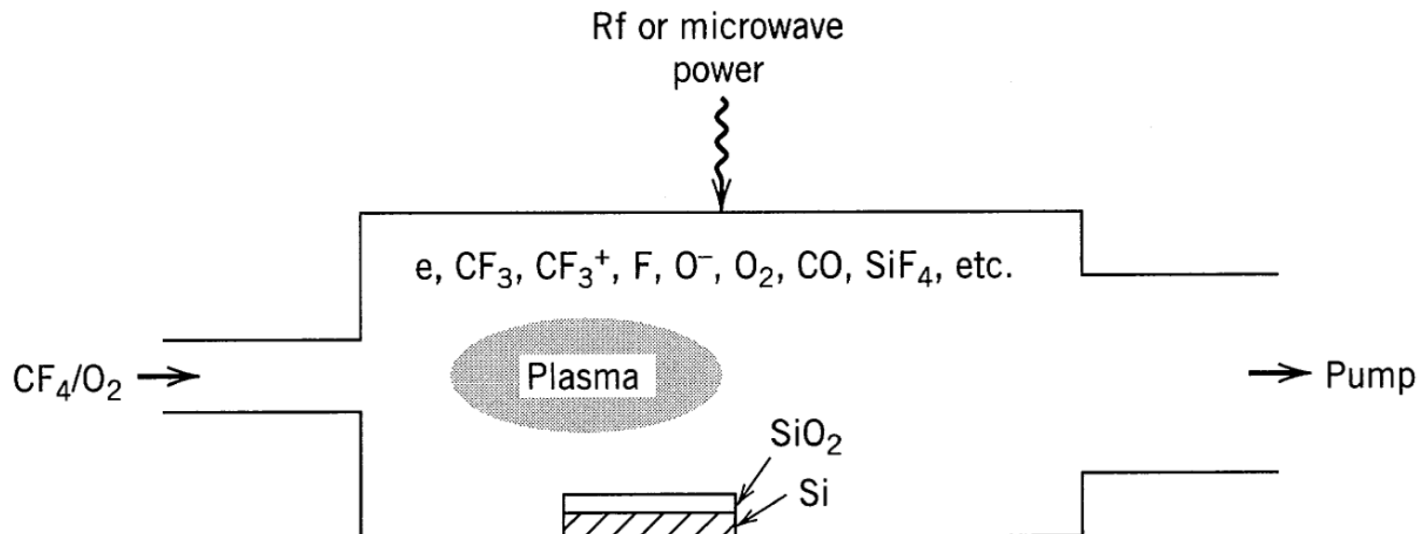
A semiconductor device is fabricated by many repetitive production process



Reference for material processing



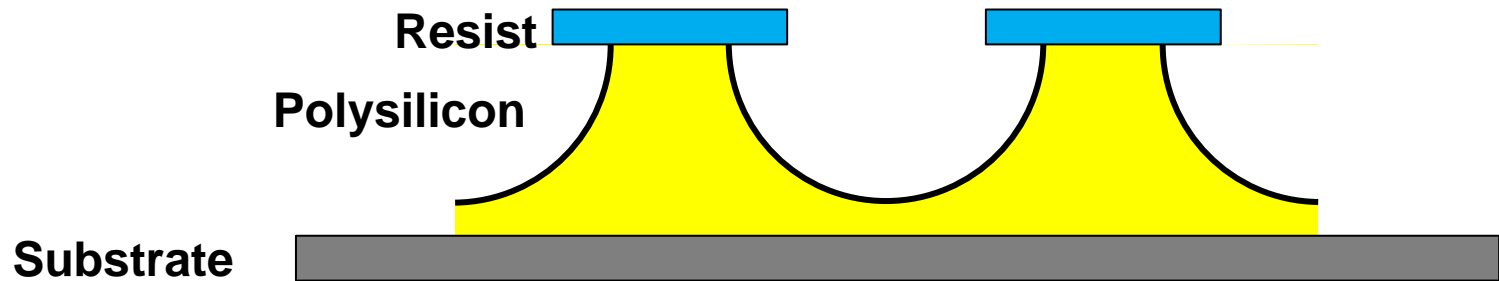
- Principles of plasma discharges and materials processing, 2nd edition, by Michael A. Lieberman and Allan J. Lichtenberg
- <http://www.eecs.berkeley.edu/~lieber/>
- Materials science of thin films, 2nd edition, by Milton Ohring
- Plasma etching, by Dennis M. Manos and Daniel L. Flamm
- Industrial plasma engineering, volume 1, by J. Reece Roth



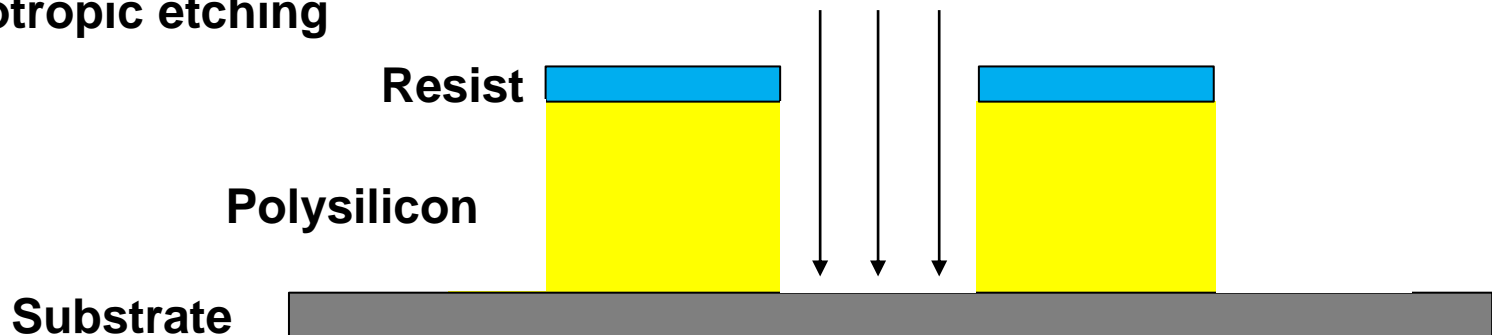
There are two types of etching: isotropic vs anisotropic



- Isotropic etching



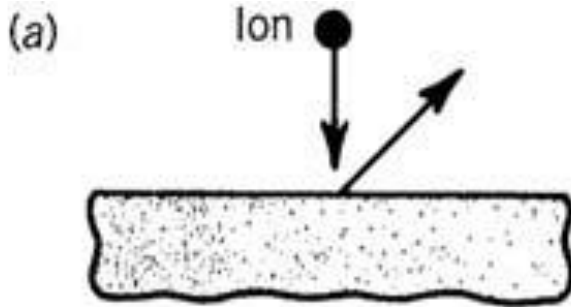
- Anisotropic etching



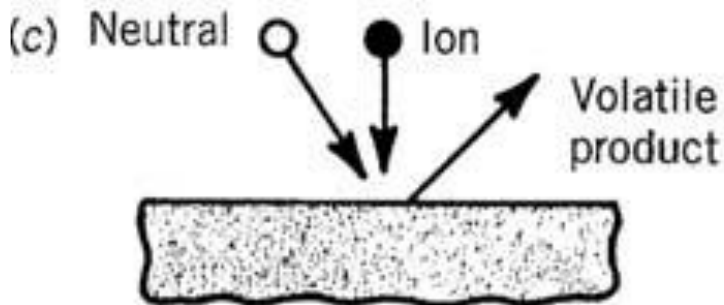
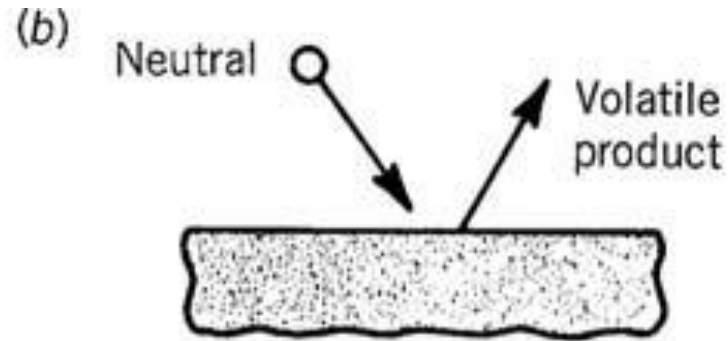
There are four major plasma etching mechanisms



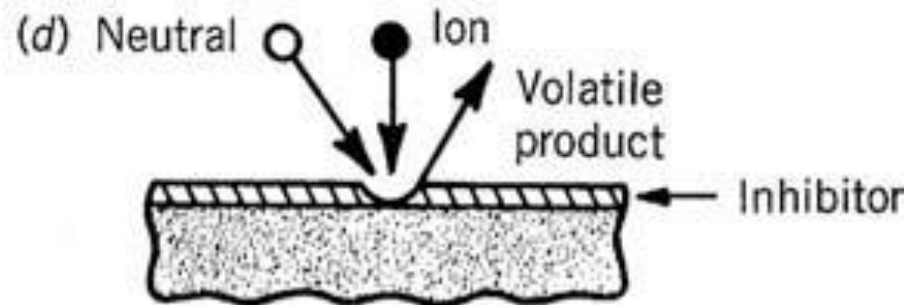
- **Sputtering**



- **Pure chemical etching**



- **Ion energy-driven etching**

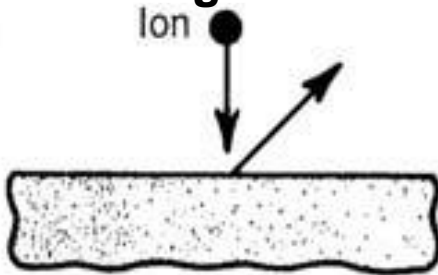


- **Ion-enhanced inhibitor etching**

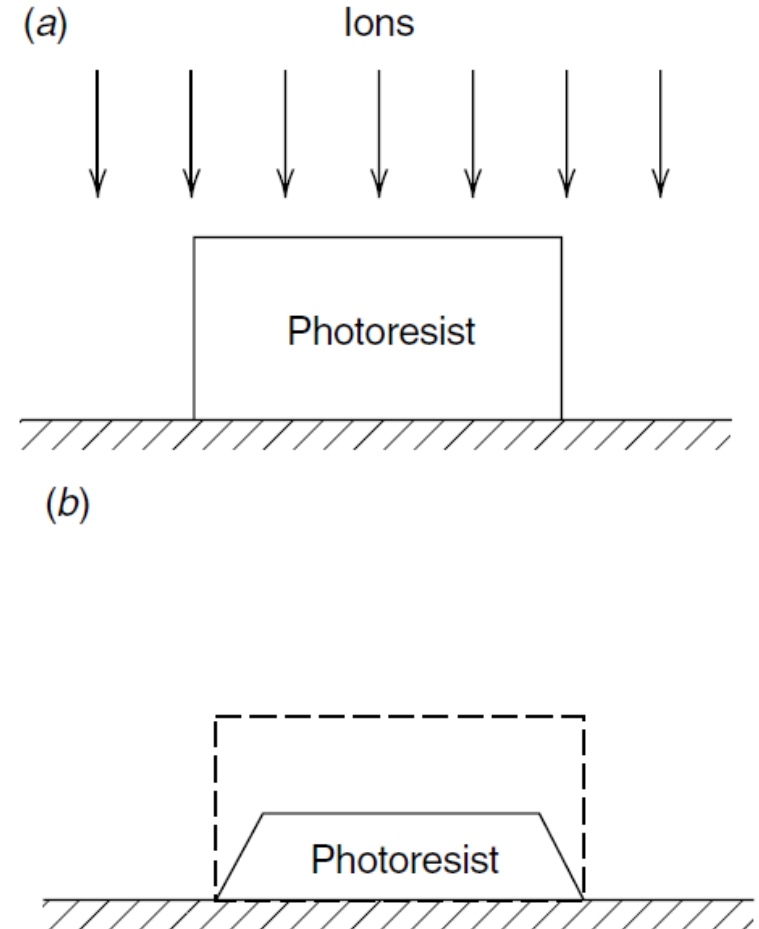
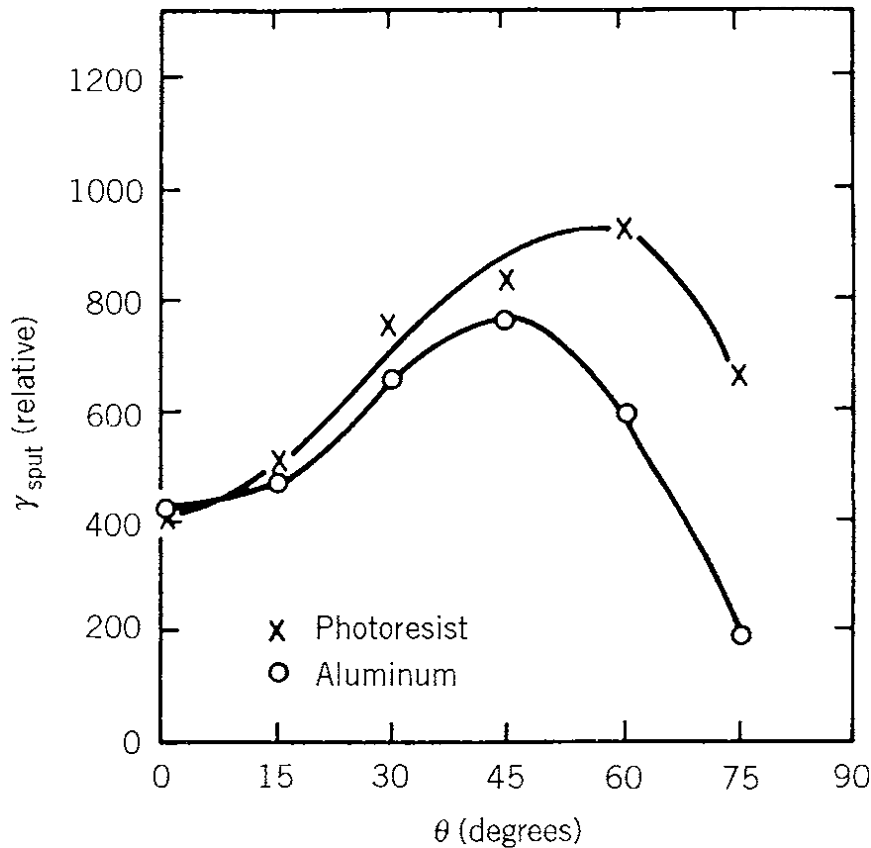
Sputtering is an unselective but anisotropic process



- Unselective process.
- Anisotropic process, strongly sensitive to the angle of incidence of the ion.
- Sputtering rates of different materials are roughly the same.
- Sputtering rates are generally low because the yield is typically of order one atom per incident ion.
- Sputtering is the only one of the four etch processes that can remove nonvolatile products from a surface.
- The process is generally under low pressure since the mean free path of the sputtered atoms must be large enough to prevent redeposition on the substrate or target.



Topographical patterns might not be faithfully transferred during sputter etching

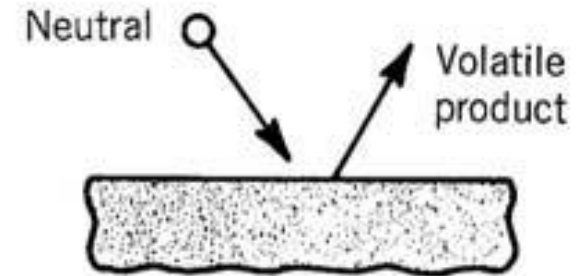
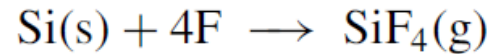


Pure chemical etching

Atoms or molecules chemically react with the surface to form gas-phase products



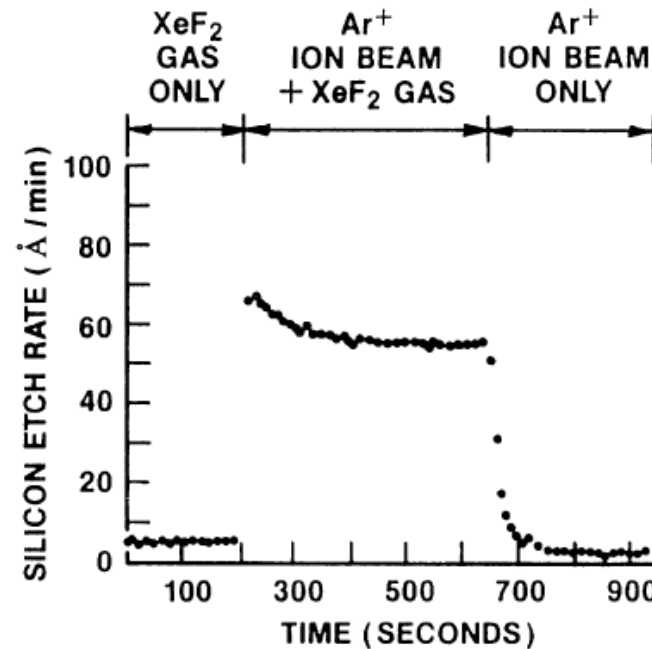
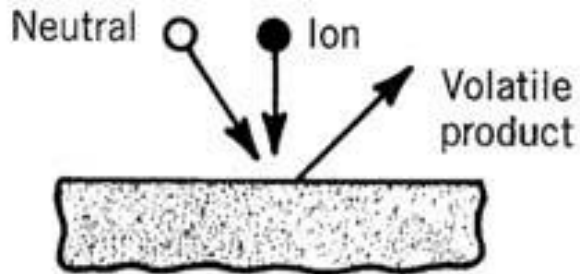
- Highly chemically selective, e.g.,



- Almost invariably isotropic.
- Etch products must be volatile.
- The etch rate can be quite large.
- Etch rate are generally not limited by the rate of arrival of etchant atoms, but by one of a complex set of reactions at the surface leading to formation of etch products.

Ion-enhanced energy-driven etching

The discharge supplies both etchants and energetic ions to the surface



- Low chemical etch rate of silicon substrate in XeF_2 etchant gas.
- **Tenfold increase in etch rate with XeF_2 + 500 V argon ions, simulating ion-enhanced plasma etching.**
- Very low “etch rate” due to the physical sputtering of silicon by ion bombardment alone.

Ion-enhanced energy-driven etching has the characteristic of both sputtering and pure chemical etching



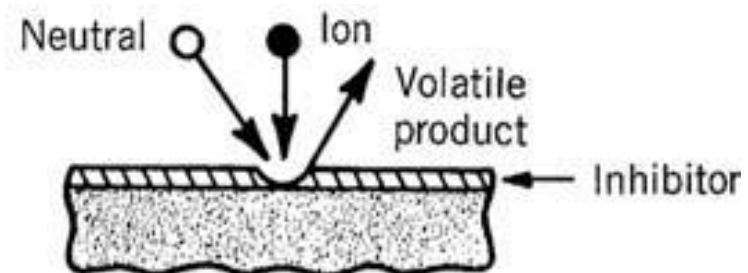
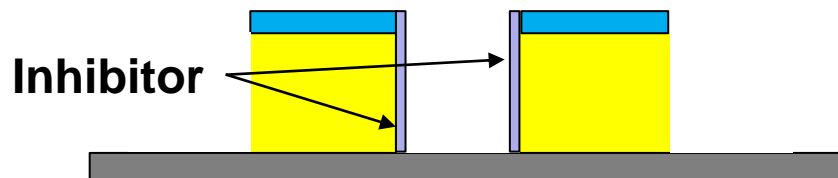
- **Chemical in nature but with a reaction rate determined by the energetic ion bombardment.**
- **Product must be volatile.**
- **Highly anisotropic.**

Ion-enhanced inhibitor etching

An inhibitor species is used



- Inhibitor precursor molecules that absorb or deposit on the substrate form a protective layer or polymer film.
- **Etchant is chosen to produce a high chemical etch rate of the substrate in the absence of either ion bombardment or the inhibitor.**
- Ion bombardment flux prevents the inhibitor layer from forming or clears it as it forms.
- Where the ion flux does not fall, the inhibitor protects the surface (side wall) from the etchant.
- May not be as selective as pure chemical etching.
- A volatile etch product must be formed.
- Contamination of the substrate and final removal of the protective inhibitor film are other issues.



Comparison of different processes



	Sputtering etching	Pure chemical etching	Ion energy-driven etching	Ion-enhanced Inhibitor etching
Selectivity	X	O	O	O
Anisotropic	O	X	O	O
Volatile product	X	O	O	O

TABLE 15.1. Etch Chemistries Based on Product Volatility

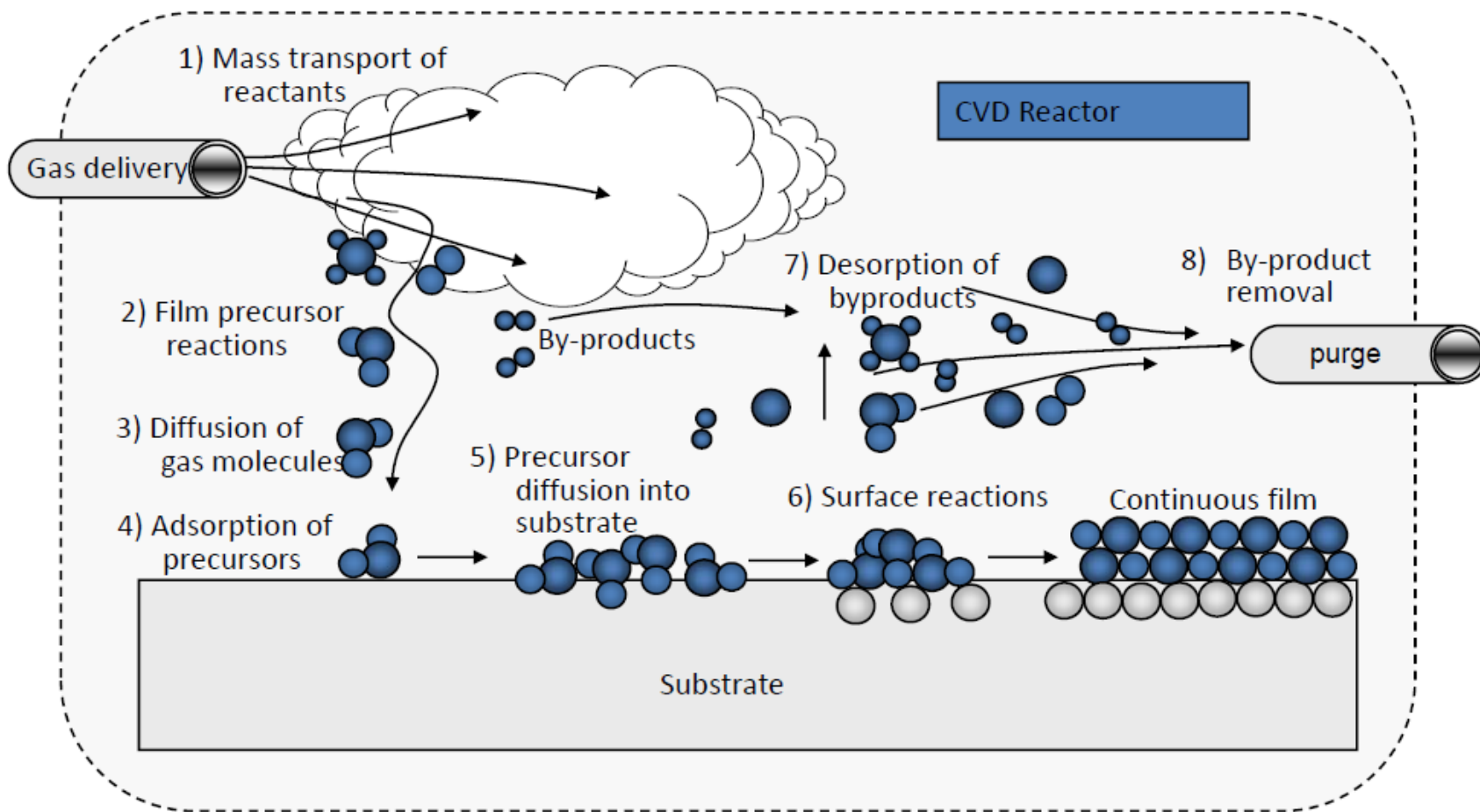
Material	Etchant Atoms
Si, Ge	F, Cl, Br
SiO ₂	F, F + C
Si ₃ N ₄ , silicides	F
Al	Cl, Br
Cu	Cl ($T > 210^{\circ}\text{C}$)
C, organics	O
W, Ta, Ti, Mo, Nb	F, Cl
Au	Cl
Cr	Cl, Cl + O
GaAs	Cl, Br
InP	Cl, C + H

Deposition and implementation

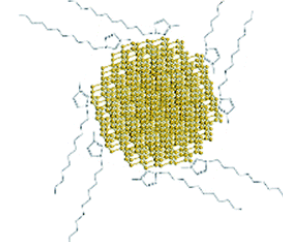
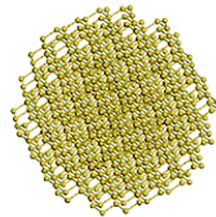
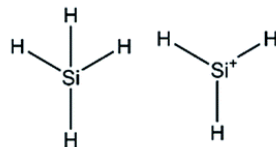
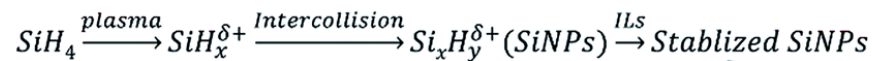
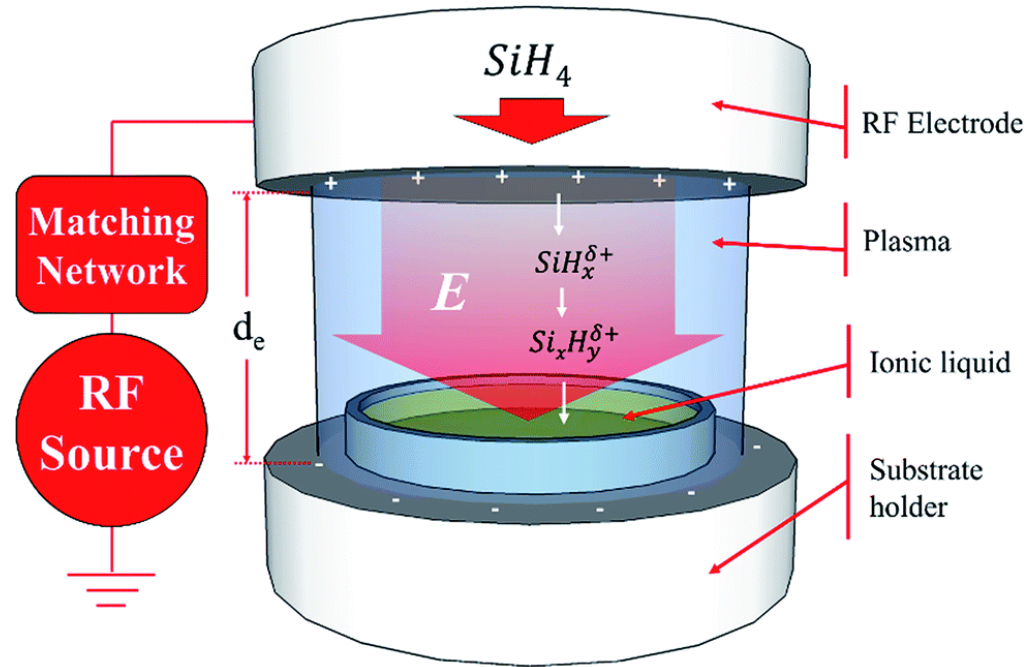


- **Plasma-assisted deposition, implantation, and surface modification are important material processes for producing films on surfaces and modifying their properties**
- **Example processes:**
 - **Plasma-enhanced chemical vapor deposition (PECVD)**
 - **Sputter deposition / physical vapor deposition (PVD)**
 - **Plasma-immersion ion implantation (PIII)**

Chemical Vapor Deposition (CVD)



Plasma-enhanced chemical vapor deposition (PECVD)



Films can be deposited in low temperatures using plasma deposition



- **Device structures are sensitive to temperature, high-temperature deposition processes cannot be used in many cases.**
- **High-temperature films can be deposited at low temperatures.**
- **Unique films not found in nature can be deposited, e.g., diamond.**

Working temperature is determined by the desired film properties

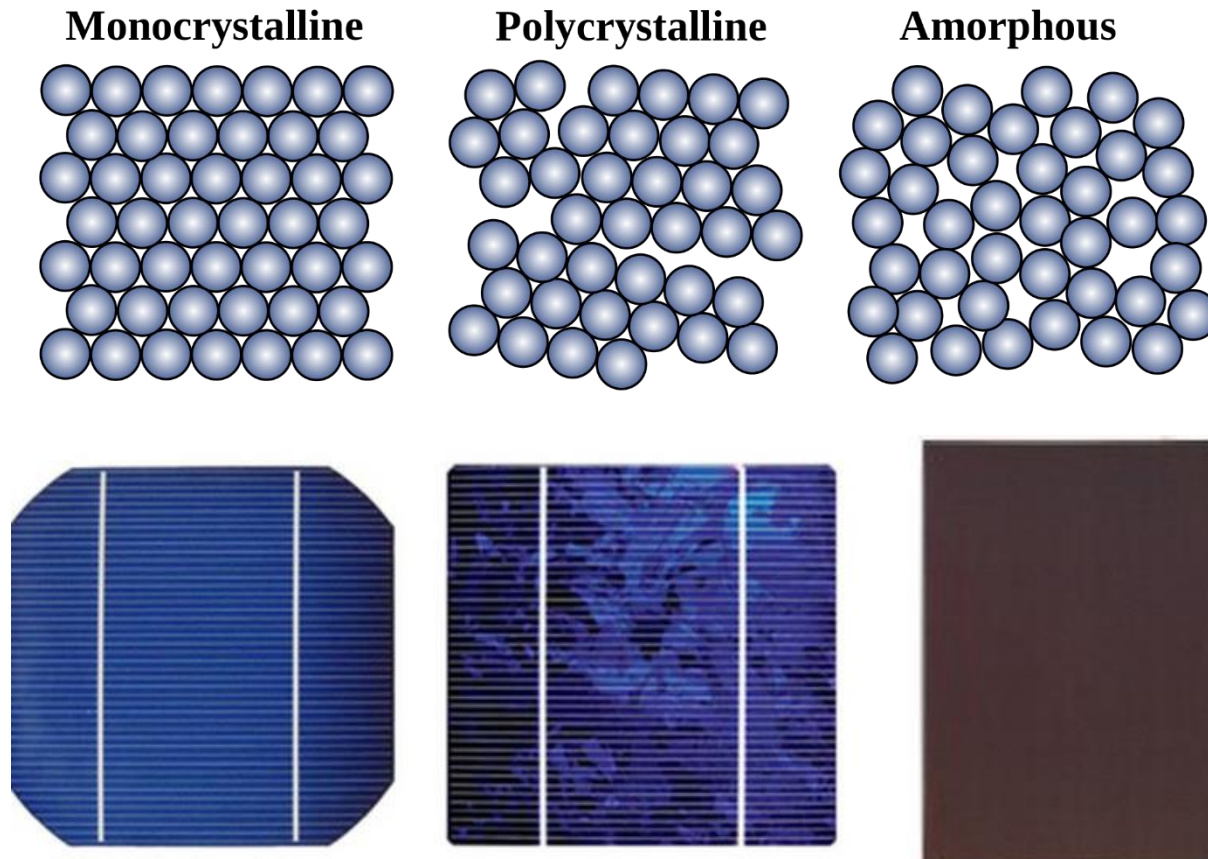


- **CVD – consists of a thermally activated set of gas-phase and surface reactions that produce a solid product at a surface.**
- **PECVD – gas-phase and the surface reactions are controlled or modified by the plasma properties.**
- **$T_e \sim 2-5$ eV in PECVD is much greater than the substrate temperature, the temperature in PECVD is much less than CVD.**
- **Deposition rates are usually not very sensitive to the substrate temperature T .**
- **Film properties such as composition, stress, and morphology, are functions of T .**
- **Low-temperature PECVD films are amorphous, not crystalline, which can more easily be achieved with chemical vapor deposition (CVD).**

Example of using PECVD – amorphous silicon



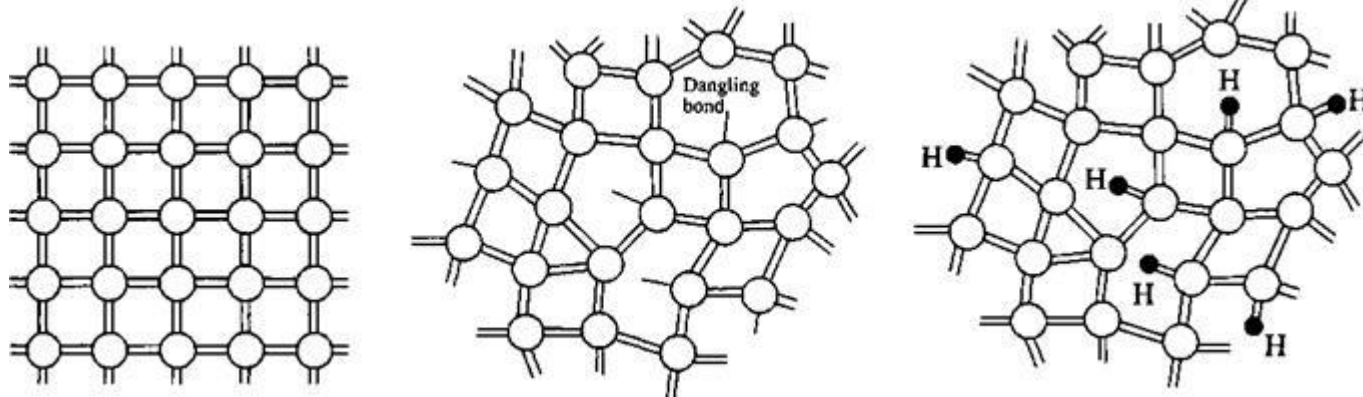
- Amorphous silicon thin films are used in solar cells



Example of using PECVD – amorphous silicon



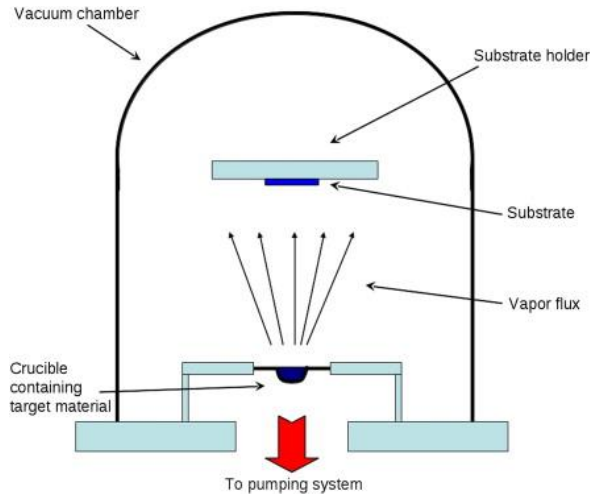
- H is required so that SiH_4 is used
 - For the material to be semiconducting.
 - Terminate the dangling bonds.
 - The dangling bonds are created by ion bombardment (SiH_3^+) which also removes hydrogen from the surface.
 - SiH_3 and SiH_2 radicals are important precursors for film growth while SiH_4 also participates in surface reactions.



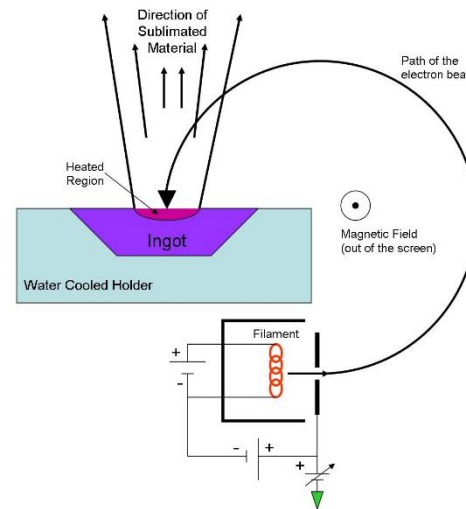
Physical vapor deposition can be achieved by heating the deposited material



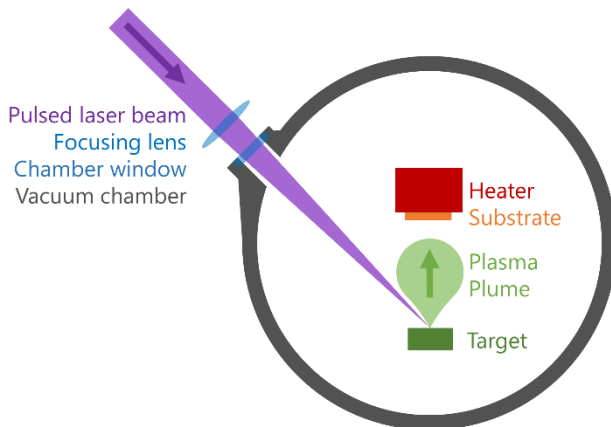
- **Thermal evaporator**



- **Electron-beam evaporator**

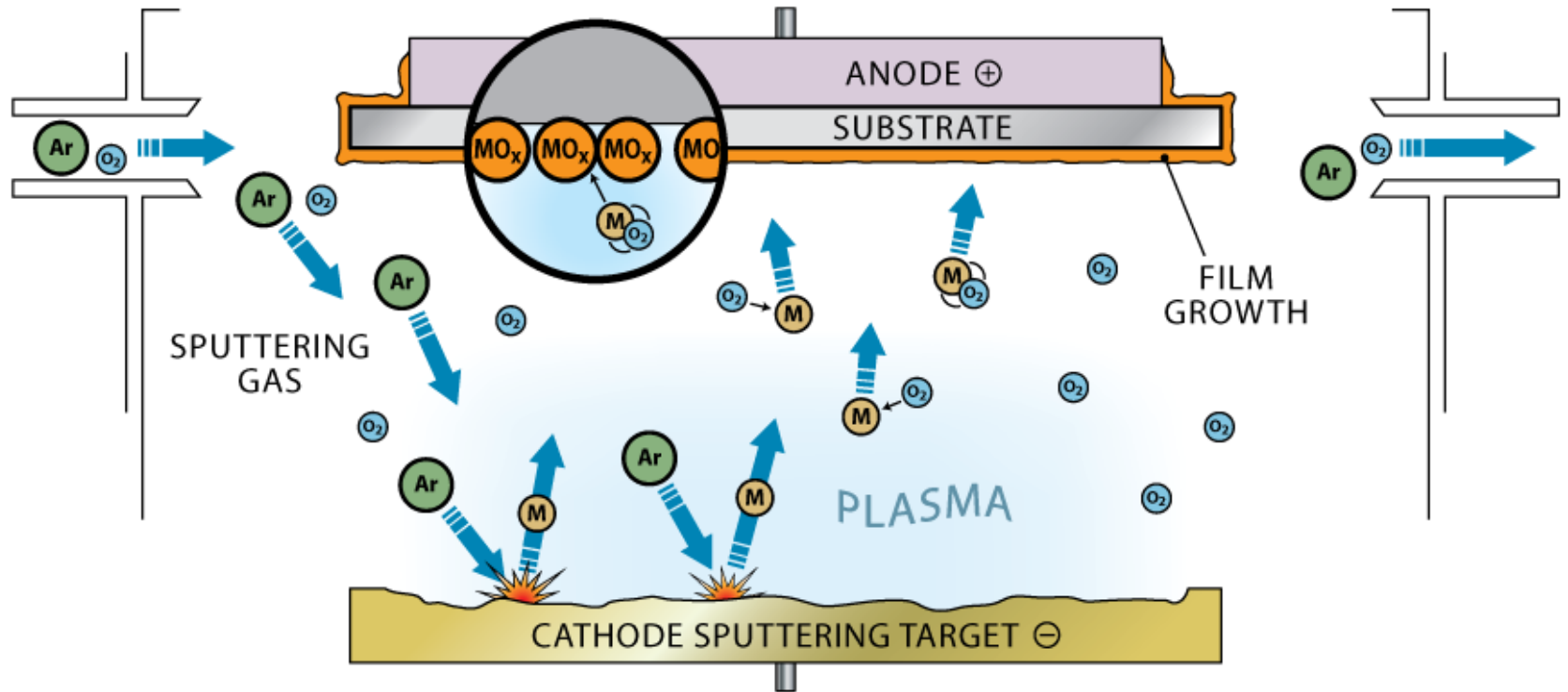


- **Pulsed-laser deposition**



https://en.wikipedia.org/wiki/Pulsed_laser_deposition
 Engineered biomimicry by A. Lakhtakia and R. J. Martin-Palma
https://en.wikipedia.org/wiki/Electron-beam_physical_vapor_deposition

Sputtering deposition



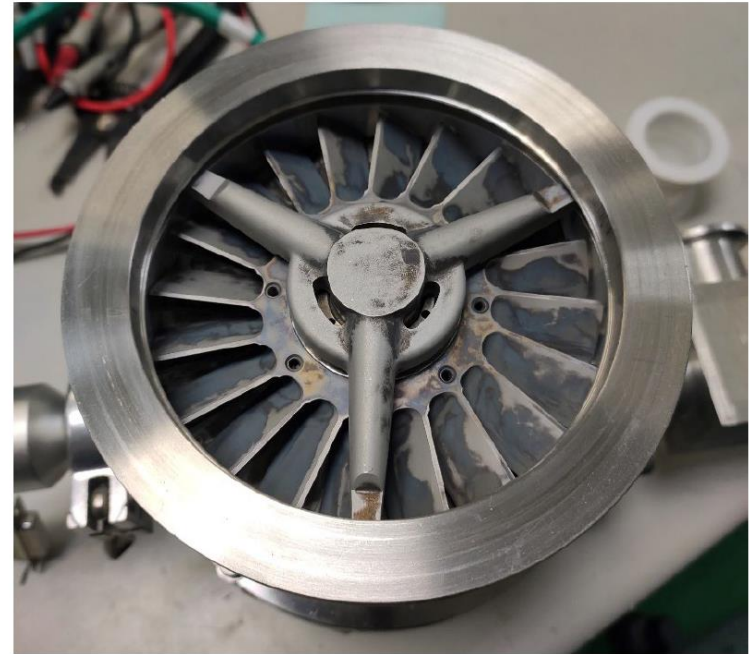
The chamber becomes very dirty after the deposition process



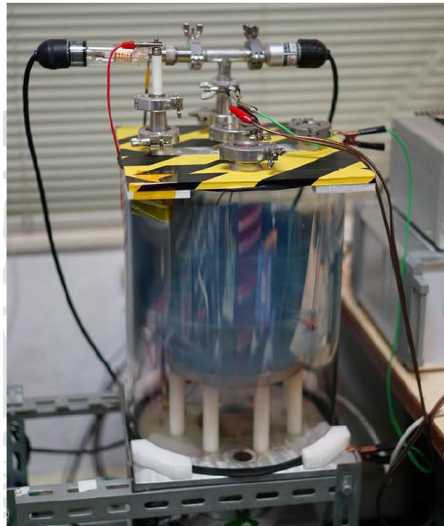
- Before



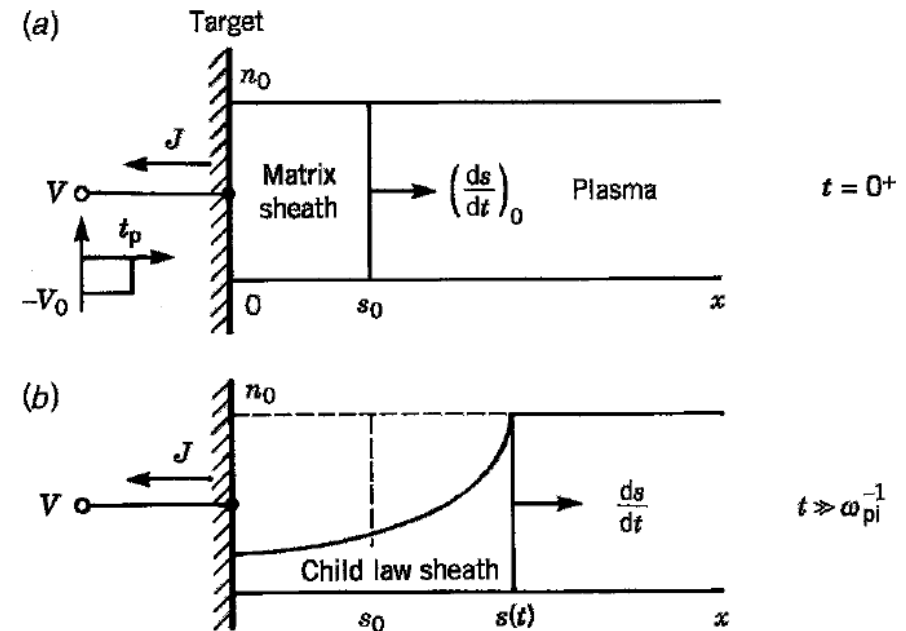
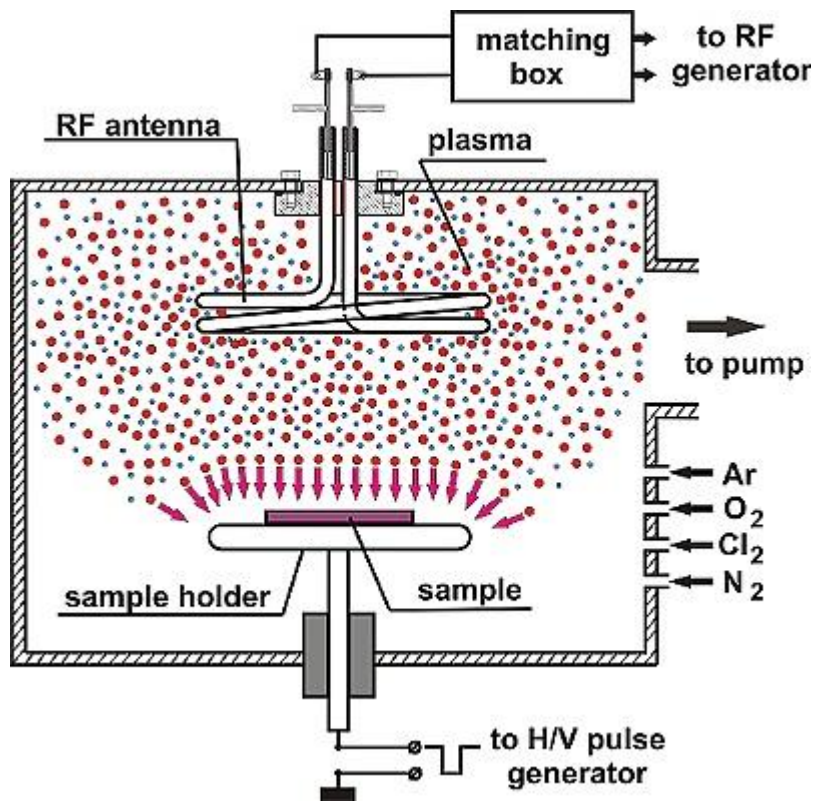
- The turbomolecular pump is also very dirty after the process.



- After

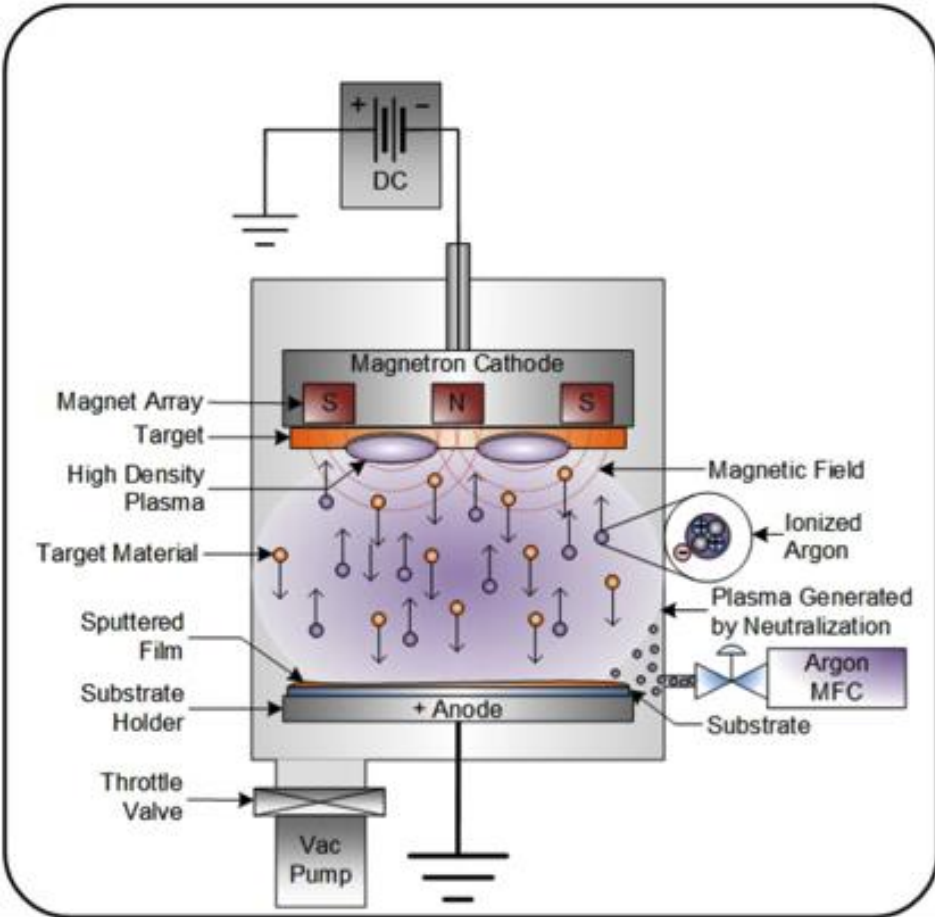
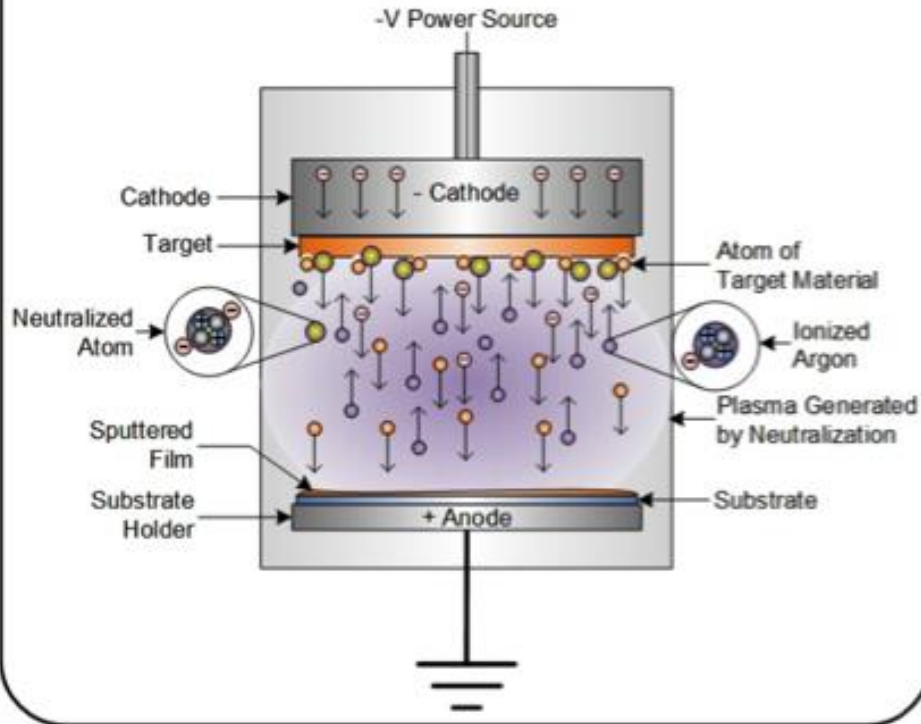


Plasma-immersion ion implantation (PIII)

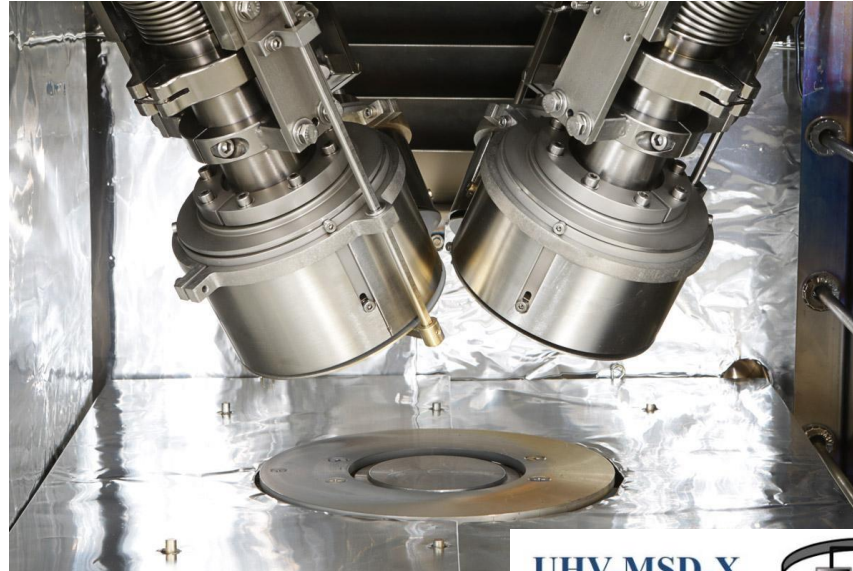
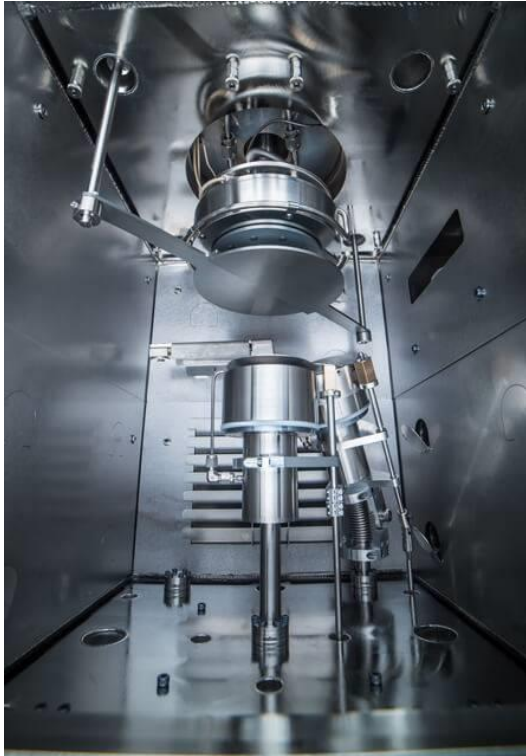


- Silicon doping – ions such as B, P, As are implanted
- Surface hardening of metals – N, C are implanted

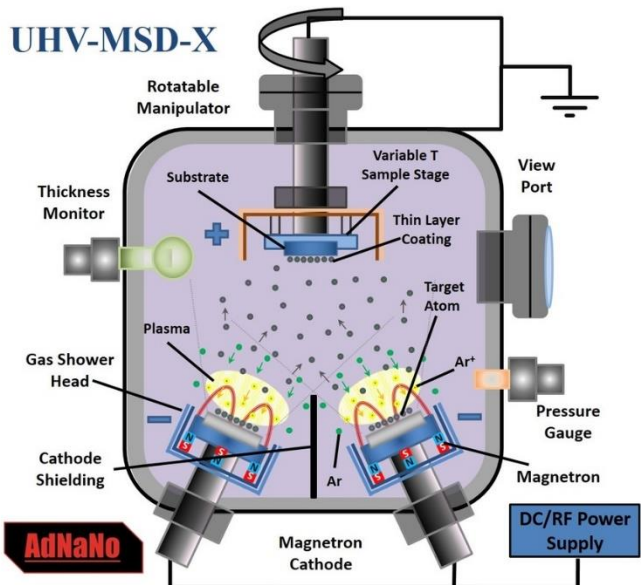
Magnetron sputtering provides higher deposition rates than conventional sputtering



Examples of magnetron sputtering deposition



UHV-MSD-X



<https://angstromengineering.com/tech/magnetron-sputtering/pulsed-dc/>
<https://dynavac.com/wp-content/uploads/2017/09/Confocal-Sputtering-2.jpg>
<https://www.adnano-tek.com/magnetron-sputtering-deposition-msd.html>

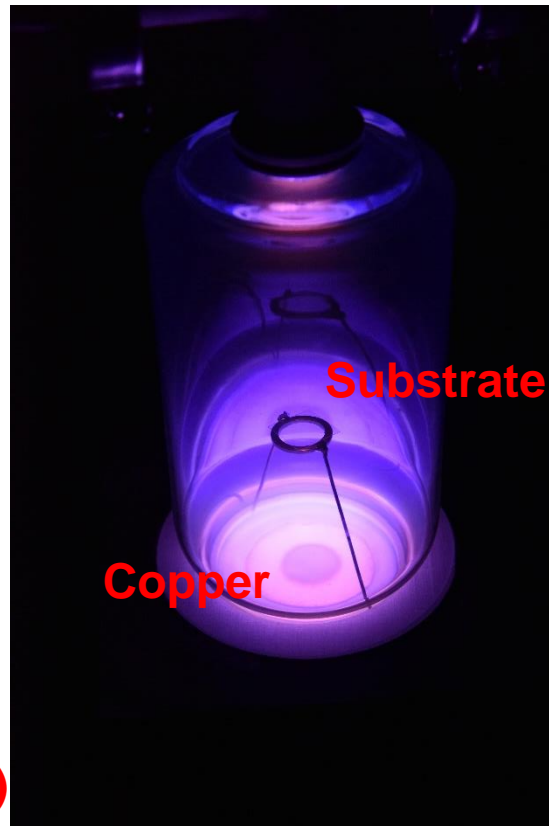
Demonstration experiments – magnetron sputtering



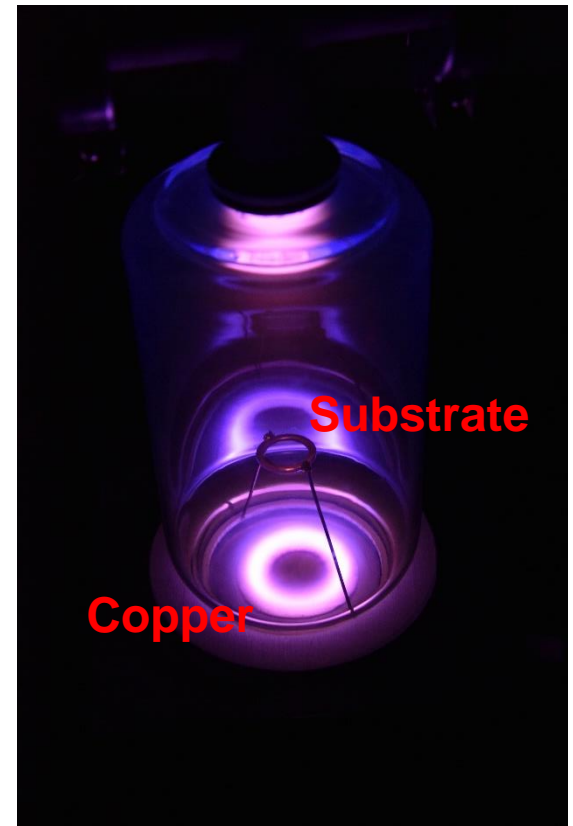
- System



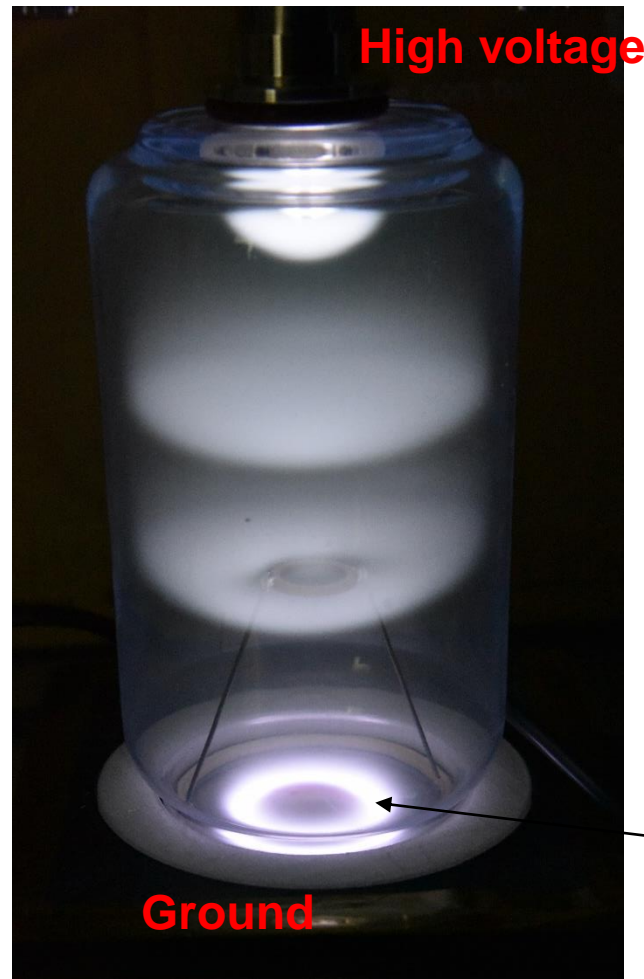
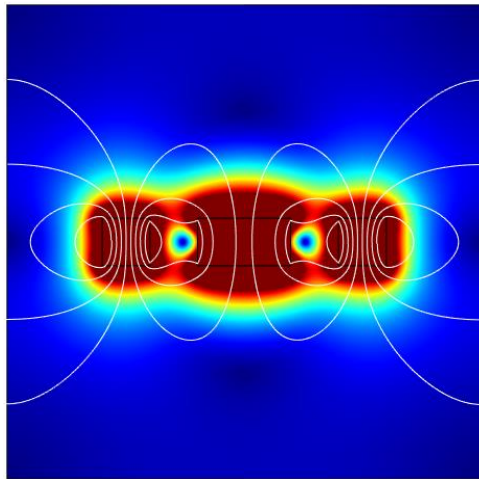
- Without magnet



- With magnet

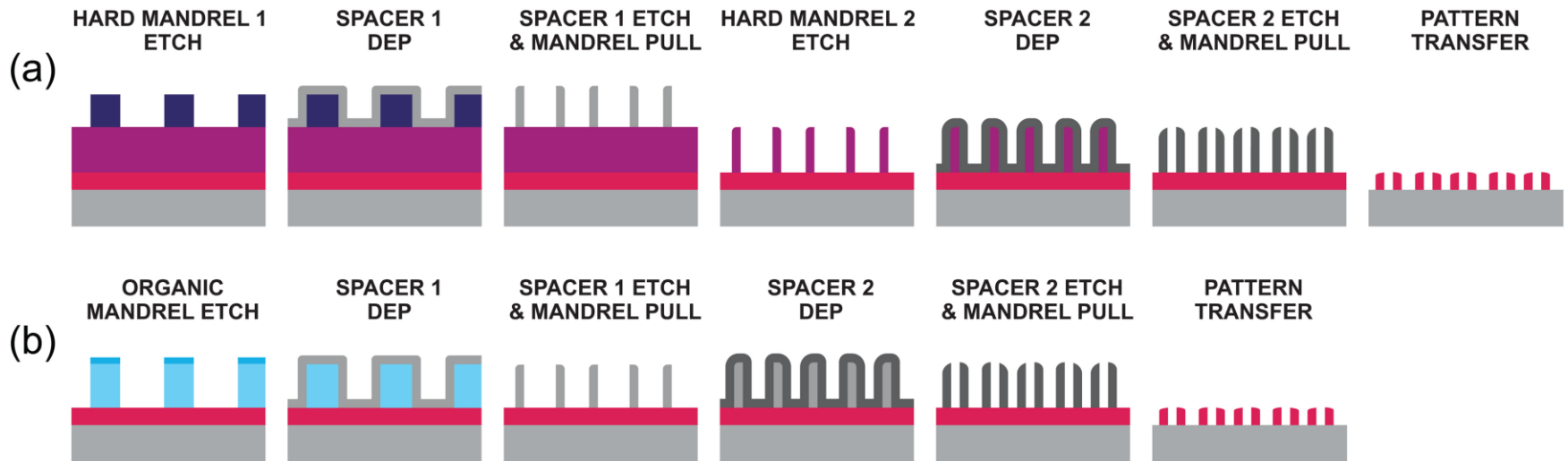


A bright ring occurs when the magnet is inserted into the system



Confined electrons

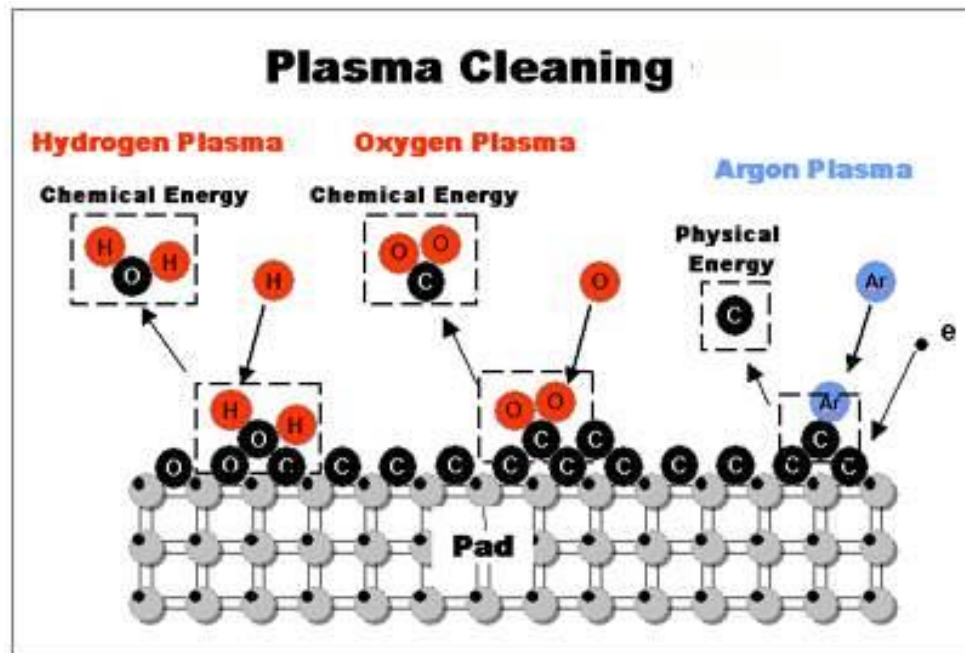
self-aligned quadruple patterning



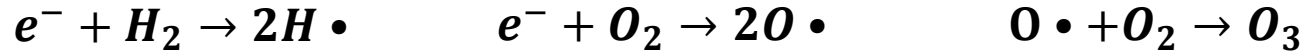
Plasma can be used for cleaning surface



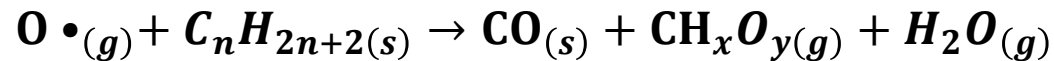
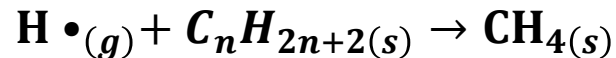
- Cleaning mechanisms:
 - Chemical reactions by free radicals
 - Physical sputtering by high energy ions



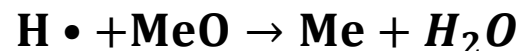
Free radicals are generated and used in chemical reactions



- Highly reactive free radicals generated in plasma may react with the hydrocarbon contaminants of surface oxide.
- Both $H \bullet$ and $O \bullet$ can react with grease or oil on surface to form volatile hydrocarbons.



- $O \bullet$ is more reactive than $H \bullet$. But $O \bullet$ may also react with surface metal to form oxide, deteriorating the material properties. Nevertheless, $H \bullet$ can make metal oxide back to metal.



The effect of chemical reactions is increased as the pressure increases



- **Advantages:**

- **Stable gas products are formed.**
- **No redeposition problem.**
- **High etching selectivity.**

- **Disadvantages:**

- **Higher concentration of H_2 or O_2 is required to ensure an appropriate etching rate.**
- **H_2 safety or O_2 strong oxidation ability needs to be monitored.**

High energy ions are used in physical sputtering cleaning



- Ions generated in plasma can be accelerated toward the substrate to physically bombard away the atoms of contaminants.
- The physical sputtering rate increases as the following quantities increase:
 - Plasma density;
 - Accelerating voltage;
 - Mass of bombardment atoms.
- The physical sputtering is also enhanced by lowering the pressure.
- High cathode bias is used.
- Ar^+ has strong sputtering effect.

The physical sputtering rate increases with higher cathode bias and Ar concentration and lower pressure



- **Advantages:**

- Highly efficient cleaning effect can be achieved.
- Gas consumption rate can be very low.

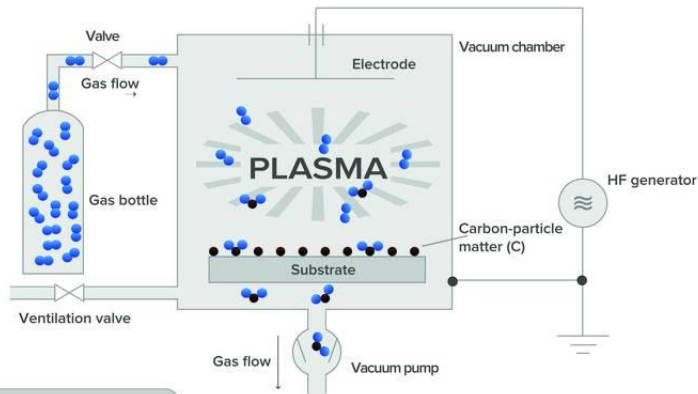
- **Disadvantages:**

- Etching problems – non-selective etching by physical sputtering.
- Redeposition problems: the products sputtered out may be highly unstable and tend to deposit again downstream.

Plasma cleaning examples



Low-pressure plasma system: Generation with a low-frequency or high-frequency generator

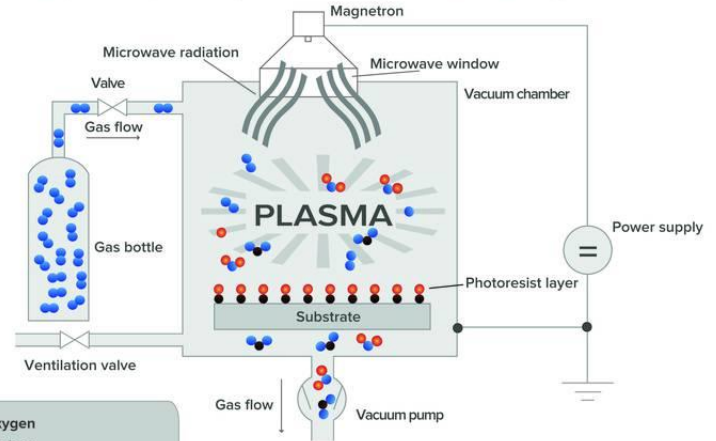


- Oxygen
- Carbon

e.g.: The removal of carbon-particle matter with O₂ plasma
 $C + O^2 \rightarrow CO_2 \uparrow$

Diagram 6

Low-pressure plasma system: Cleaning with a microwave generator



- Oxygen
- Carbon
- Hydrogen

e.g.: Removal of photoresist
 $C + O_2 \rightarrow CO_2 \uparrow$
 $2H + O \rightarrow H_2O \uparrow$

Diagram 7

Plasma cleaning needs to work in the regime of abnormal glow discharge



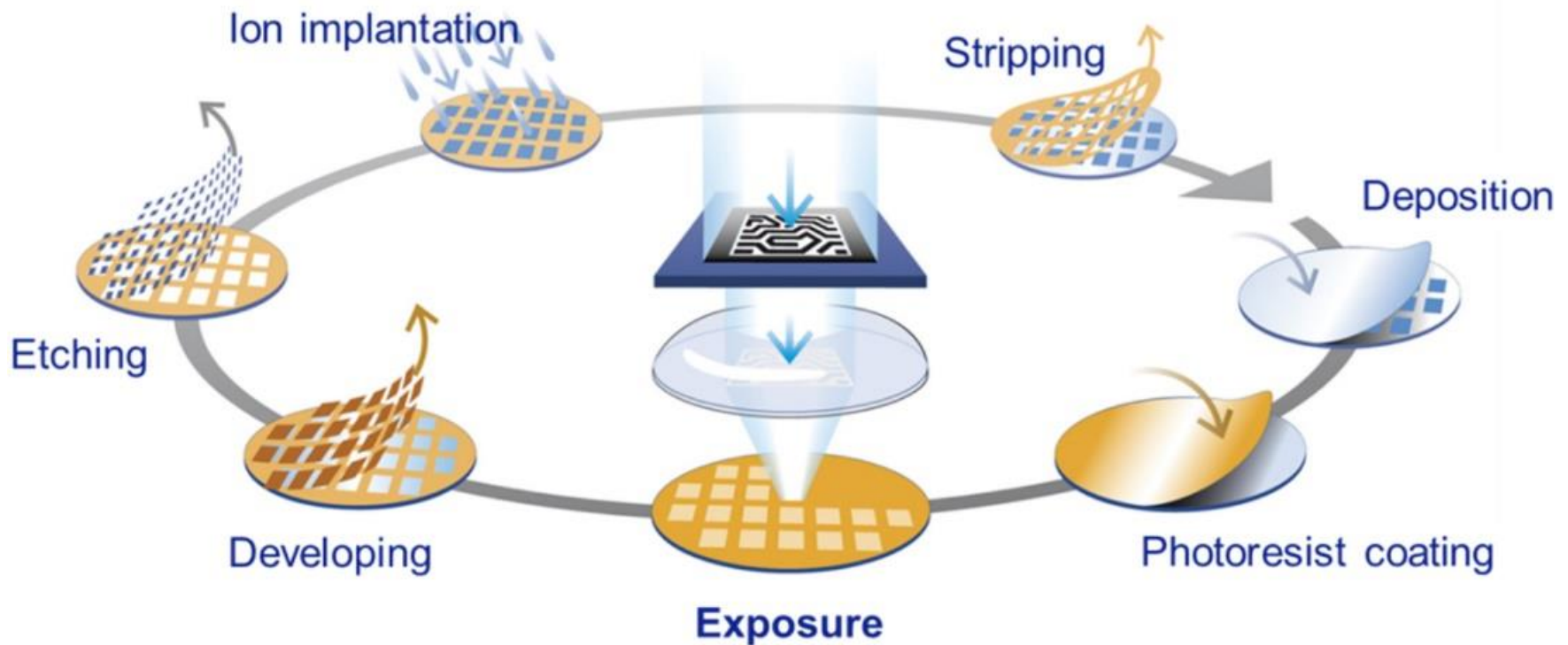
- Top view



- Side view



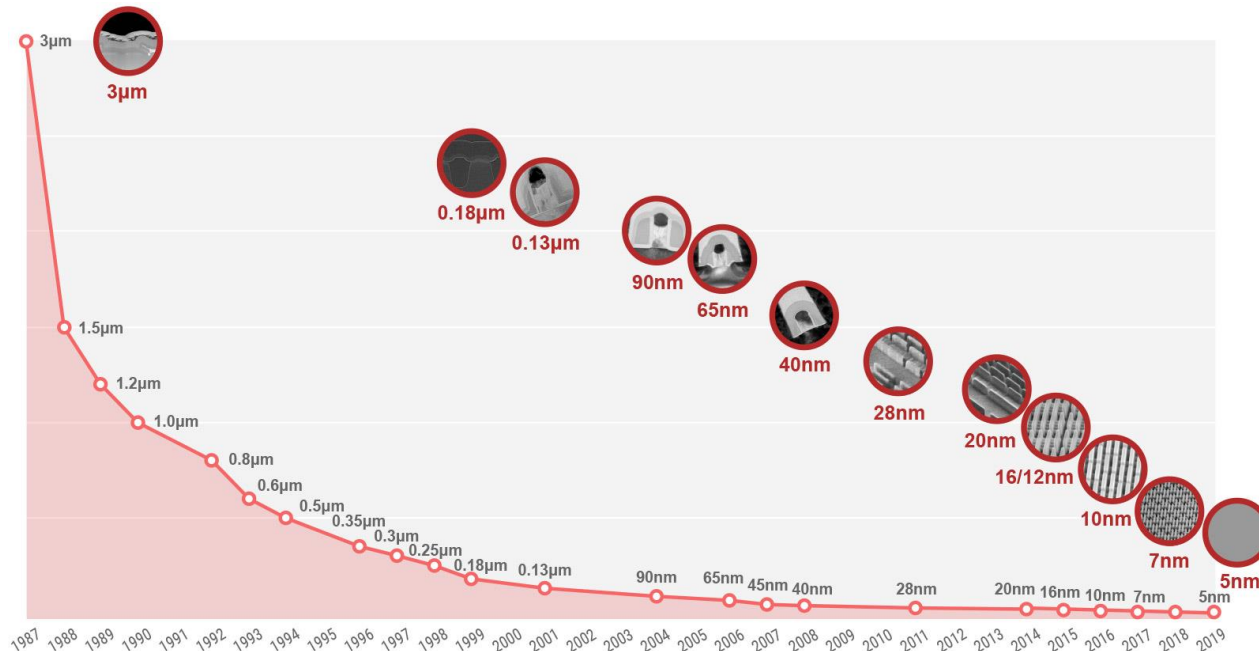
A semiconductor device is fabricated by many repetitive production process



Ultraviolet lithography (EUVL) is one of the key technologies in semiconductor manufacturing nowadays



- The process technology of Taiwan Semiconductor Manufacturing Company Limited (TSMC):



- Optical diffraction needs to be taken into account.
- Shorter wavelength is preferred.

• Light source with a center wavelength of 13.5 nm is used.

EUV lithography becomes important for semiconductor industry



- 0.15 billion USD for each EUV light source.

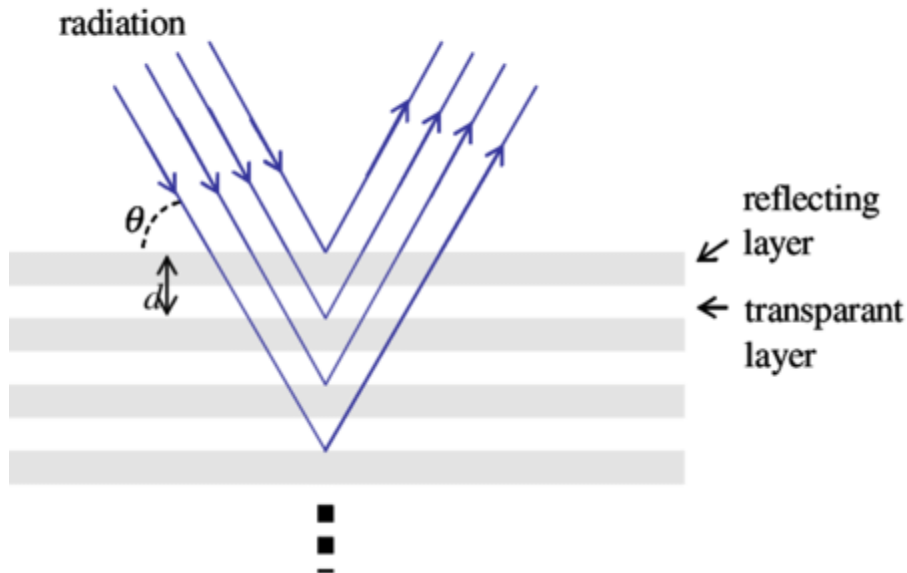
<https://www.youtube.com/watch?v=NHSR6AHNiDs>



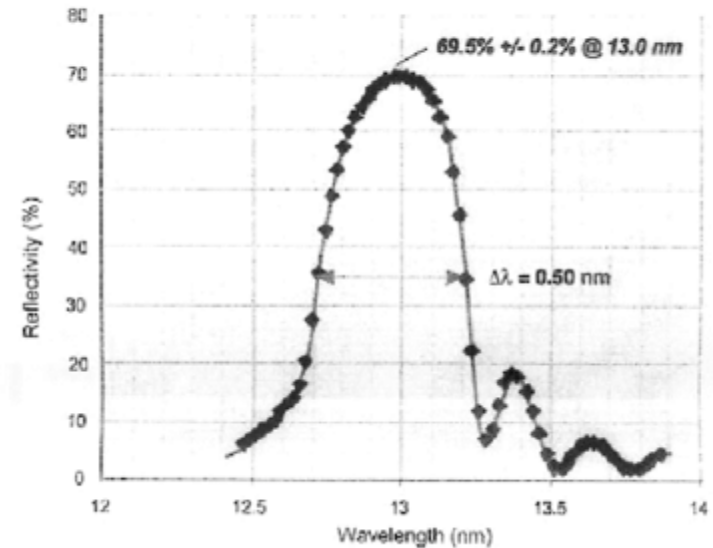
EUV light can only be reflected using multilayer mirrors



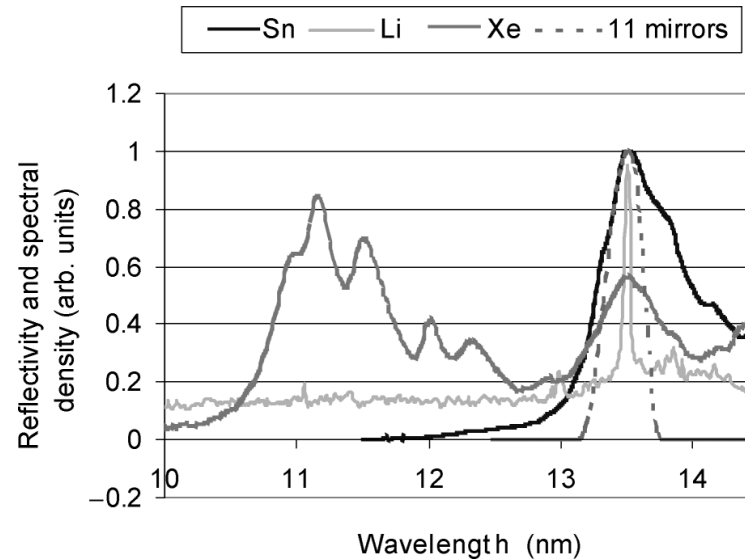
a)



b)



13.5-nm EUV light is picked for EUV lithography



- $\lambda = 13.5 \text{ nm} \pm 1\%$ is required.
- At $T=35\text{-}40 \text{ eV}$ ($\sim 450,000 \text{ K}$), in-band emission occurs.
- Xenon:
 - $4p^6 4d^8 \rightarrow 4p^6 4d^7 5p$ from single ion stage Xe^{10+}
 - UTA @ 11 nm
- Tin:
 - $4p^6 4d^N \rightarrow 4p^5 4d^{N+1} + 4p^6 4d^{N-1} 4f$ ($1 \leq N \leq 6$) in ions ranging from Sn^{8+} to Sn^{12+}
 - UTA @ 13.5 nm
- UTA: unresolved transition array

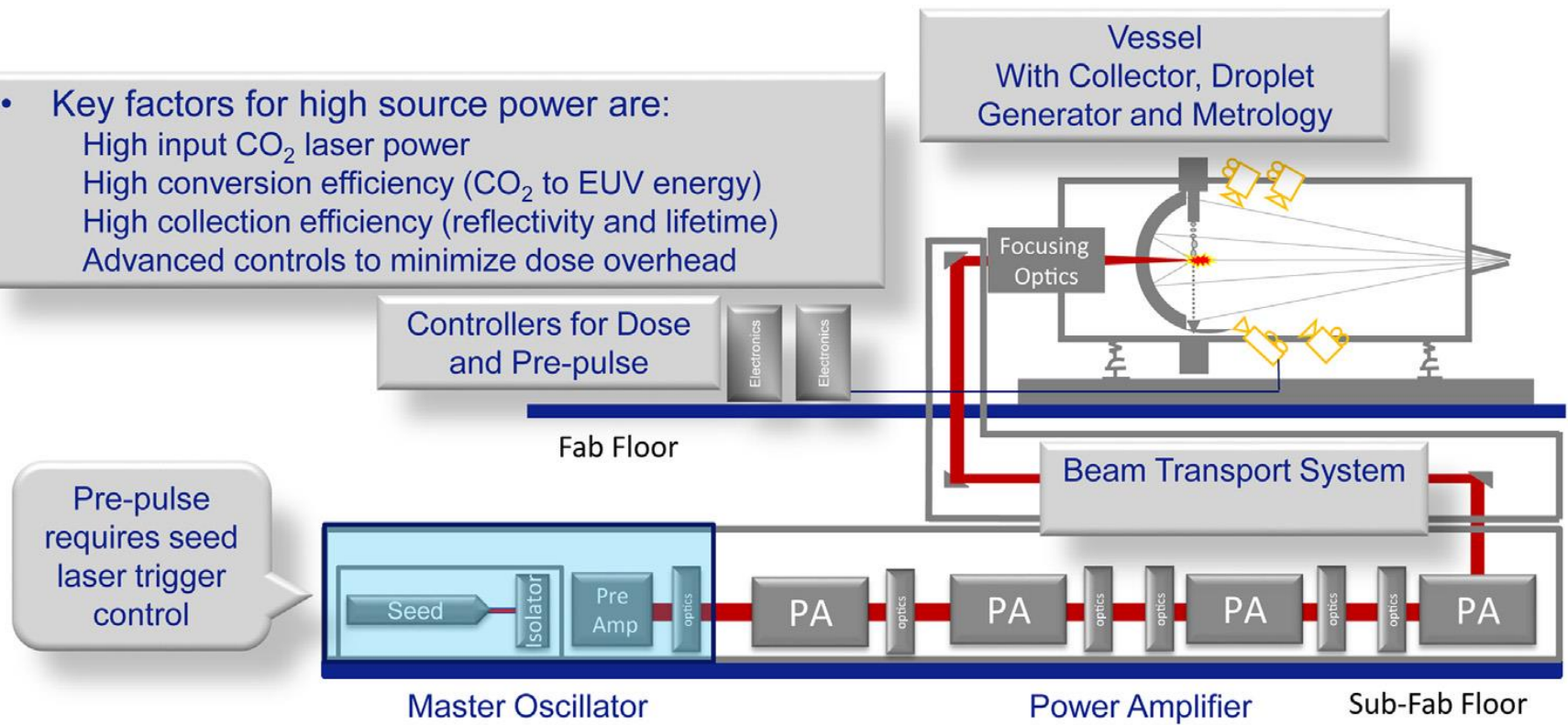
V. Bakshi, EUV sources for lithography

R. S. Abhari, etc., J. Micro/Nanolithography, MEMS, and MOEMS, 11, 021114 (2012)

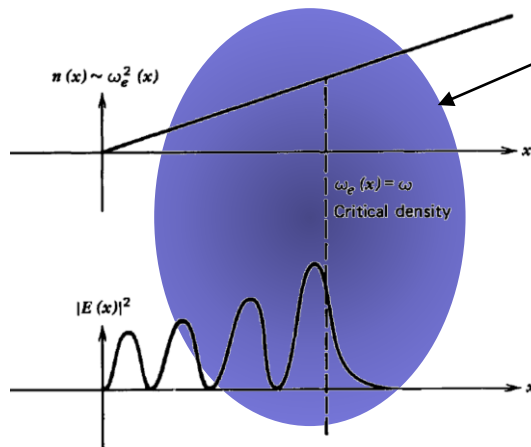
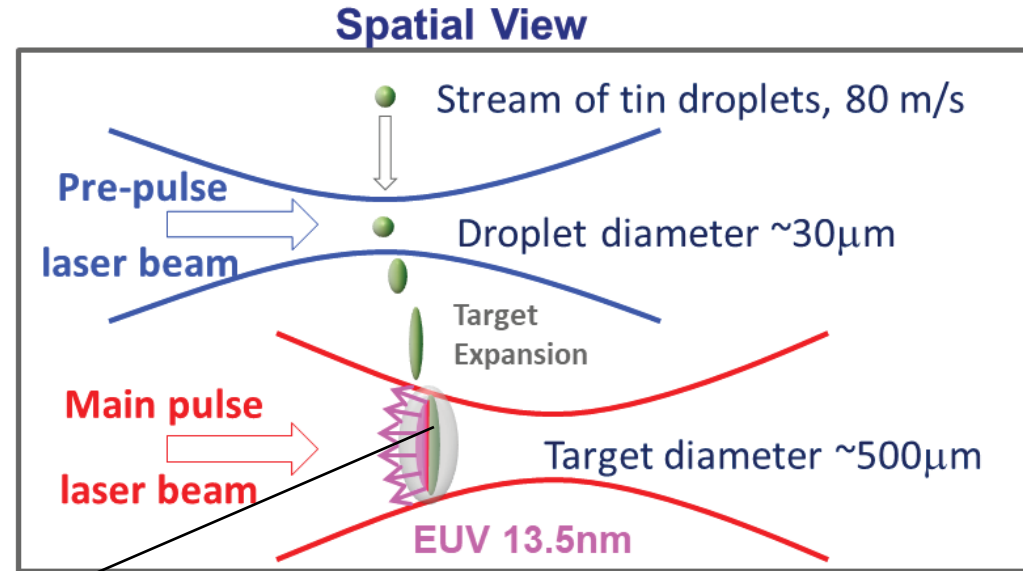
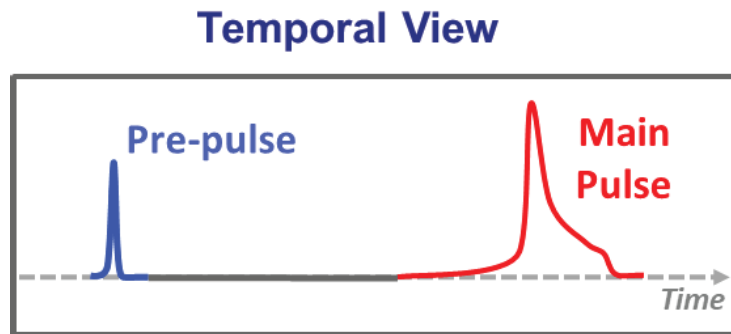
EUV light is generated from laser-produced plasma (LPP)



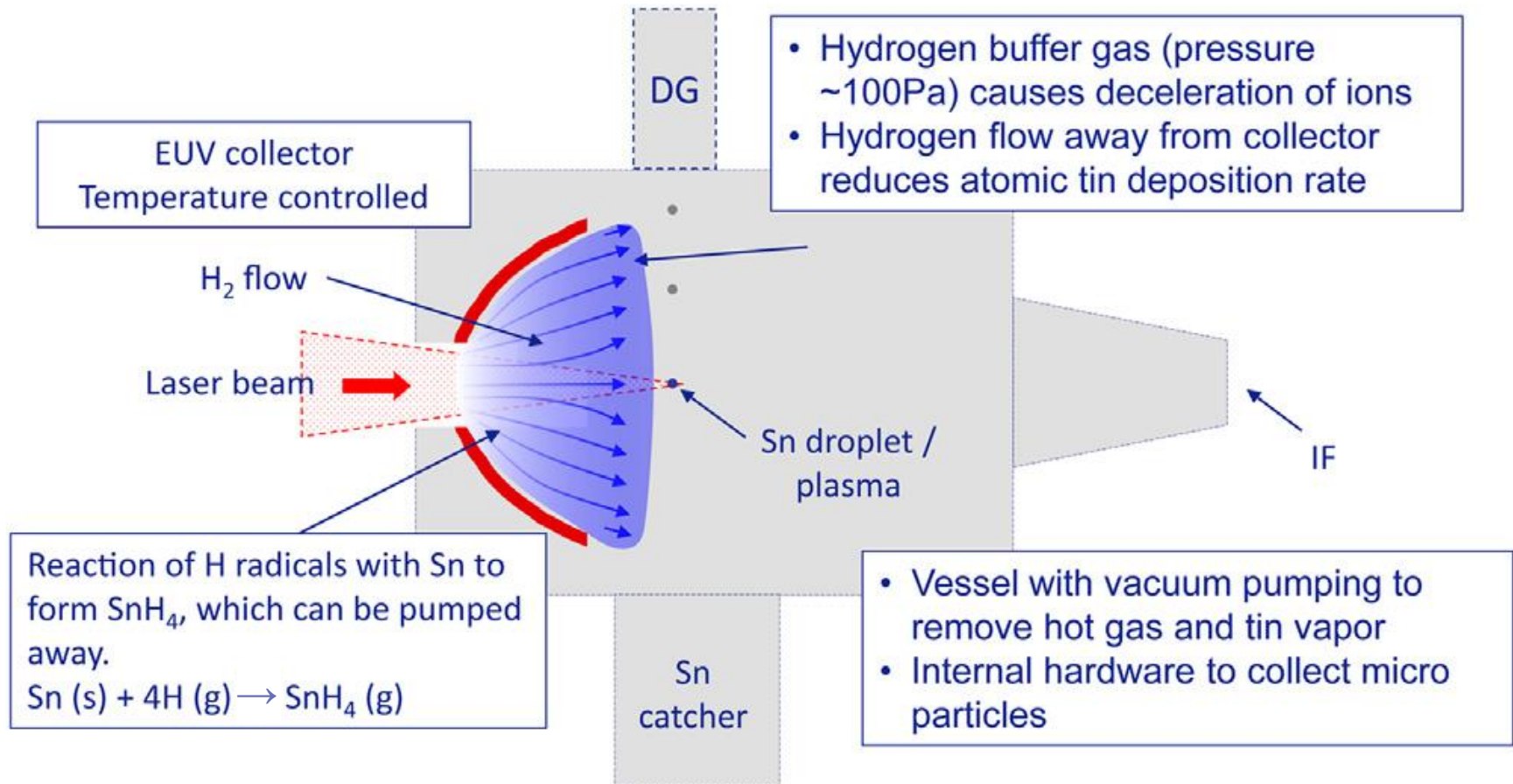
- Key factors for high source power are:
 - High input CO₂ laser power
 - High conversion efficiency (CO₂ to EUV energy)
 - High collection efficiency (reflectivity and lifetime)
 - Advanced controls to minimize dose overhead



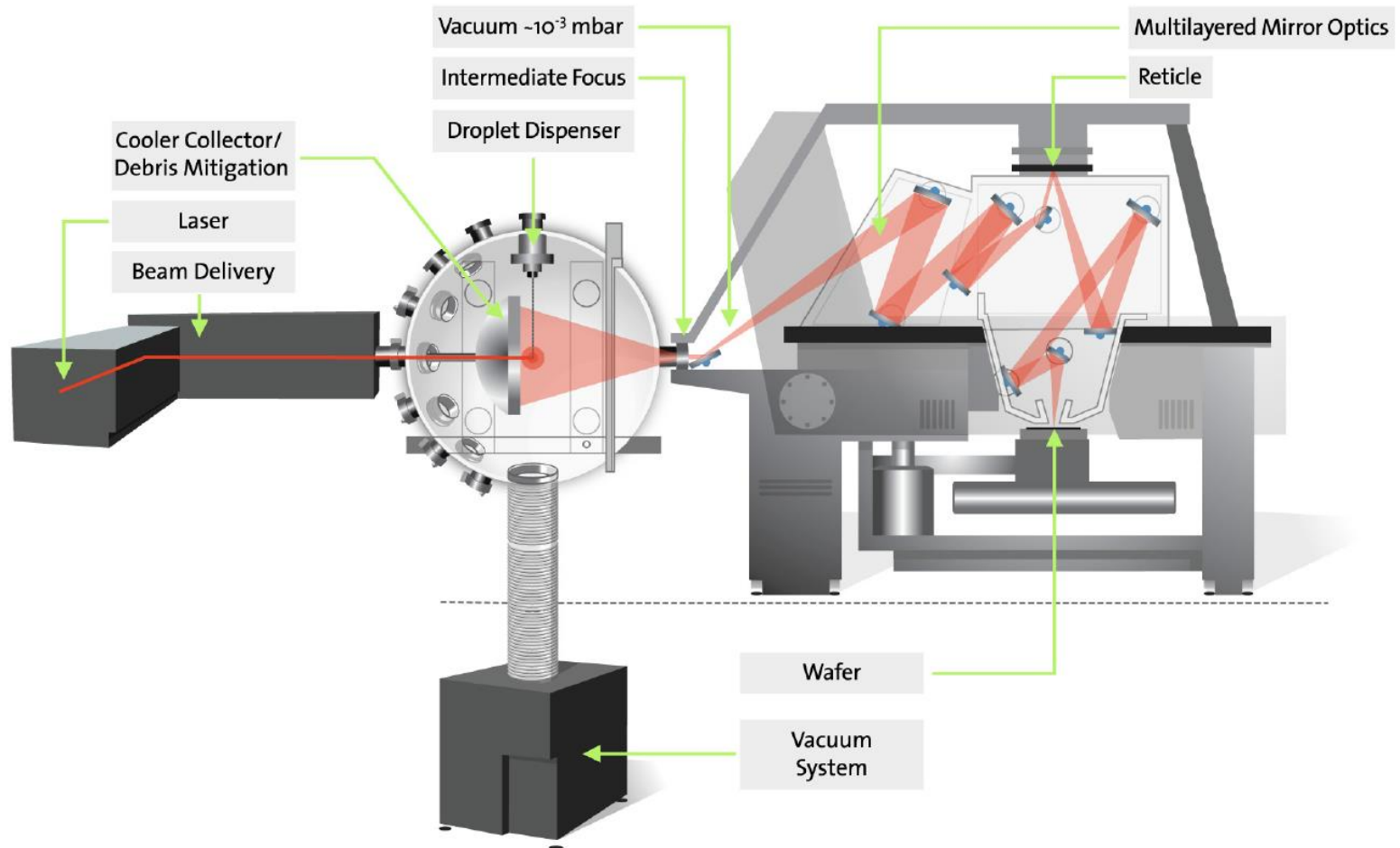
Two laser pulses are used to heat the plasma



Hydrogen buffer gas with a pressure of ~100 Pa is used to protect the collector mirror



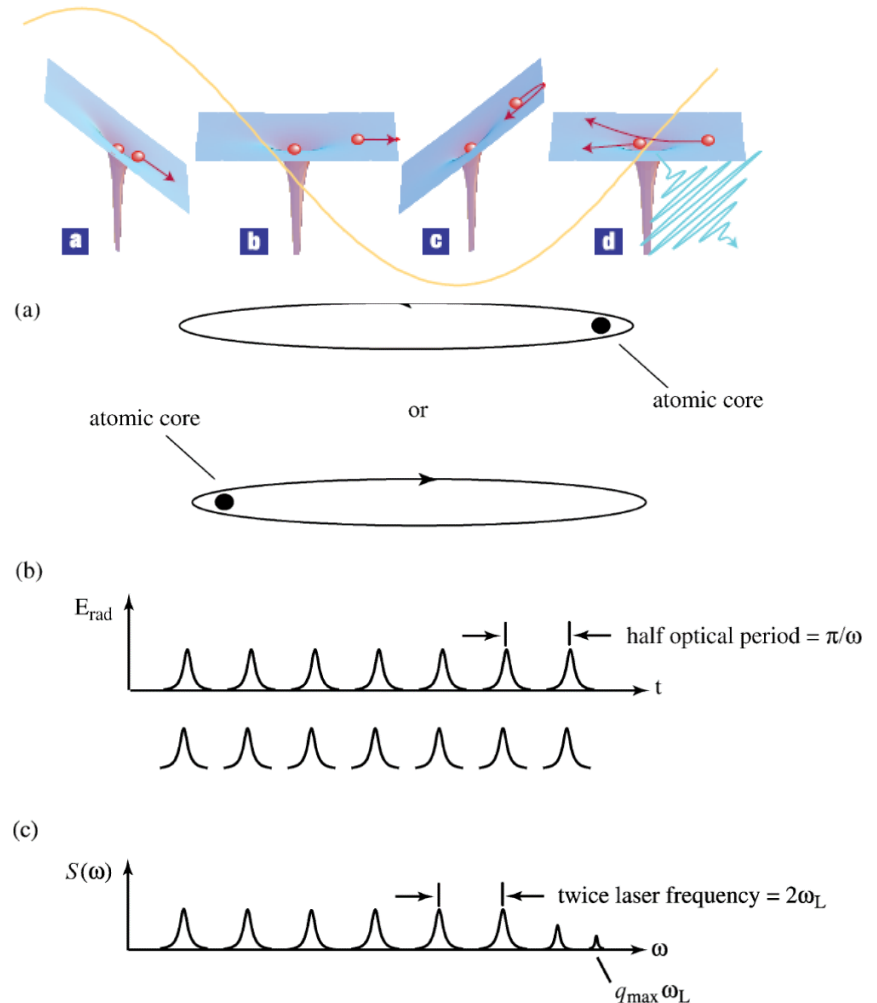
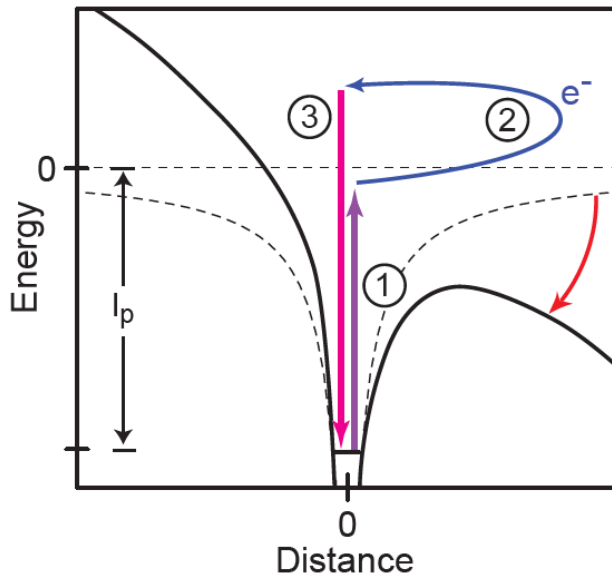
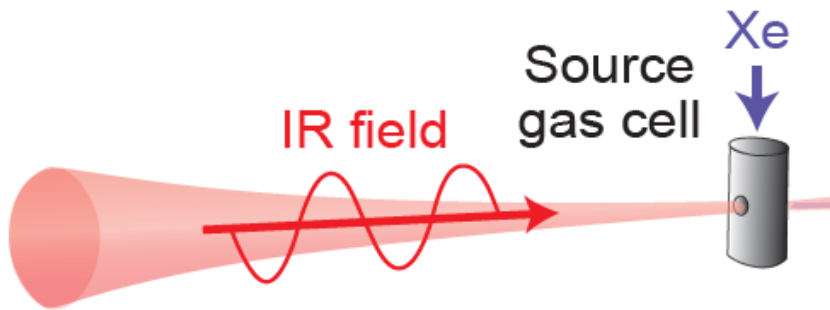
Laser-produced plasma (LPP) is used in the EUV lithography



High harmonic generation from high-power laser

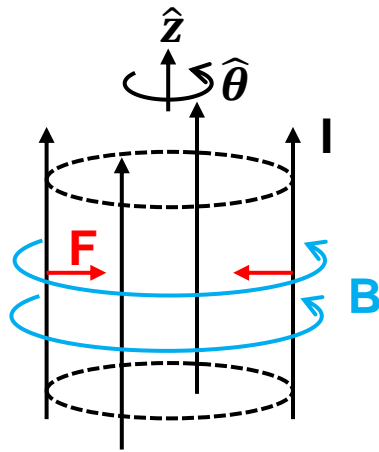


- For $I < 10^{18} \text{ w/cm}^2$



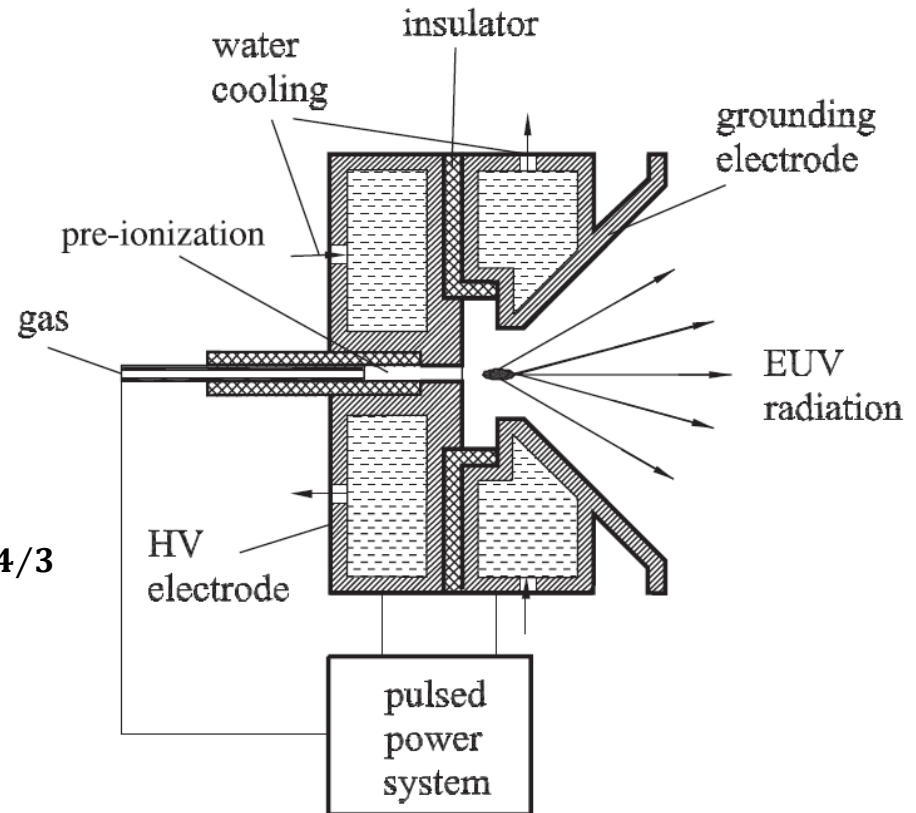
- M. Krüger, et al., *Appl. Sci.* 9, 378 (2019)
- *Nonlinear Optics 3rd edition*, by Robert W. Boyd
- P. B. Corkum and F. Krausz, *Nature Phys.*, 3, 381 (2007)

EUV light can be generated using discharged-produced plasma



- **Adiabatic compression:**

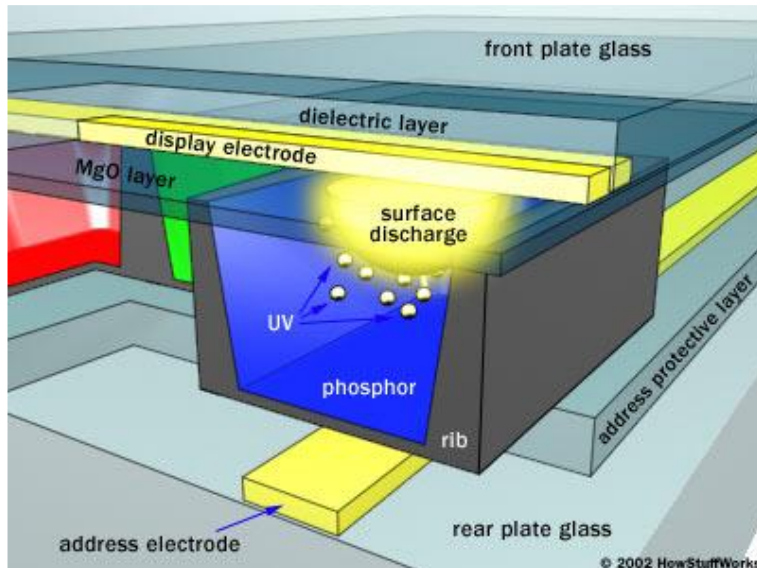
$$TV^{\gamma-1} = \text{const} \quad T_f = T_o \left(\frac{r_o}{r_f} \right)^{4/3}$$



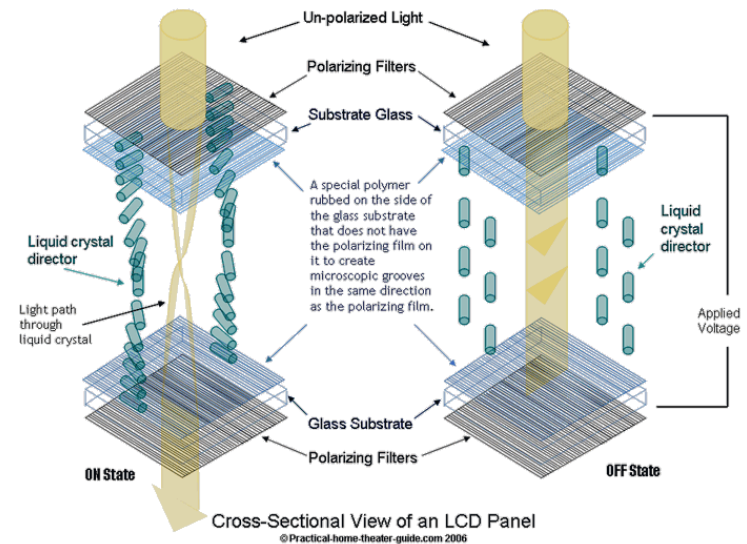
Light source and display systems



Plasma display panel (PDP)



Liquid crystal display (LCD)

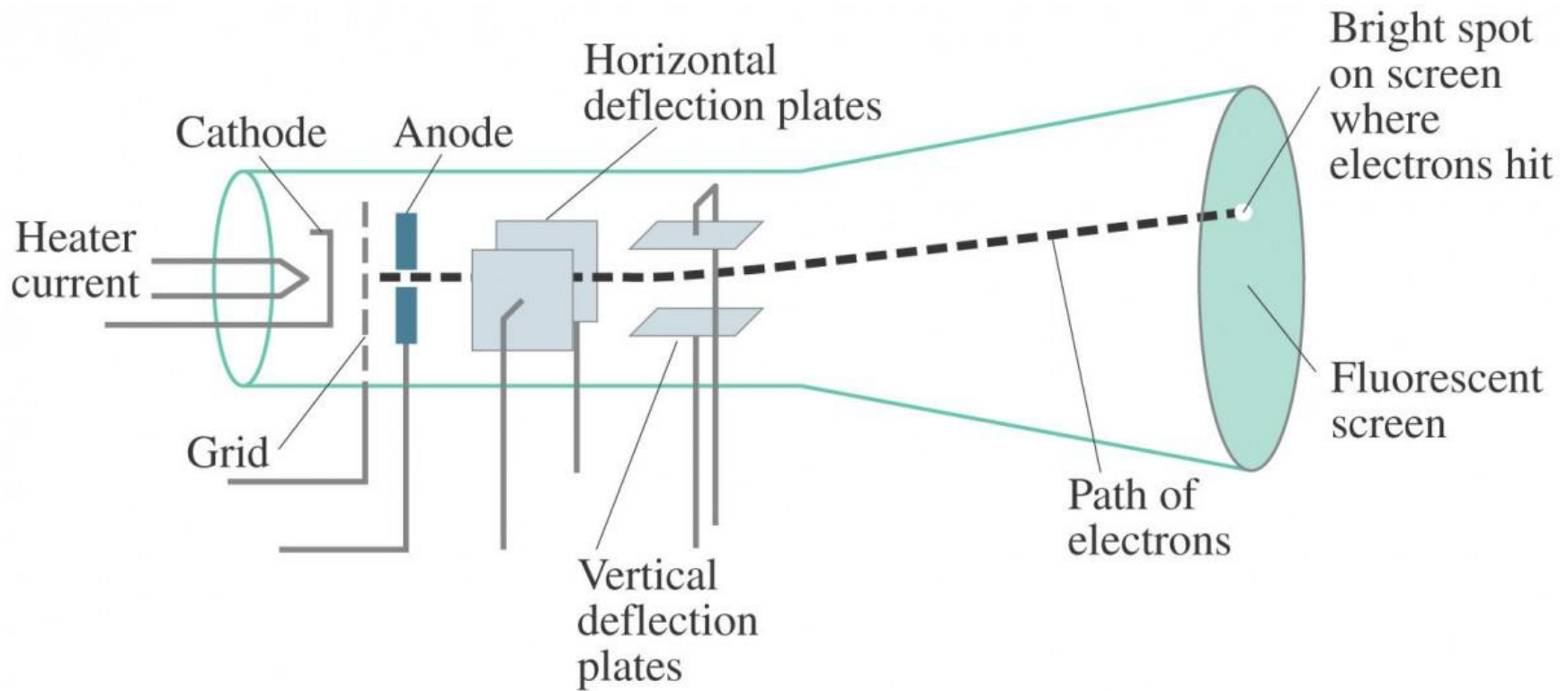


Outlines

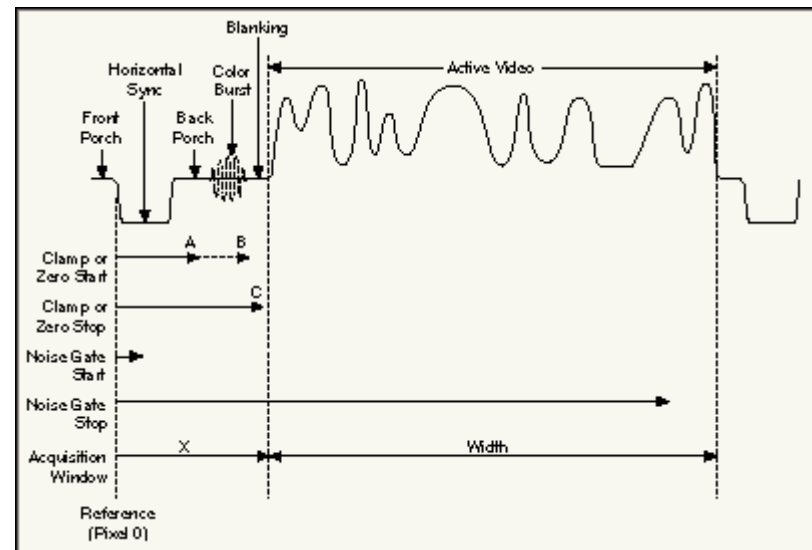
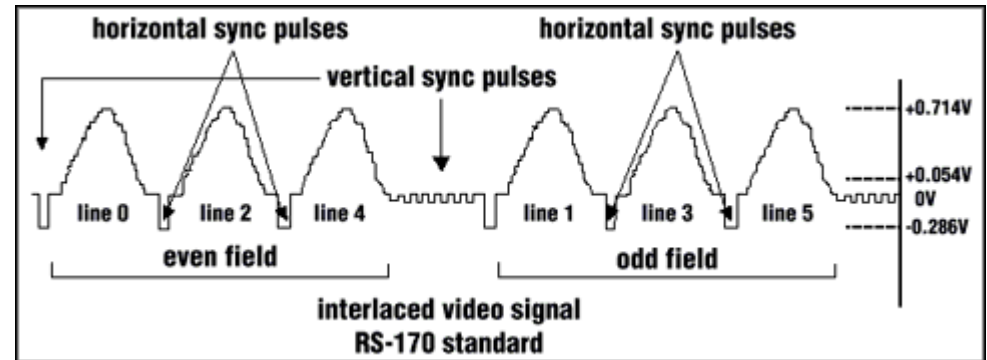
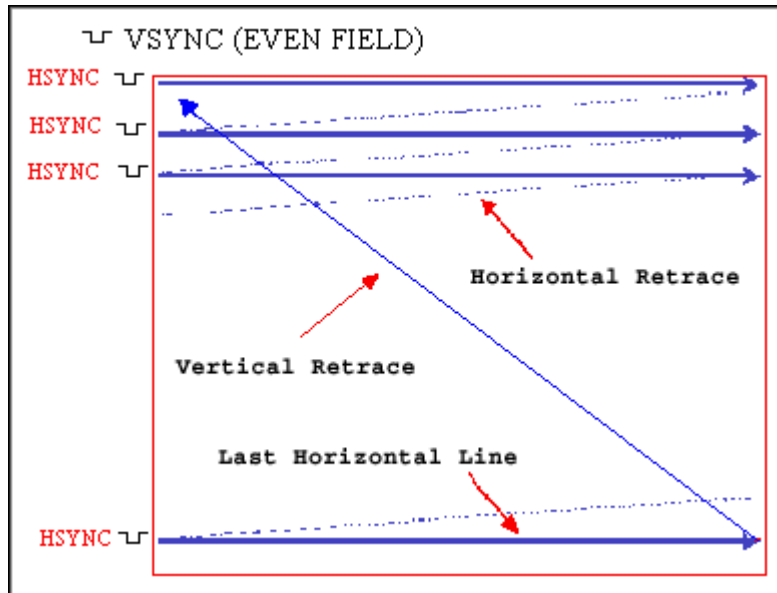


- **Cathode Ray Tube**
- **Color space (CIE 1931 color spaces)**
- **History of plasma display panel (PDP)**
- **Design of PDP**
- **Liquid crystal display (LCD)**
- **LCD vs PDP**

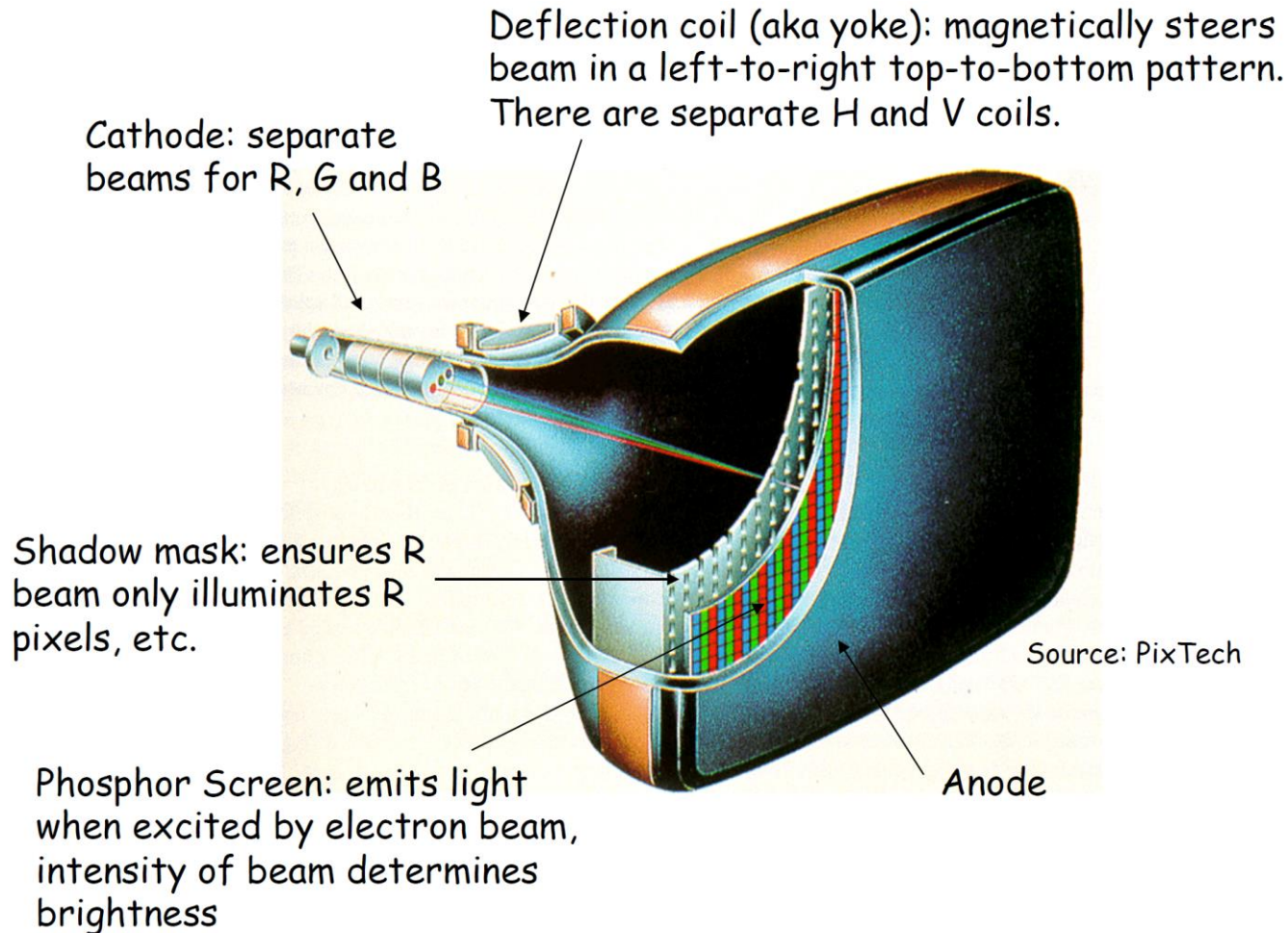
Cathode Ray Tube uses electron beams to light the fluorescent screen



The image is shown by scanning through the whole screen with the single electron beam



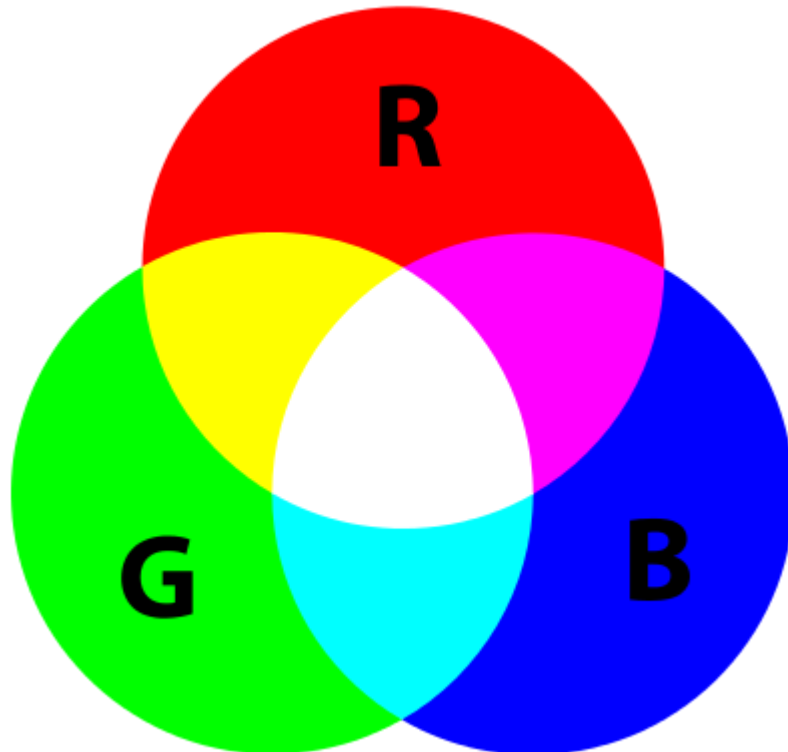
Color image is formed by using three electron beams scanning through three different color channels



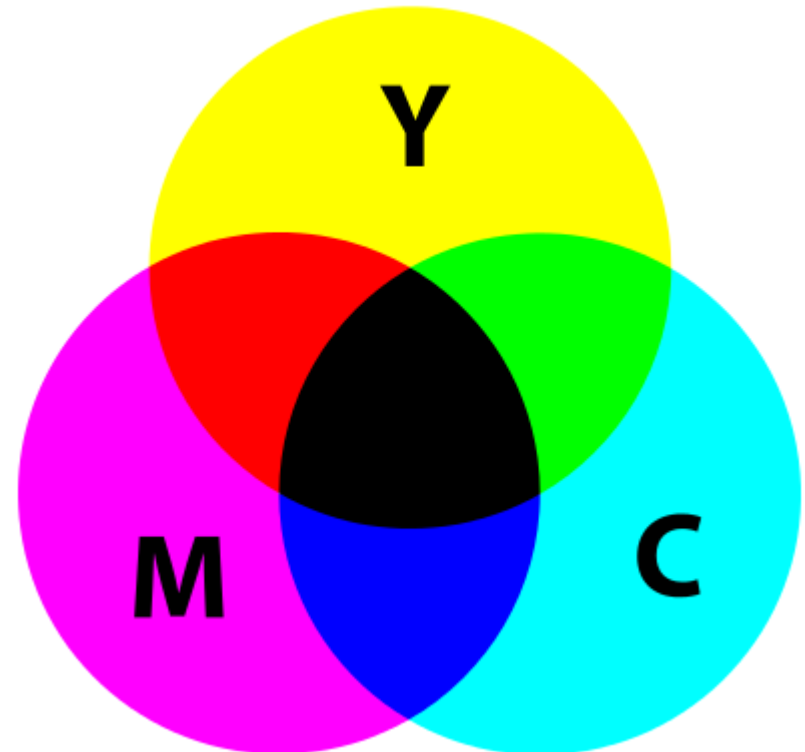
Color can be created using three primary colors



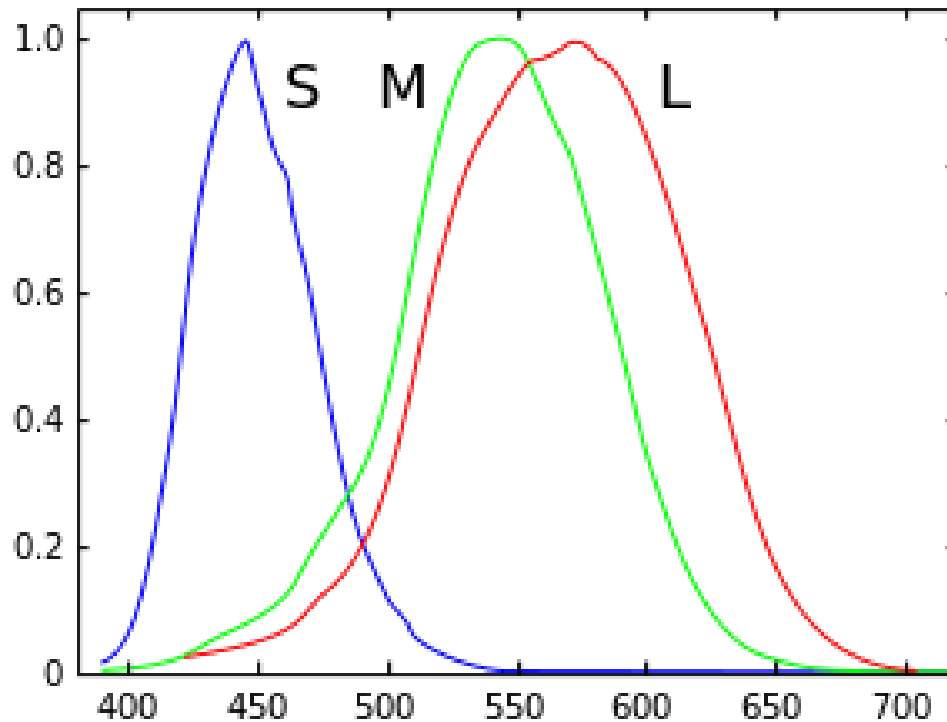
Additive primaries



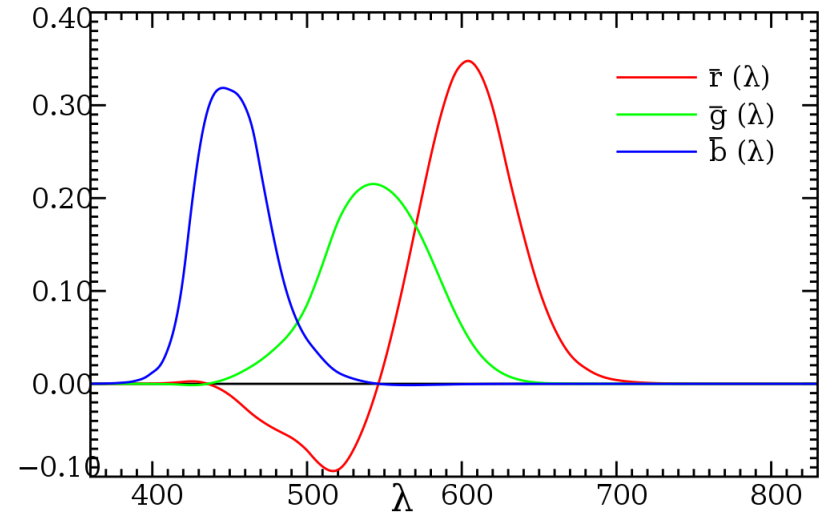
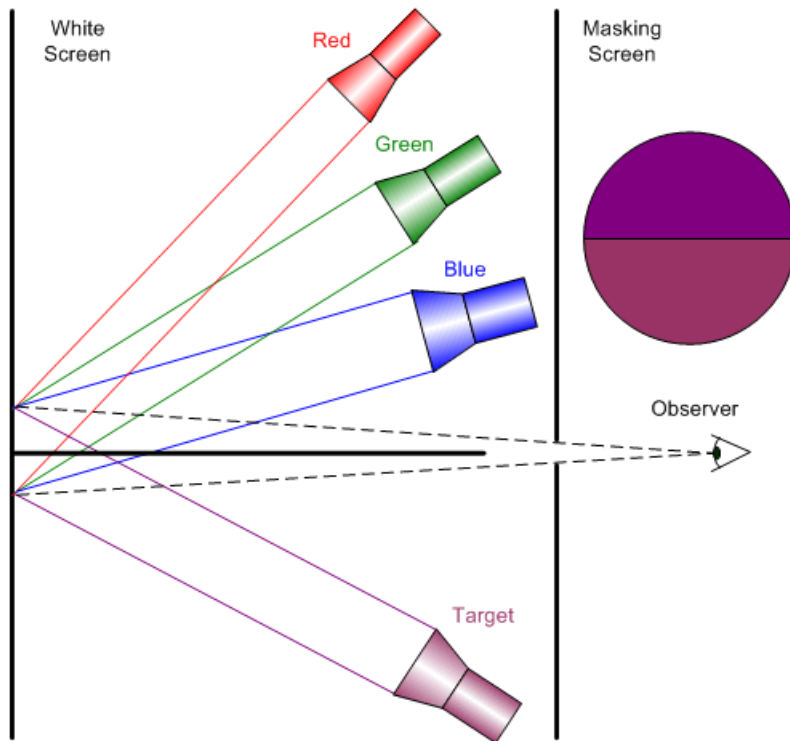
Subtractive primaries



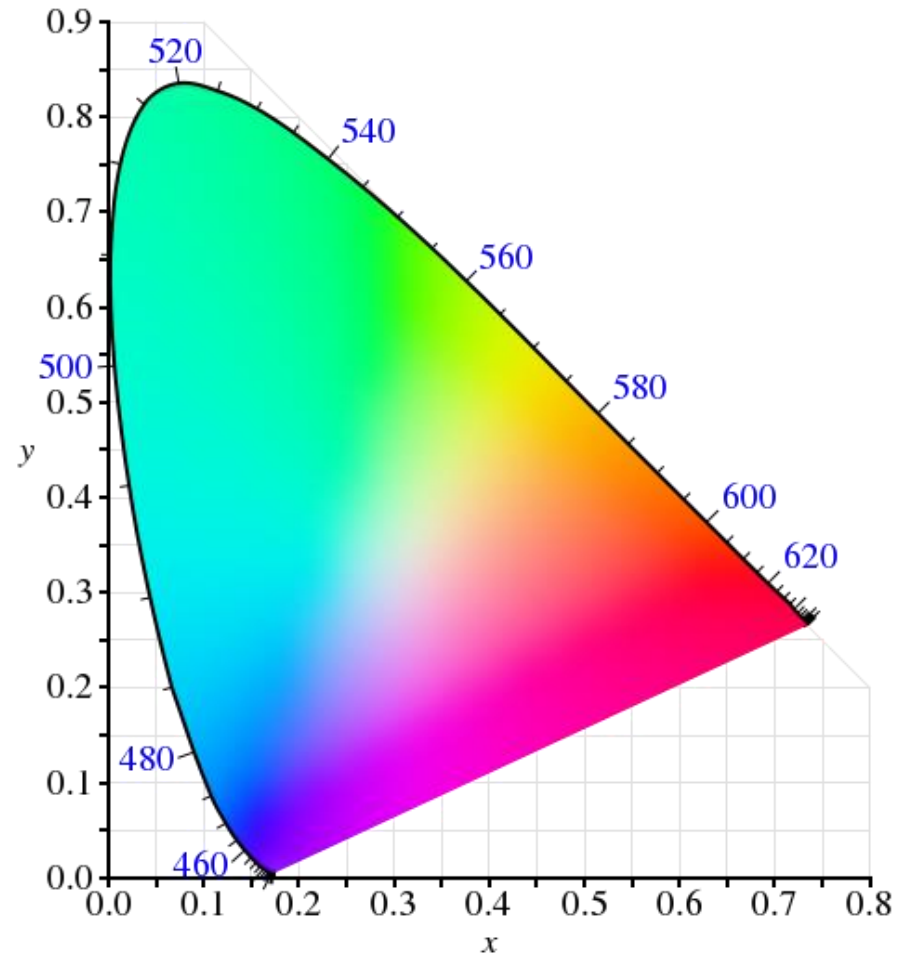
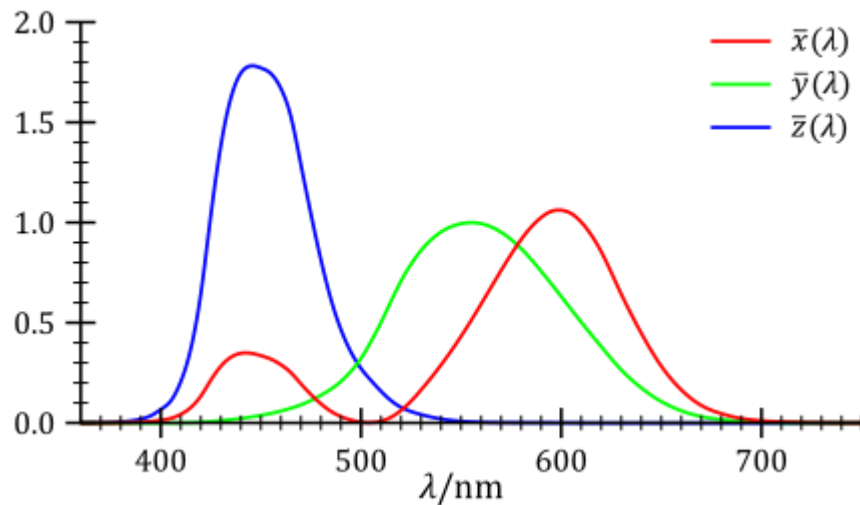
Human retina has three kinds of “cones” that have different spectral response



Spectral response of retina “cones” are tested using light sources with single wavelength

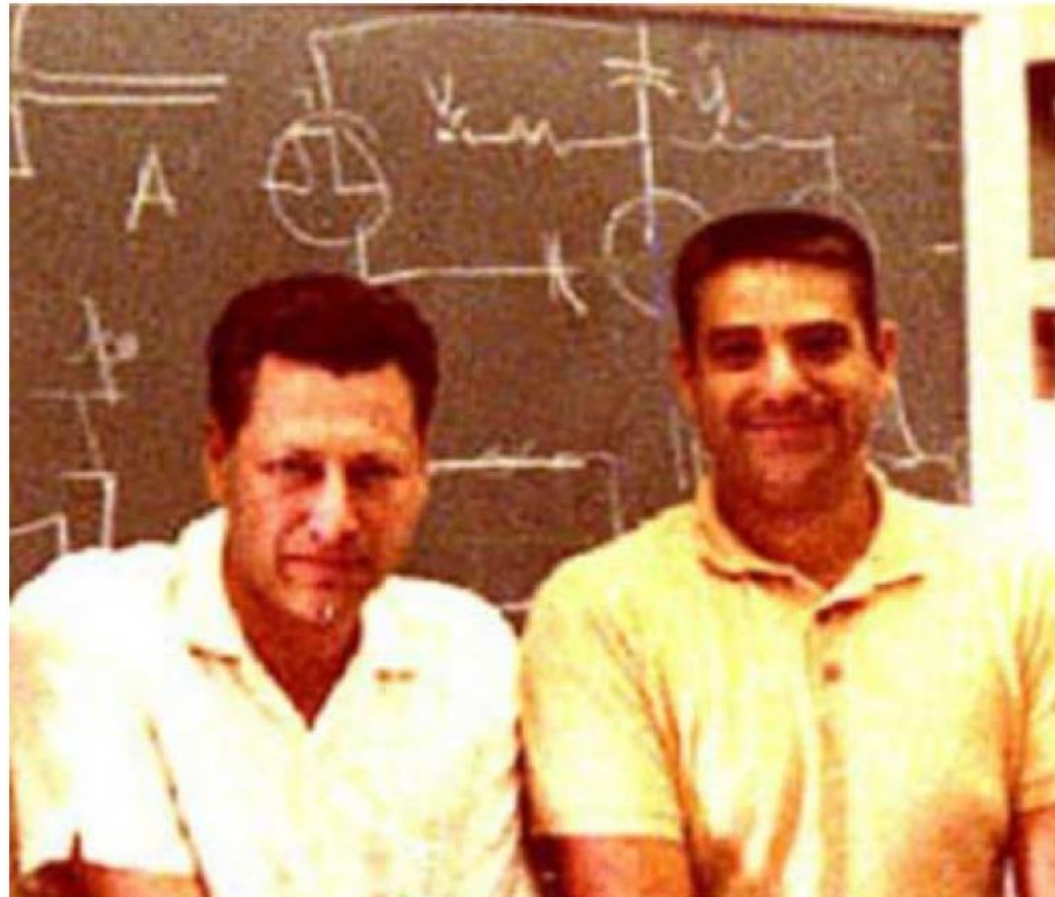


The CIE 1931 color space chromaticity diagram is the standard color space



History of PDP

Plasma display panel was invented at the University of Illinois in 1967



Prof. H. Gene Slottow

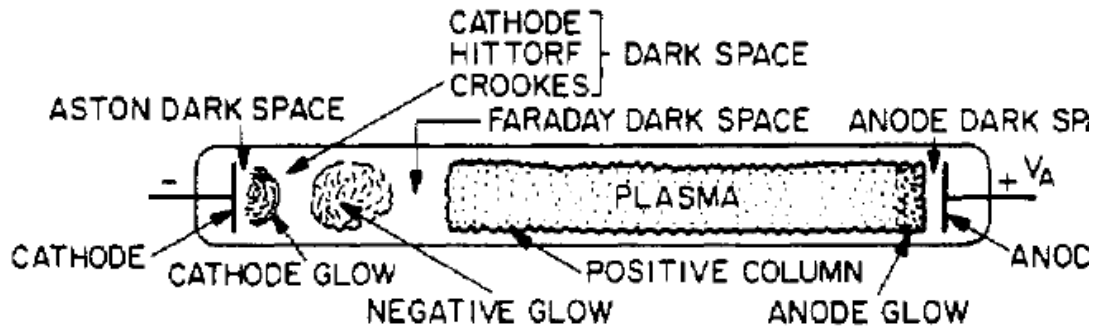
Prof. Donald L. Bitzer

PDP was invented due to a need for Programmed Logic for Automatic Teaching Operations (PLATO) in 1960s



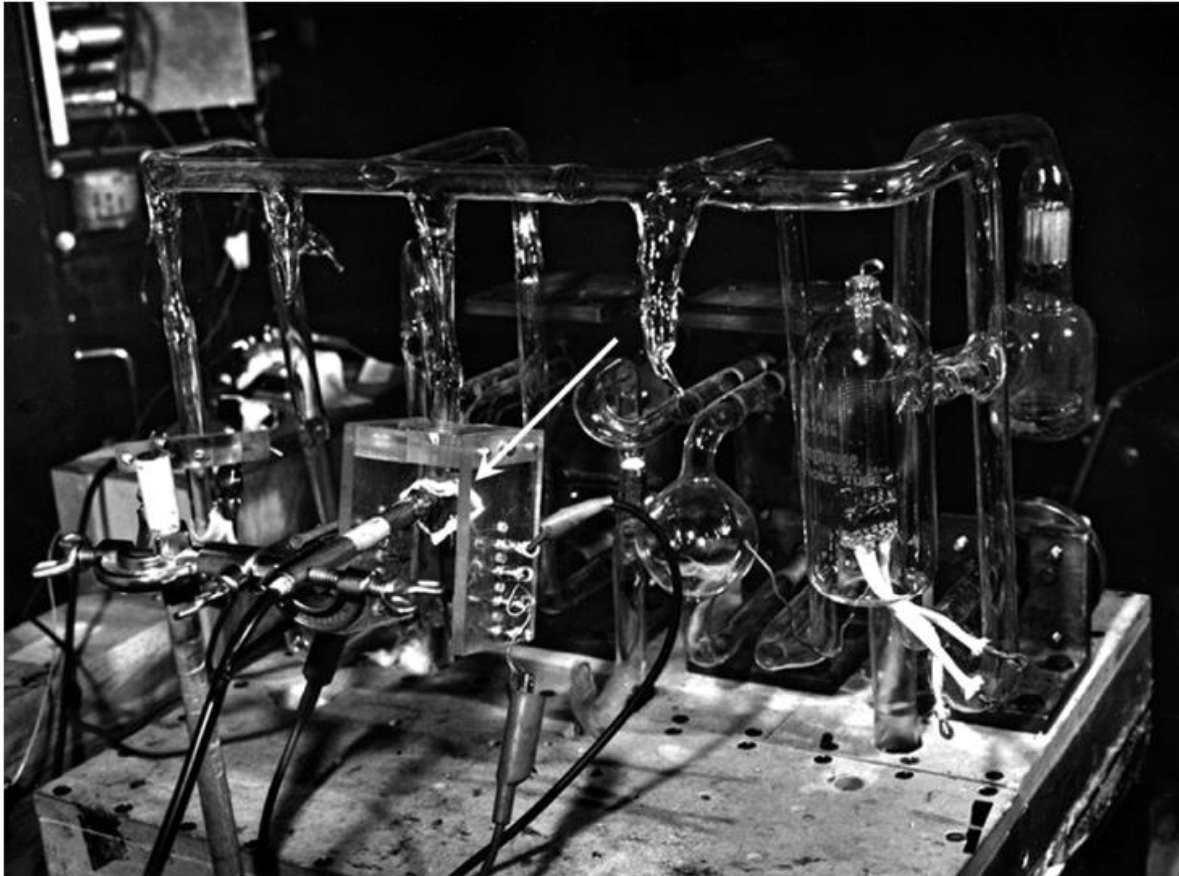
<https://topwallpapers.pw/computer/keyboards-computers-history-teletype-typewriters-desktop-hd-wallpaper-1035981/>
https://en.wikipedia.org/wiki/Punched_tape
[https://en.wikipedia.org/wiki/PLATO_\(computer_system\)](https://en.wikipedia.org/wiki/PLATO_(computer_system))

The positive column in a glow discharge is used to excite phosphors in color PDP



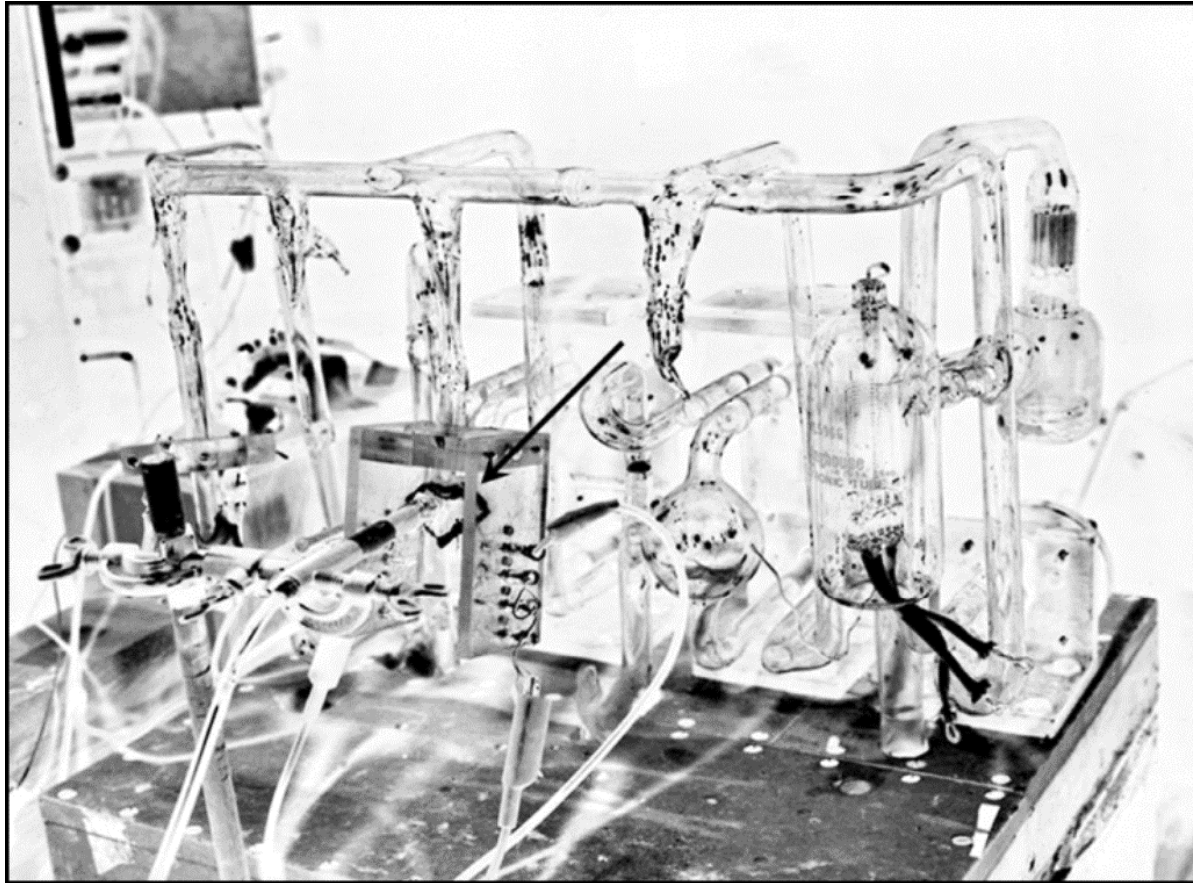
- Majority of monochrome PDPs use the negative glow as the light source
- The positive column is used to excite phosphors in fluorescent lamps and in color PDPs

Early plasma panel (PD) attached to the glass vacuum system used for the first plasma displays at UI



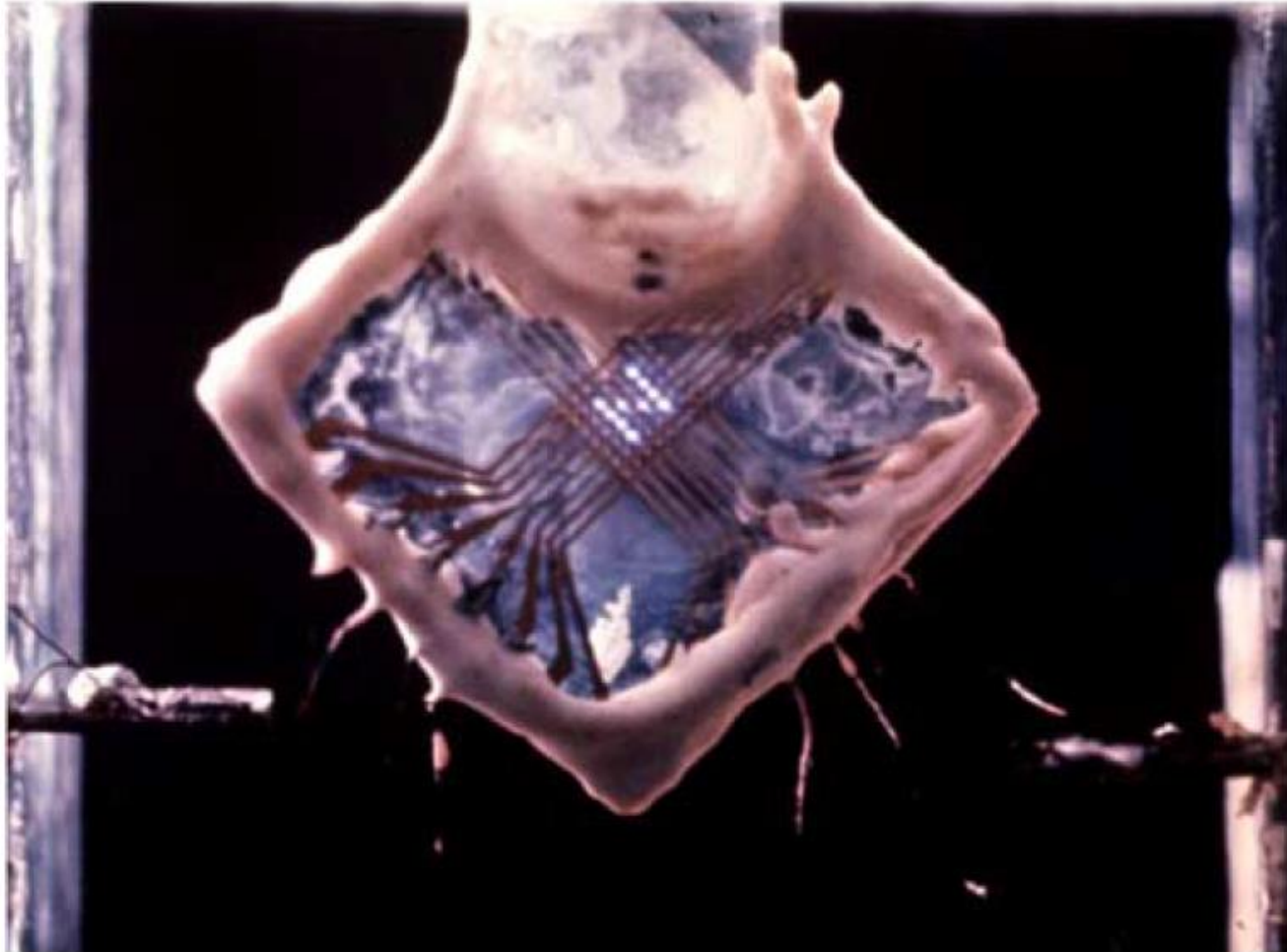
- It had the same alternating sustain voltage, neon, gas, and dielectric glass insulated electrodes that are used for plasma TVs today.

Early plasma panel (PD) attached to the glass vacuum system used for the first plasma displays at UI

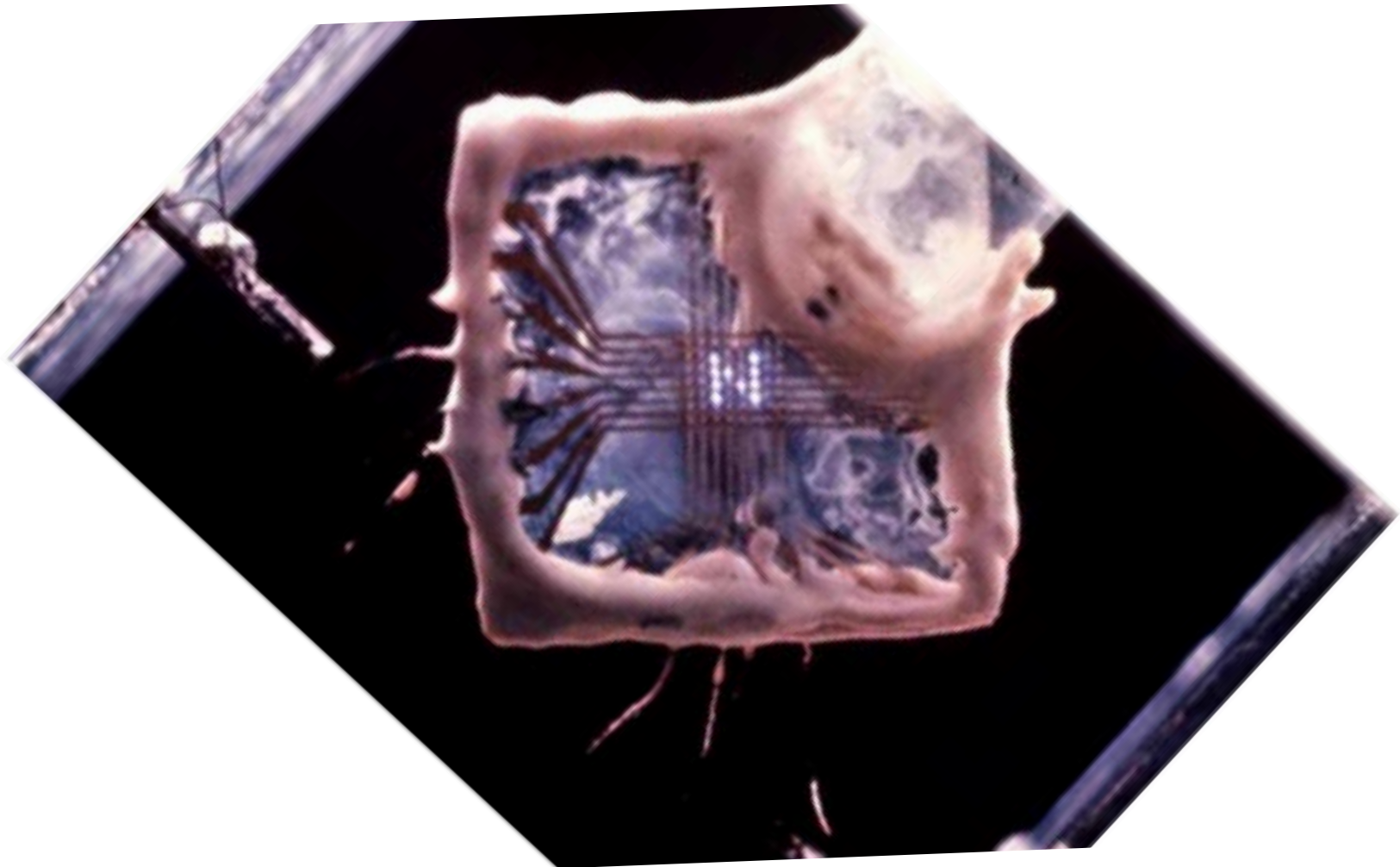


- It had the same alternating sustain voltage, neon, gas, and dielectric glass insulated electrodes that are used for plasma TVs today.

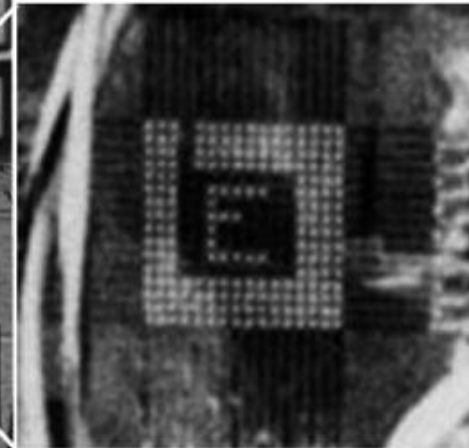
Early 4x4 pixel panel has achieved matrix addressability for the first time



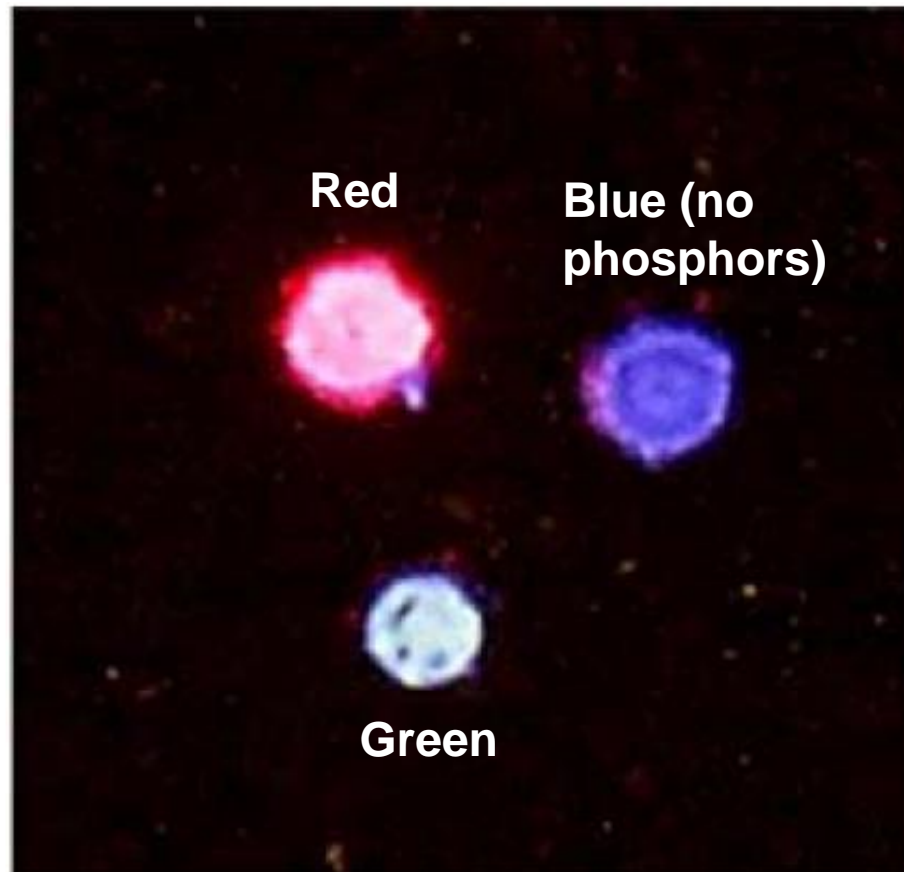
Early 4x4 pixel panel has achieved matrix addressability for the first time



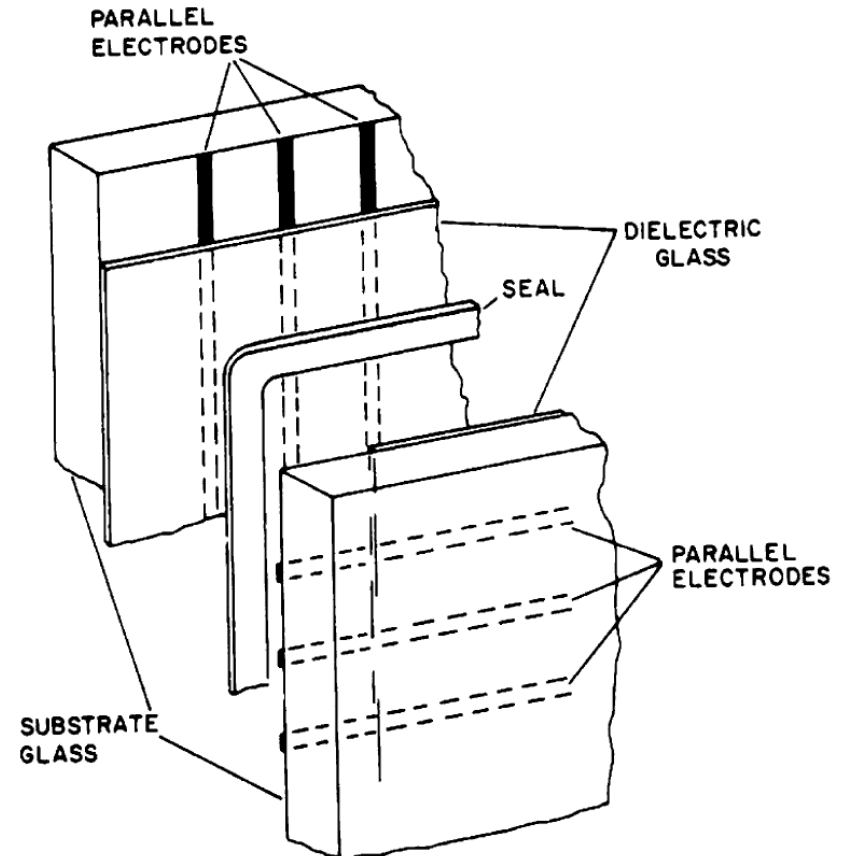
A 16x16 pixel PD, developed in 1967, needed to be addressed manually



First color PD was three cell prototype with red and green color phosphors excited by a xenon gas discharge



Open-cell structure developed in 1968

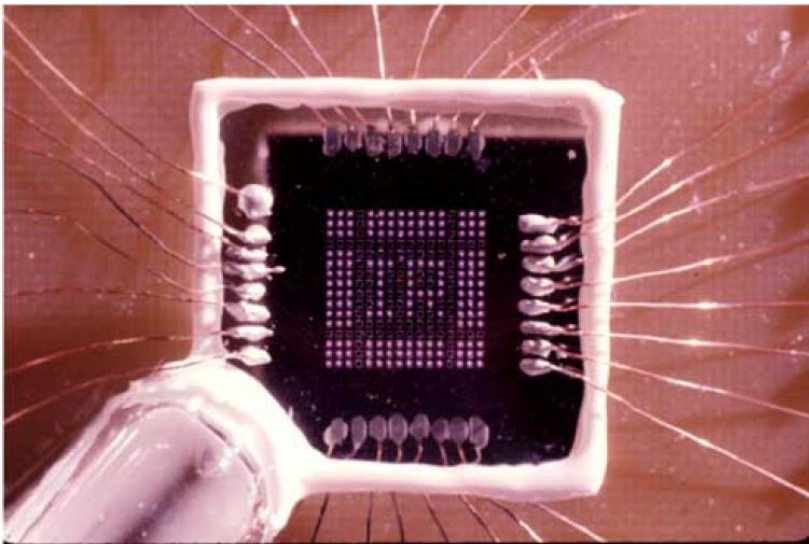


- It could be baked under vacuum at 350 °C to drive out contaminants.

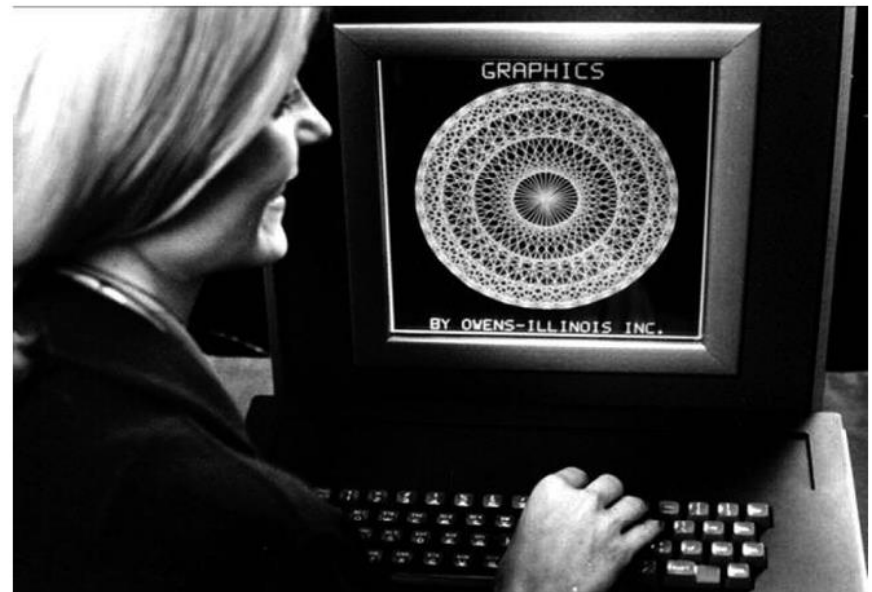
More progress



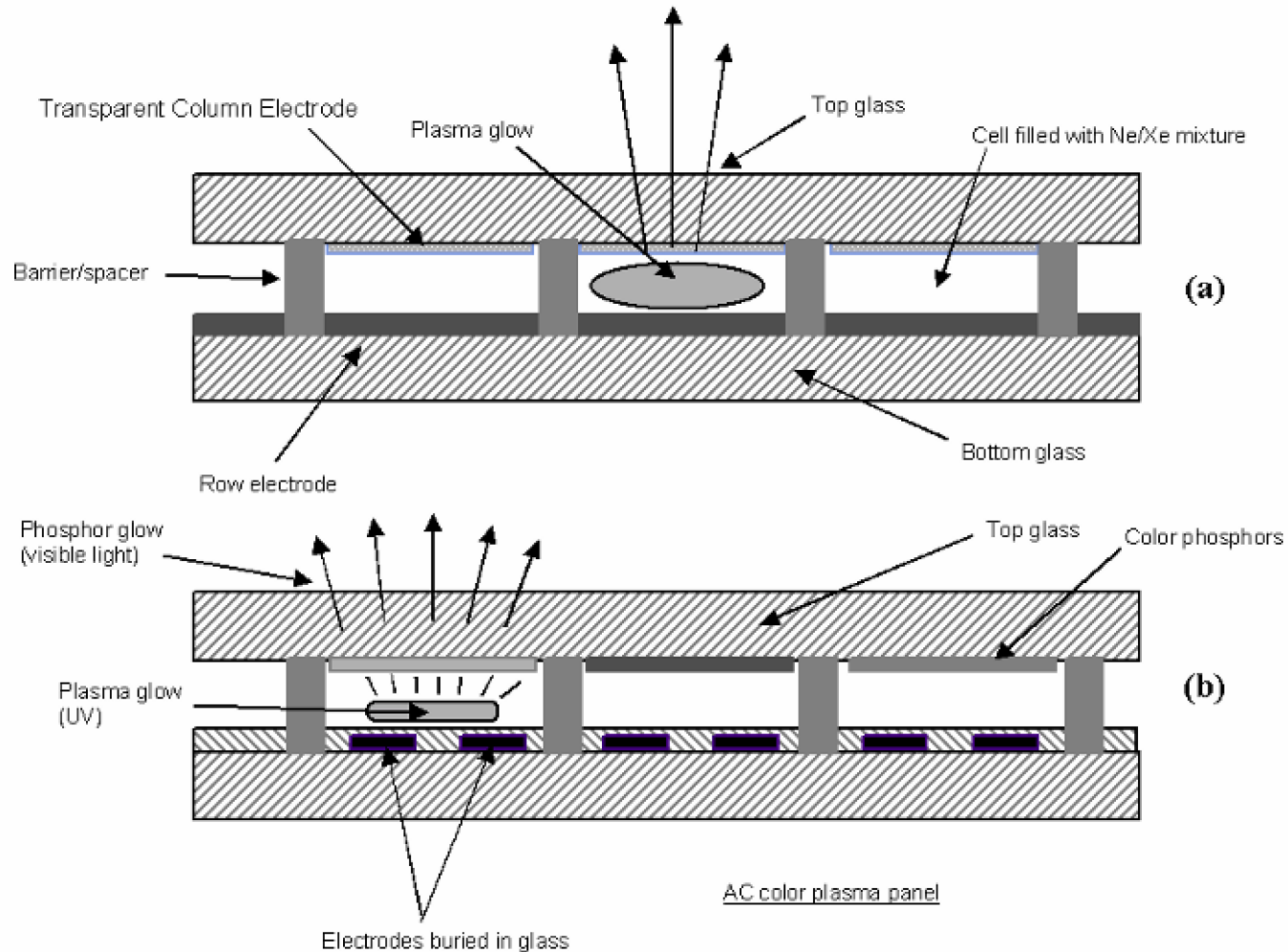
**1968, University of Illinois
16x16 pixels**



**1971, Owens-Illinois
512x512 pixels**

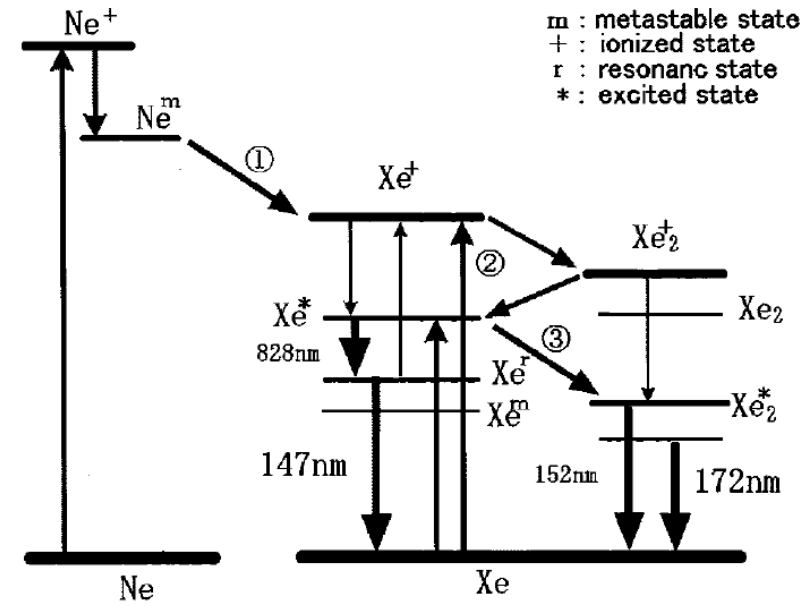
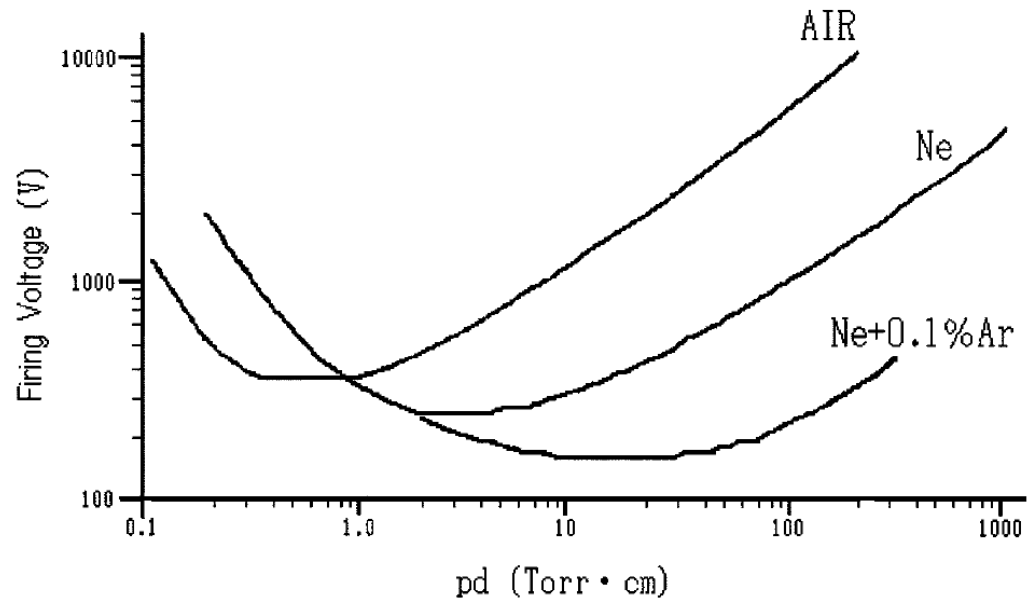


Color PDPs had short display lifetime due to the degradation of color phosphors caused by ion sputtering

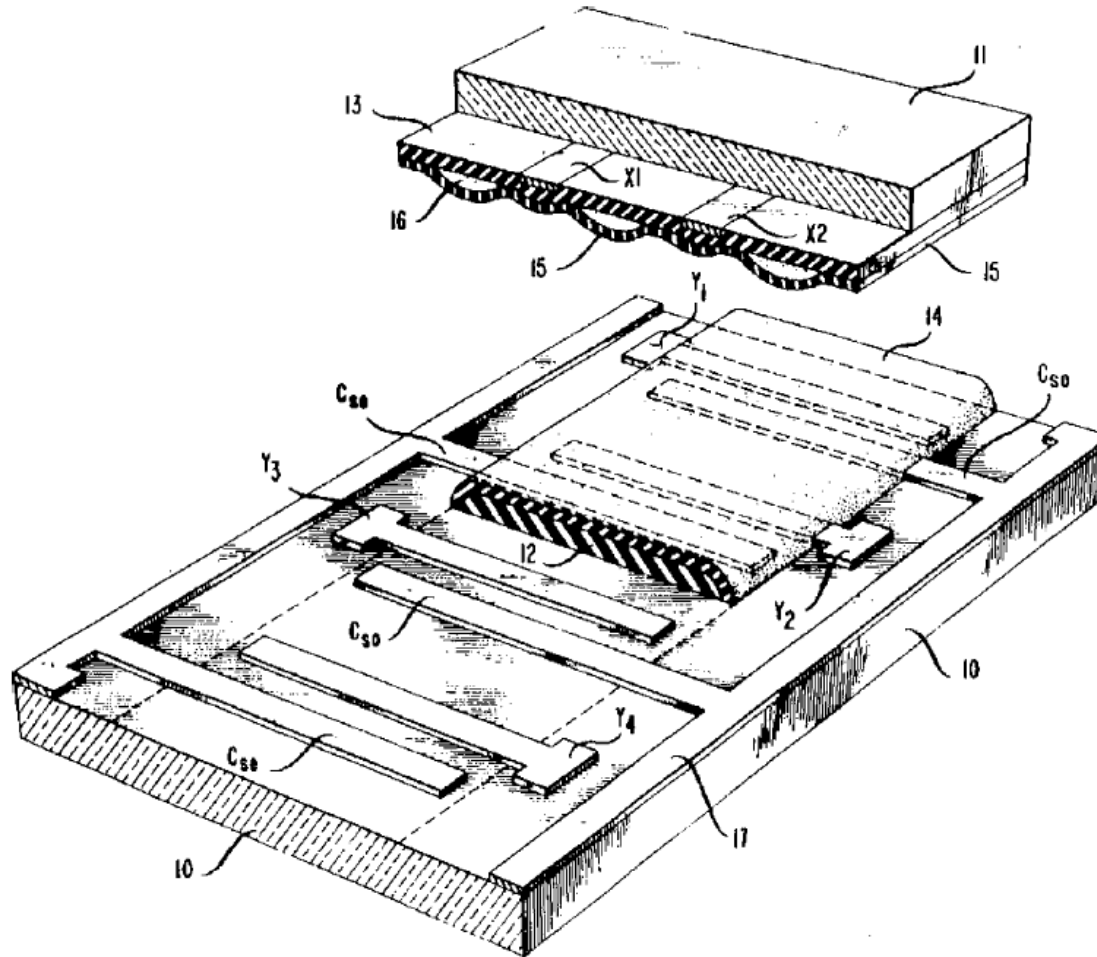


Design of PDP

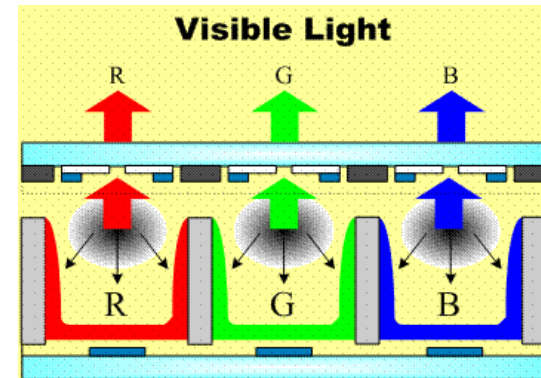
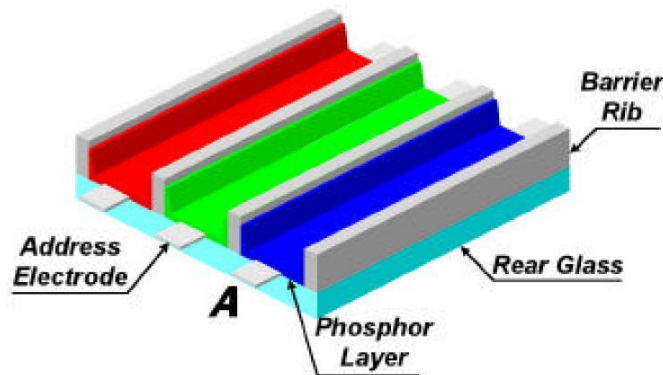
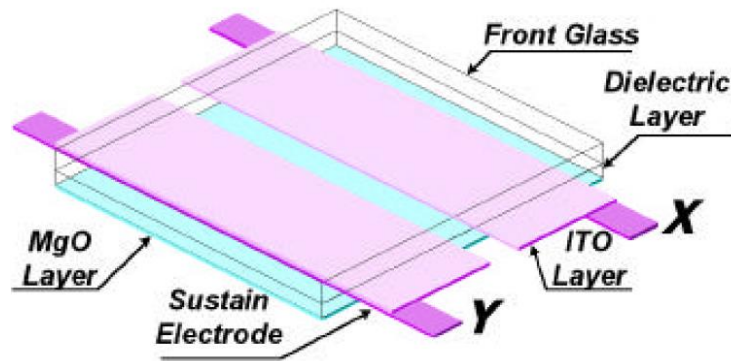
A lower breakdown voltages can be obtained with very small amounts of added gas



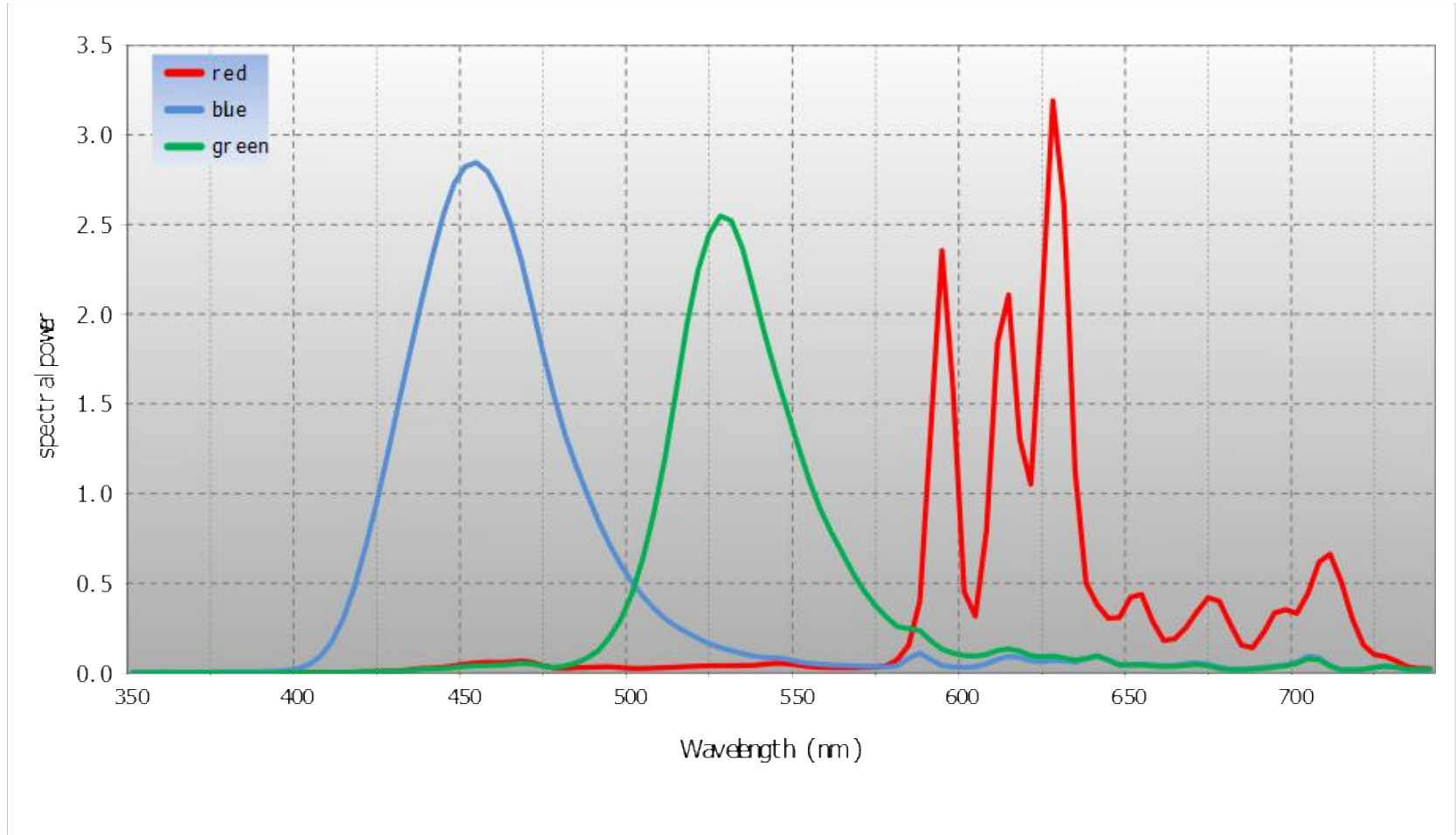
AT&T three-electrode patent



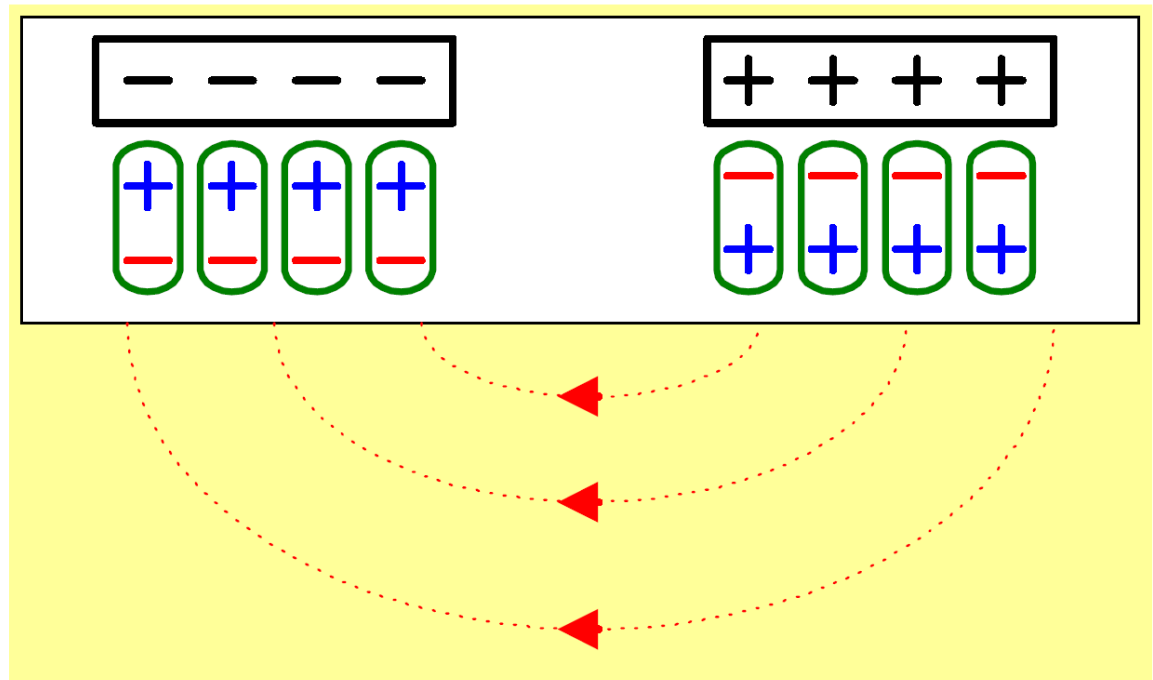
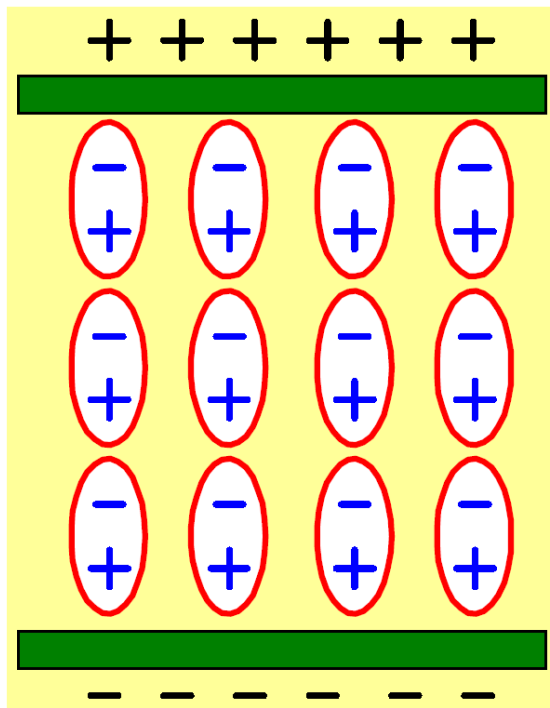
Reflective phosphor geometry is used in most of today's plasma TVs



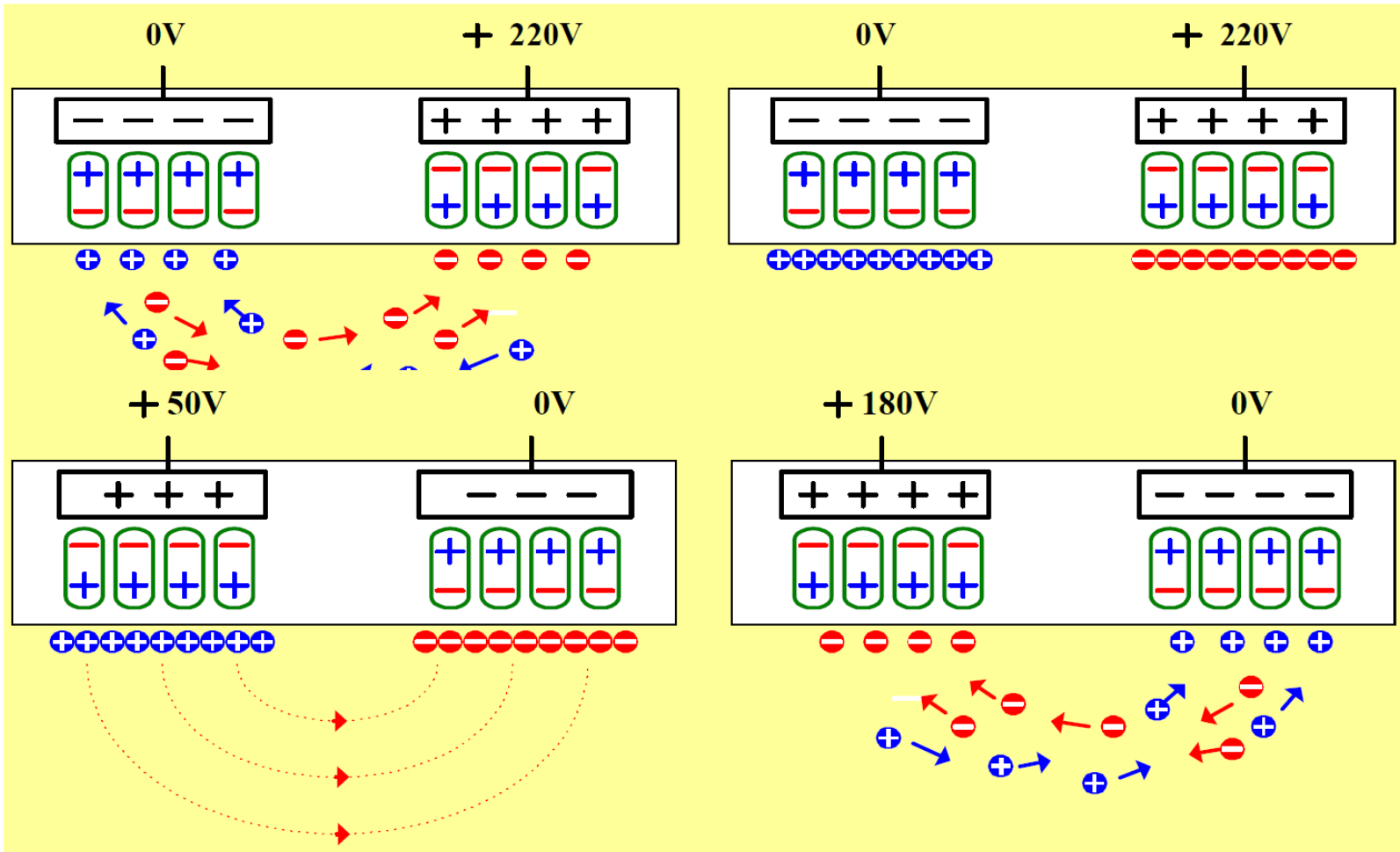
Spectrum of the different phosphors



The foundation of AC discharge

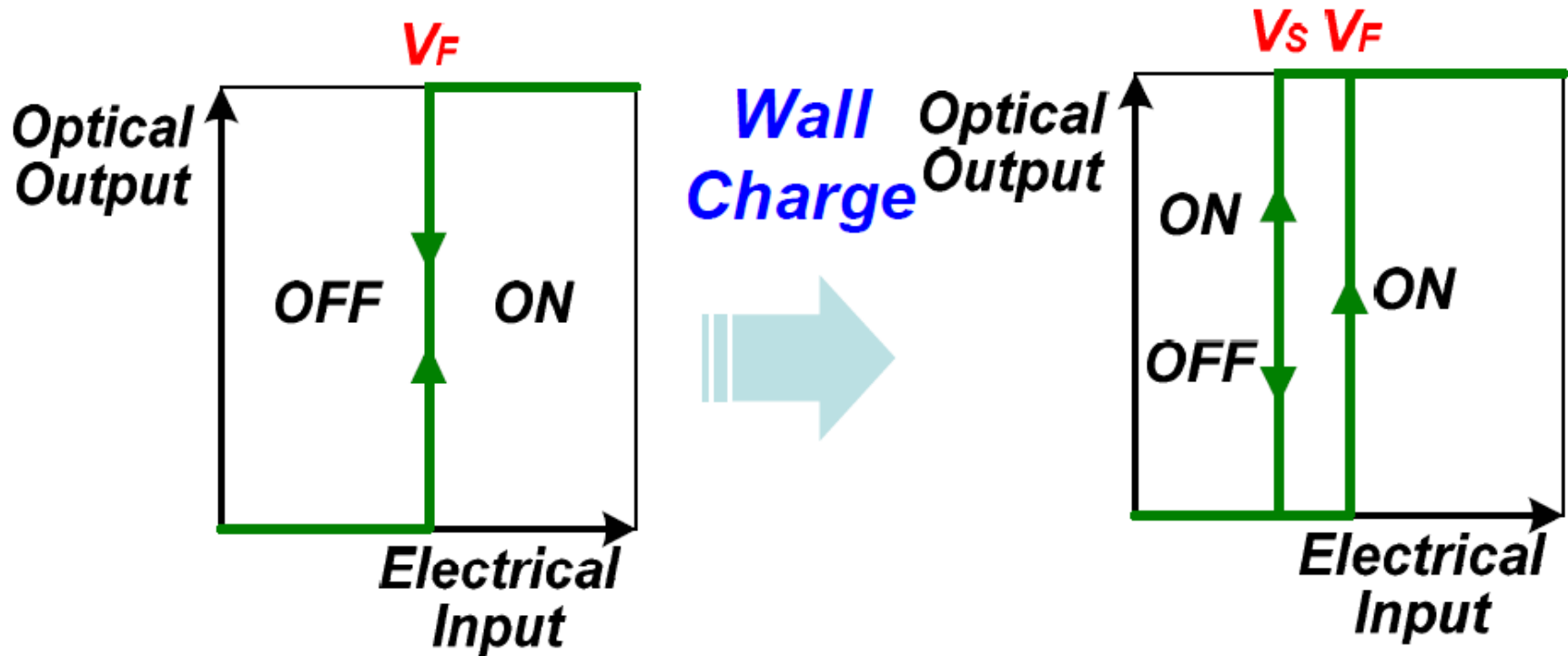


The plasma can be sustained using ac discharged



- **Wall discharge reduced the required discharge voltage**

Wall discharge reduced the required discharge voltage

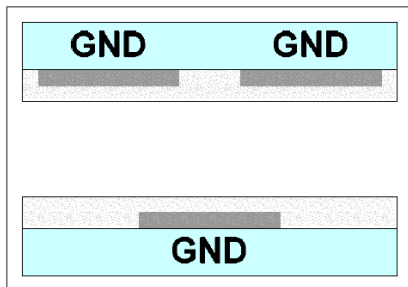


ON/OFF State Selection

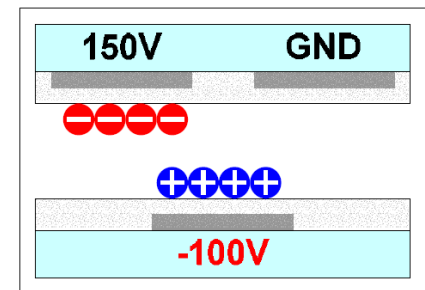
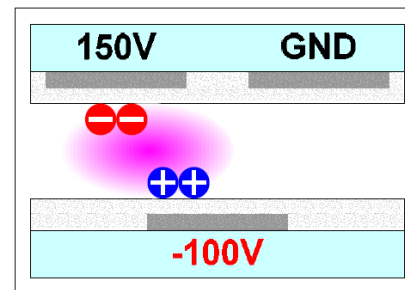
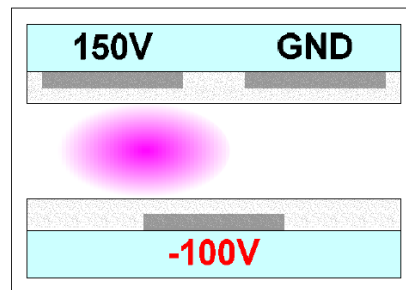


$V_F : 250V$

ON Cell



OFF Cell



(i)

(ii)

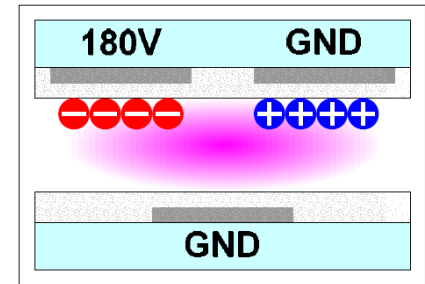
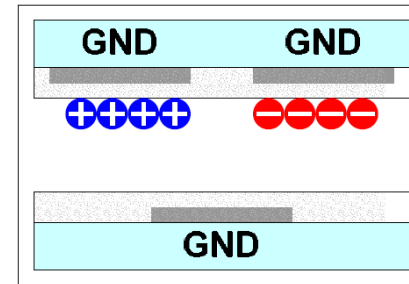
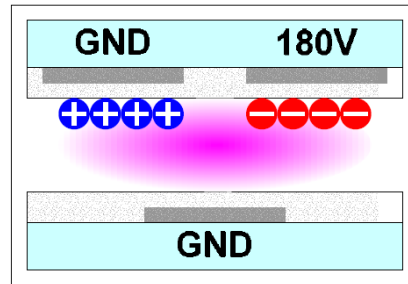
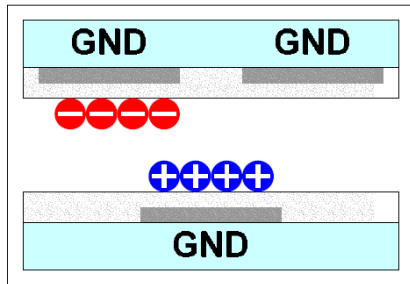
(iii)

(iv)

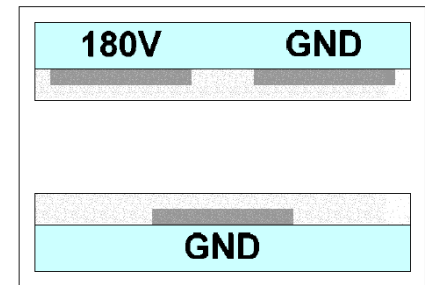
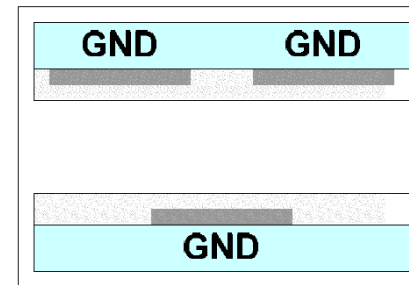
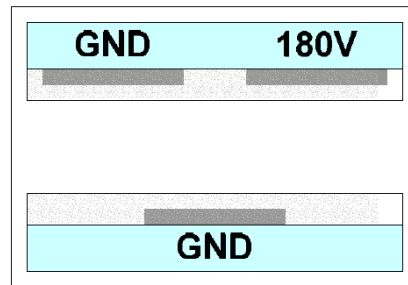
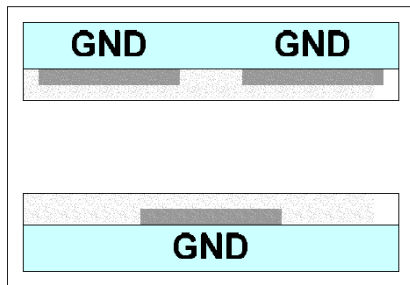
Sustain discharge



ON Cell



OFF Cell



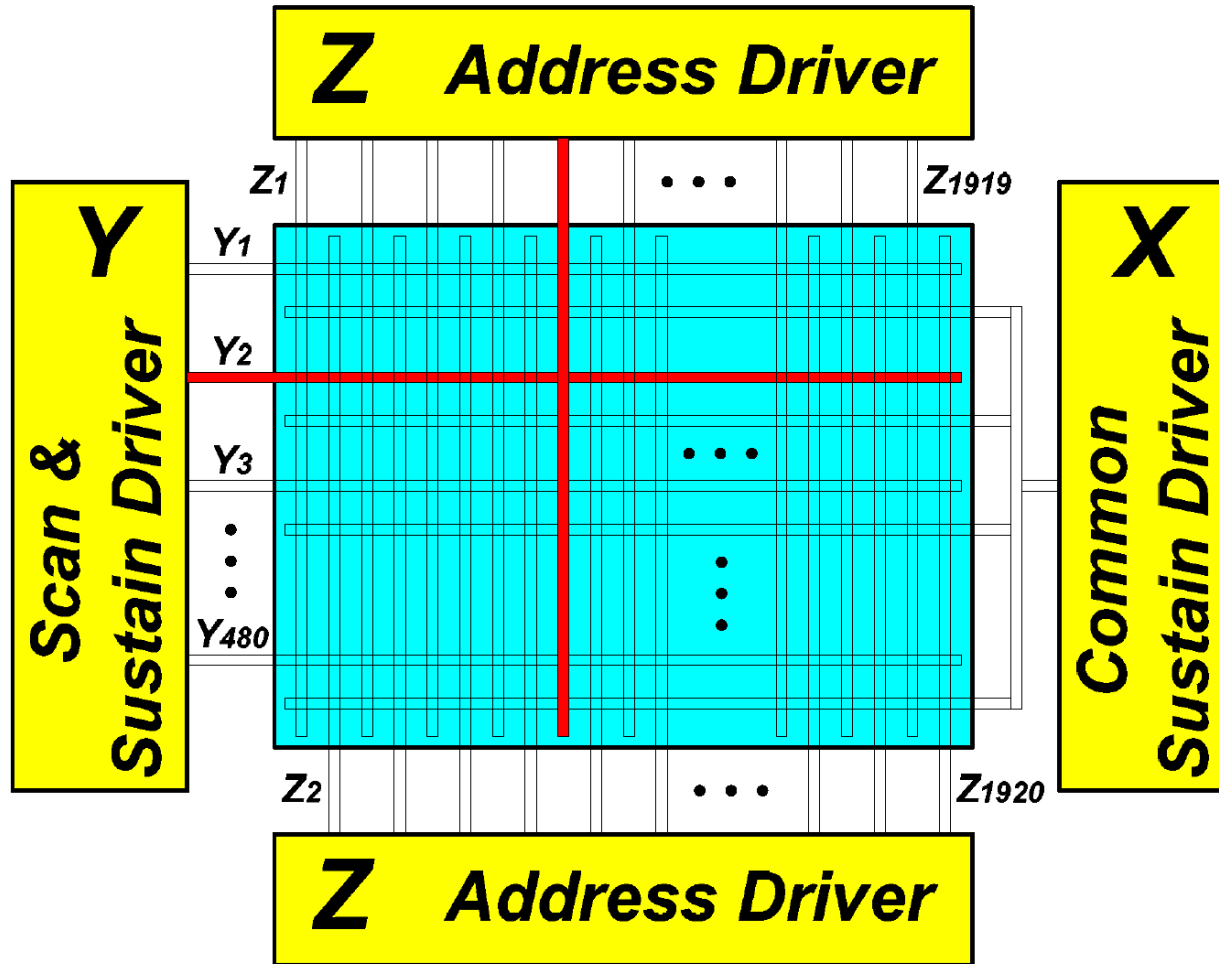
(i)

(ii)

(iii)

(iv)

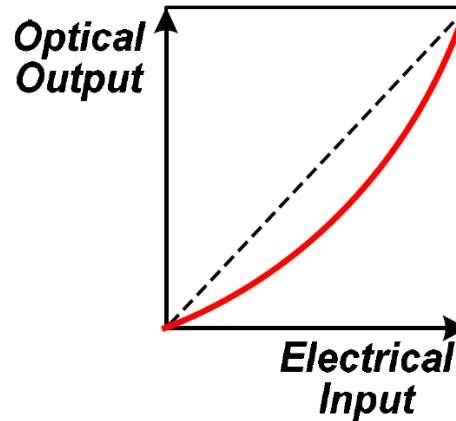
Address and sustain electrodes are connected to different drivers



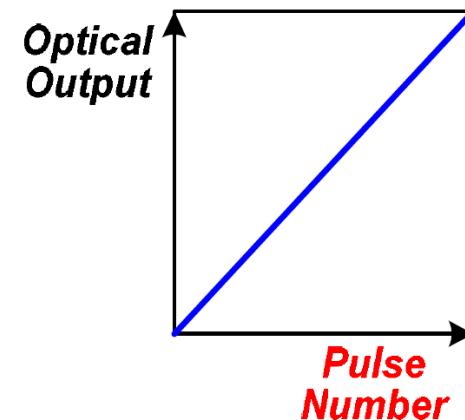
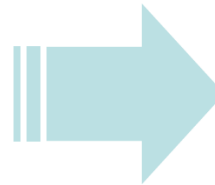
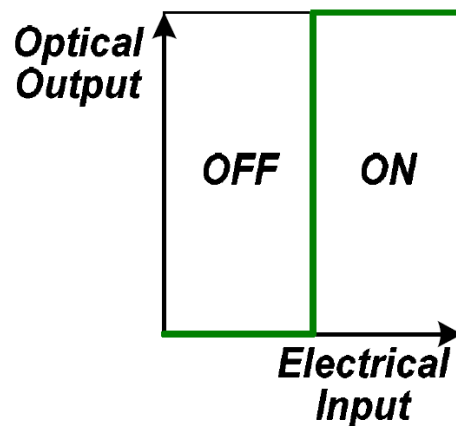
PDP pixel can only be either ON or OFF



- Cathode Ray Tube :



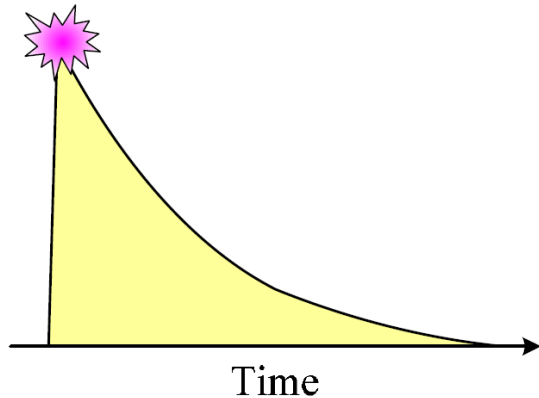
- Plasma Display Panel :



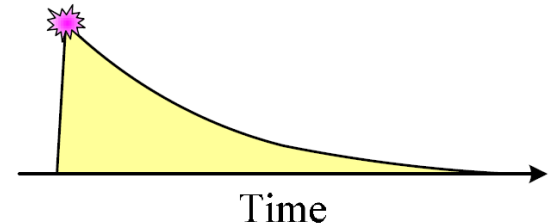
PDP luminance is controlled by using number of light pulses



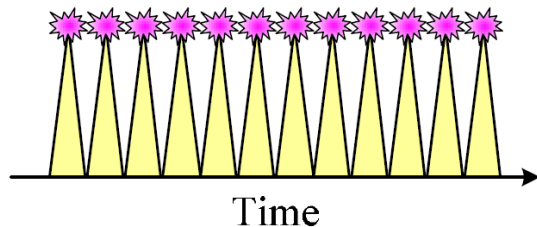
- CRT : Control the Luminance using **Electron Beam Intensity**



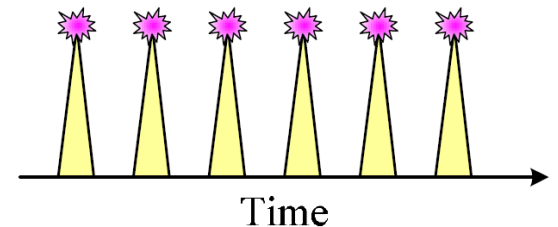
Luminance Ratio
2 : 1



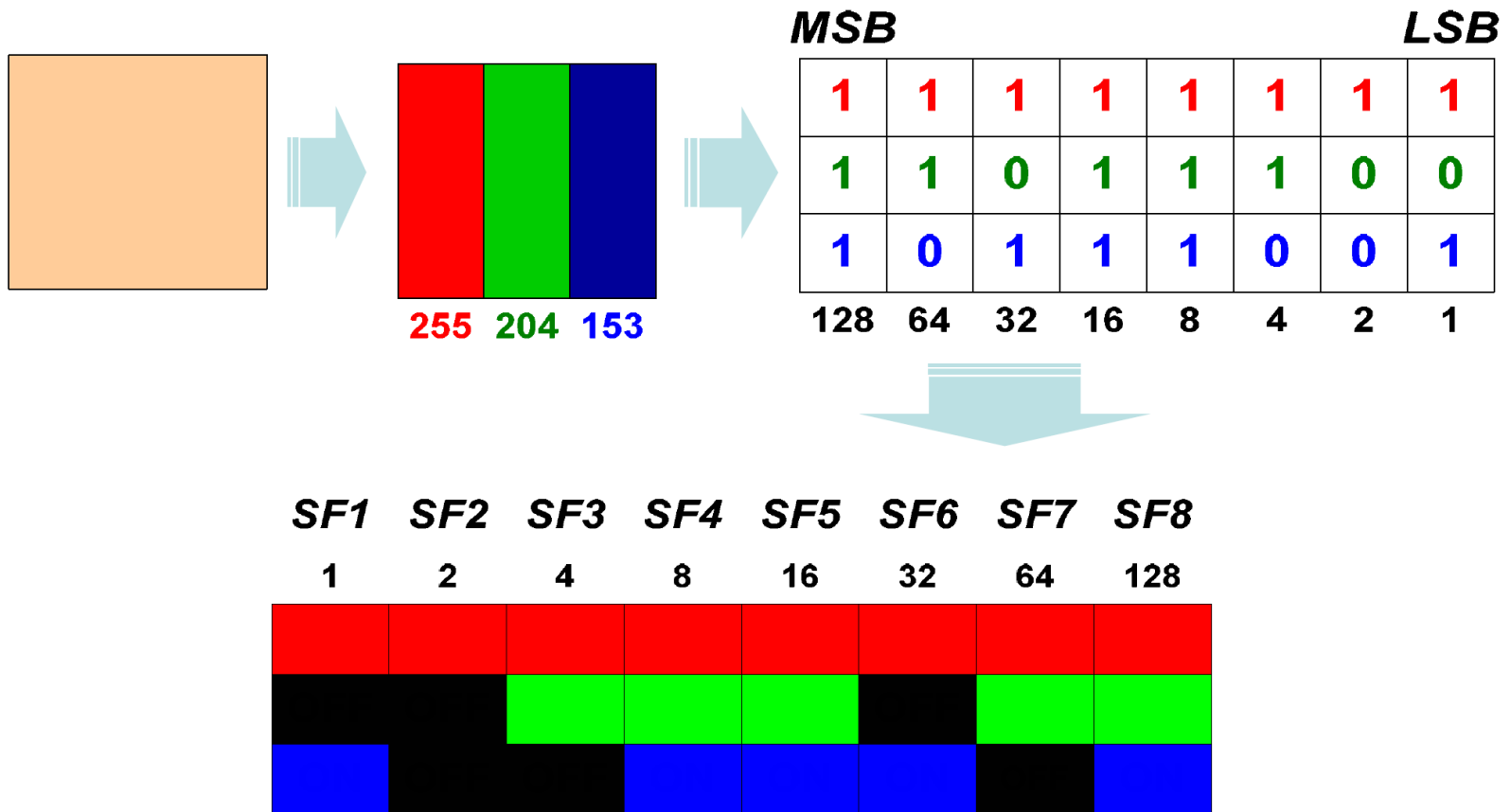
- PDP : Control the Luminance using **Number of Light Pulses**



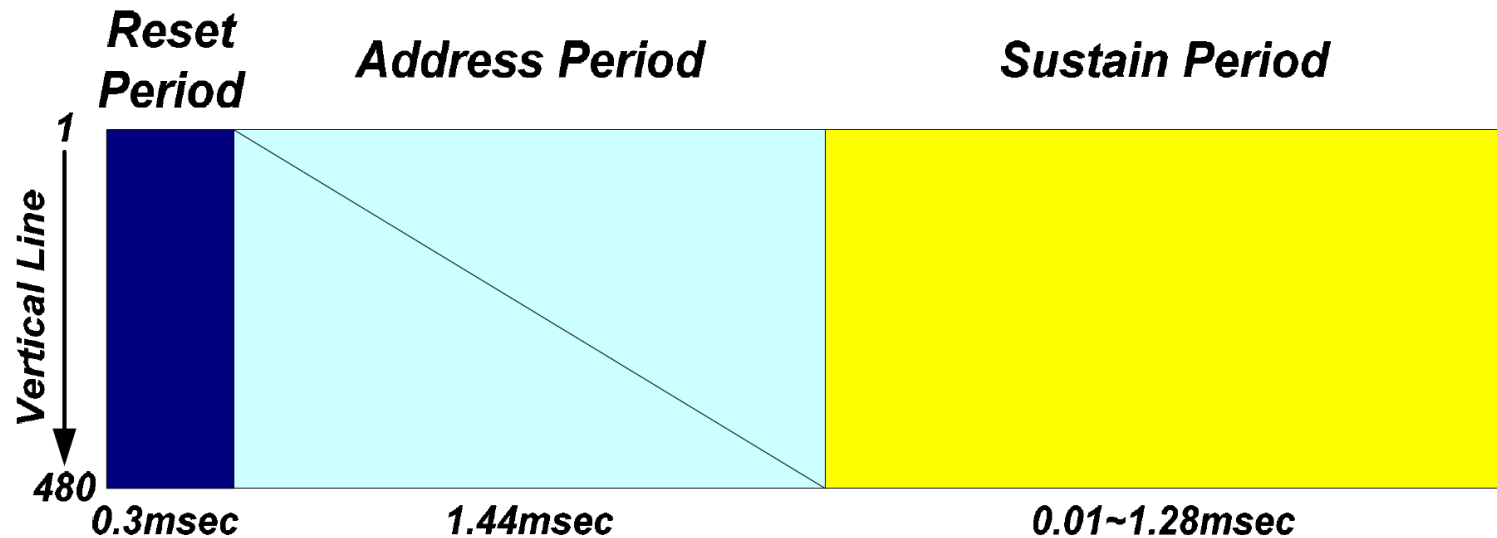
Luminance Ratio
2 : 1



A single field is divided into 8 subfield

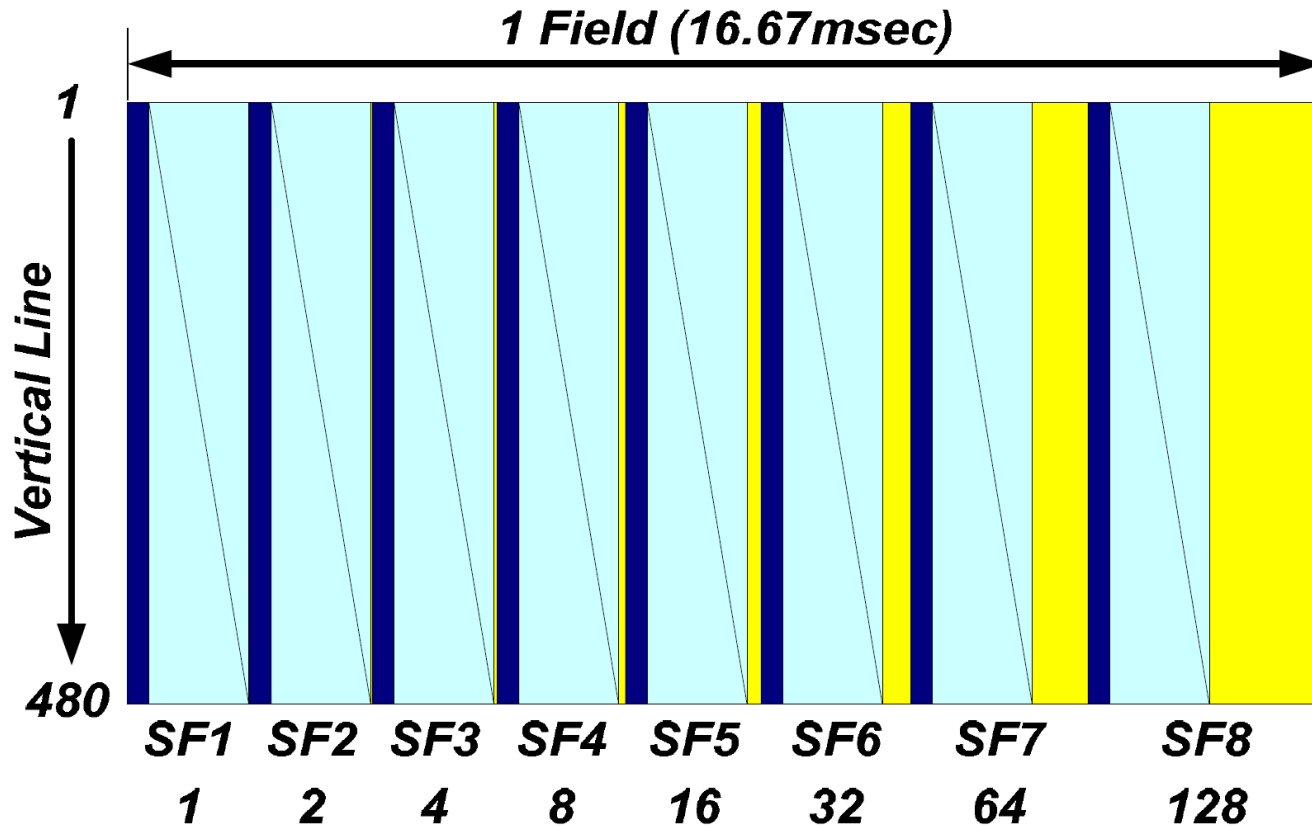


Composition of each subfield



Spec : VGA (640*480)
8 Subfield
0.03msec Address Pulse
100KHz Sustain Freq.

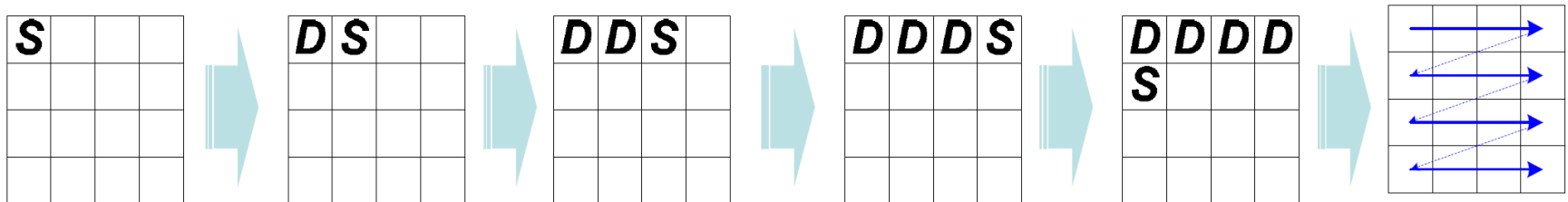
8 subfield in one TV-Field (ADS)



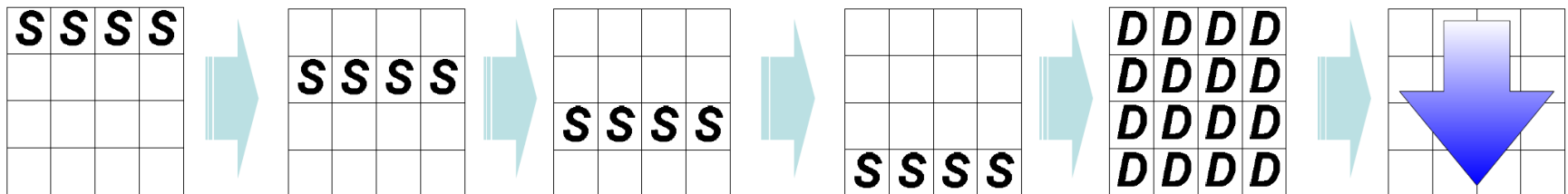
PDP uses line-by-line scanning



- Cathode Ray Tube : Cell-by-Cell Scanning



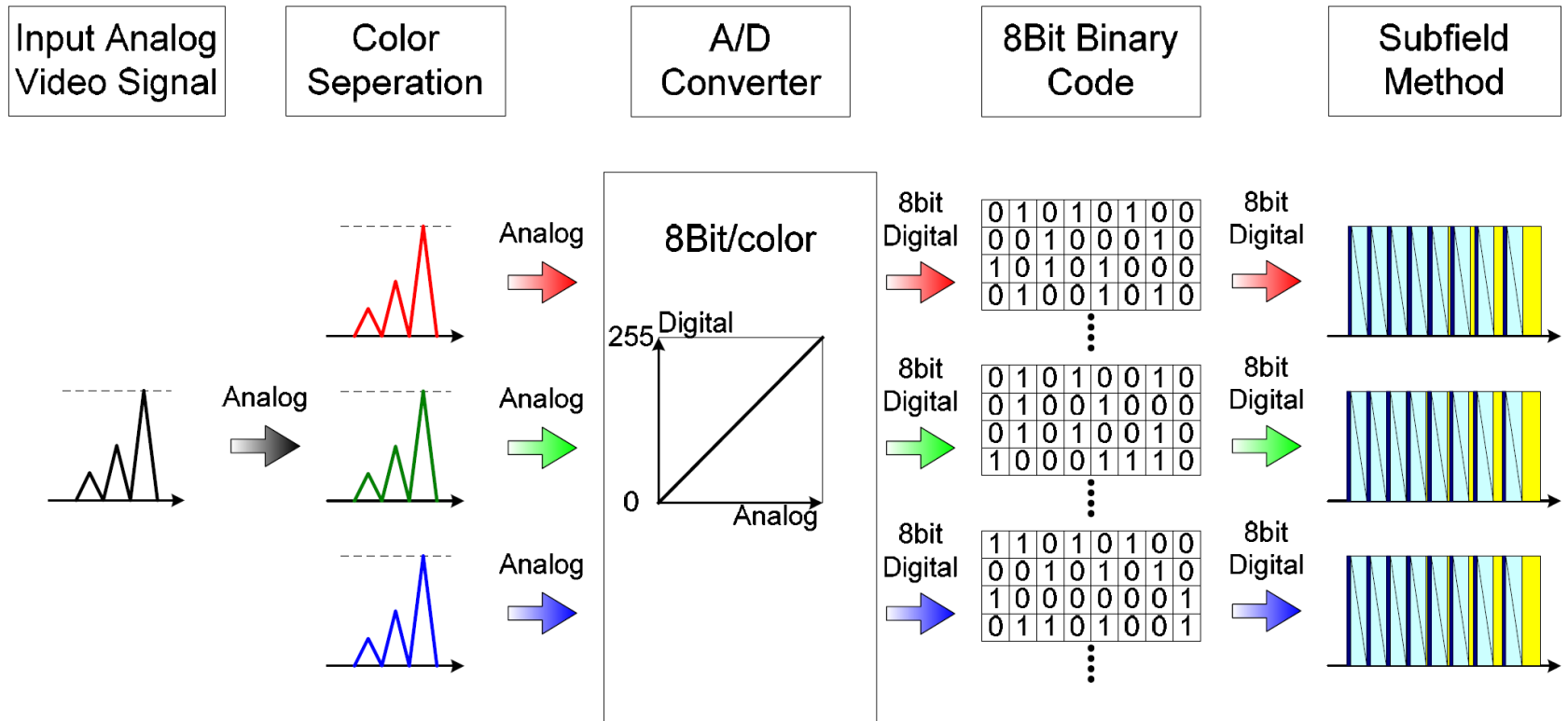
- PDP : Line-by-Line Scanning



Video signal processing



- Analog Video Signal \Rightarrow Digital Pulse Signal



Addressing period



Original Image



SF1



SF2



SF3



SF4



SF5



SF6



SF7

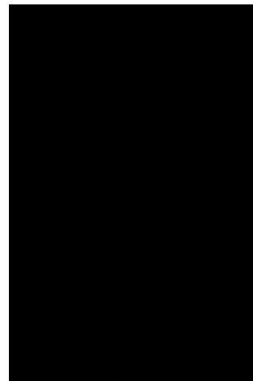


SF8

Displaying period



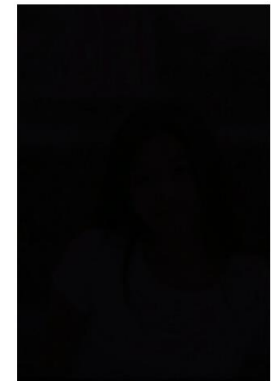
Original Image



SF1



SF2



SF3



SF4



SF5



SF6

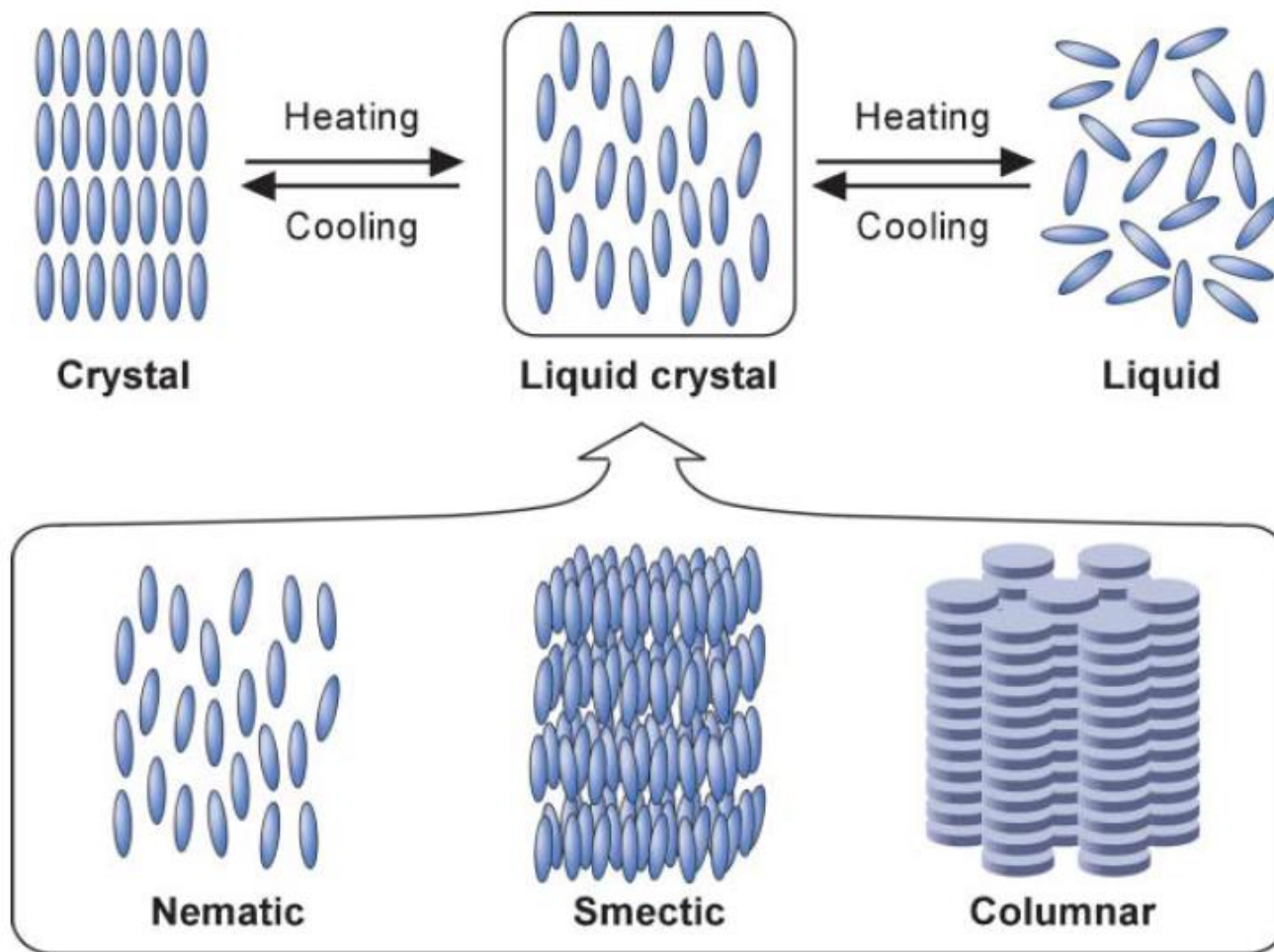


SF7

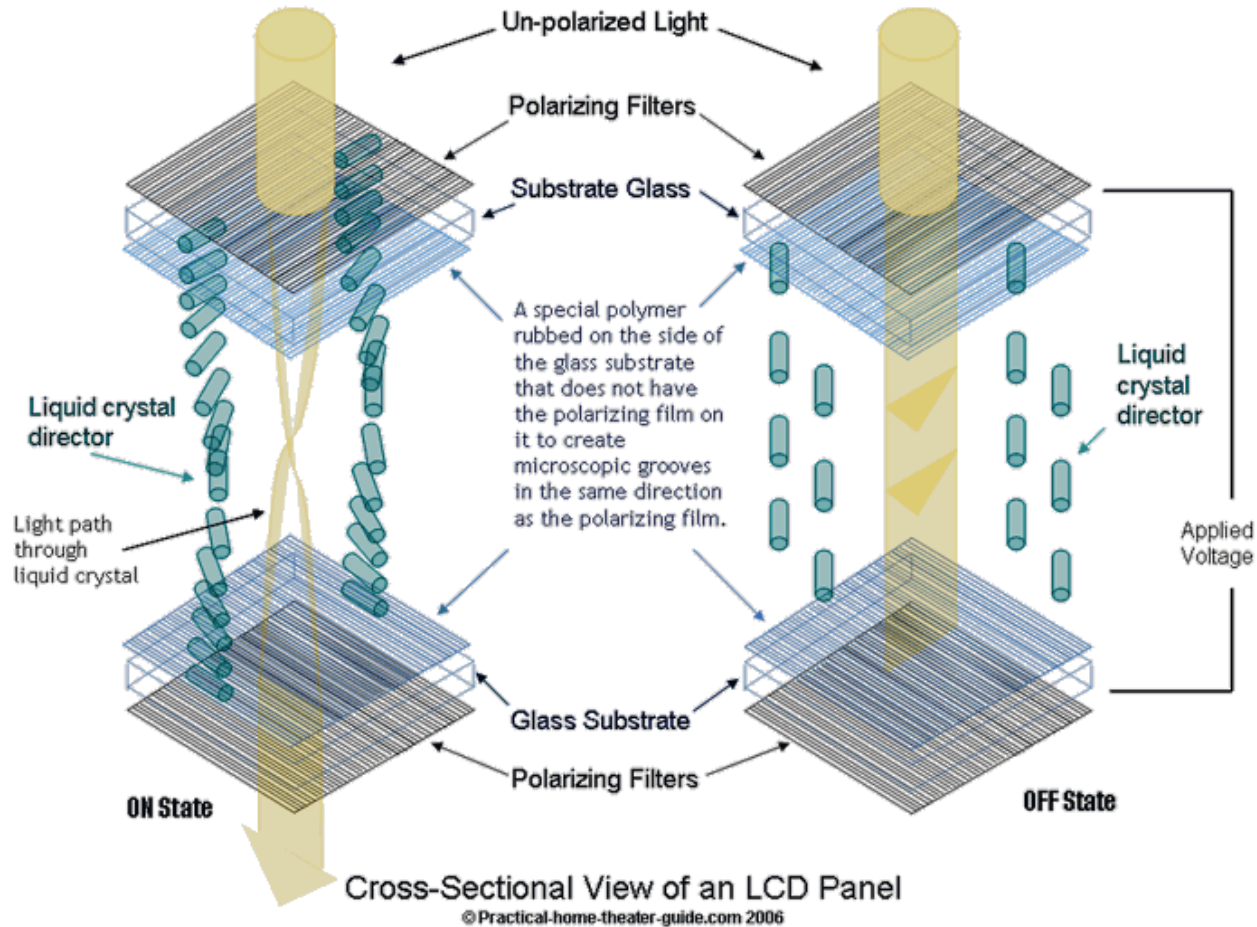


SF8

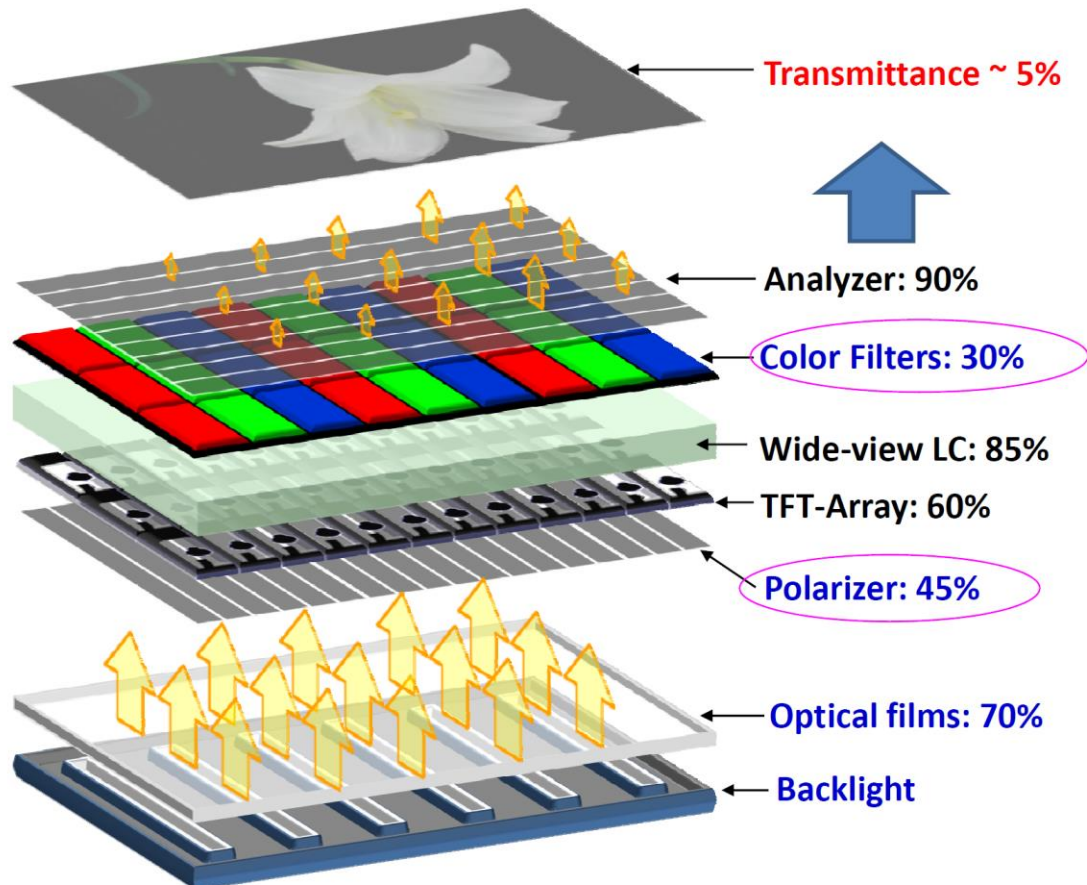
Liquid crystal are a special state of matter between liquid and crystal



Linear polarization of a light can be rotated by miss aligned liquid crystal



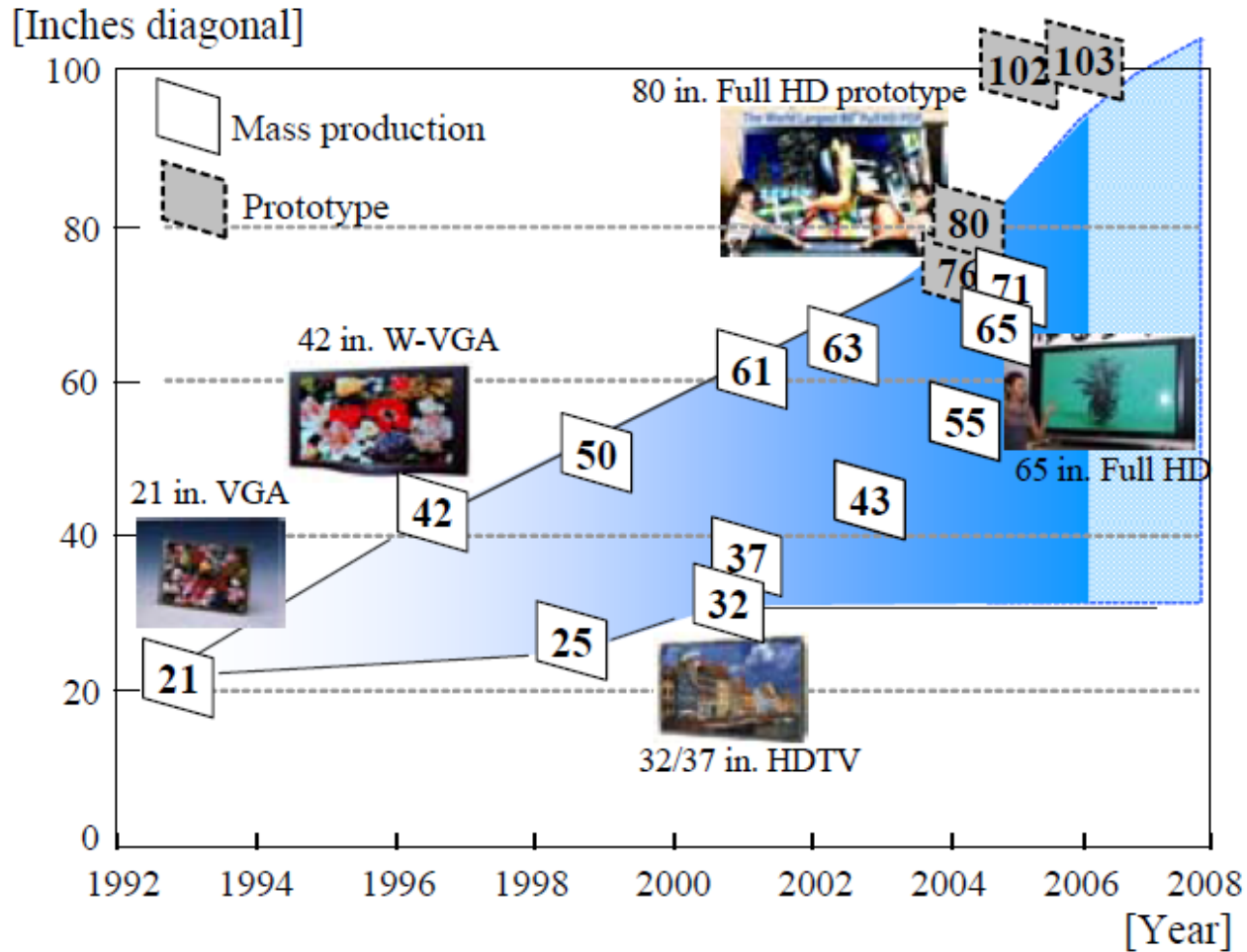
Structure of Liquid crystal display (LCD)



YB Huang, IDRC 2008

Notes from ST Wu, UCF

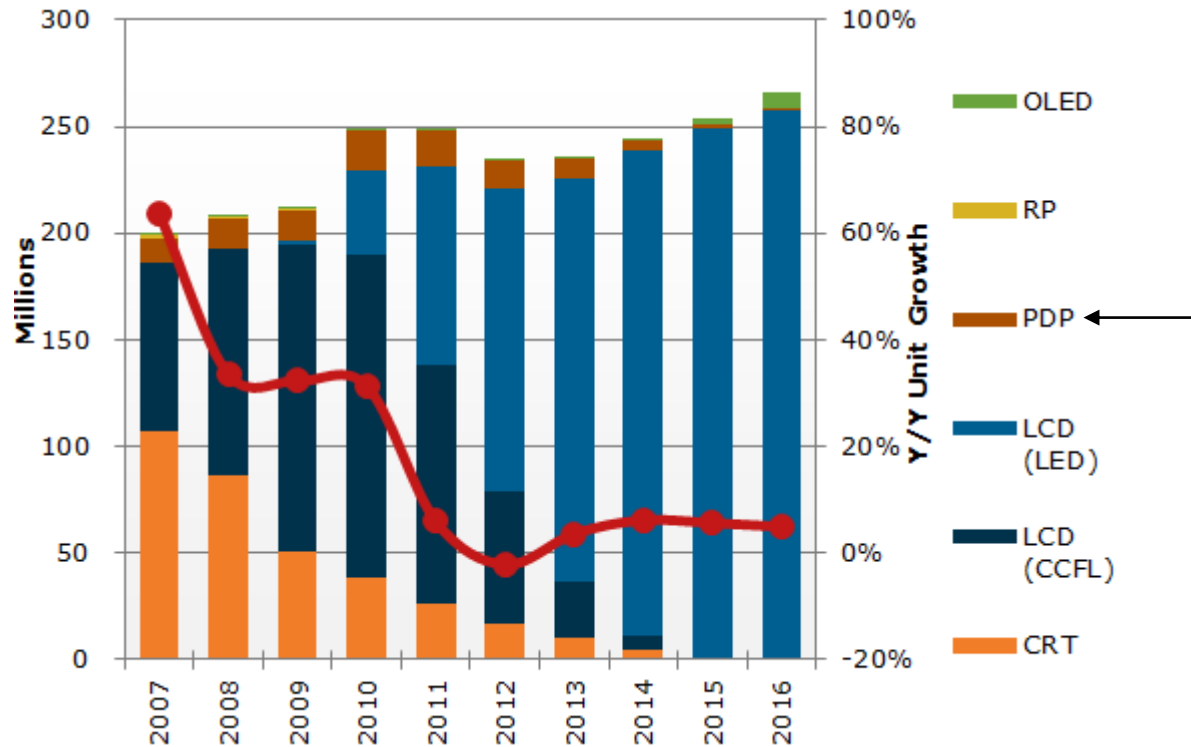
Optimistic projection of PDP market



Reality



TV Shipment Growth by Technology

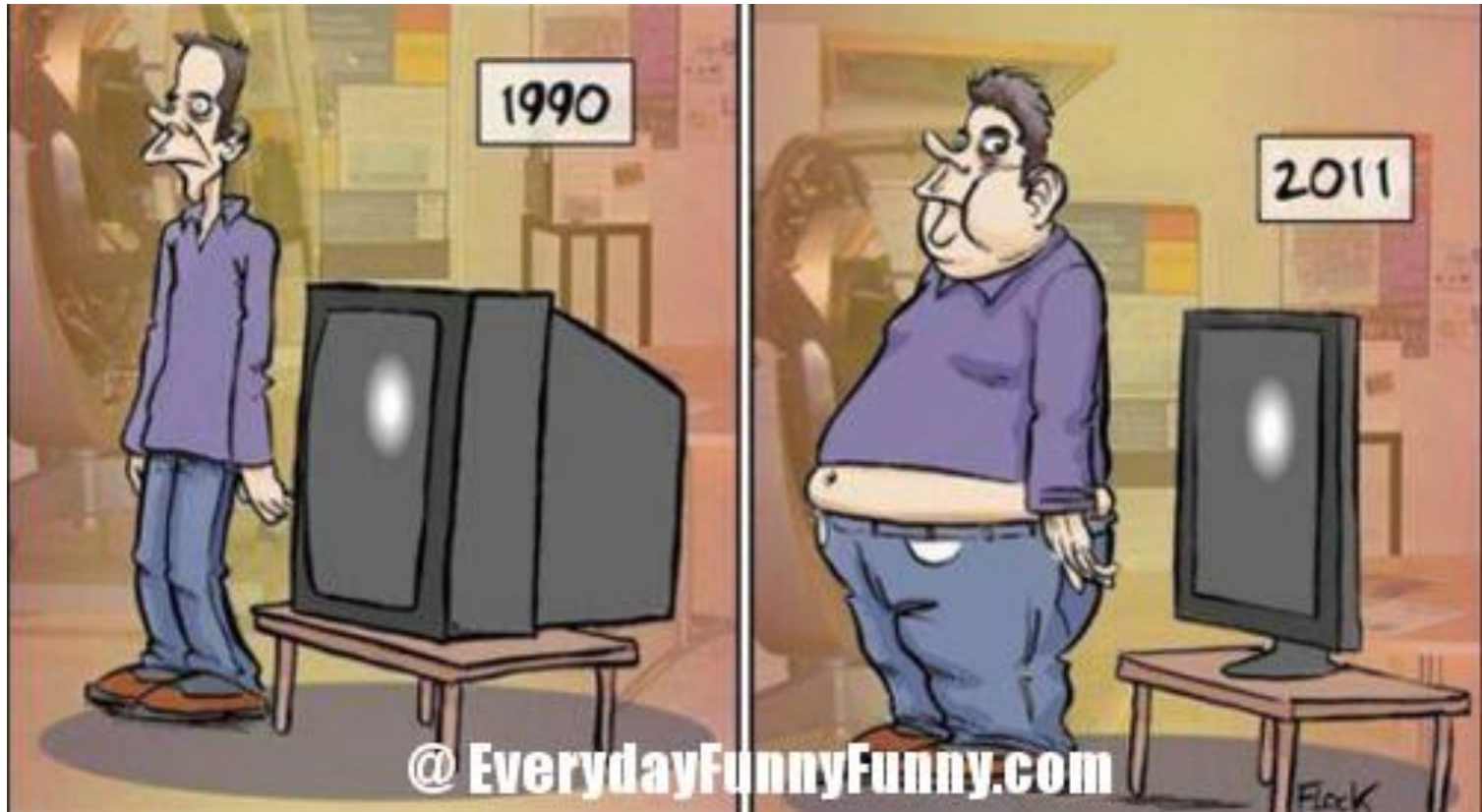


Too many reasons that PDP died!



- **Bright showroom conditions put plasmas at a distinct disadvantage versus LED-lit LCDs**
- **Aesthetics may have played a role in hastening plasma's demise**
- **UHD/4K caught on quickly**
- **Screen-size limitations also played a part in plasmas plight**
- **You can't bend a plasma**
- **Plasmas were harder to deal with than LCDs**
- **While OLED is still in the early stages of development, there's no question it offers greater potential than plasma**
- **Energy efficiency may have played a part in putting plasma out to pasture**
- **Plasma was the original flat-panel technology, People just thought of it as old technology.**
- **Projectors improved in quality and prices dropped**

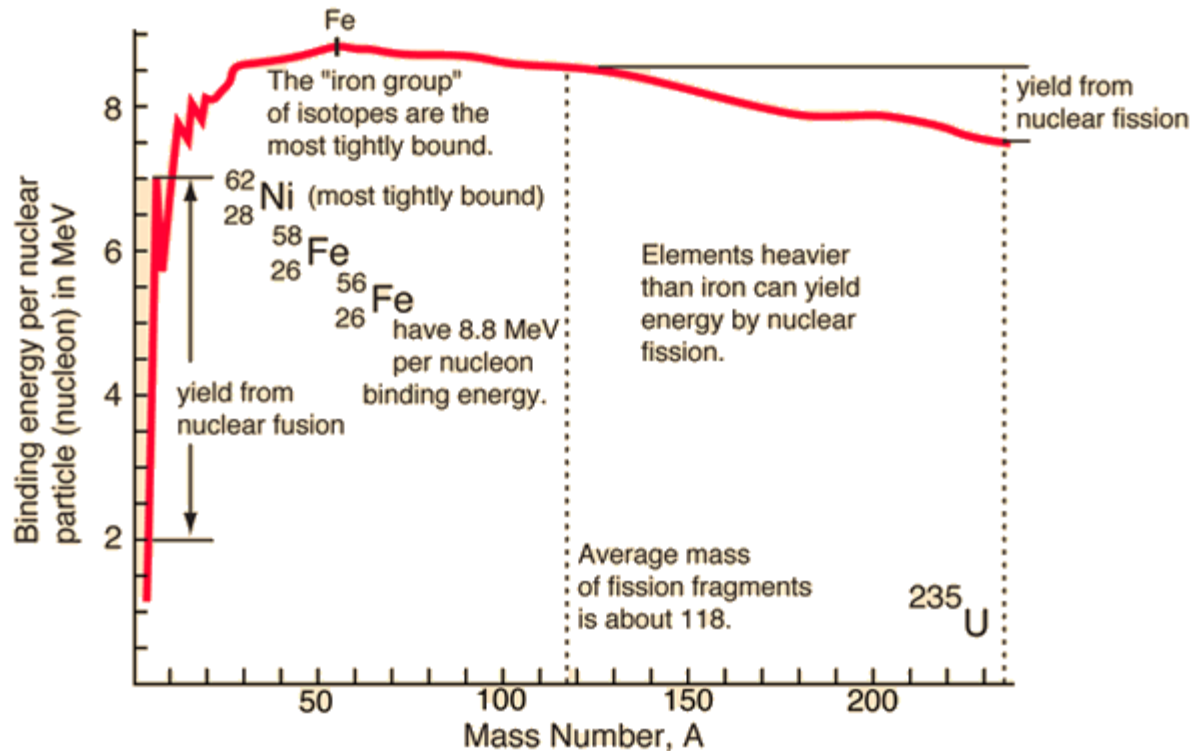
Let's stand up and do exercise!!



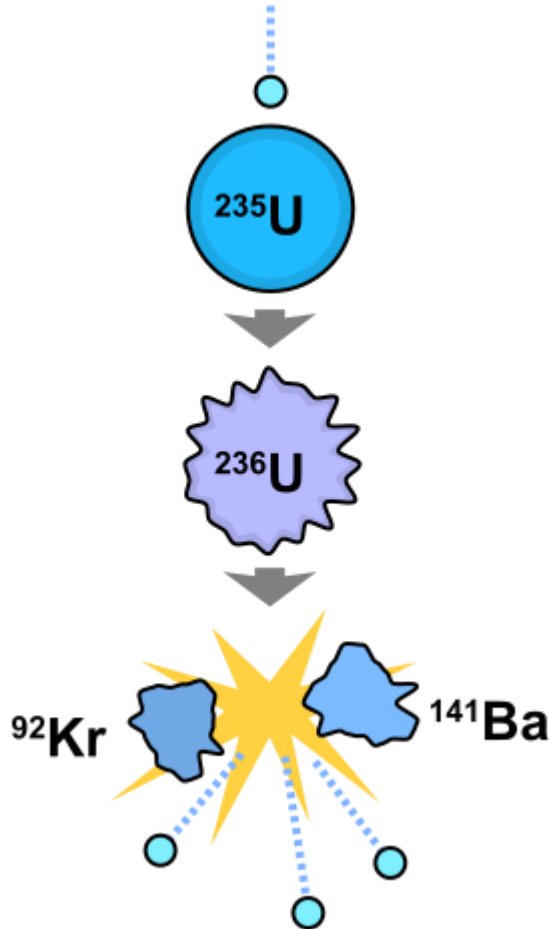
The hydrogen bomb



The “iron group” of isotopes are the most tightly bound

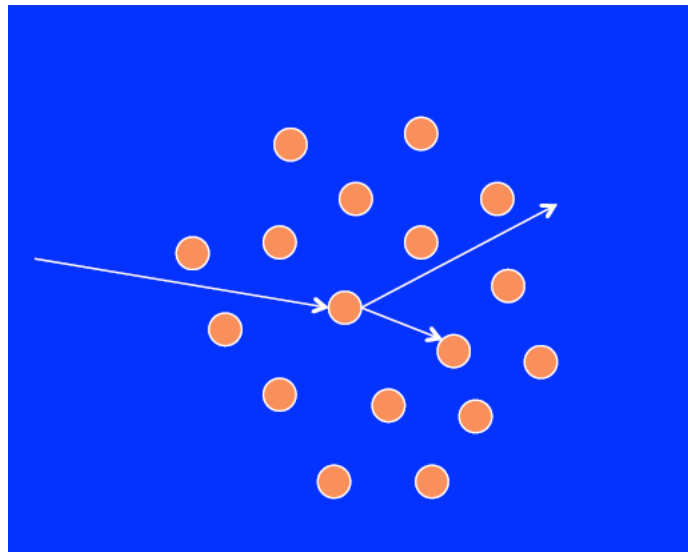


Chain reaction can happen in U^{235} fission reaction

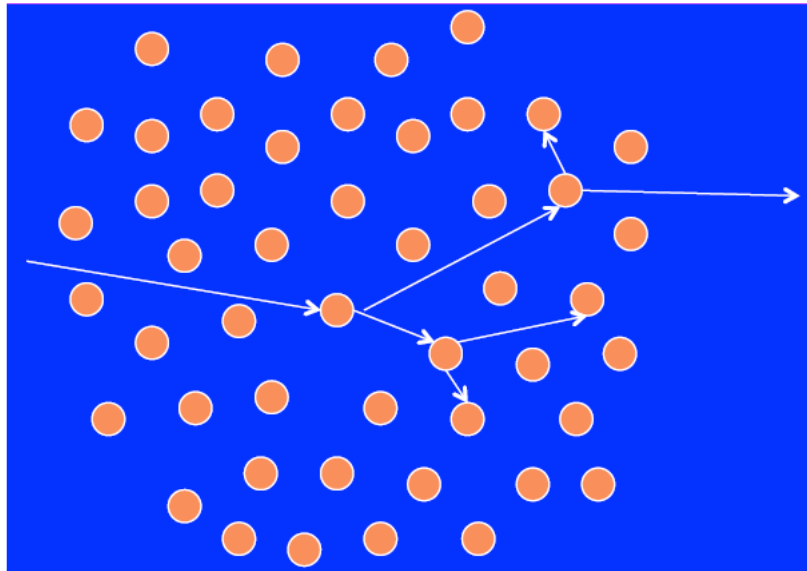


- ~ 200 million electron volts (MeV)/fission, ~million times more than chemical reactions
- Energy for bombs, or for civilian power can generate huge amounts of energy (and toxicity) in a small space with a modest amount of material
- Source of safety, security issues for nuclear power

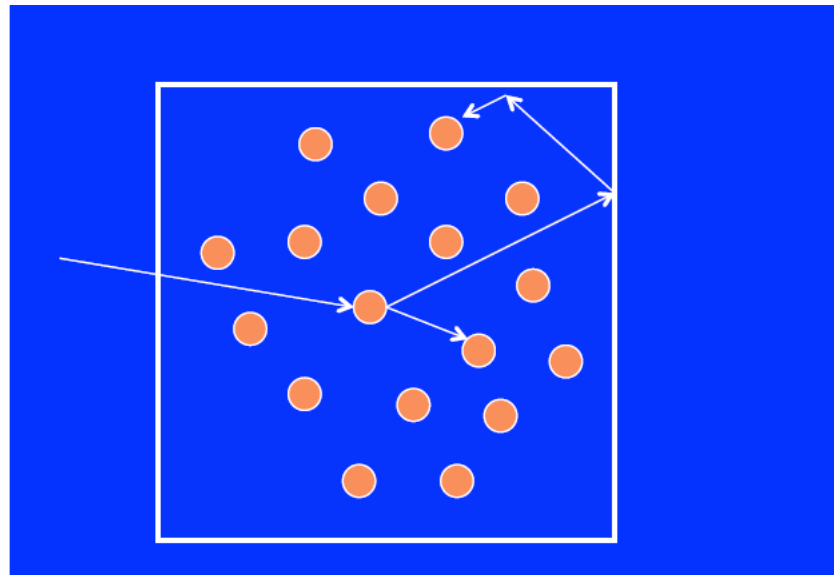
The neutrons are leaking out and stopping the chain reaction in a sub-critical mass



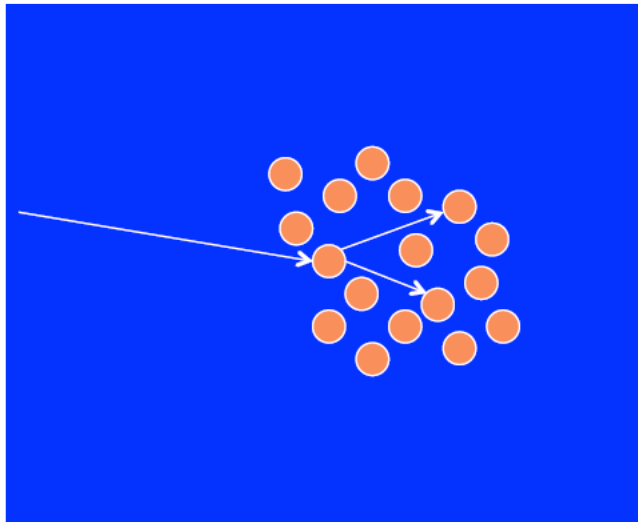
Solution 1: add more material



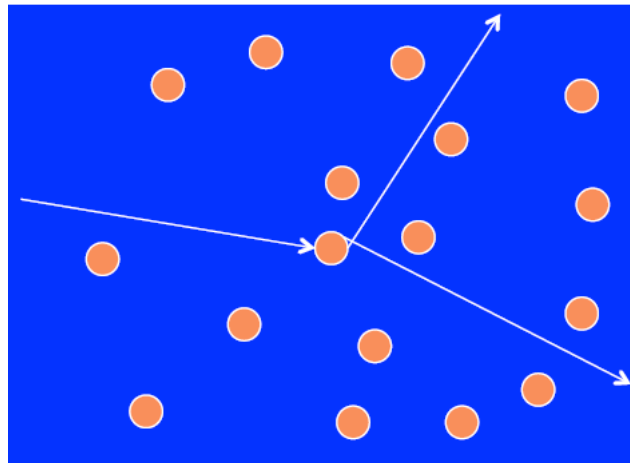
Solution2: reflect the neutron back in



Solution 3: increase the density



How to get the material together before it blows apart?

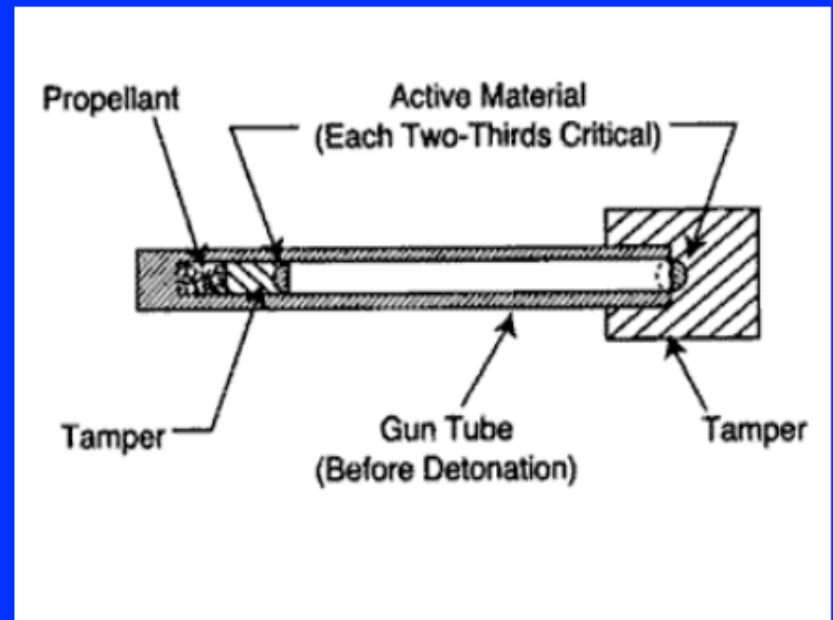


- **There are always neutrons around**
- **Once chain reaction starts, material will heat up, expand, stop reaction**
- **How to get enough material together fast enough?**

Gun-type bomb

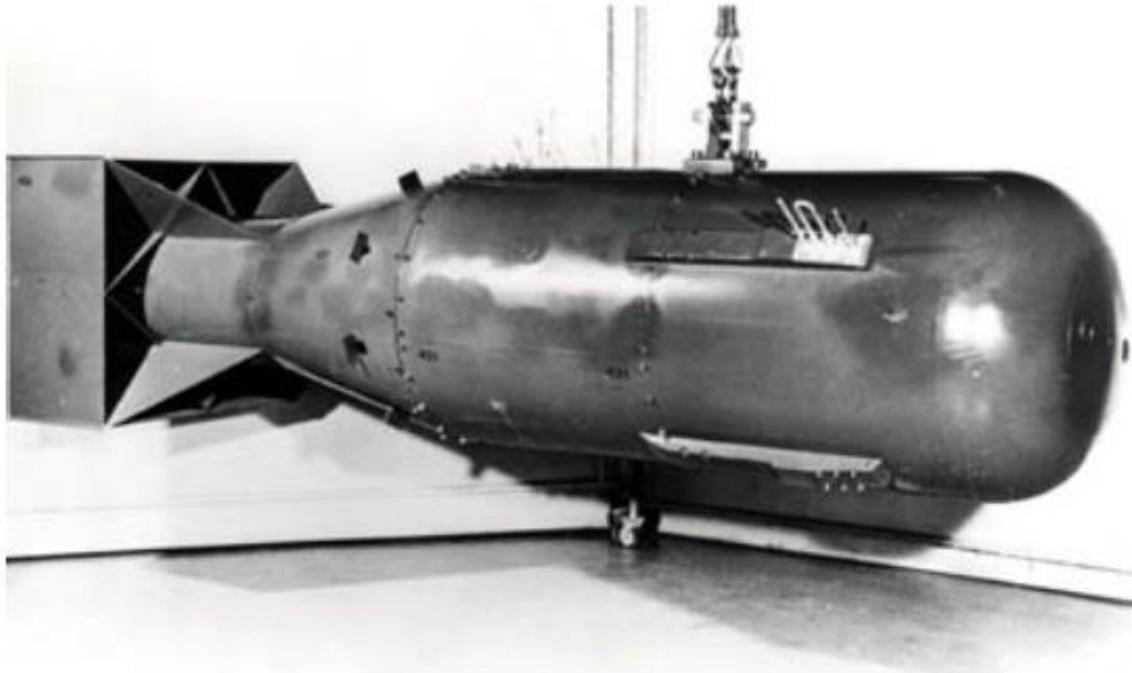


- **Simple, reliable – can be built without testing**
- **Highly inefficient – require lots of nuclear material (50-60 kg of 90% enriched HEU)**
- **Can only get high yield with HEU, not plutonium**
- **Hiroshima bomb: cannon that fired HEU projectile into HEU target**



Source: NATO

Hiroshima Bomb – “Little Boy”



Gun Type – Easiest to design and build (Hiroshima bomb was never tested)

About 13 kiloton explosive yield

Atomic bomb is very destructive



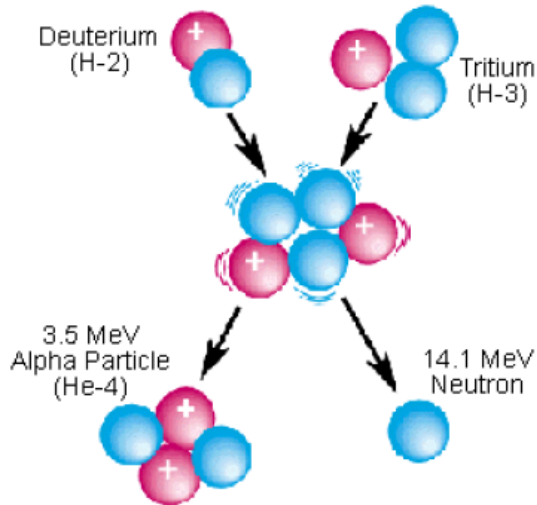
Hiroshima: August 6, 1945



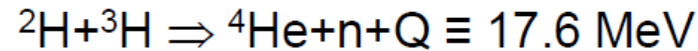
Nagasaki: August 9, 1945



The fusion process

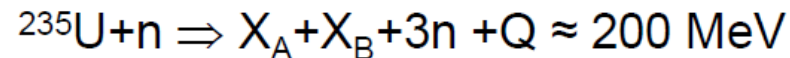
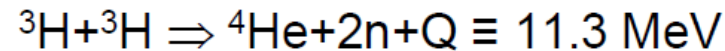
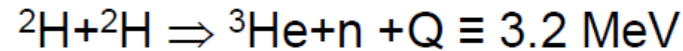
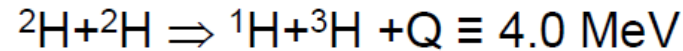


Deuterium-Tritium Fusion Reaction



Energy release $Q=17.6 \text{ MeV}$

In comparison



Fusionable Material, deuterium ${}^2\text{H}$ (D) and tritium ${}^3\text{H}$ (t):

Deuterium: natural occurrence (heavy water) (0.015%).

Tritium: natural occurrence in atmosphere through cosmic ray bombardment; radioactive with $T_{1/2}=12.3 \text{ y}$.

“Advantages” of hydrogen bomb



$$\text{Fusion of } ^2\text{H} + ^3\text{H}: \quad \frac{Q}{A} = \frac{17.6 \text{ MeV}}{(3 + 2) \text{ amu}} = 3.5 \frac{\text{MeV}}{\text{amu}}$$

$$\text{Fission of } ^{235}\text{U}: \quad \frac{Q}{A} = \frac{200 \text{ MeV}}{236 \text{ amu}} = 0.85 \frac{\text{MeV}}{\text{amu}}$$

Fusion is 4 times more powerful than fission
and generates 24 times more neutrons!

$$\text{Neutron production:} \quad ^2\text{H} + ^3\text{H}: \quad \frac{n}{A} = \frac{1}{5} = 0.2$$

$$^{235}\text{U} + n: \quad \frac{n}{A} = \frac{2}{236} = 0.0085$$

Hydrogen bomb uses a fission bomb to initiate the fusion reaction



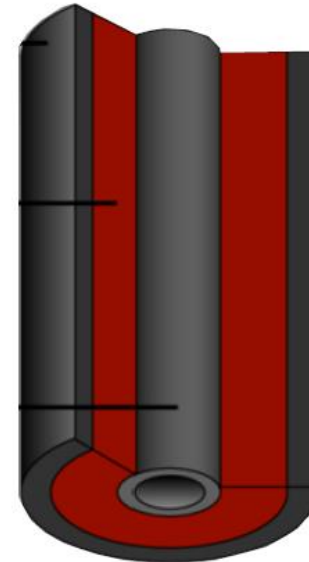
Primary Fission Device

Core: ^{239}Pu , ^{235}U ,
plus $^2\text{H}+^3\text{H}$ booster

Shell: ^{238}U tamper

High explosive lenses

Fuel



Secondary Fusion Device

Radiation channel

^{239}Pu sparkplug

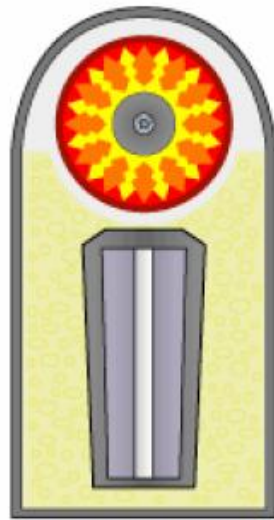
^6Li , ^2H , ^3H fusion cell

^{238}U tamper

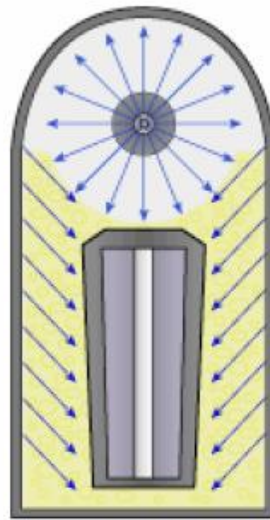
Event sequence



1. Warhead before firing; primary (fission bomb) at top, secondary (fusion fuel) at bottom, all suspended in polystyrene foam.



2. HE fires in primary, compressing plutonium core into supercriticality and beginning a fission reaction.



3. Fissioning primary emits X-rays which reflect along the inside of the casing, irradiating the polystyrene foam.



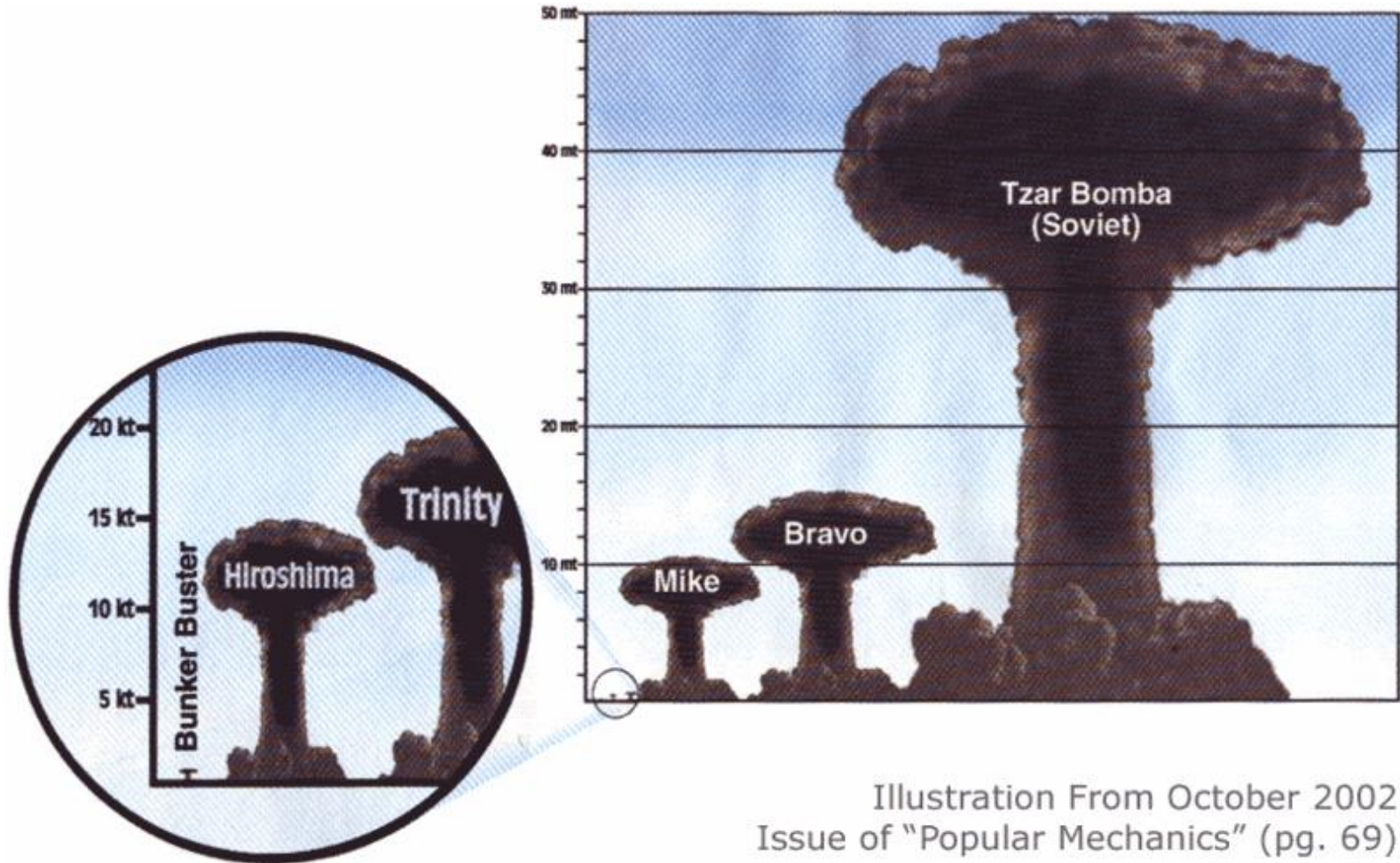
4. Polystyrene foam becomes plasma, compressing secondary, and plutonium sparkplug begins to fission.



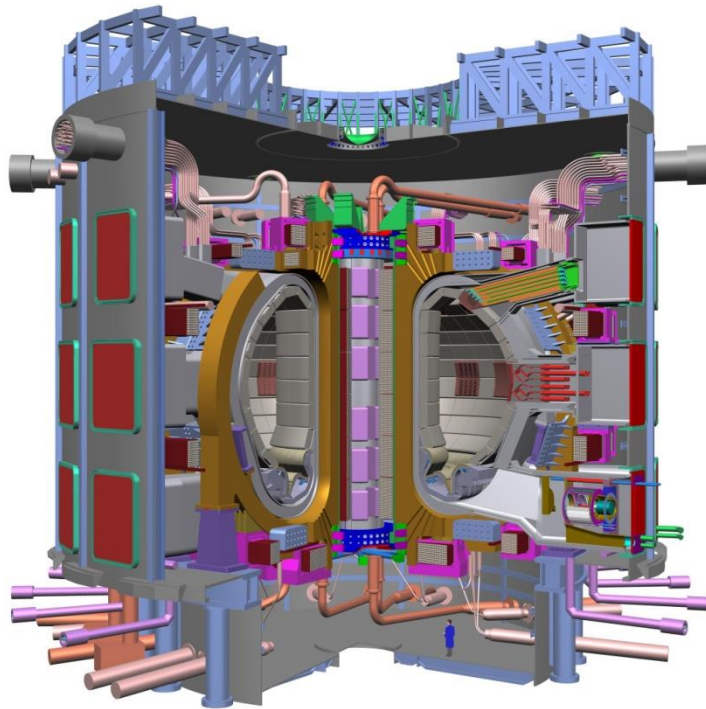
5. Compressed and heated, lithium-6 deuteride fuel begins fusion reaction, neutron flux causes tamper to fission. A fireball is starting to form...

Additional pressure from recoil of exploding shell (ablation)!

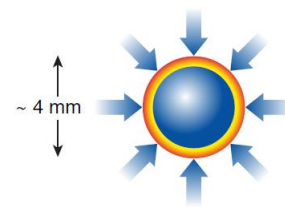
You don't want to build a hydrogen bomb!



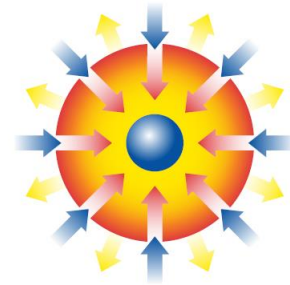
To Fuse, or Not to Fuse...



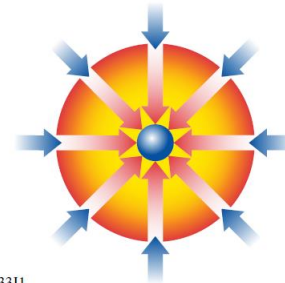
Laser light shines on the target



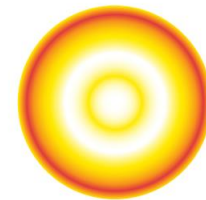
The target is compressed



The target is ignited



The target burns



U733J1

Outline



- **Introduction to nuclear fusion**
- **Magnetic confinement fusion (MCF)**
 - Tokamak
 - Stellarator
- **Inertial confinement fusion (ICF)**
 - Indirection drive ICF
 - Direct drive ICF
- **Innovation idea – MCF + ICF**
- **Pulsed-power system at NCKU**

Outline

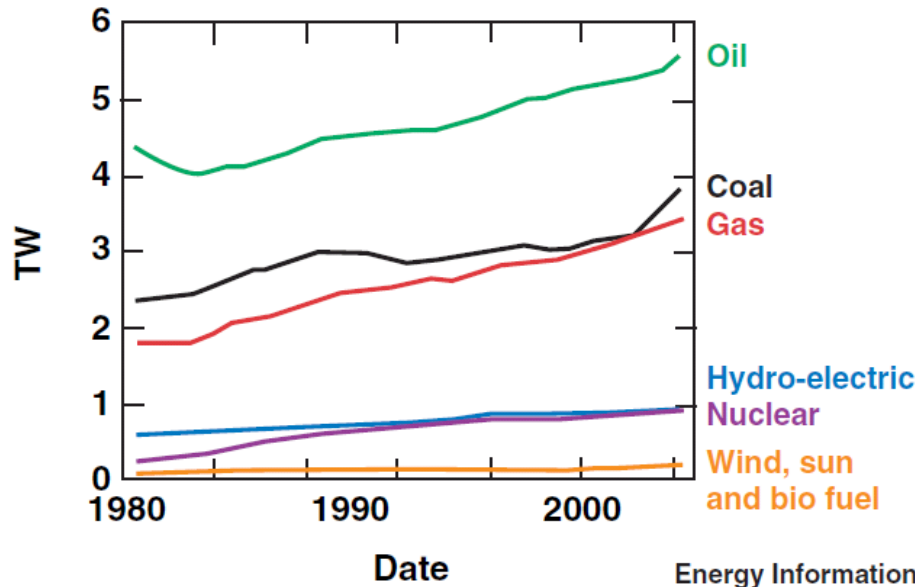


- **Introduction to nuclear fusion**
- **Magnetic confinement fusion (MCF)**
 - Tokamak
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 - Direct drive ICF
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World energy consumption is dominated by the use of dwindling fossil fuels



Fossil fuel	Estimated reserve	(2005 consumption rate) Years remaining
Oil	1,277,702 million barrels	32 years
Natural gas	~6,500,000 billion cubic ft	72 years
Coal	1,081,279 million tons	252 years

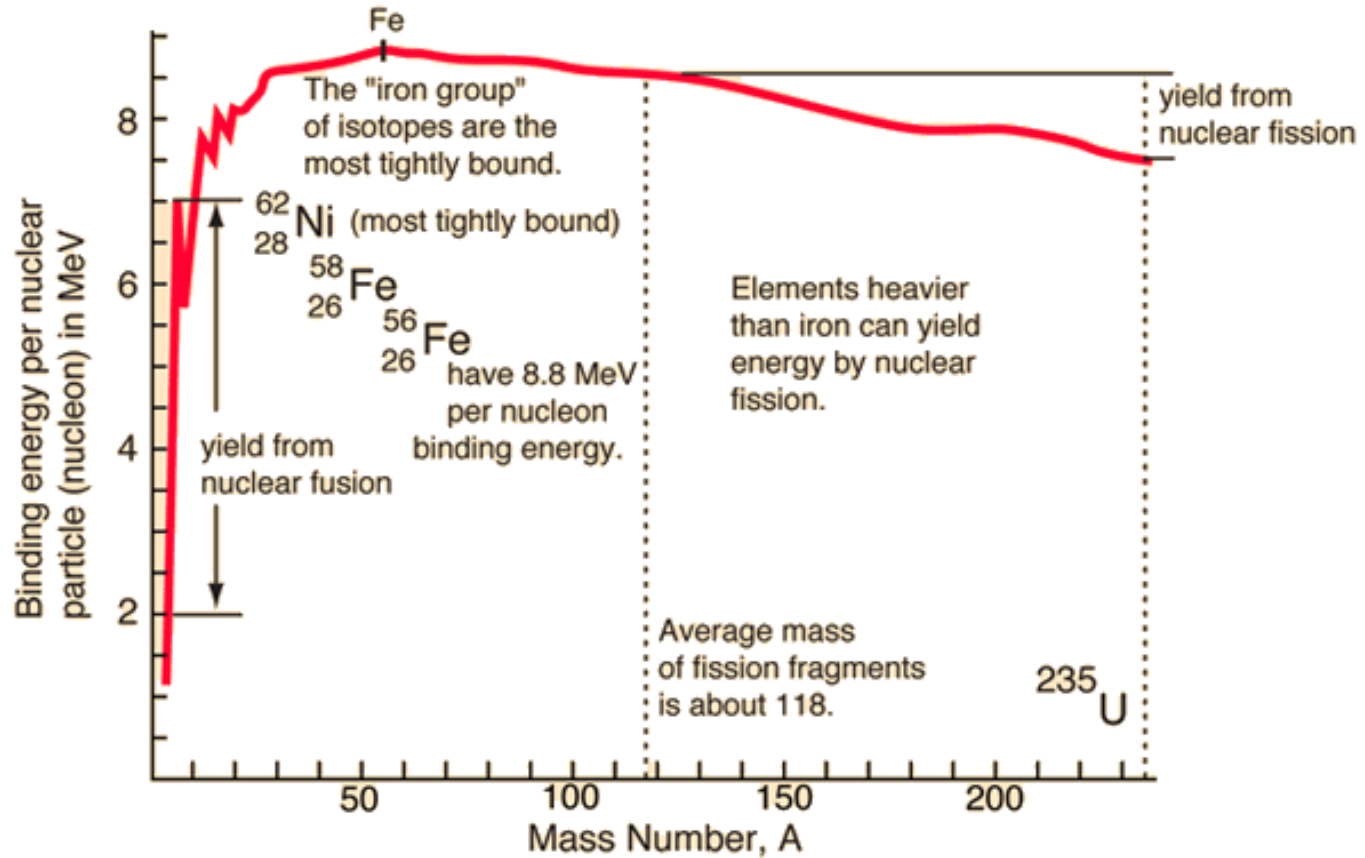


While predictions about the exact number of remaining years vary, fossil fuels will run out.

Energy Information Administration (EIA) 2006 Annual Report, U.S. Department of Energy, Washington, D.C.

E15657

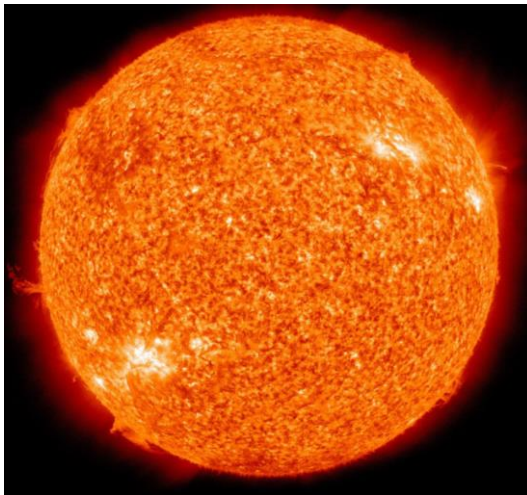
The “iron group” of isotopes are the most tightly bound



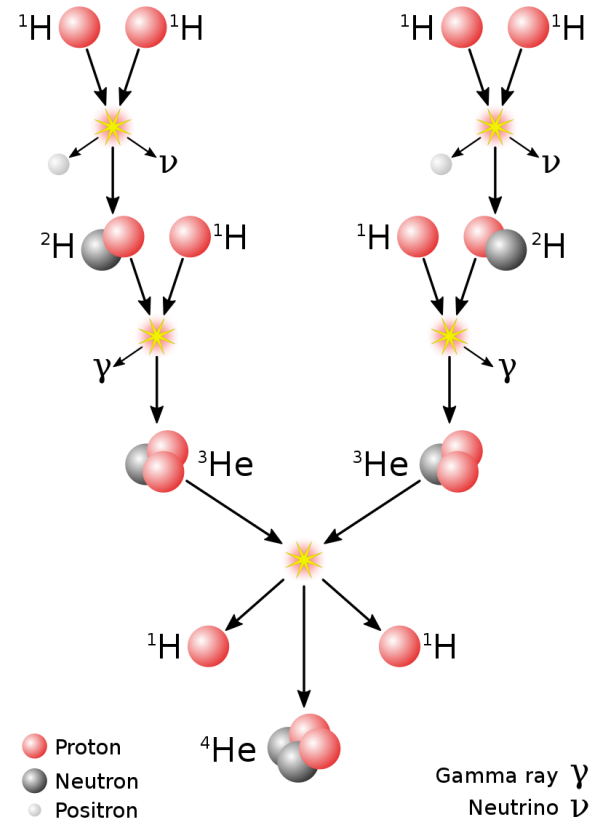
Fusion in the sun provides the energy



- Proton-proton chain in sun or smaller



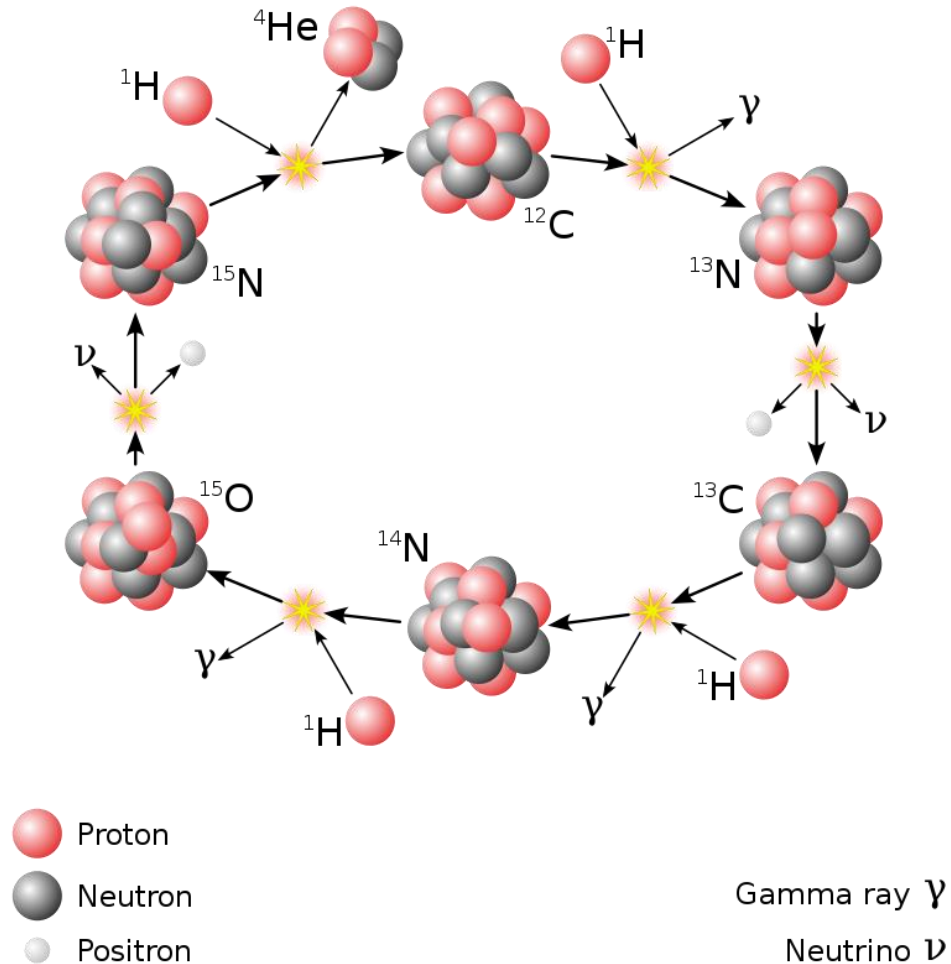
- Particles are confined by the gravity.



<https://en.wikipedia.org/wiki/Sun>

https://en.wikipedia.org/wiki/Nuclear_fusion

In heavy sun, the fusion reaction is the CNO cycle



The cross section of proton-proton chain is much smaller than D T fusion



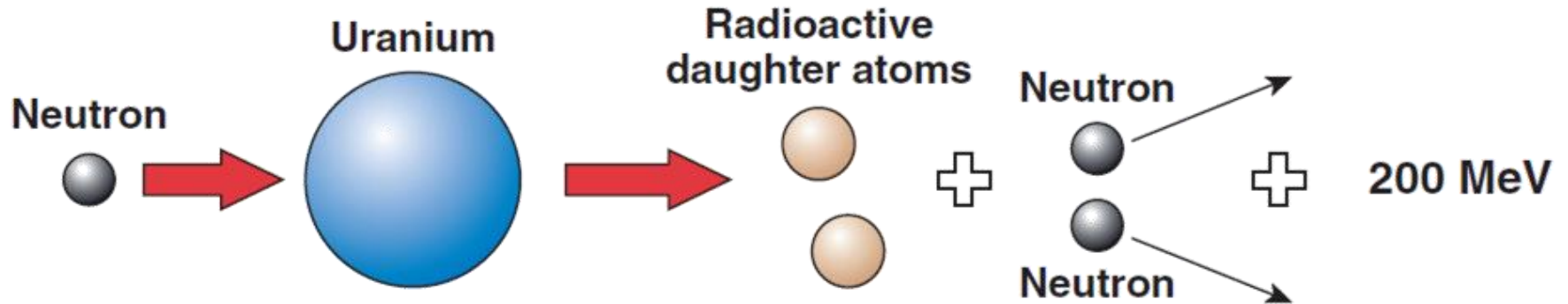
Reaction	$\sigma_{10 \text{ keV}}$ (barn)	$\sigma_{100 \text{ keV}}$ (barn)	σ_{max} (barn)	ϵ_{max} (keV)
$\text{D}+\text{T}\rightarrow\alpha+\text{n}$	2.72×10^{-2}	3.43	5.0	64
$\text{D}+\text{T}\rightarrow\text{T}+\text{p}$	2.81×10^{-4}	3.3×10^{-2}	0.06	1250
$\text{D}+\text{T}\rightarrow{}^3\text{He}+\text{n}$	2.78×10^{-4}	3.7×10^{-2}	0.11	1750
$\text{T}+\text{T}\rightarrow\alpha+2\text{n}$	7.90×10^{-4}	3.4×10^{-2}	0.16	1000
$\text{D}+{}^3\text{He}\rightarrow\alpha+\text{p}$	2.2×10^{-7}	0.1	0.9	250
$\text{p}+{}^6\text{Li}\rightarrow\alpha+{}^3\text{He}$	6×10^{-10}	7×10^{-3}	0.22	1500
$\text{p}+{}^{11}\text{B}\rightarrow 3\alpha$	(4.6×10^{-17})	3×10^{-4}	1.2	550
$\text{p}+\text{p}\rightarrow\text{D}+\text{e}^++\text{v}$	(3.6×10^{-26})	(4.4×10^{-25})		
$\text{p}+{}^{12}\text{C}\rightarrow{}^{13}\text{N}+\gamma$	(1.9×10^{-26})	2.0×10^{-10}	1.0×10^{-4}	400
${}^{12}\text{C}+{}^{12}\text{C}$ (all branches)		(5.0×10^{-103})		

- “()” are theoretical values while others are measured values.

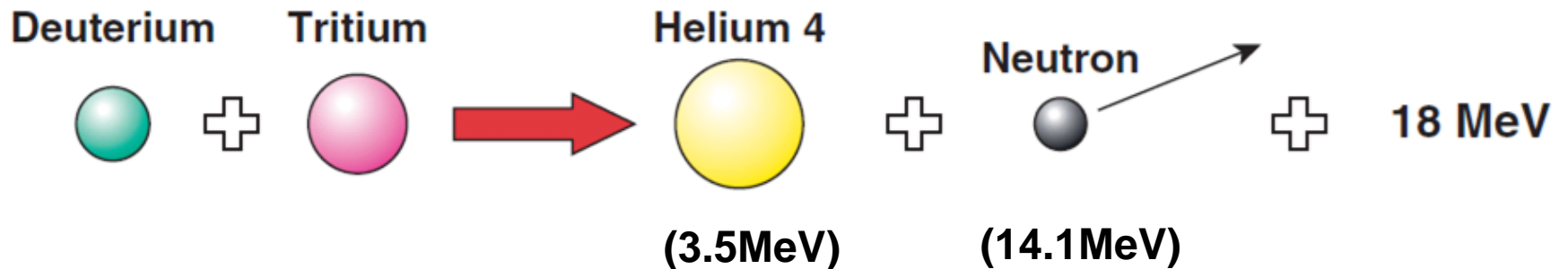
Nuclear fusion and fission release energy through energetic neutrons



Fission



Fusion



Nuclear fusion provides more energy per atomic mass unit (amu) than nuclear fission



Fusion of ${}^2\text{H}+{}^3\text{H}$:
$$\frac{Q}{A} = \frac{17.6 \text{ MeV}}{(3 + 2) \text{ amu}} = 3.5 \frac{\text{MeV}}{\text{amu}}$$

Fission of ${}^{235}\text{U}$:
$$\frac{Q}{A} = \frac{200 \text{ MeV}}{236 \text{ amu}} = 0.85 \frac{\text{MeV}}{\text{amu}}$$

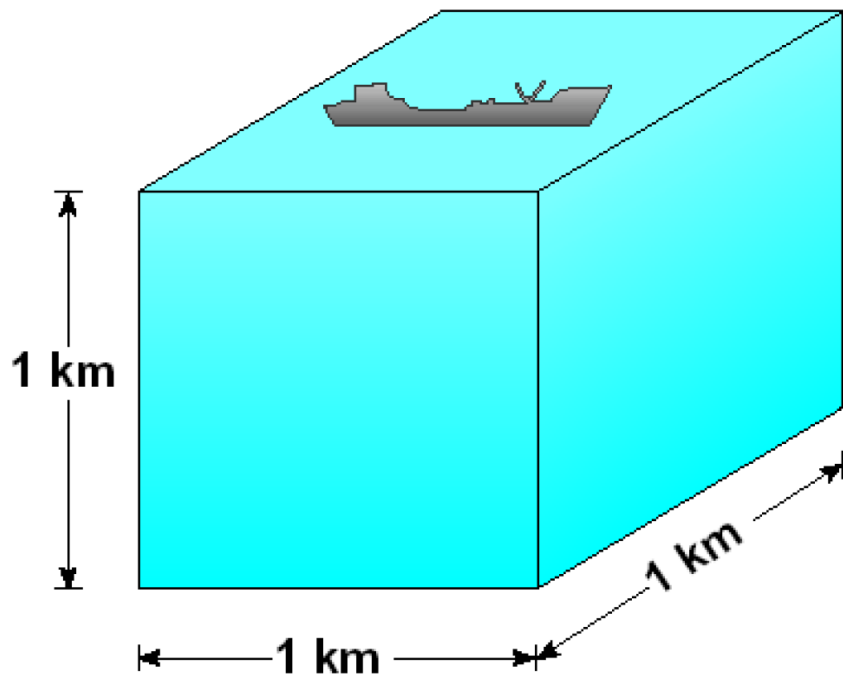
	Half-life (years)
U235	7.04×10^8
U238	4.47×10^9
...	
Tritium	12.3

What could you do with 1 kg DT?



- **1 kg DT -> 340 Tera joules**
 - **You can drive your car for ~40,000 km (back and forth between Keelung and Kaoshiung for 50 times).**
 - **You can keep your furnace running for 8 years.**
 - **You can blow things up! 1 TJ = 250 tons of TNT.**

Enormous fusion fuel can be produced from sea water



= Total energy
of world oil
reserve

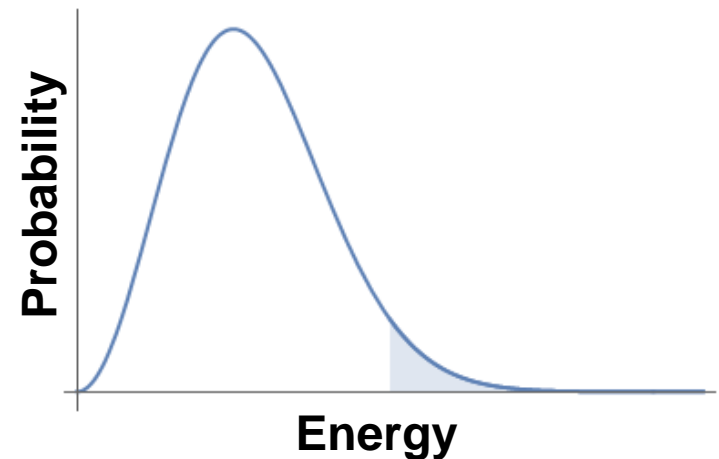
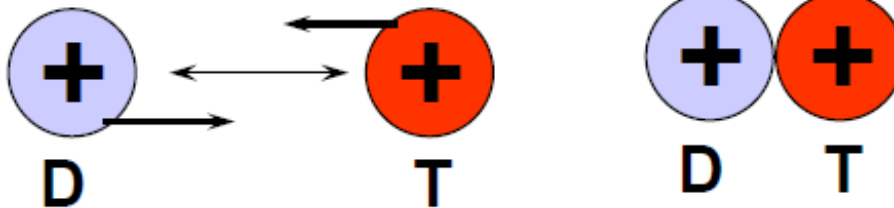
A “hot plasma” at 100M °C is needed



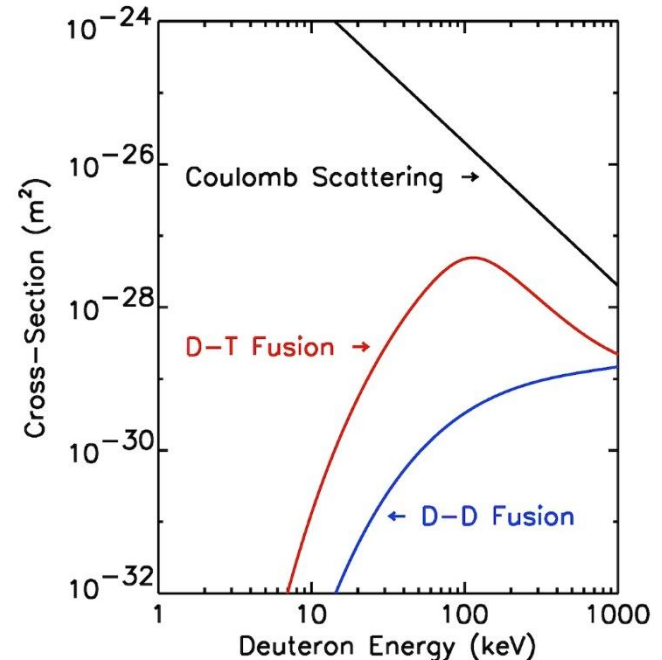
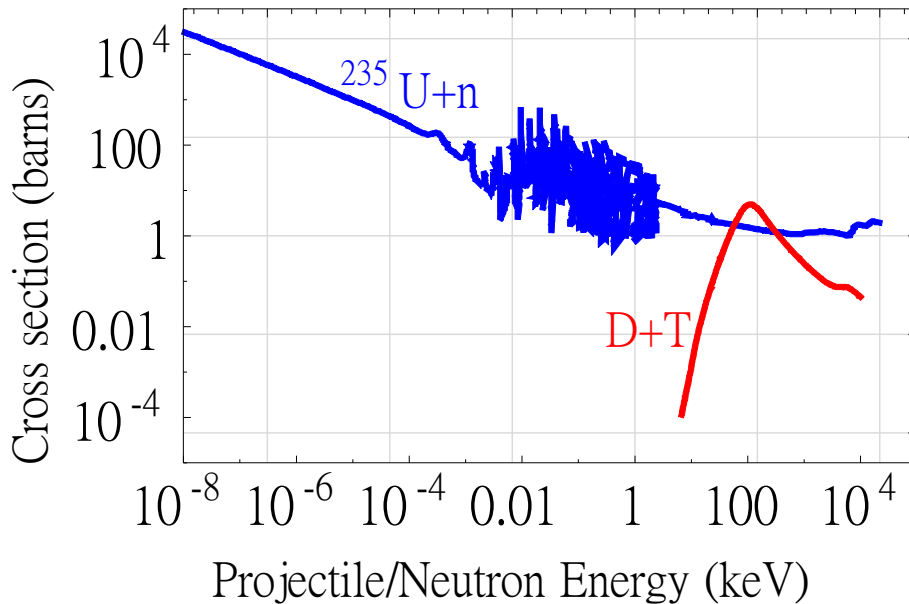
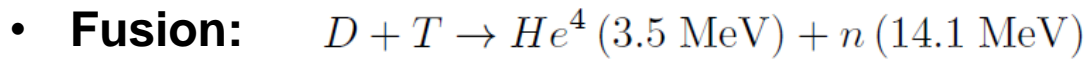
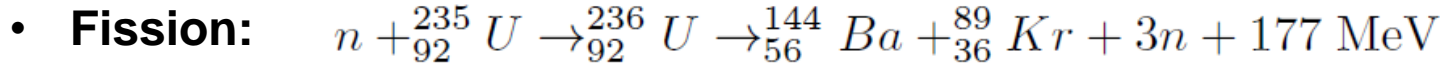
- Probability for fusion reactions to occur is low at low temperatures due to the coulomb repulsion force.



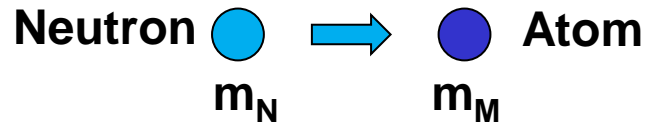
- If the ions are sufficiently hot, i.e., large random velocity, they can collide by overcoming coulomb repulsion



Fusion is much harder than fission, a “hot plasma” at 100M °C is needed



Fast neutrons are slowed down due to the collisions



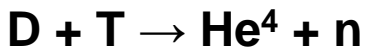
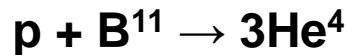
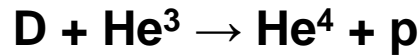
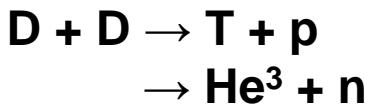
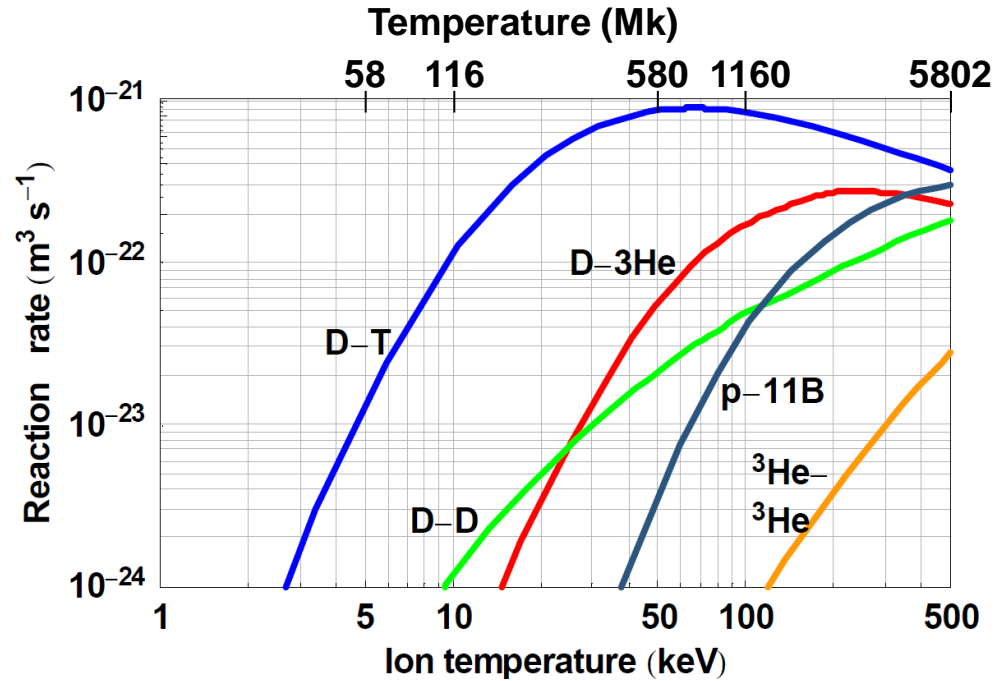
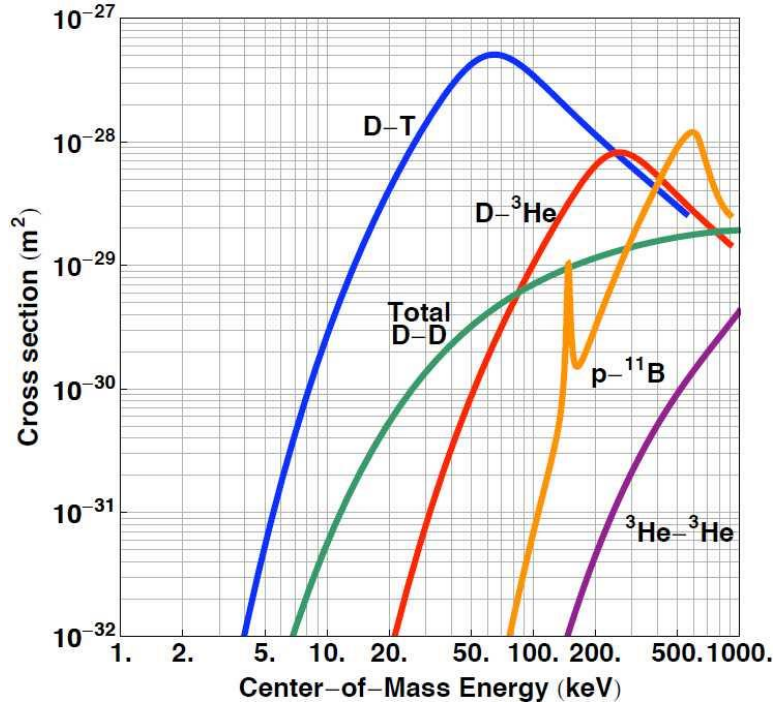
- A moderator is used to slow down fast neutrons but not to absorb neutrons.
- For $m_M \sim m_N$, the energy decrement is higher. Therefore, H slows down neutron most efficiently.
- However, $H + n \rightarrow D$, i.e., H absorbs neutrons.
- The best option is the D in the heavy water (D_2O).

	Energy decrement	Neutron scattering cross section (σ) (Barns)	Neutron absorption cross section (σ) (Barns)
H	1	49 (H_2O)	0.66 (H_2O)
D	0.7261	10.6 (D_2O)	0.0013 (D_2O)
C	0.1589	4.7 (Graphite)	0.0035 (Graphite)

https://en.wikipedia.org/wiki/Neutron_moderator#cite_note-Weston-4

https://energyeducation.ca/encyclopedia/Neutron_moderator#cite_note-3

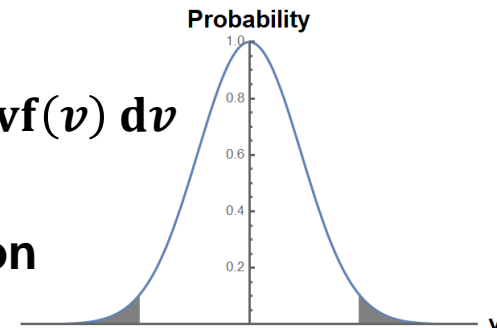
Fusion doesn't come easy



• Reaction rate:

$$\langle \sigma v \rangle = \int \sigma(v) v f(v) dv$$

Cross section



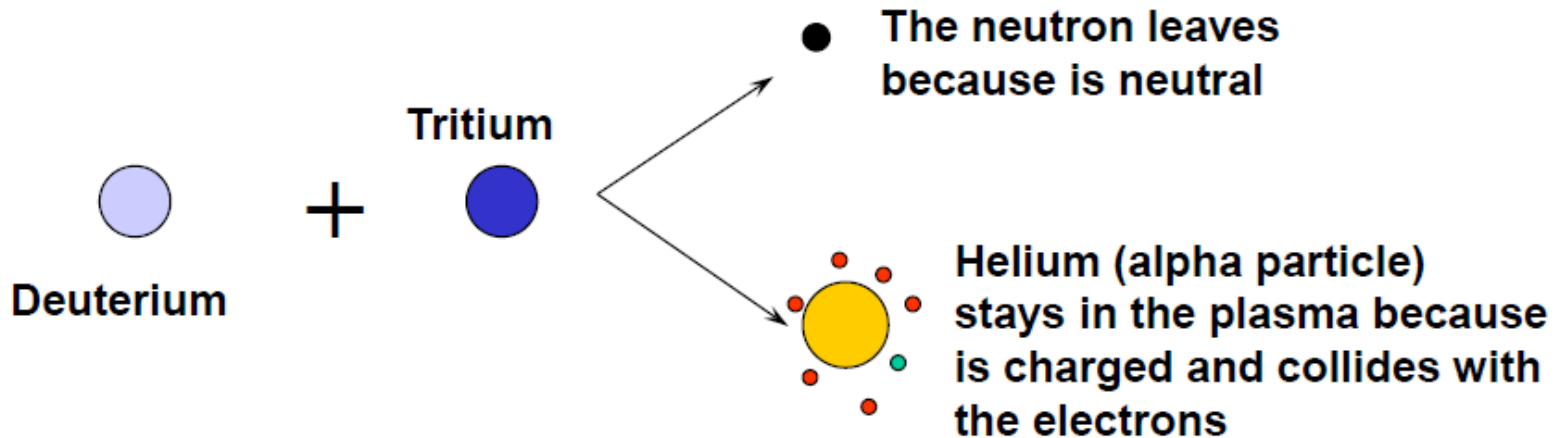
<https://i.stack.imgur.com/wXQD5.jpg>

Santarius, J. F., "Fusion Space Propulsion – A Shorter Time Frame Than You Think", JANNAF, Monterey, 5-8 December 2005.

It takes a lot of energy or power to keep the plasma at 100M °C



- Let the plasma do it itself!



- The α -particles heat the plasma.

Under what conditions the plasma keeps itself hot?



- **Steady state 0-D power balance:**

$$S_{\alpha} + S_h = S_B + S_k$$

S_{α} : α particle heating

S_h : external heating

S_B : Bremsstrahlung radiation

S_k : heat conduction lost

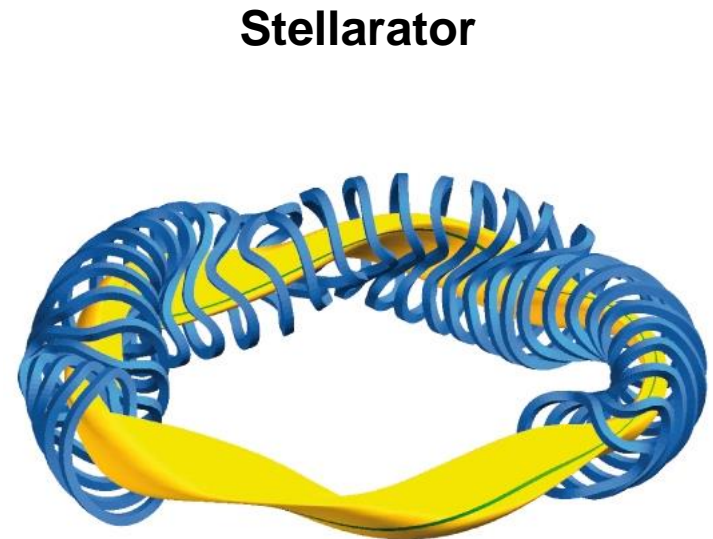
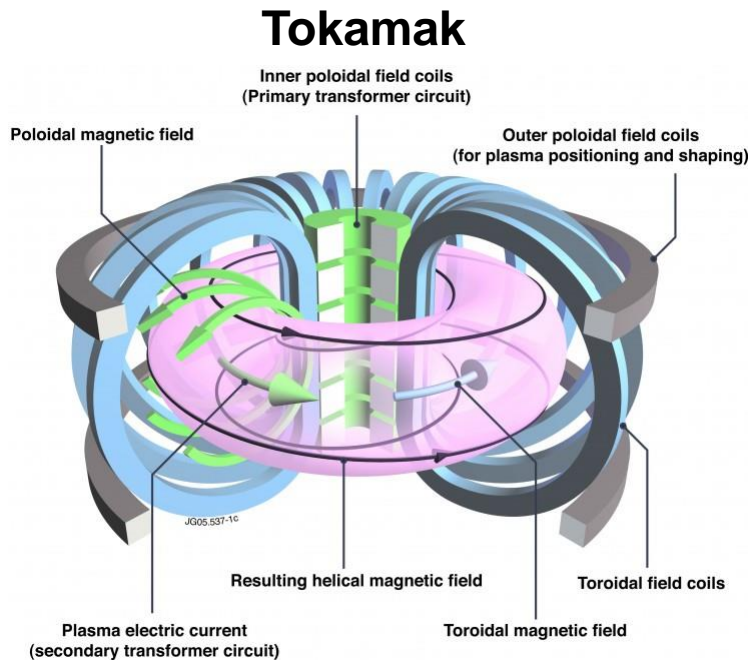
Ignition condition: $P\tau > 10 \text{ atm-s} = 10 \text{ Gbar} \cdot \text{ns}$

- **P: pressure, or called energy density**
- **τ is confinement time**

The plasma is too hot to be contained



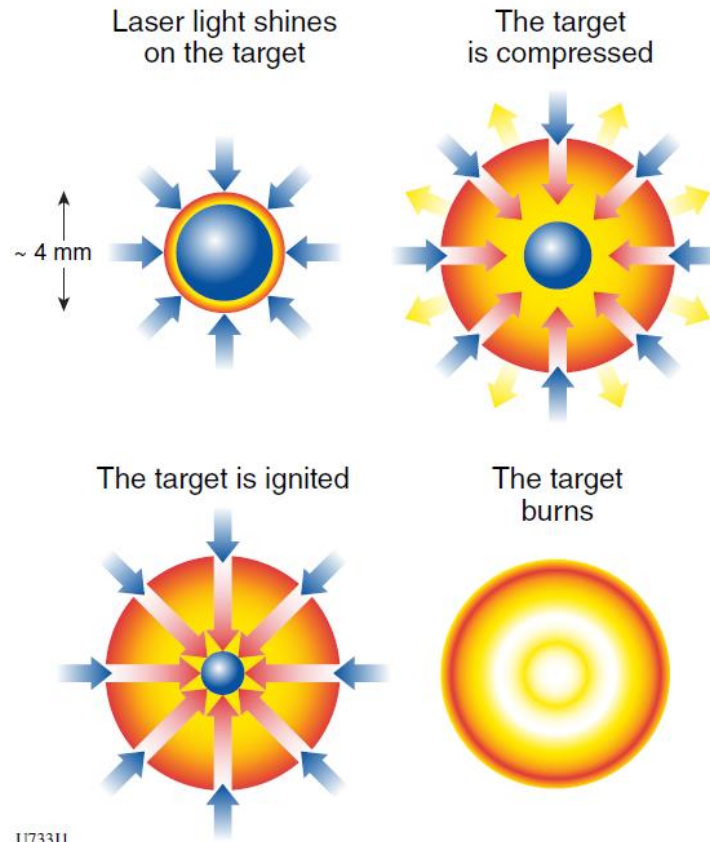
- **Solution 1: Magnetic confinement fusion (MCF), use a magnetic field to contain it. $P \sim \text{atm}$, $\tau \sim \text{sec}$, $T \sim 10 \text{ keV}$ ($10^8 \text{ }^\circ\text{C}$)**



Don't confine it!



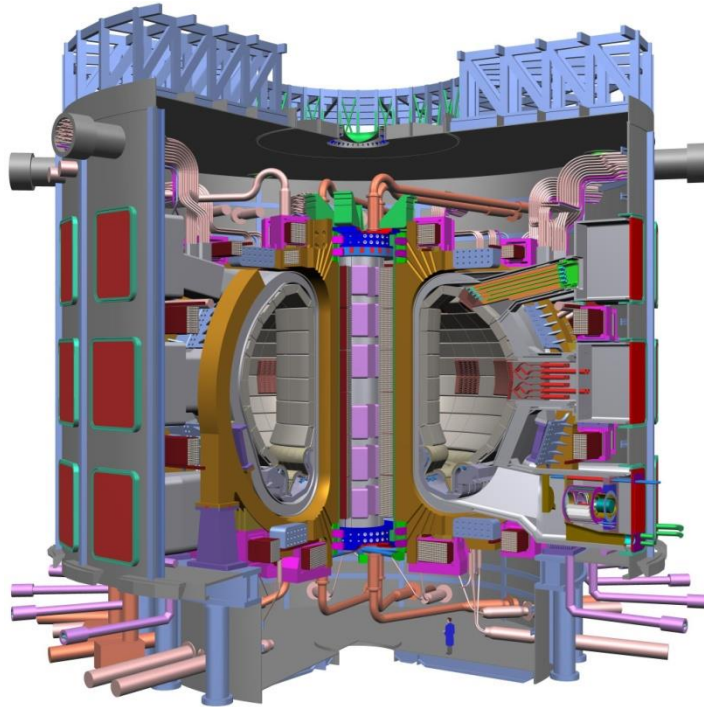
- **Solution 2: Inertial confinement fusion (ICF). Or you can say it is confined by its own inertia: $P \sim \text{Gigabar}$, $\tau \sim \text{nsec}$, $T \sim 10 \text{ keV}$ ($10^8 \text{ }^\circ\text{C}$)**



To control? Or not to control?

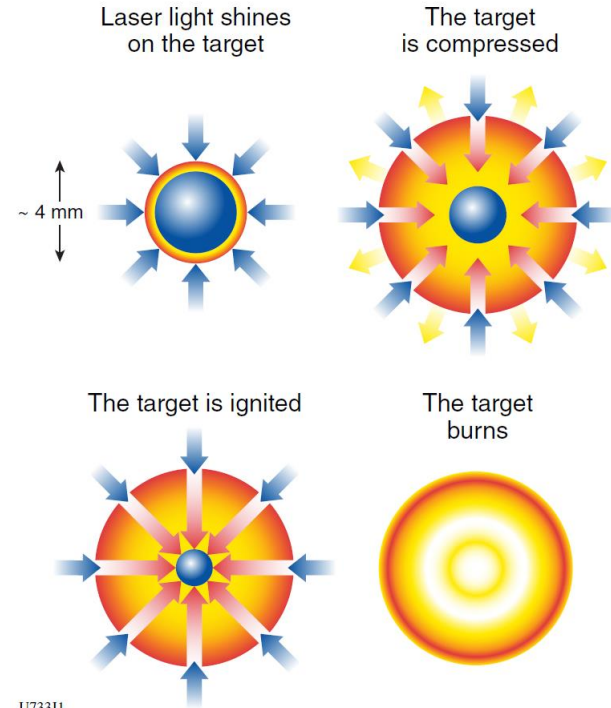


- **Magnetic confinement fusion (MCF)**



- Plasma is confined by toroidal magnetic field.

- **Inertial confinement fusion (ICF)**



- A DT ice capsule filled with DT gas is imploded by laser.

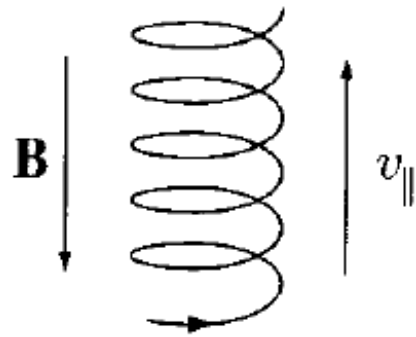
Laboratory for Laser Energetics, University of Rochester is a pioneer in laser fusion

Outline

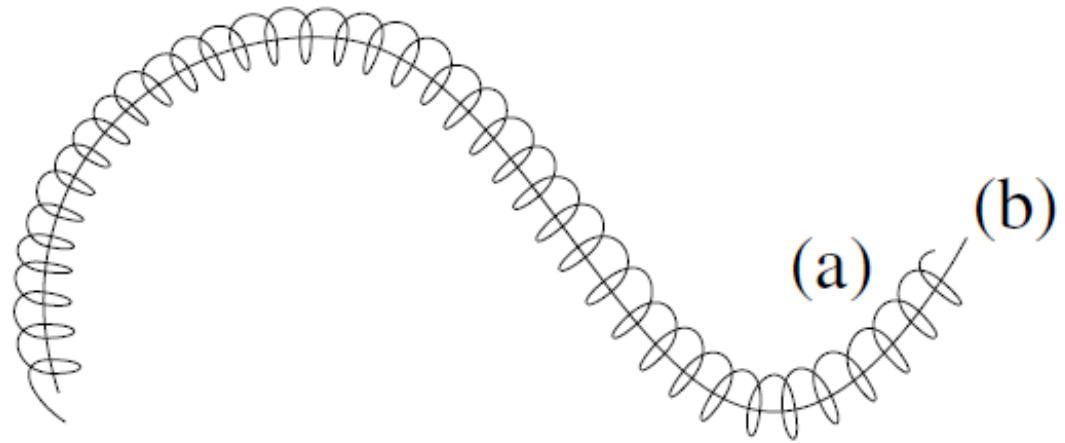


- Introduction to nuclear fusion
- **Magnetic confinement fusion (MCF)**
 - Tokamak
 - Stellarator
- Inertial confinement fusion (ICF)
 - Indirection drive ICF
 - Direct drive ICF
- Innovation idea – MCF + ICF
- Pulsed-power system at NCKU

Charged particles gyro around the magnetic fields



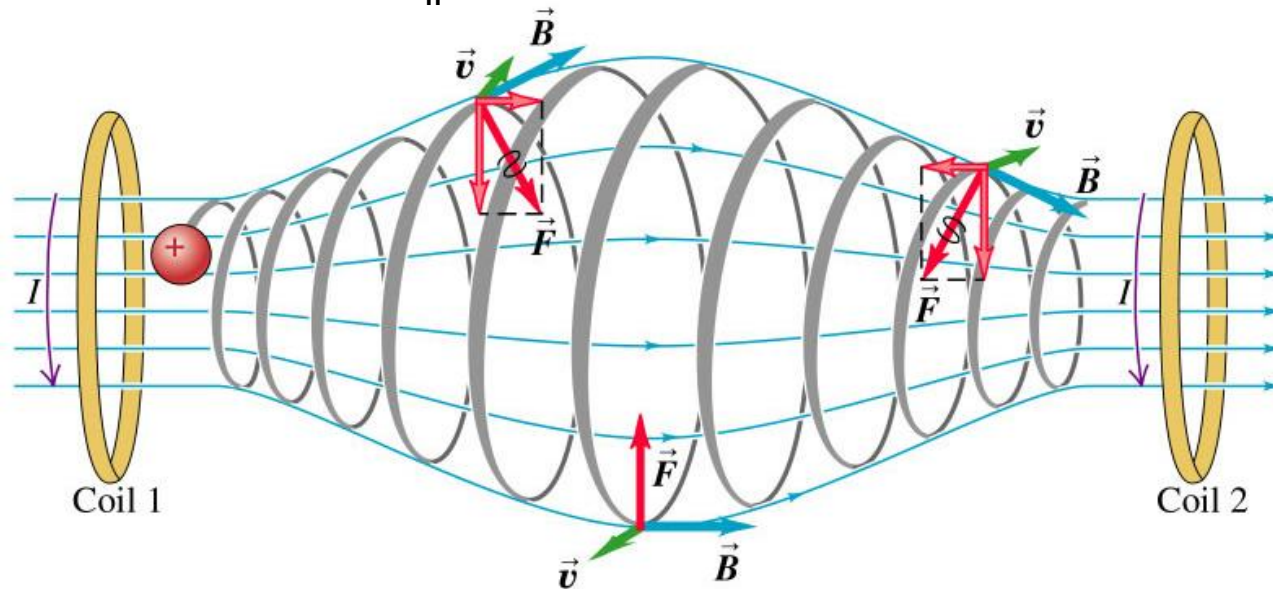
$$r_L = \frac{mv_{\perp}}{|q|B}$$



Charged particles can be partially confined by a magnetic mirror machine



- Charged particles with small v_{\parallel} eventually stop and are reflected while those with large v_{\parallel} escape.

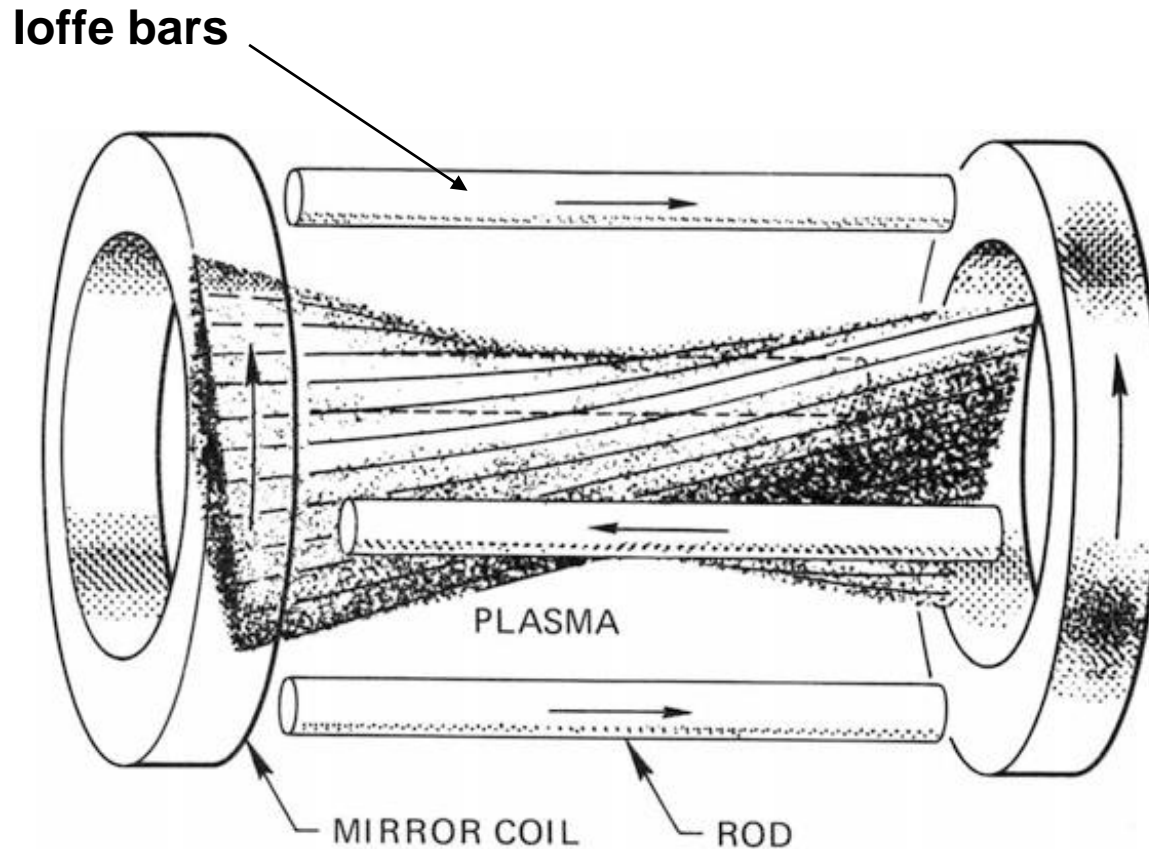


$$\frac{1}{2}mv^2 = \frac{1}{2}mv_{\parallel}^2 + \frac{1}{2}mv_{\perp}^2$$

- Large v_{\parallel} may occur from collisions between particles.

- Those confined charged particle are eventually lost due to collisions.

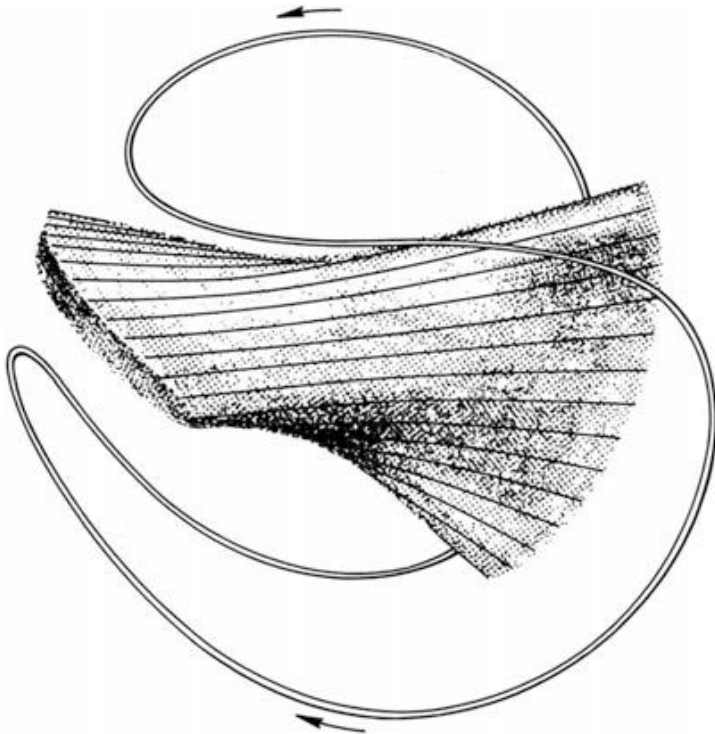
“Ioffe bars” are added to stabilize the Rayleigh-Taylor instabilities at the center of the mirror machine



A “baseball coil” is obtained if one links the coils and the bars into a single conductor



- Baseball coil



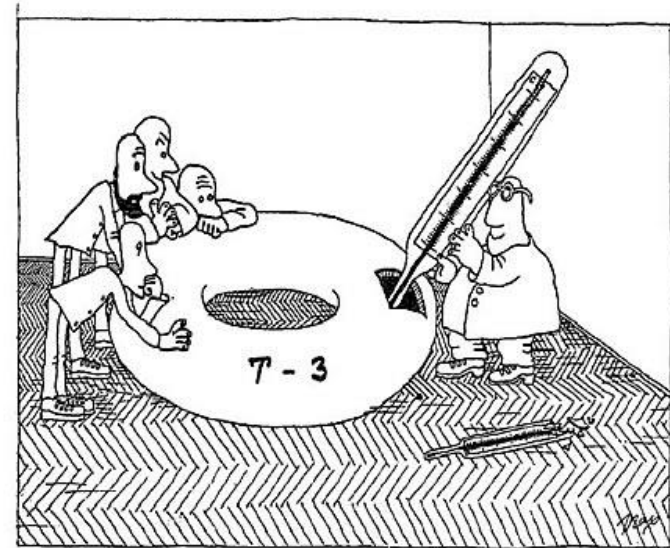
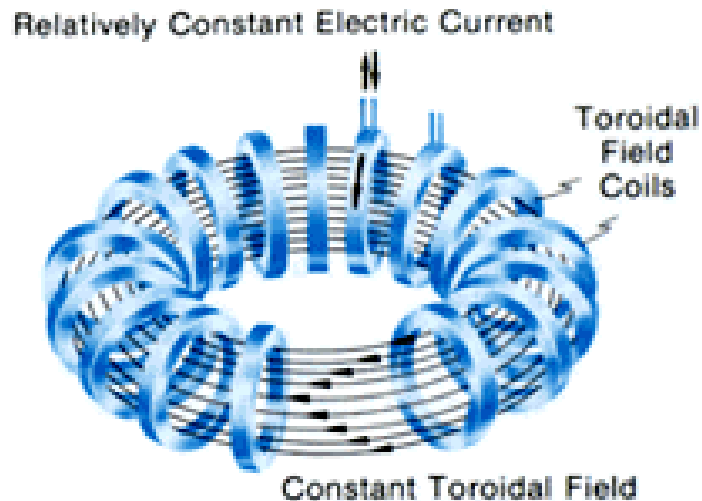
- MFTF-B mirror machine



Plasma can be confined in a doughnut-shaped chamber with toroidal magnetic field



- Tokamak - "toroidal chamber with magnetic coils" (тороидальная камера с магнитными катушками)



<https://www.iter.org/mach/tokamak>

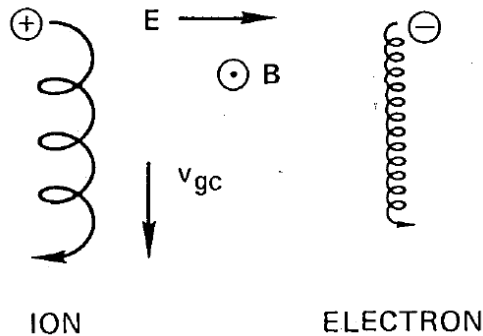
https://en.wikipedia.org/wiki/Tokamak#cite_ref-4

Drawing from the talk "Evolution of the Tokamak" given in 1988 by B.B. Kadomtsev at Culham.

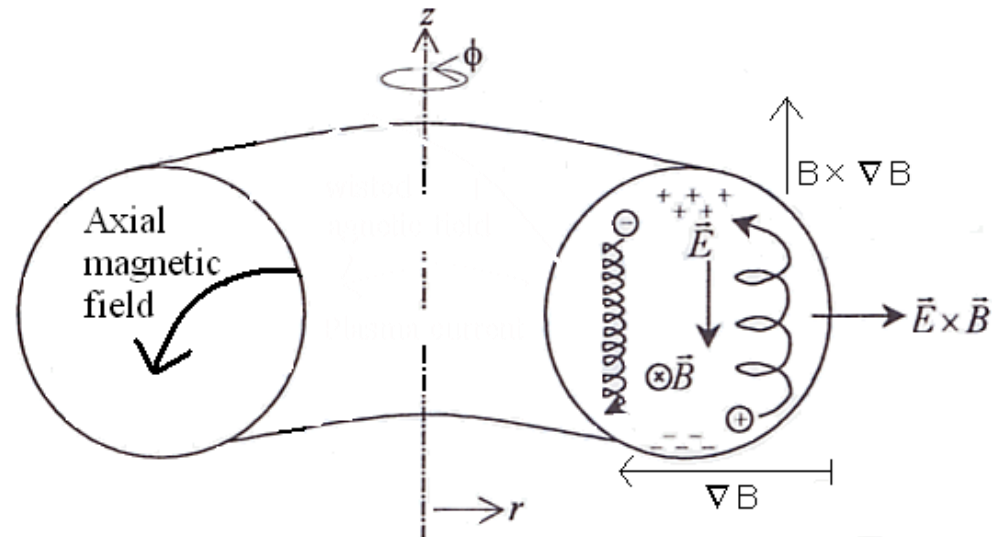
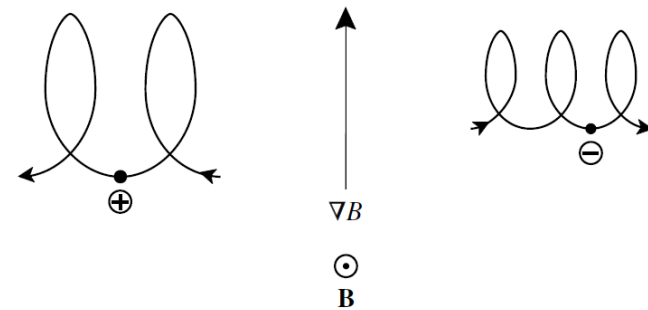
Charged particles drift across field lines



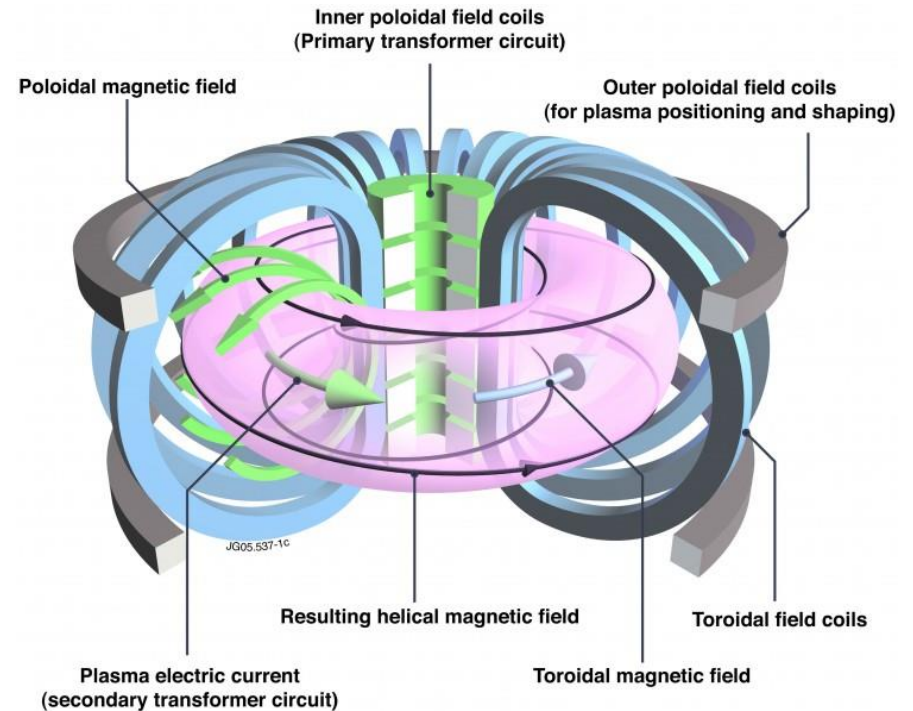
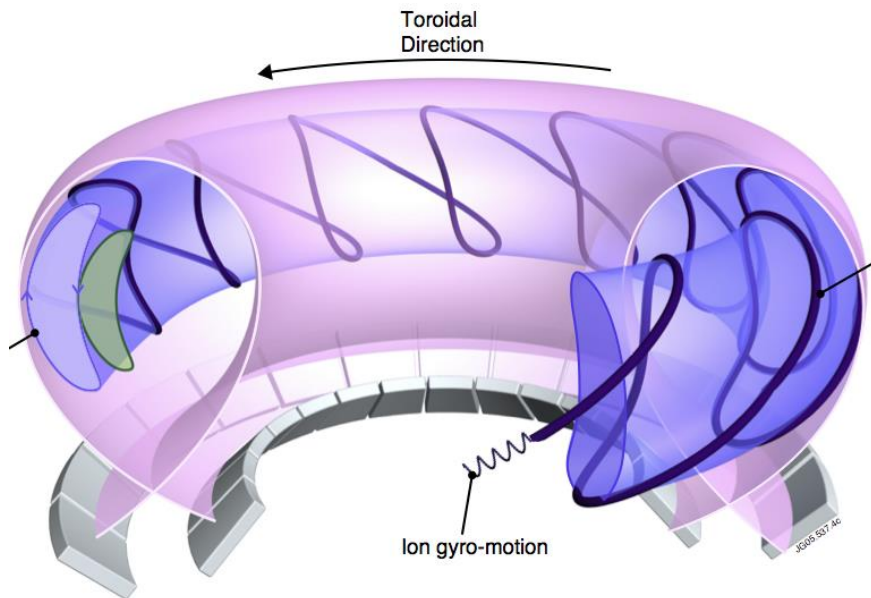
- **ExB drift**



- **Grad-B drift**



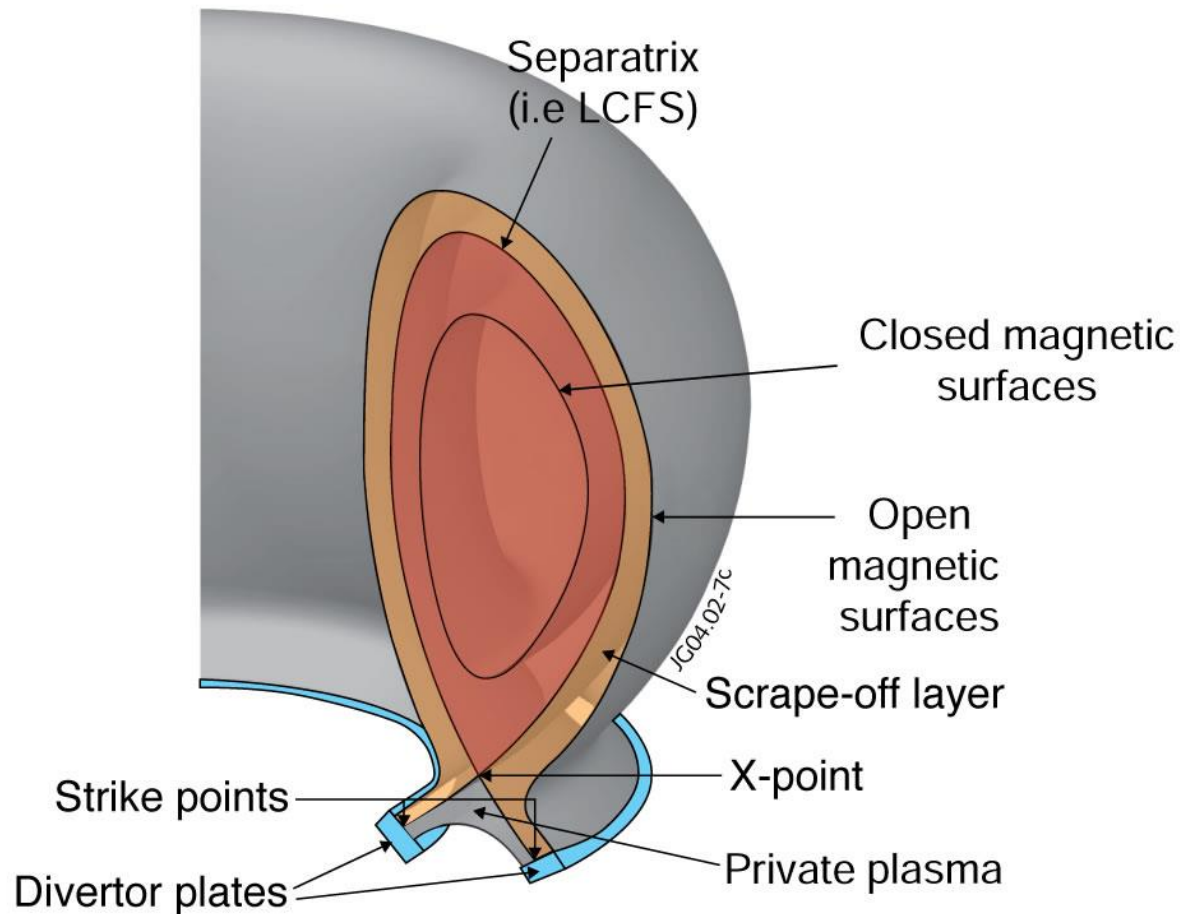
A poloidal magnetic field is required to reduce the drift across field lines



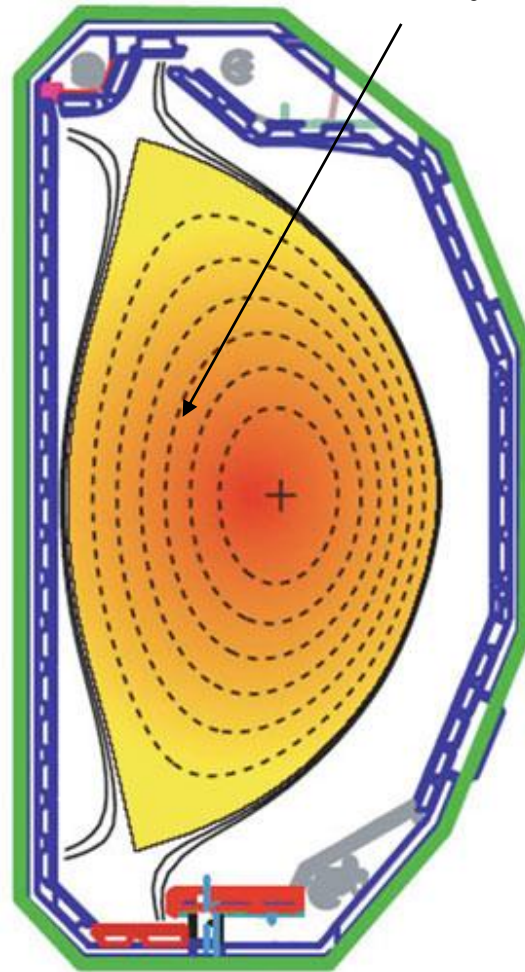
A poloidal magnetic field is required to reduce the drift across field lines



A divertor is needed to remove impurities and the power that escapes from the plasma



D-shaped tokamak with diverter is more preferred nowadays

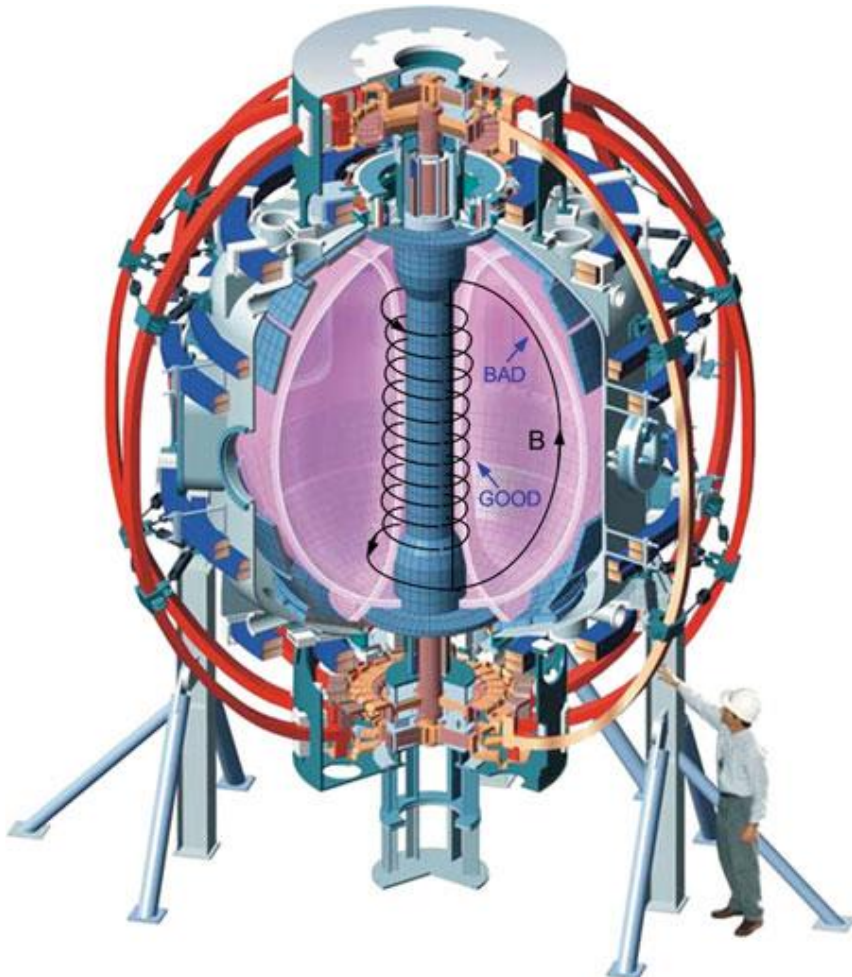


- Make the plasma closer to the major axis

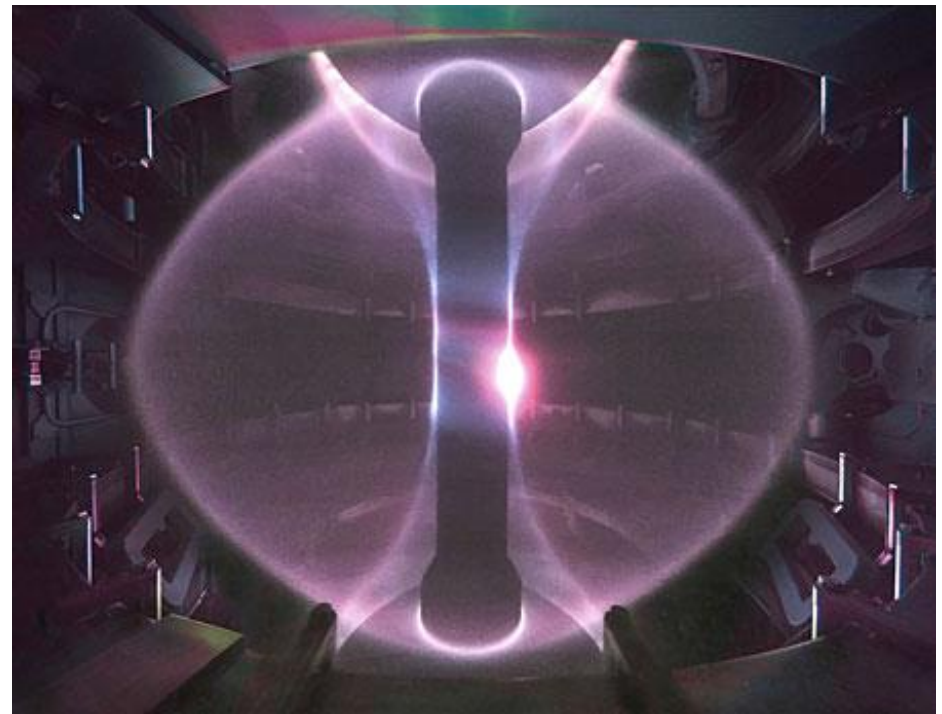
Spherical tokamak is formed when the aspect ratio of a tokamak is reduced to the order of unity



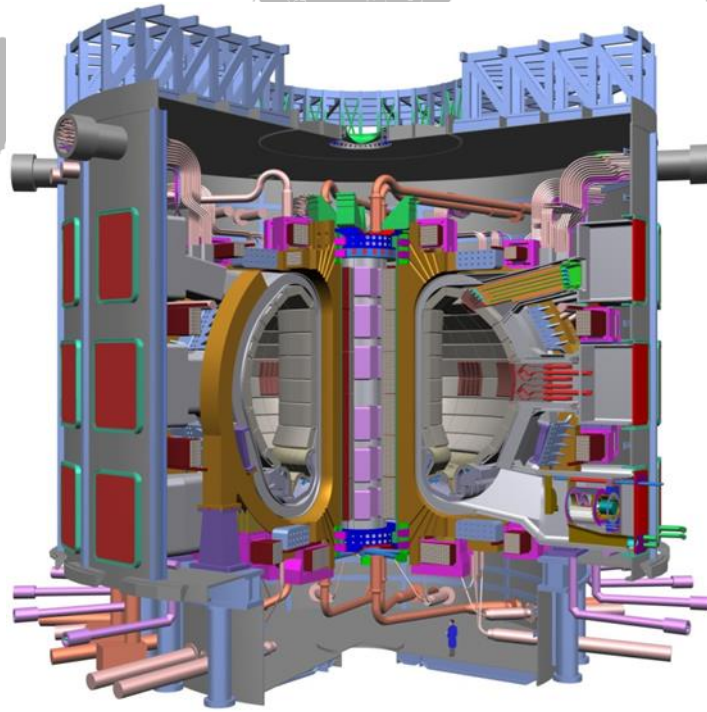
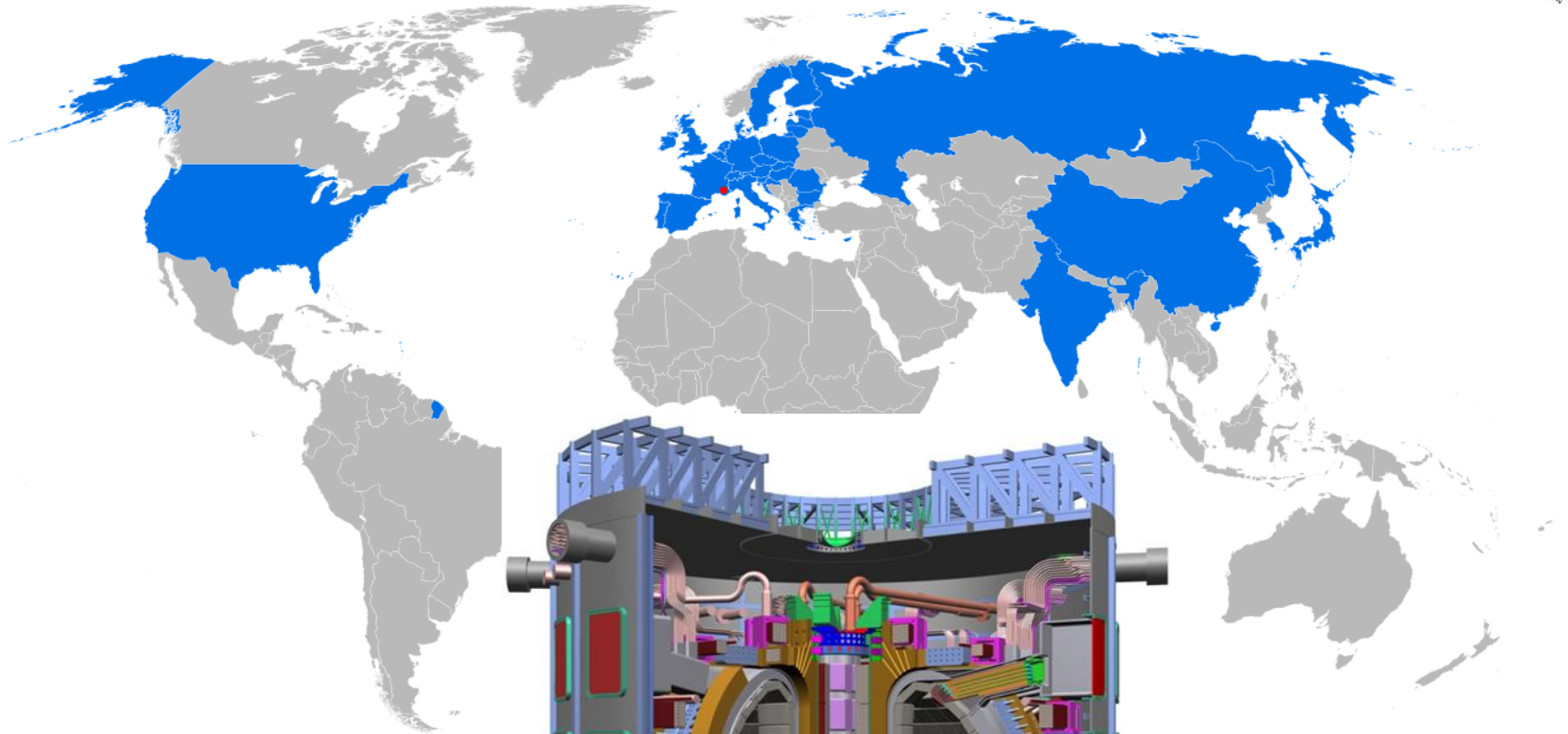
- NSTX @ Princeton



- MegaAmpere Spherical Tokamak (MAST) @ Culham center for fusion energy, UK



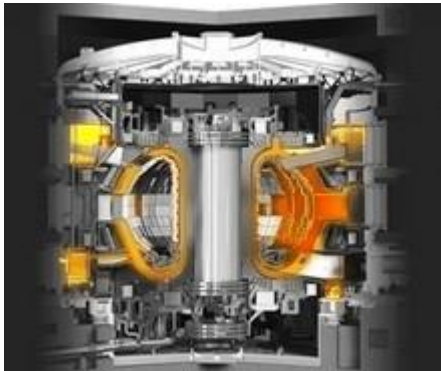
ITER ("The Way" in Latin) is one of the most ambitious energy projects in the world today



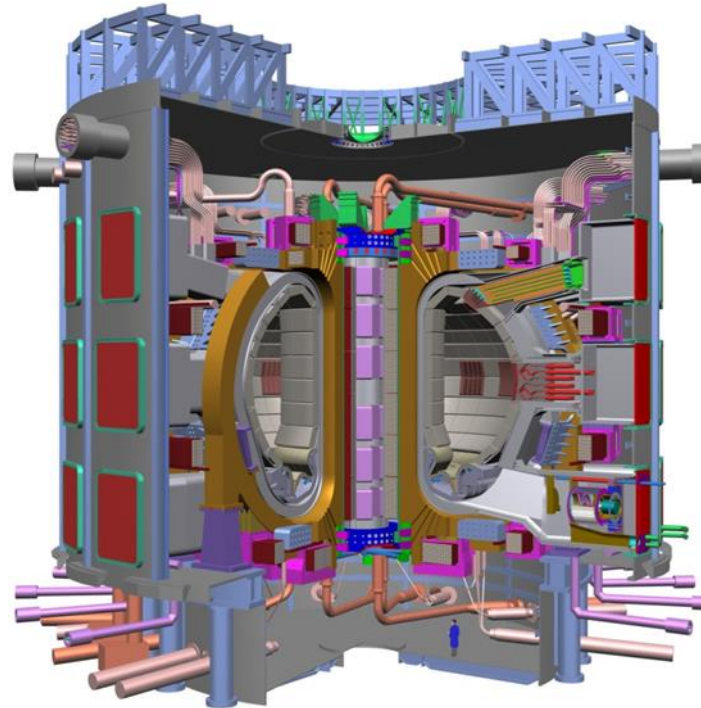
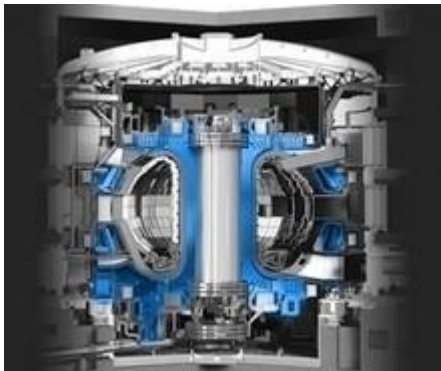
ITER ("The Way" in Latin) is one of the most ambitious energy projects in the world today



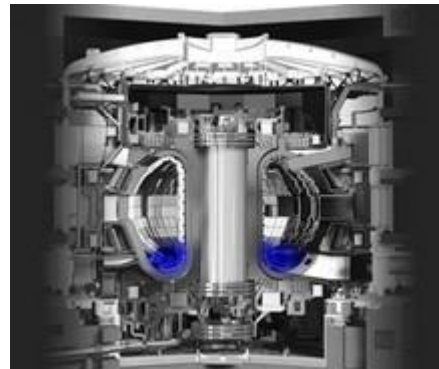
- Vacuum vessel



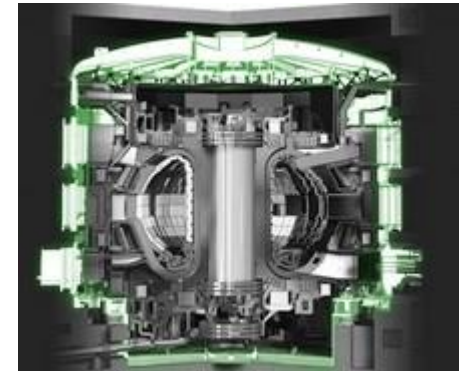
- Magnets



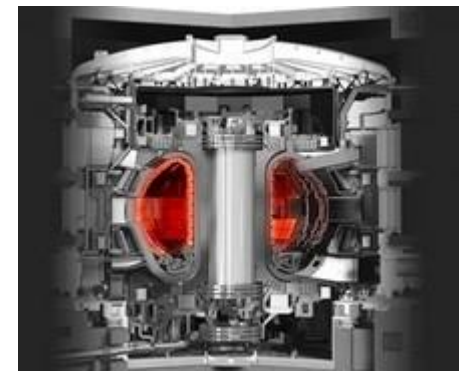
- Divertor



- Cryostat



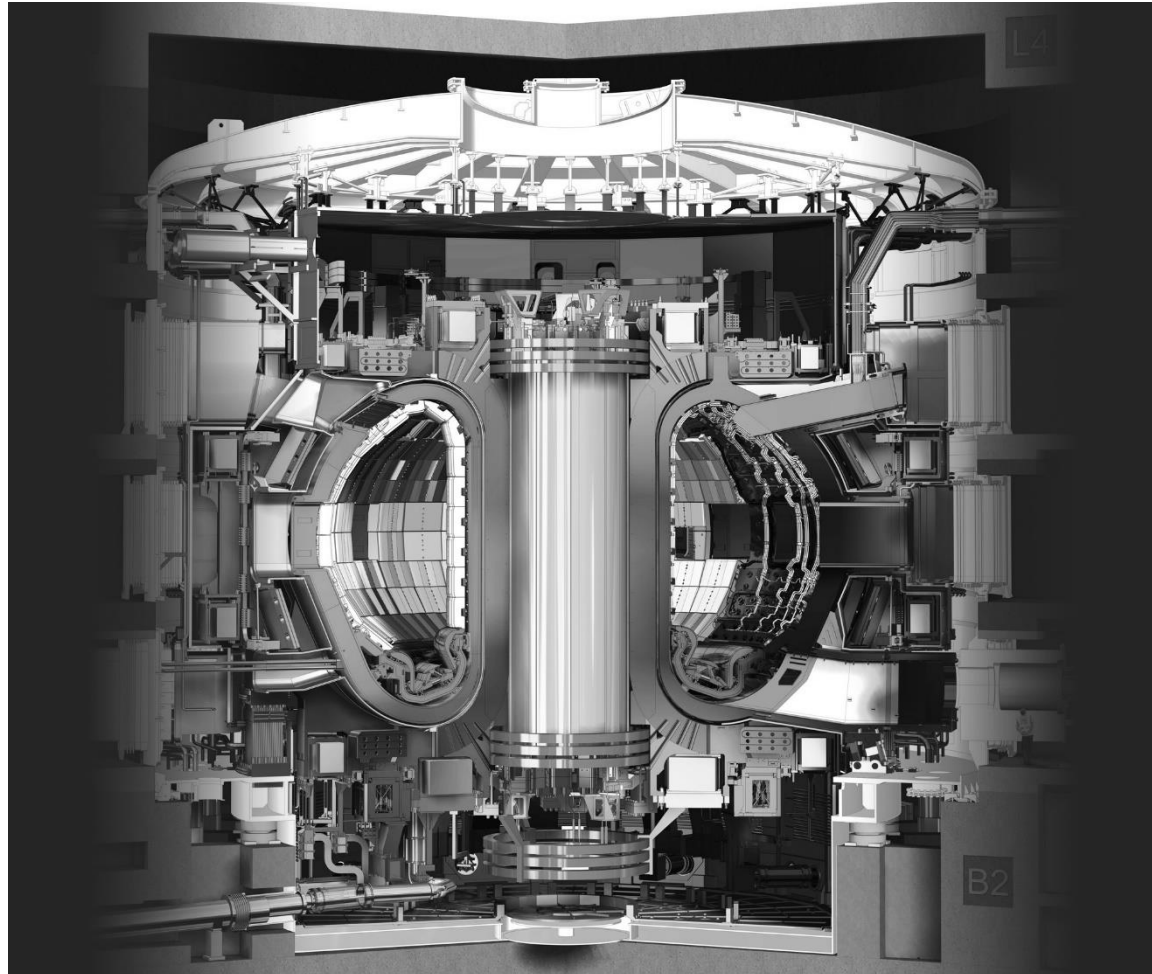
- Blanket



ITER



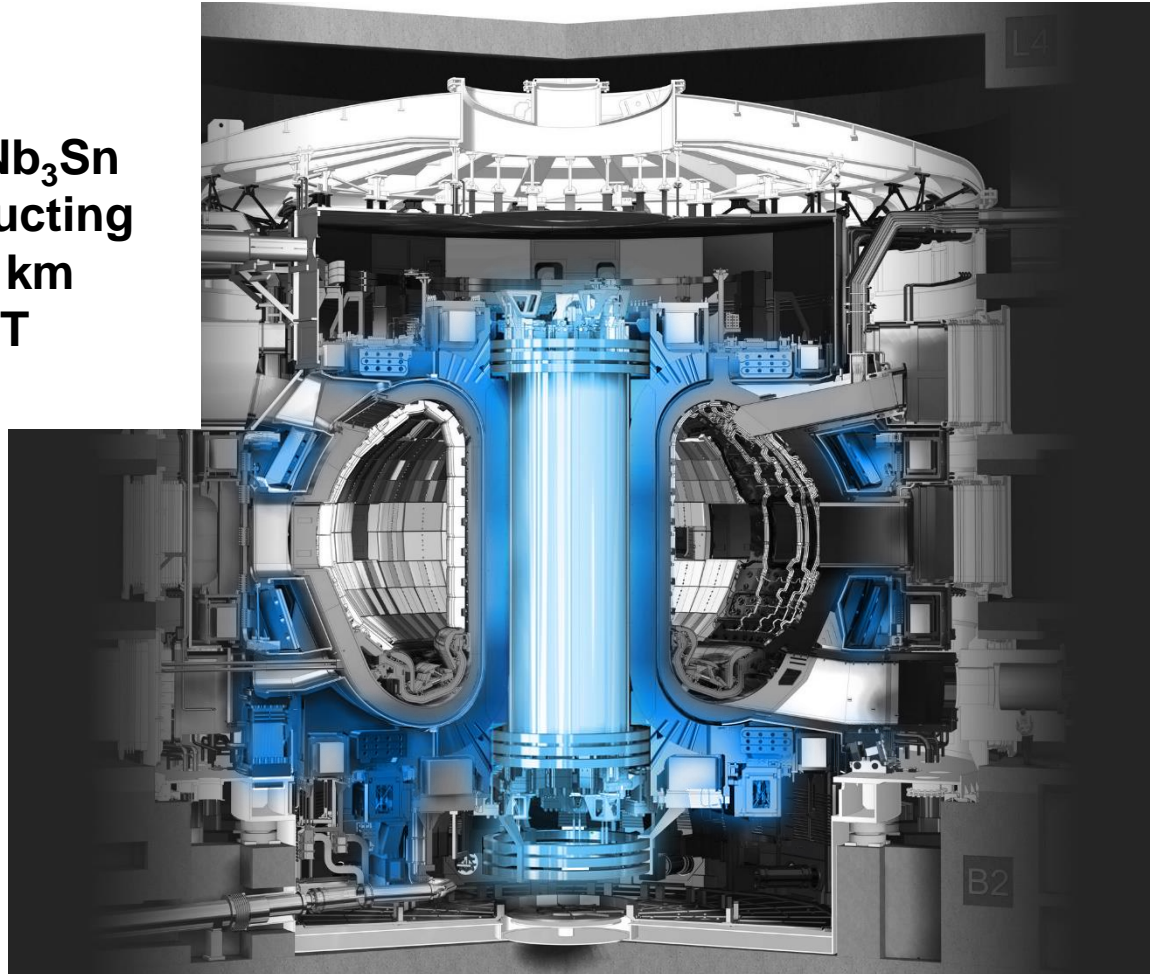
- $T=150\text{M } ^\circ\text{C}$
- $P=500\text{ MW}$



ITER – Magnets



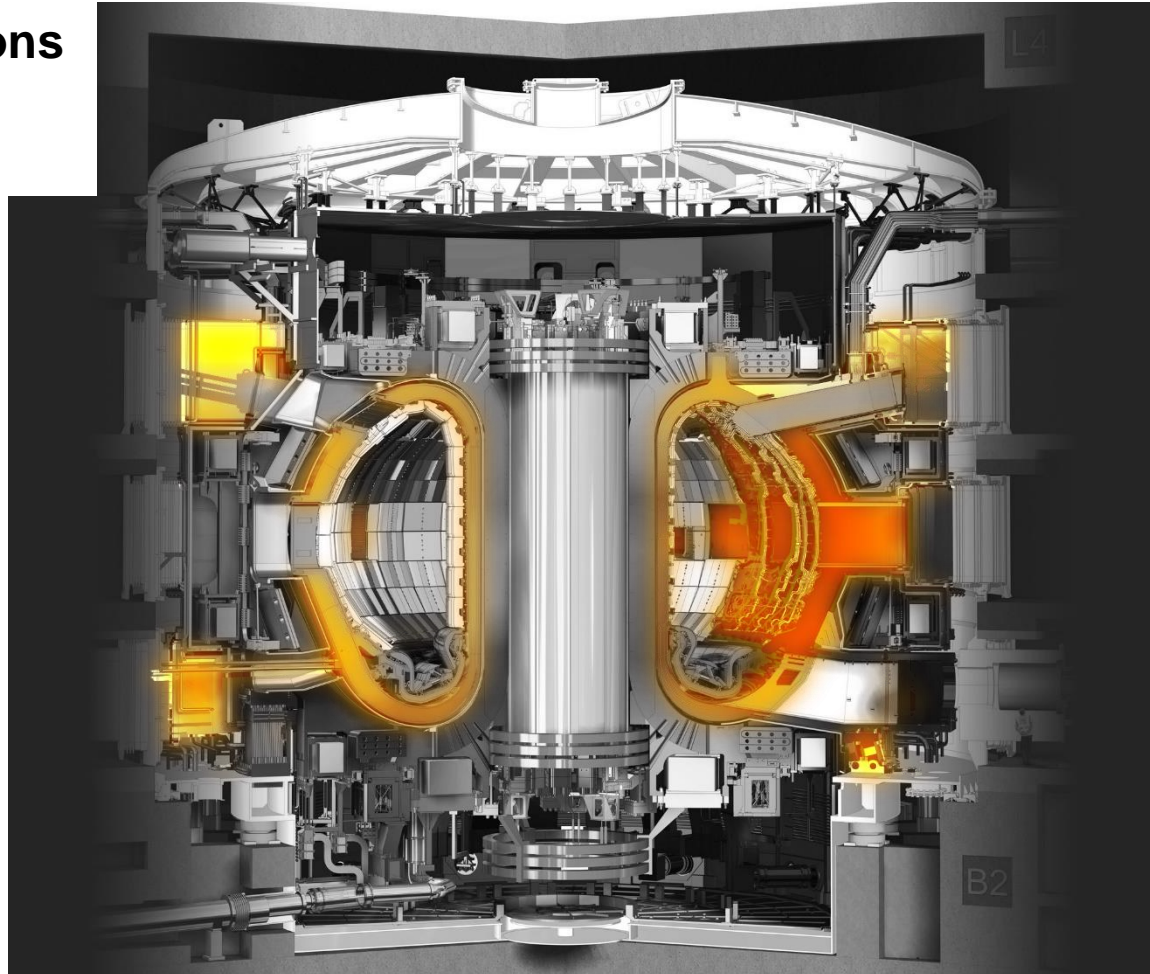
- $E_B=51$ GJ
- $T_B=4$ K
- Length of Nb_3Sn superconducting strand: 10^5 km
- $B_{T,max}=11.8$ T
- $B_{P,max}=6$ T



ITER – Vacuum vessel



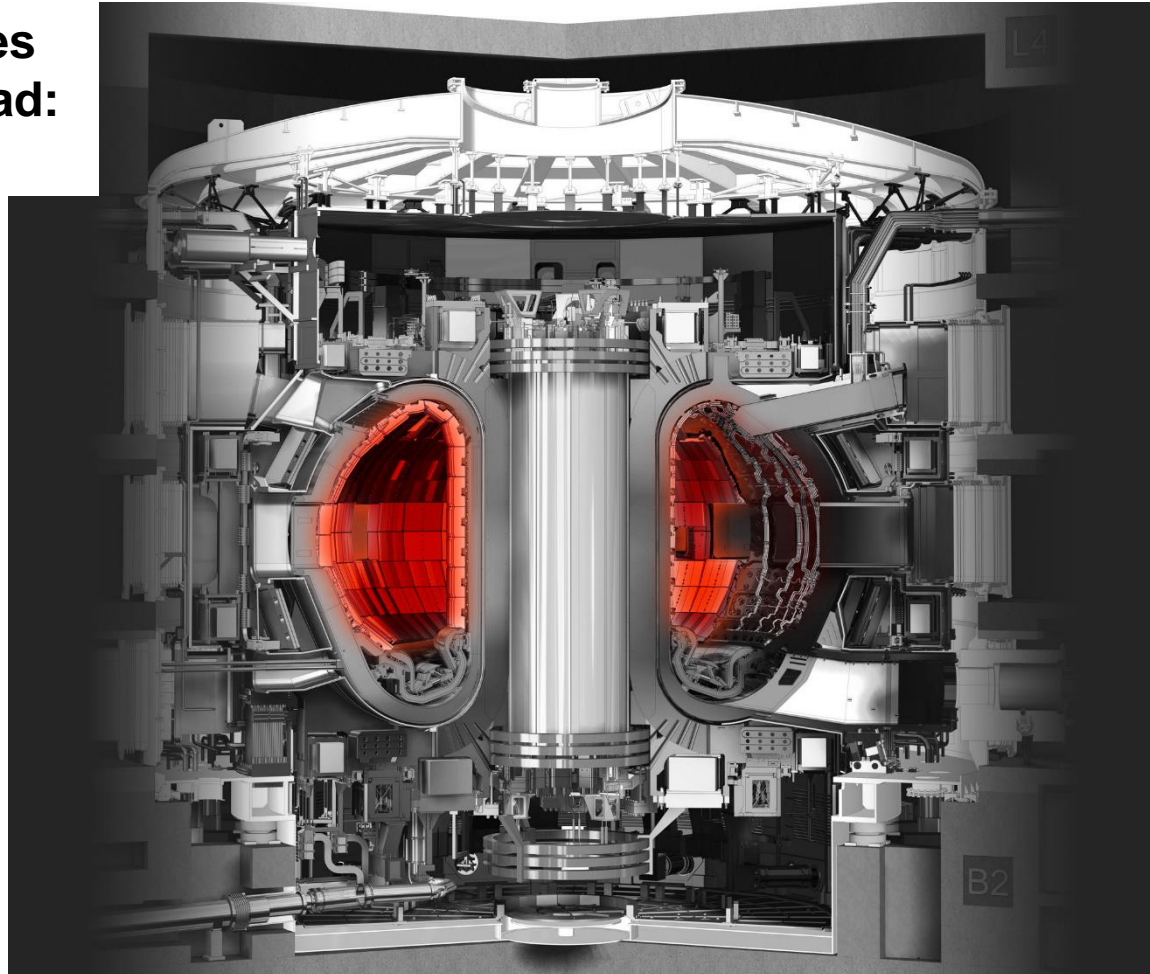
- $W = 8000$ tons
- $V = 840$ m³
- $R = 6$ m



ITER – Blanket



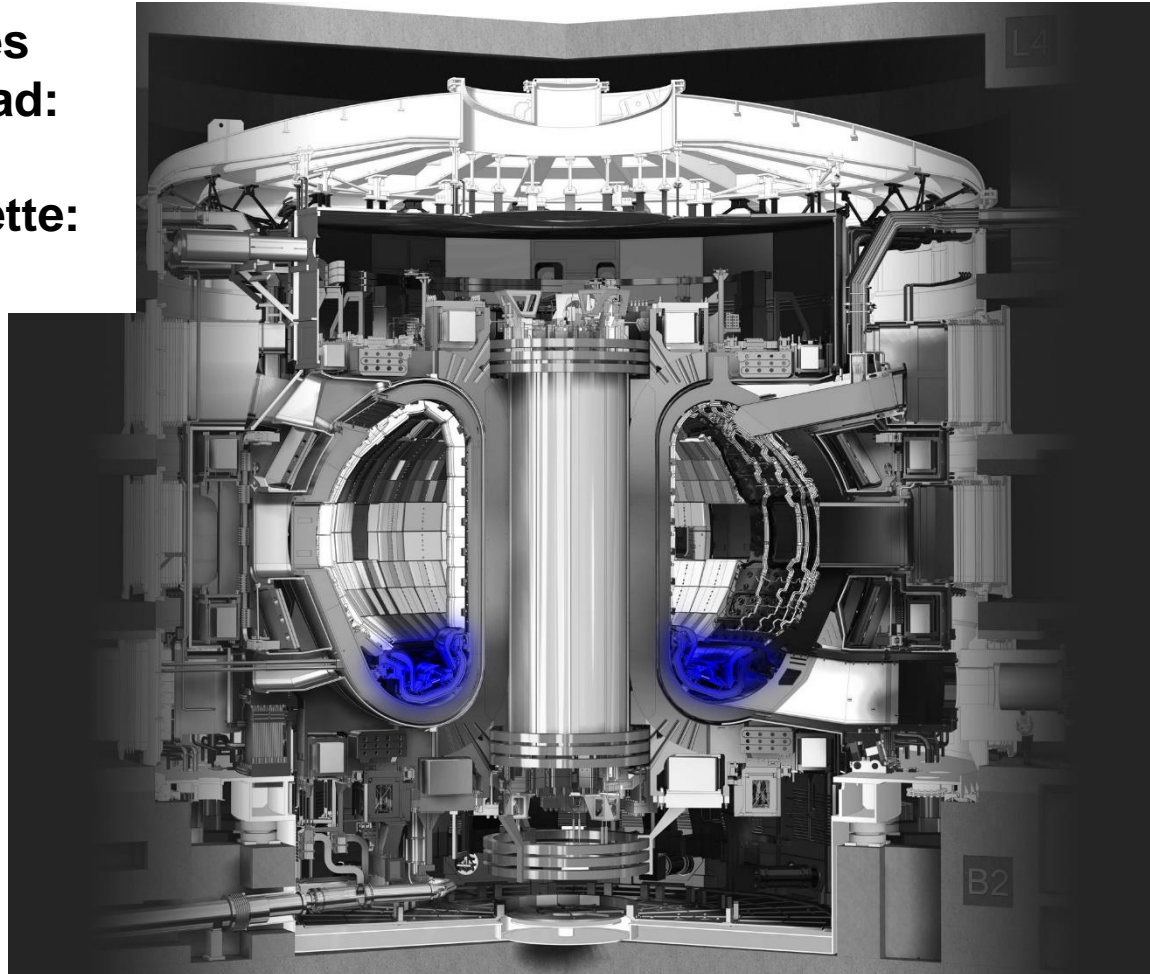
- 440 modules
- Thermal load:
736 MW



ITER – Divertor



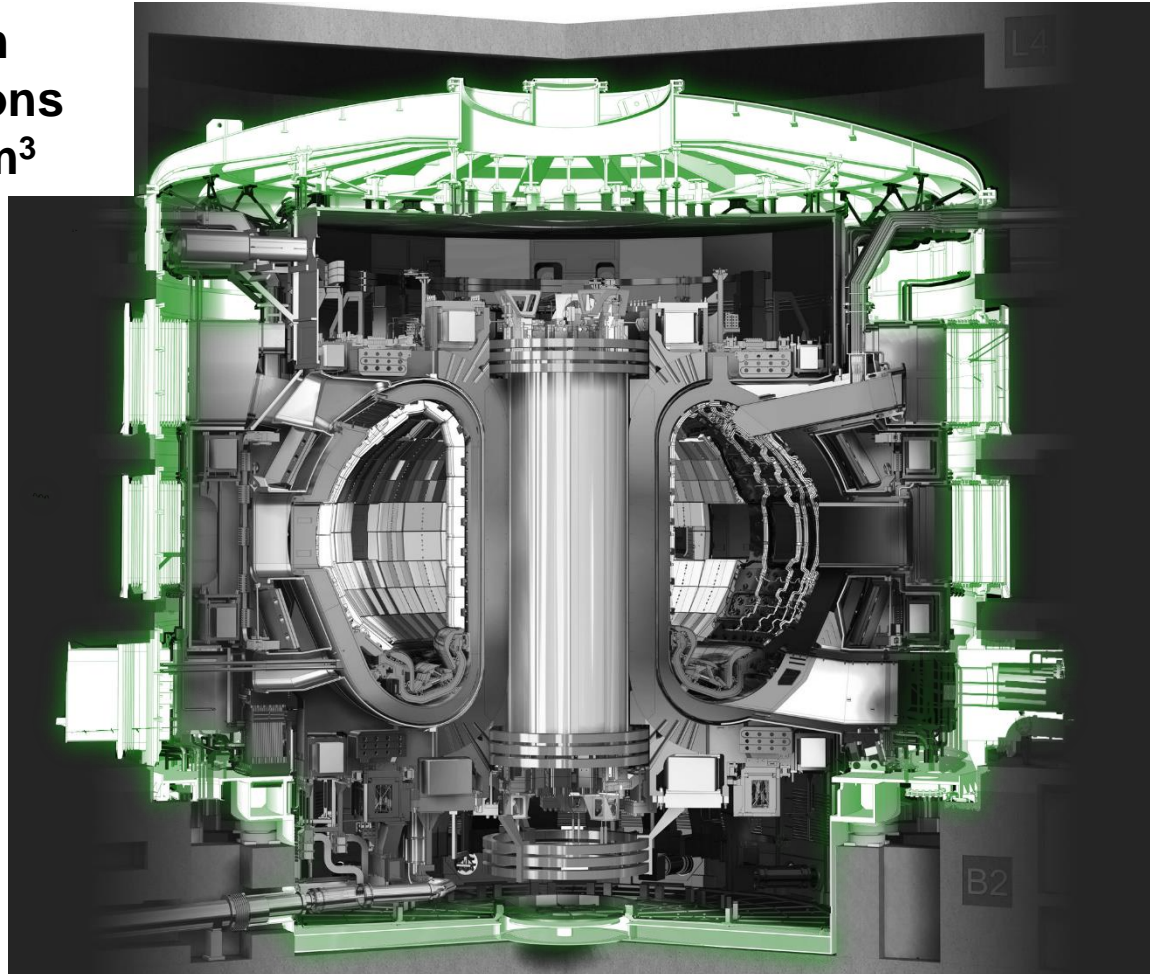
- **54 cassettes**
- **Thermal load:
20 MW/m²**
- **Each cassette:
10 tons**



ITER – Crystat



- $P = 10^{-6}$ atm
- $W = 3800$ tons
- $V = 16000$ m³

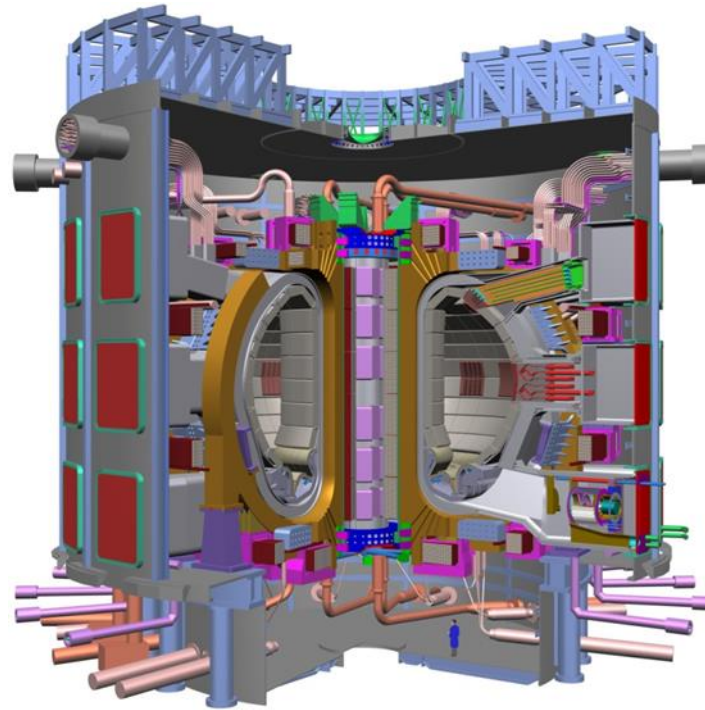


Supporting systems



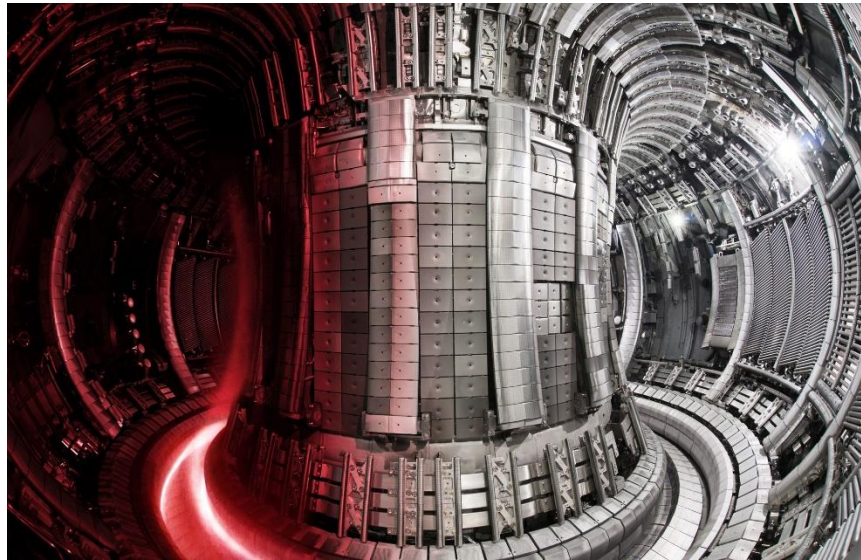
- **Tritium breeding**
- **Control, Data access and Communication (CODAC)**
- **Cooling water**
- **Cryogenics**
- **Diagnostics**
- **Fuel cycle**
- **Hot cell - a secure environment for processing, repair or testing, etc., of components that have become activated by neutrons.**
- **Power supply**
- **Remote handling**
- **Heating and current drive**
- **Vacuum system**

There is a long way to go, but we are on the right path...



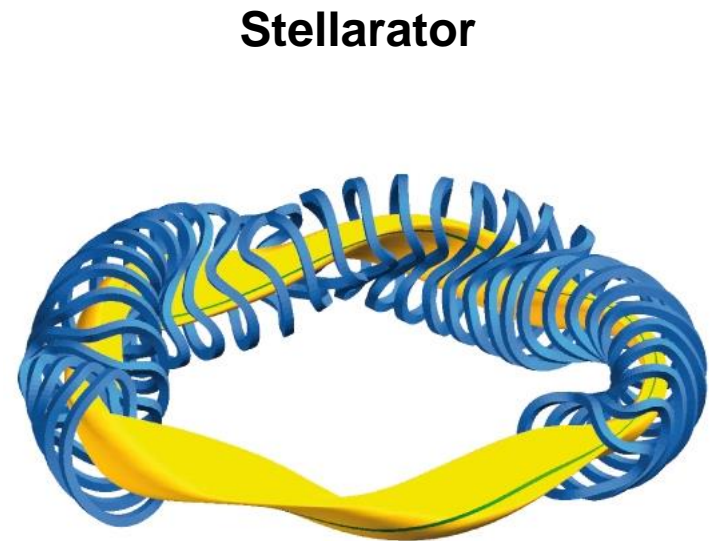
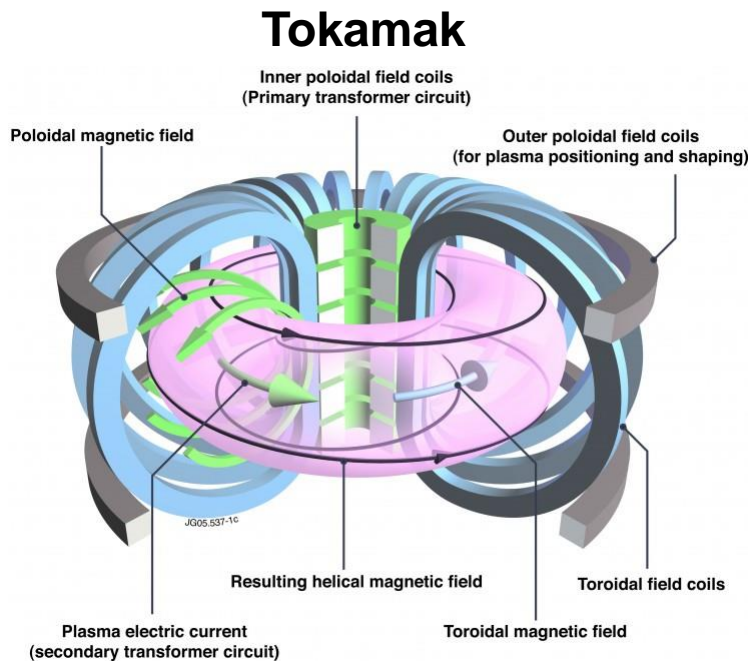
- **Dec 2025** **First Plasma**
- **2035** **Deuterium-Tritium Operation begins**

Joint European Torus (JET) facility has a record-breaking 59 megajoules of sustained fusion energy

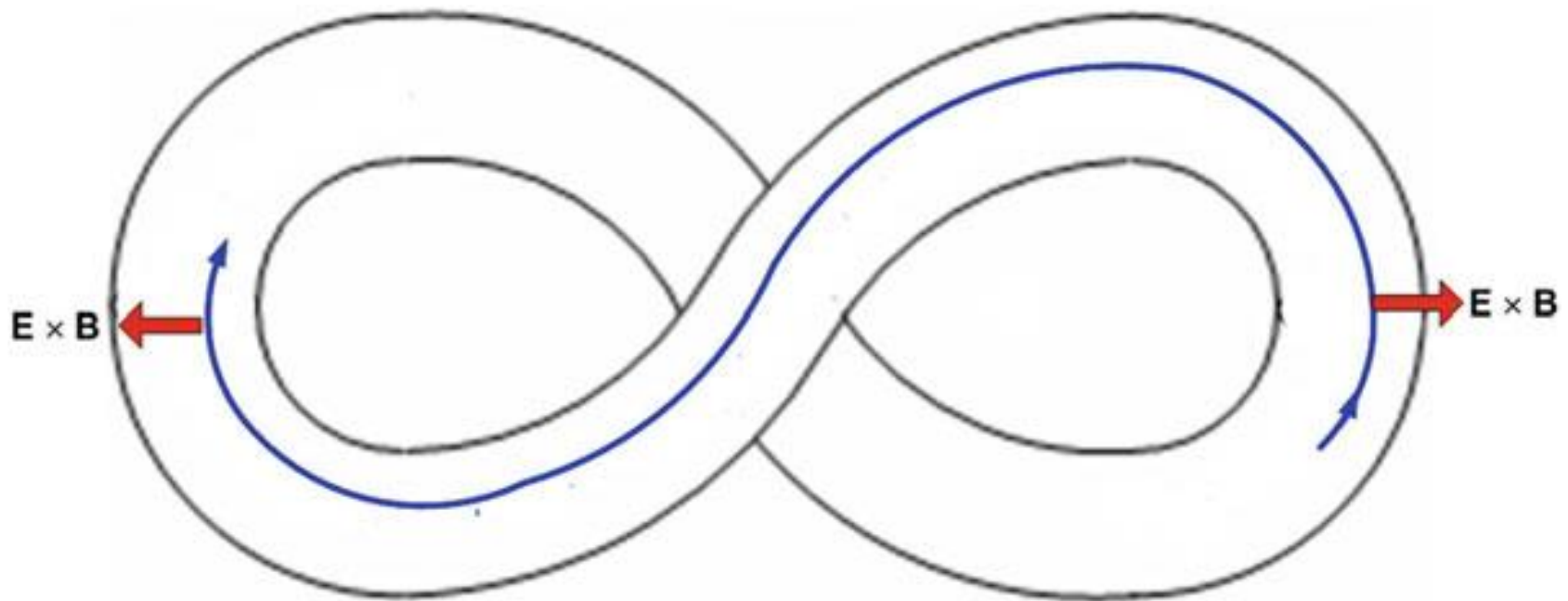


- **Record-breaking 59 megajoules of sustained fusion energy in Joint European Torus (JET) facility in Oxford demonstrates powerplant potential and strengthens case for ITER.**

Stellarator uses twisted coil to generate poloidal magnetic field



A figure-8 stellarator solved the drift issues



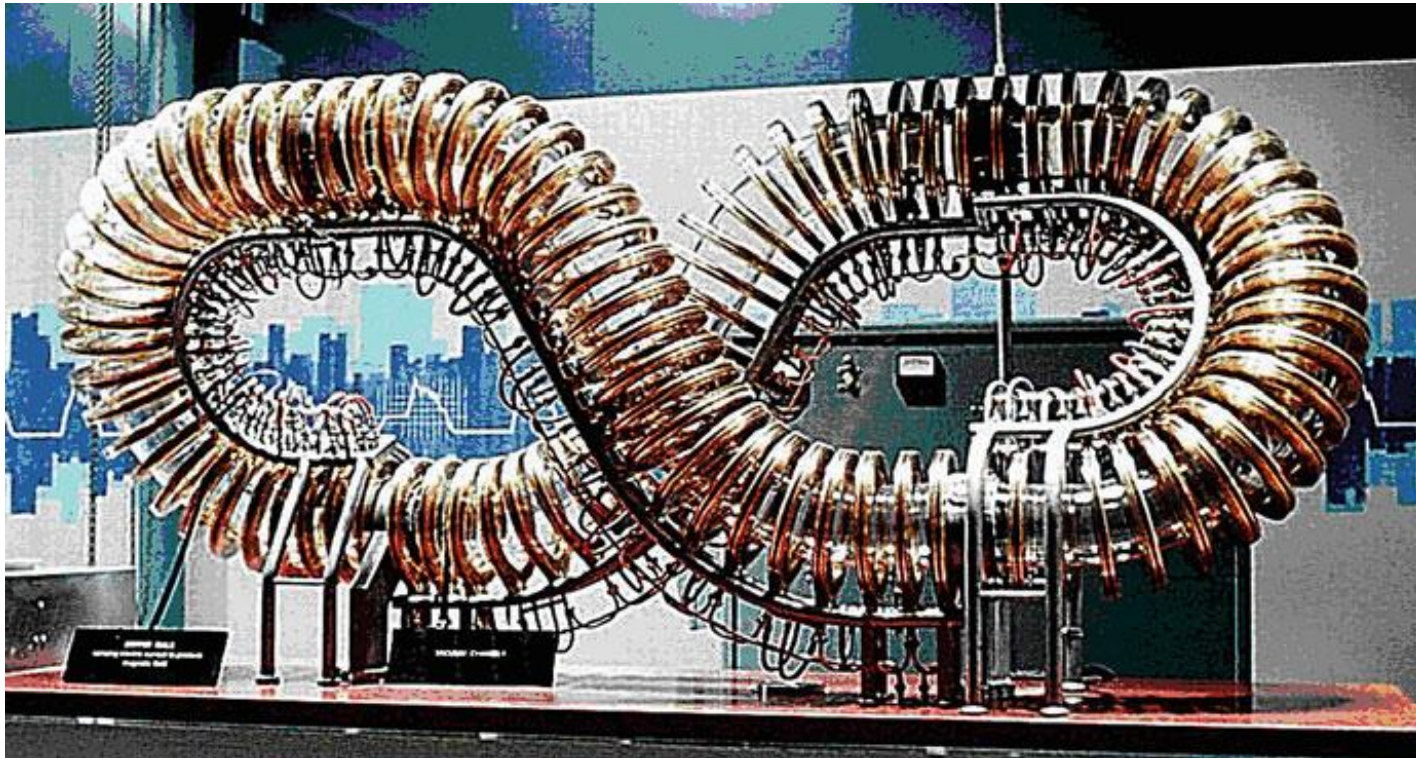
A figure-8 stellarator solved the drift issues



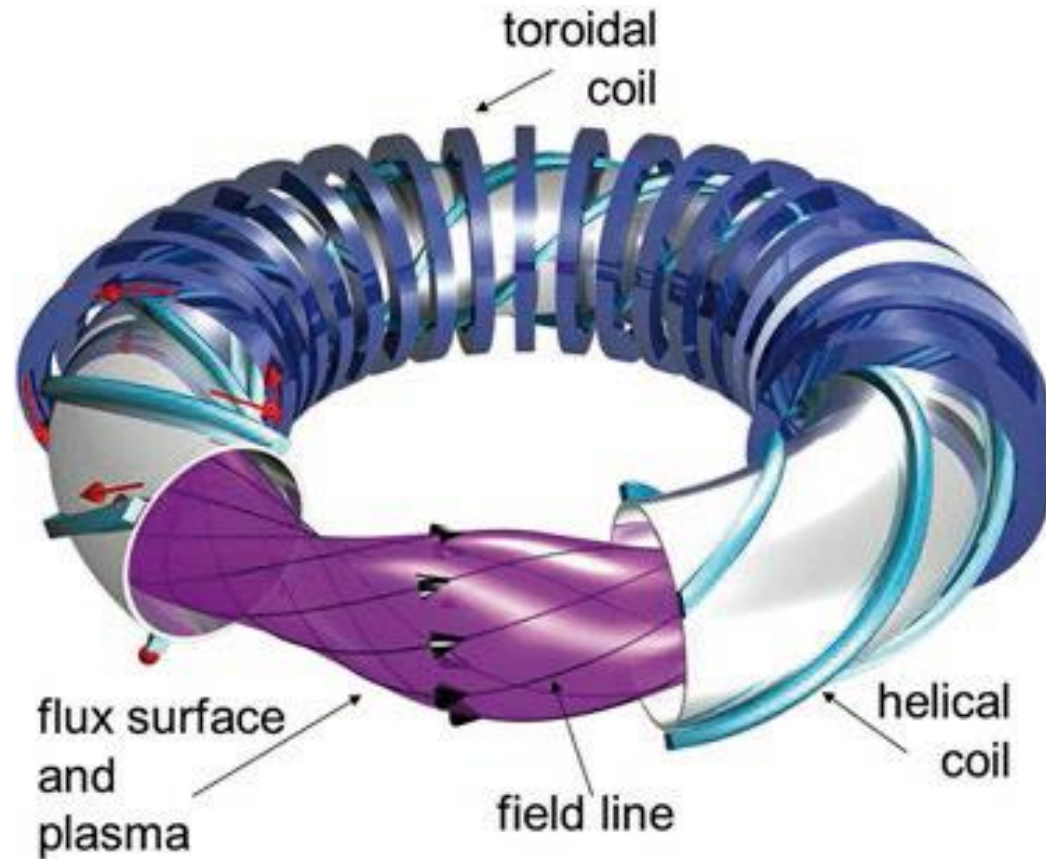
Lyman Spitzer, Jr. came out the idea during a long ride on a ski lift at Garmisch-Partenkirchen



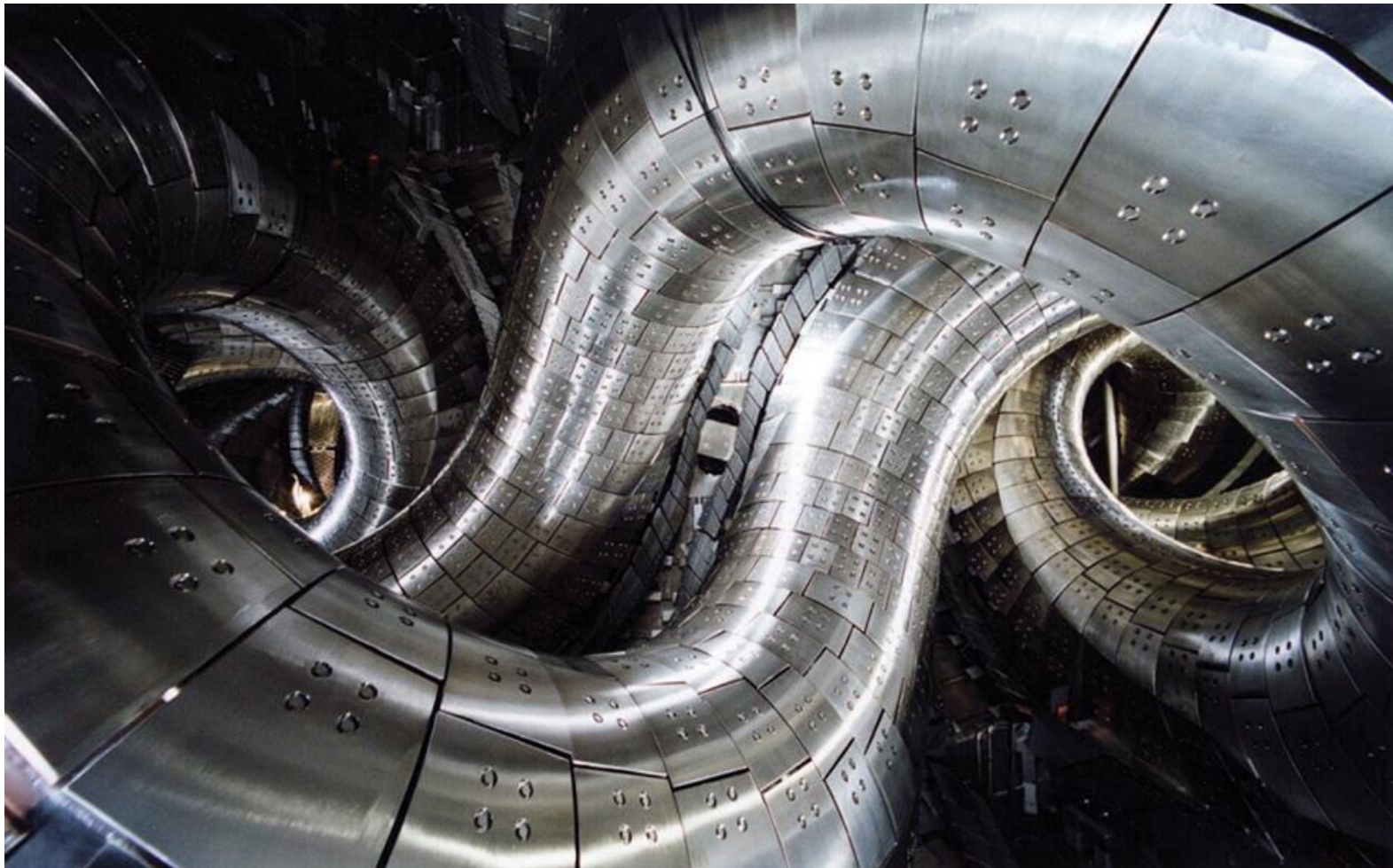
Exhibit model of a figure-8 stellarator for the Atoms for Peace conference in Geneva in 1958



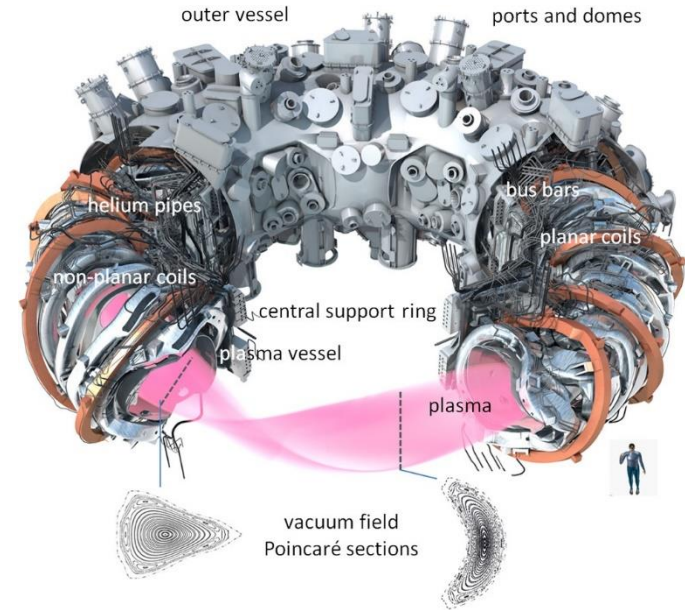
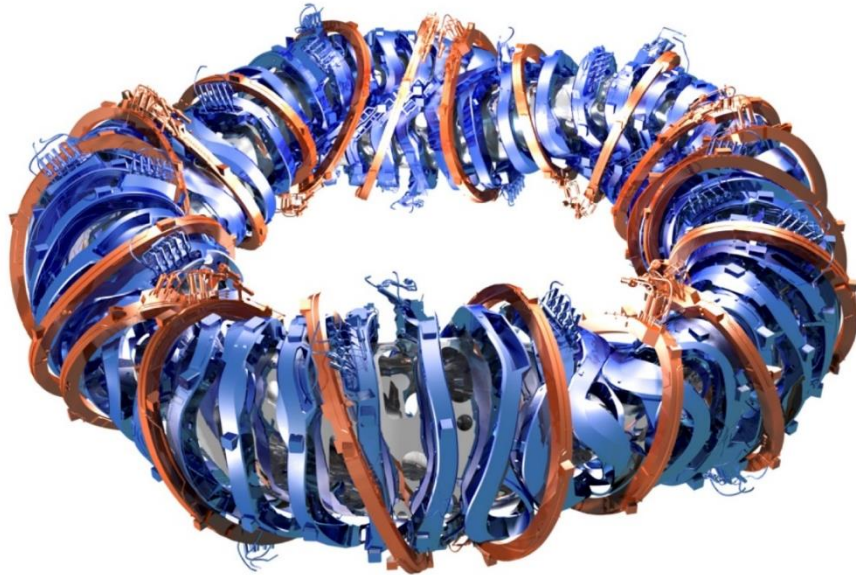
Twisted magnetic field lines can be provided by toroidal coils with helical coils



LHD stellarator in Japan



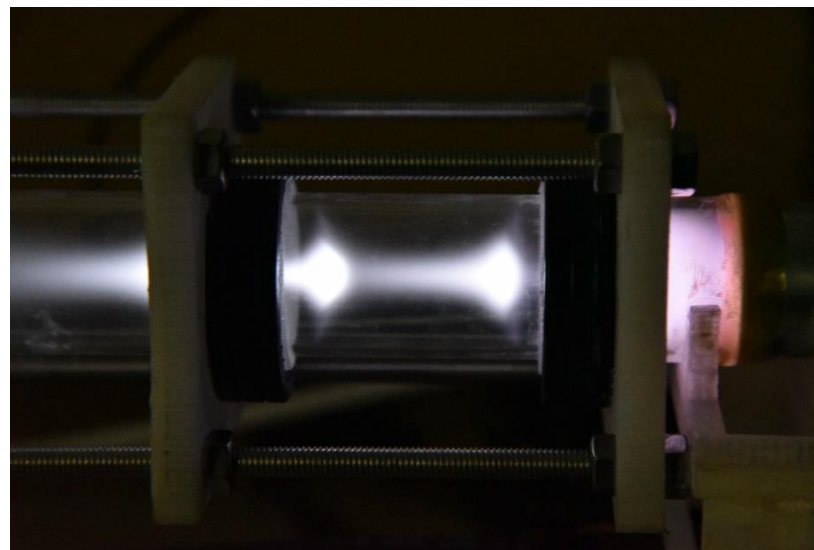
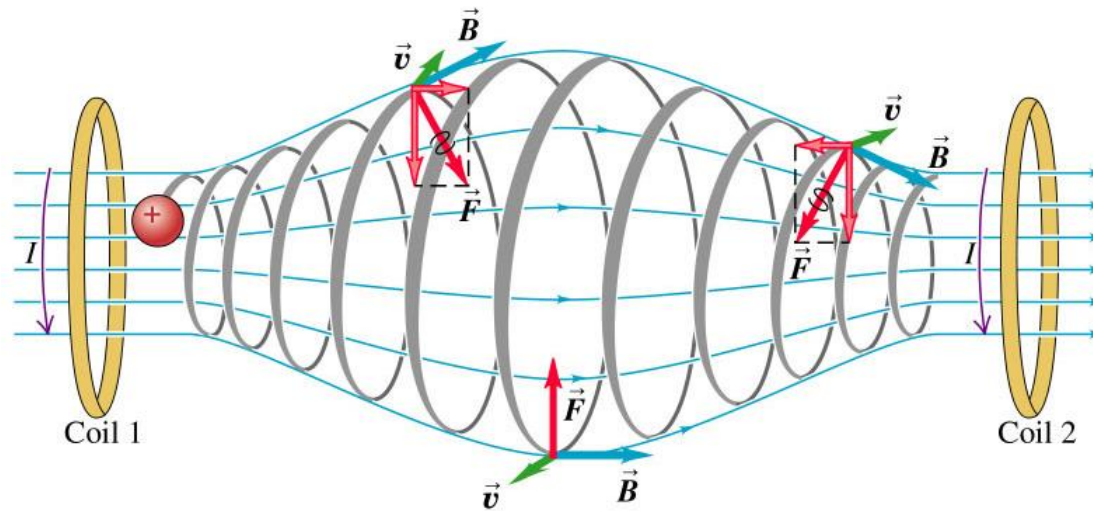
Wendelstein 7-X is a stellarator built by Max Planck Institute for Plasma Physics (IPP)



- **Wendelstein 7-x is now installing new diverters.**



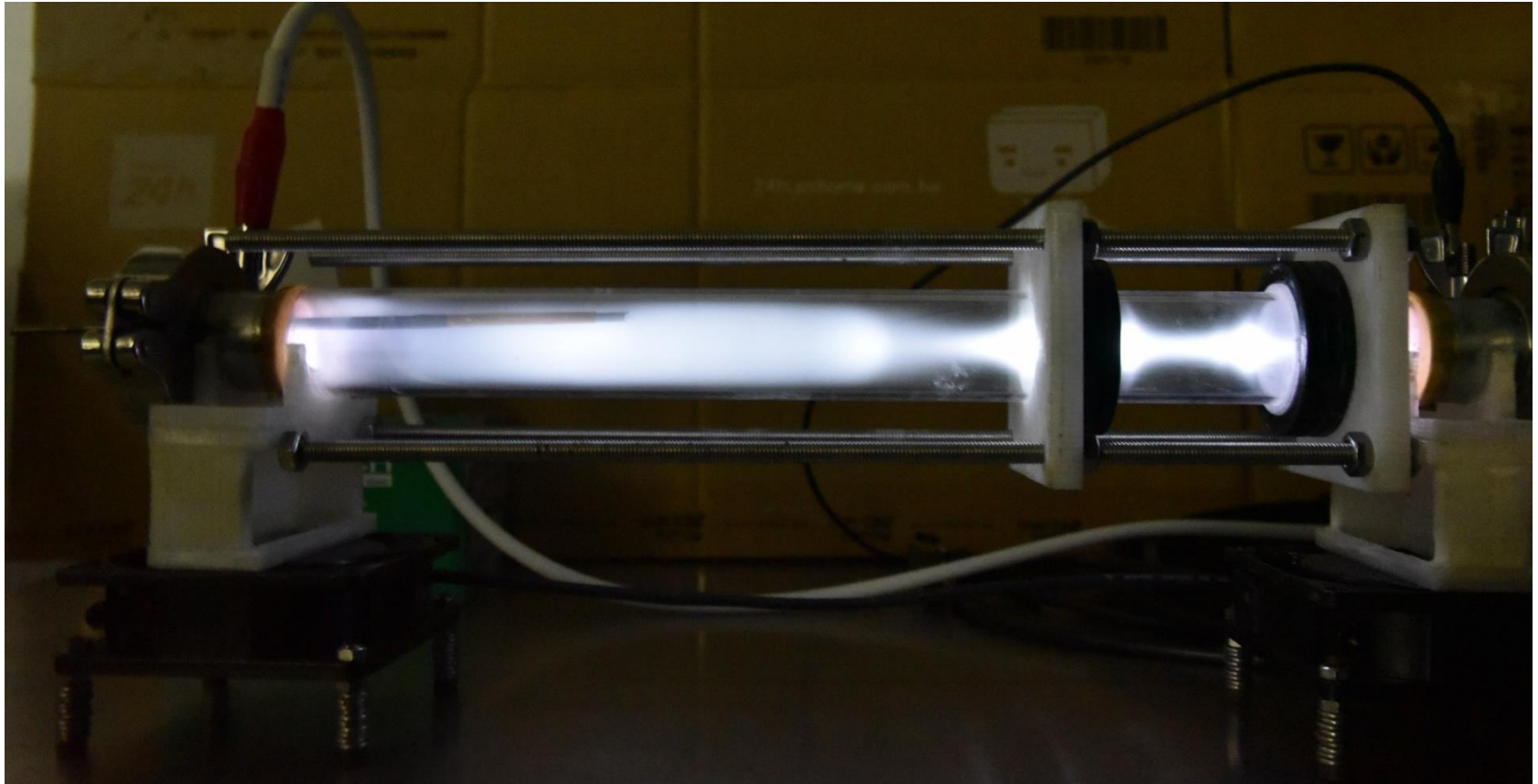
Demonstration of a magnetic mirror machine



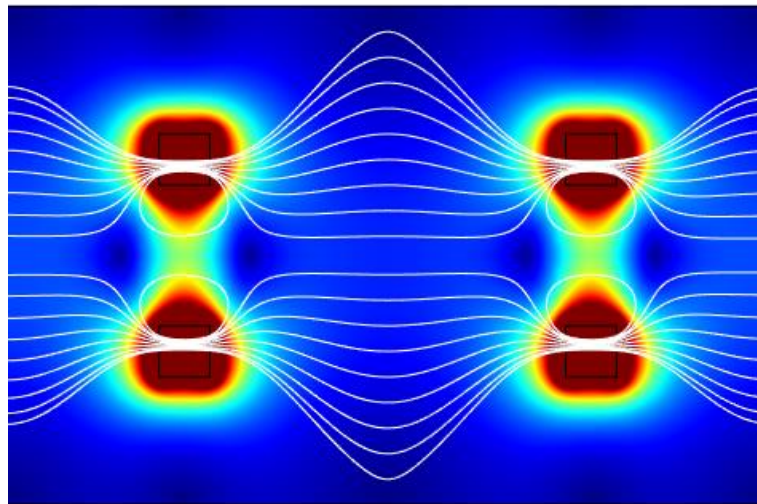
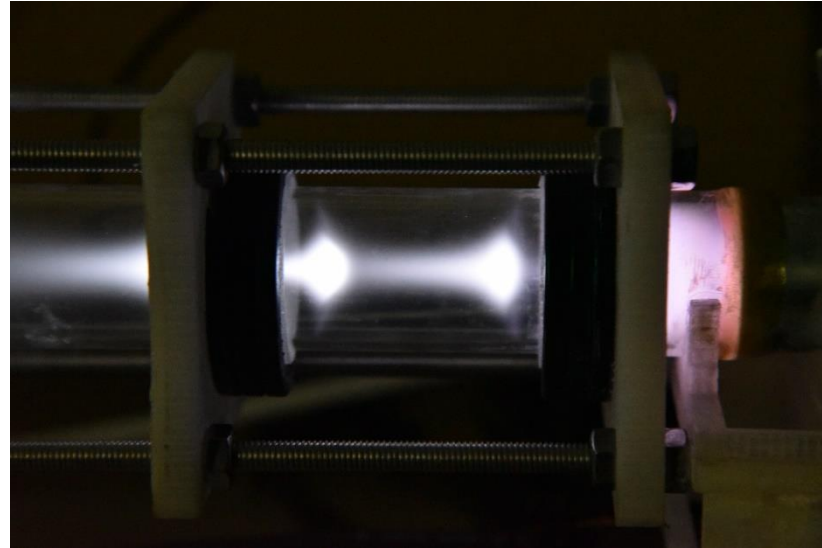
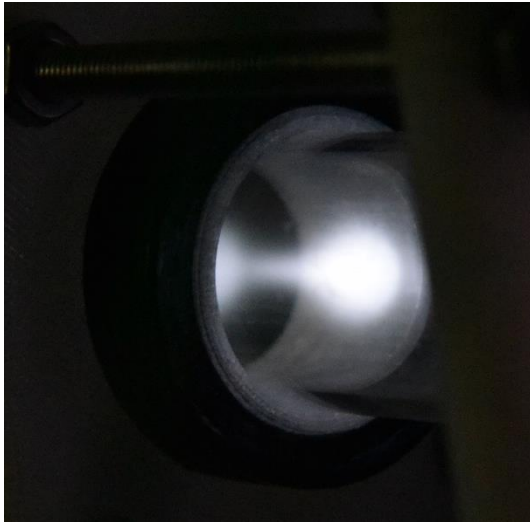
Show video.

<https://i.stack.imgur.com/GIzGZ.jpg>

Plasma is partially confined by the magnetic field



Many mirror points are provided by a pair of ring-type magnets

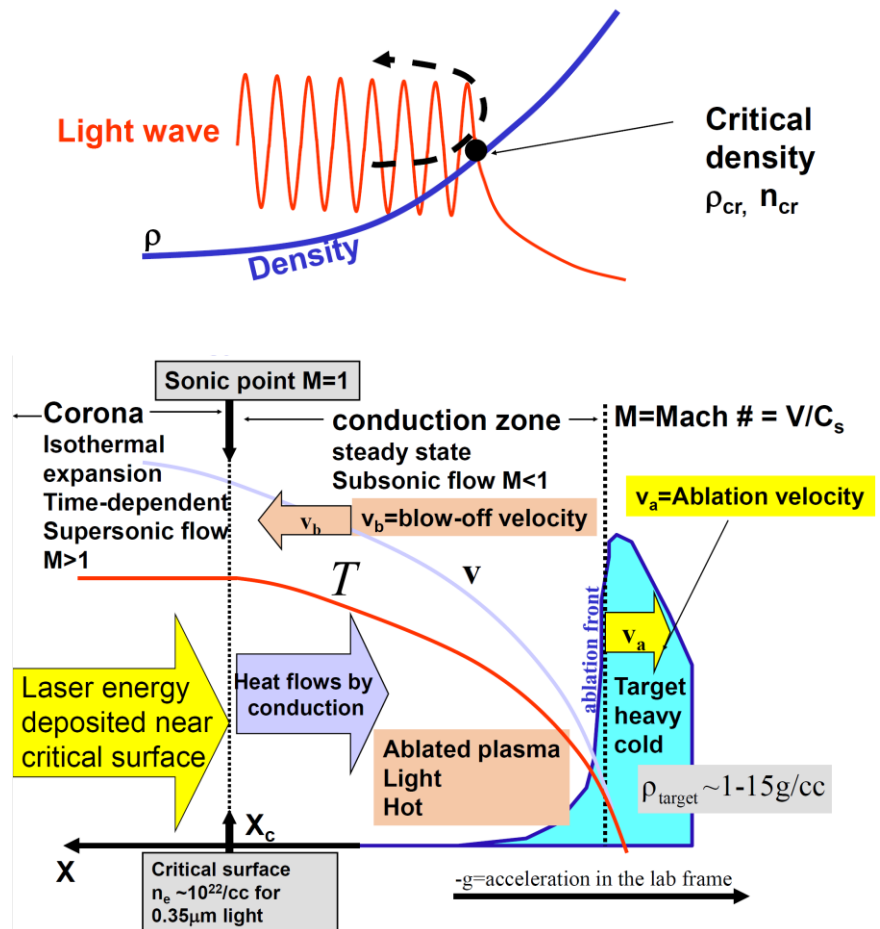
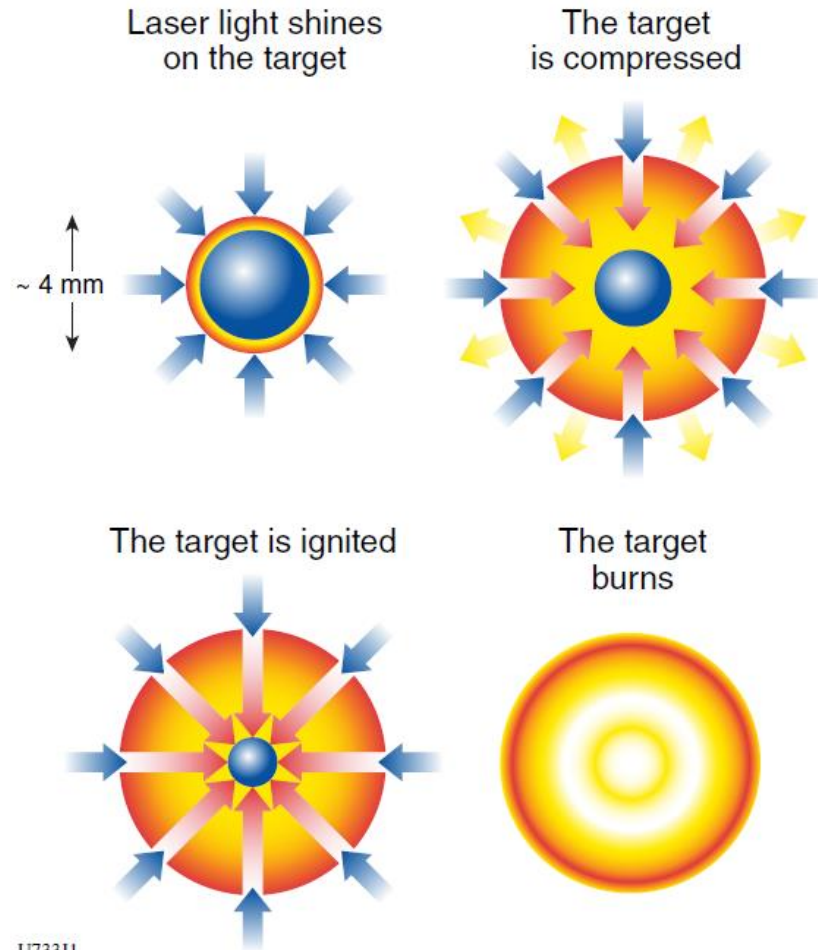


Outline



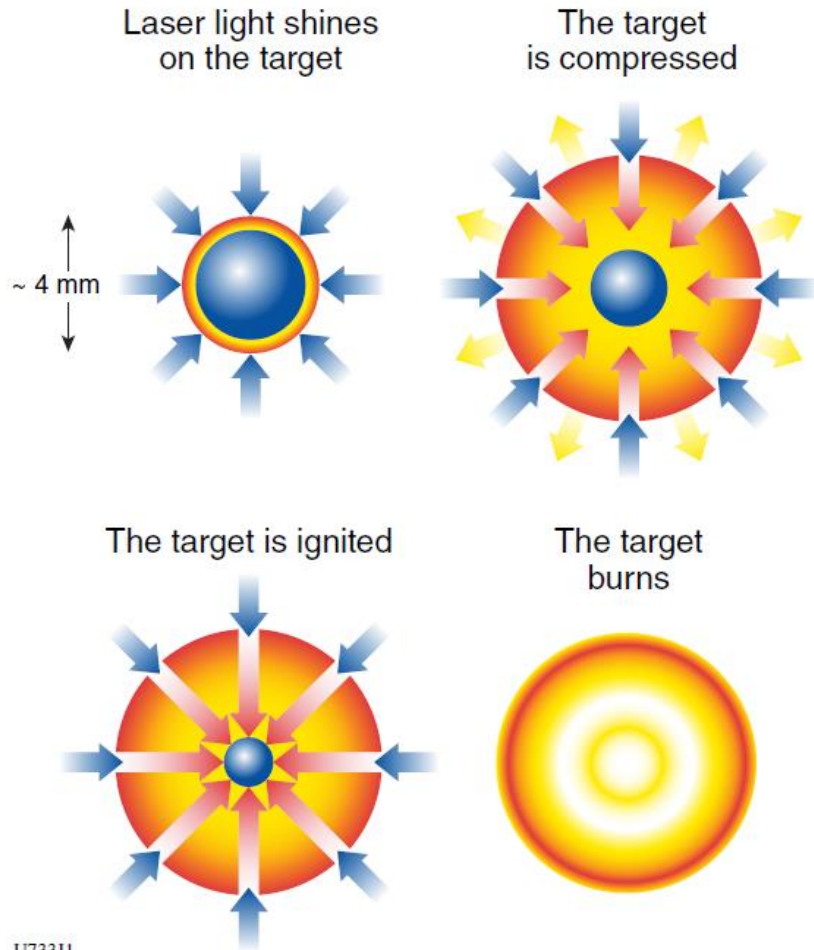
- Introduction to nuclear fusion
- Magnetic confinement fusion (MCF)
 - Tokamak
 - Stellarator
- Inertial confinement fusion (ICF)
 - Indirection drive ICF
 - Direct drive ICF
- Innovation idea – MCF + ICF
- Pulsed-power system at NCKU

Compression happens when outer layer of the target is heated by laser and ablated outward

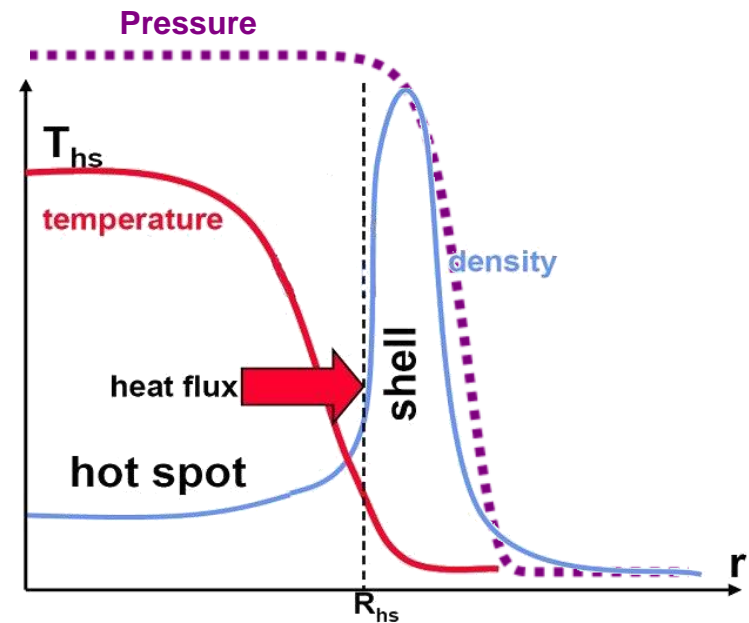


U733J1

Plasma is confined by its own inertia in inertial confinement fusion (ICF)



Spatial profile at stagnation

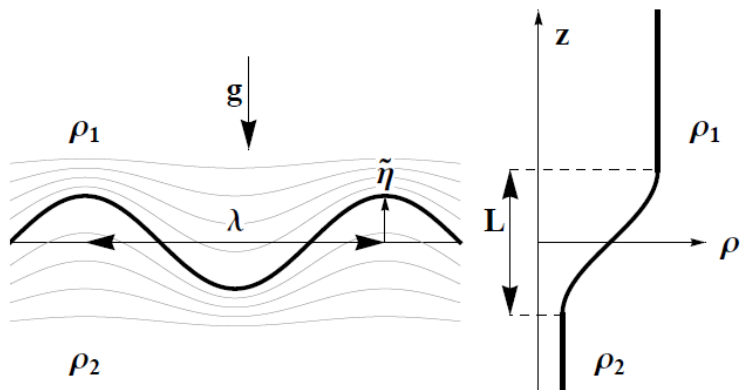


U733J1

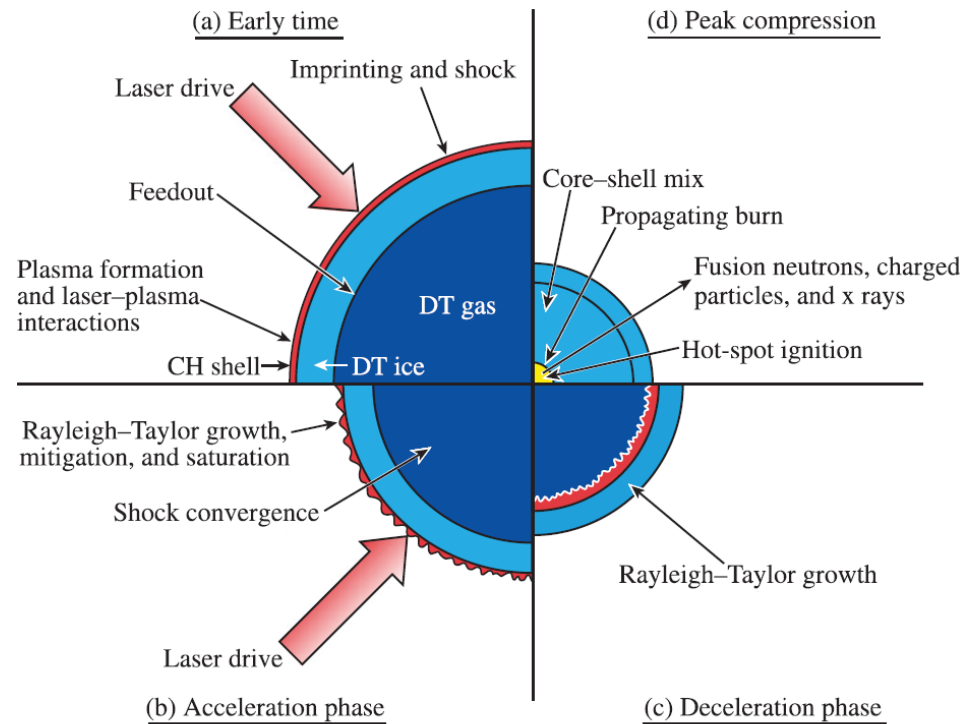
A ball can not be compressed uniformly by being squeezed between several fingers



• Rayleigh-Taylor instability



• Stages of a target implosion

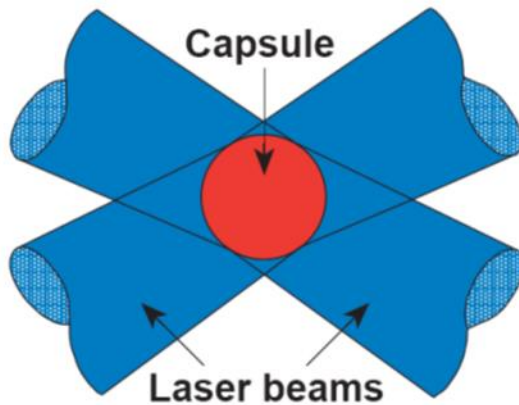


E9886J1

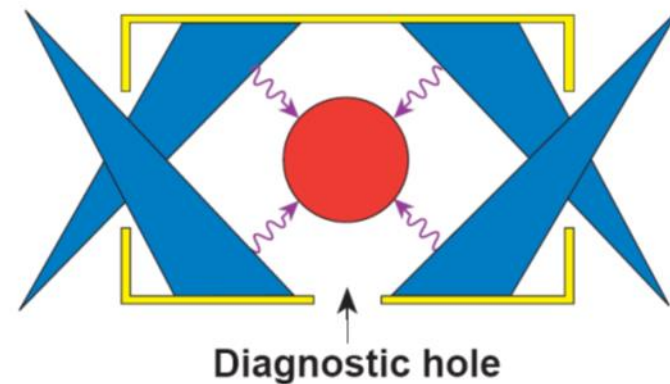
A spherical capsule can be imploded through directly or indirectly laser illumination



Direct-drive target



Indirect-drive target



Hohlraum using
a cylindrical high-Z case

Rochester is known as “The World's Image Center”



There are many famous optical companies at Rochester



Kodak



Eastman school of music



BAUSCH + LOMB

Laboratory for Laser Energetics, University of Rochester is a pioneer in laser fusion

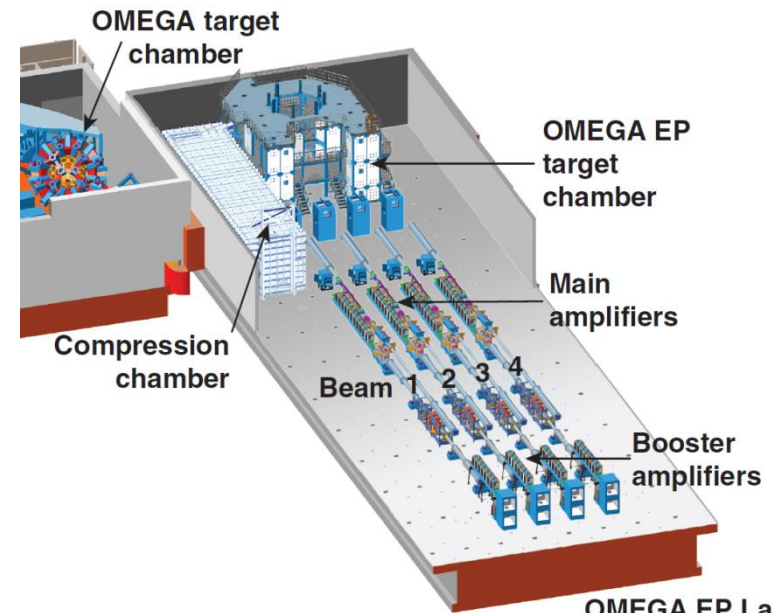
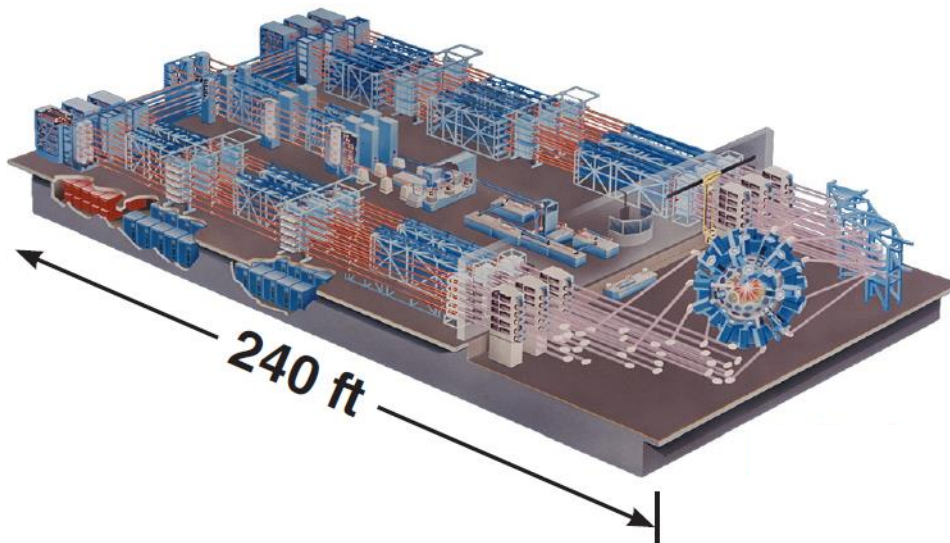


- **OMEGA Laser System**

- 60 beams
- >30 kJ UV on target
- 1%~2% irradiation nonuniformity
- Flexible pulse shaping

- **OMEGA EP Laser System**

- 4 beams; 6.5 kJ UV (10ns)
- Two beams can be high-energy petawatt
 - 2.6 kJ IR in 10 ps
 - Can propagate to the OMEGA or OMEGA EP target chamber



The OMEGA Facility is carrying out ICF experiments using a full suite of target diagnostics

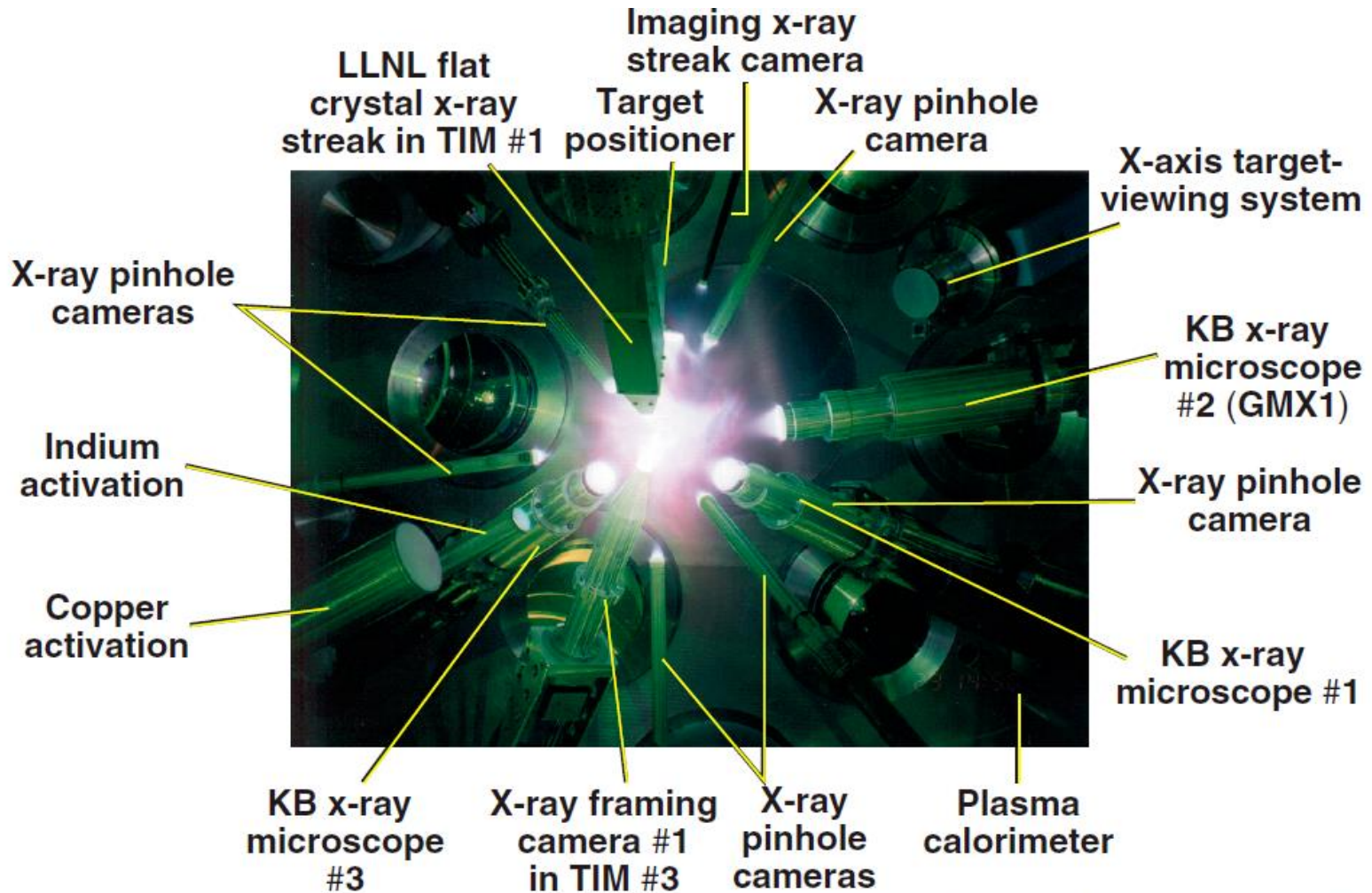
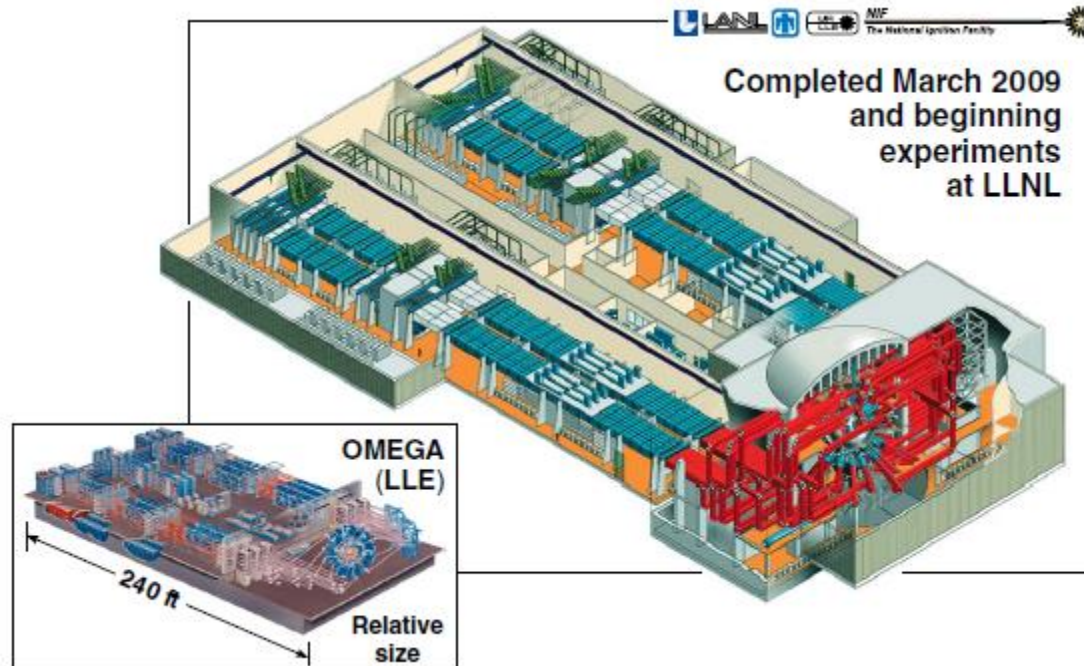


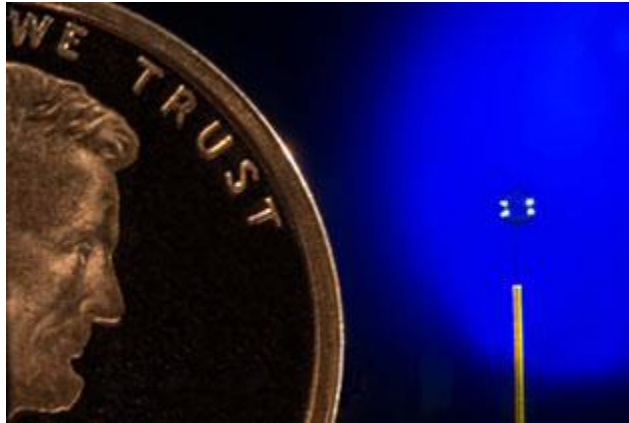
Photo taken from port H11B

The 1.8-MJ National Ignition Facility (NIF) will demonstrate ICF ignition and modest energy gain

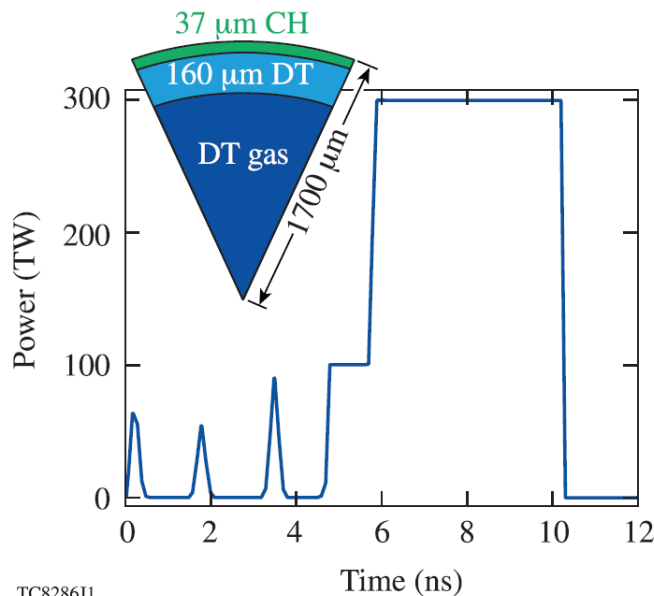


OMEGA experiments are integral to an ignition demonstration on the NIF.

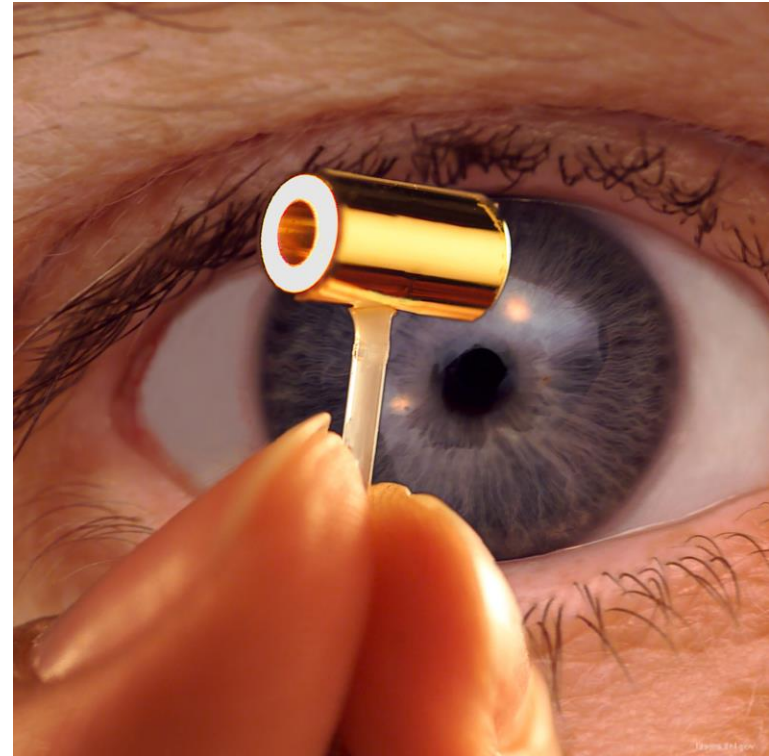
Targets used in ICF



- **Triple-point temperature : 19.79 K**



TC8286J1



<http://www.lle.rochester.ed>
https://en.wikipedia.org/wiki/Inertial_confinement_fusion
R. S. Craxton, etc., *Phys. Plasmas* **22**, 110501 (2015)

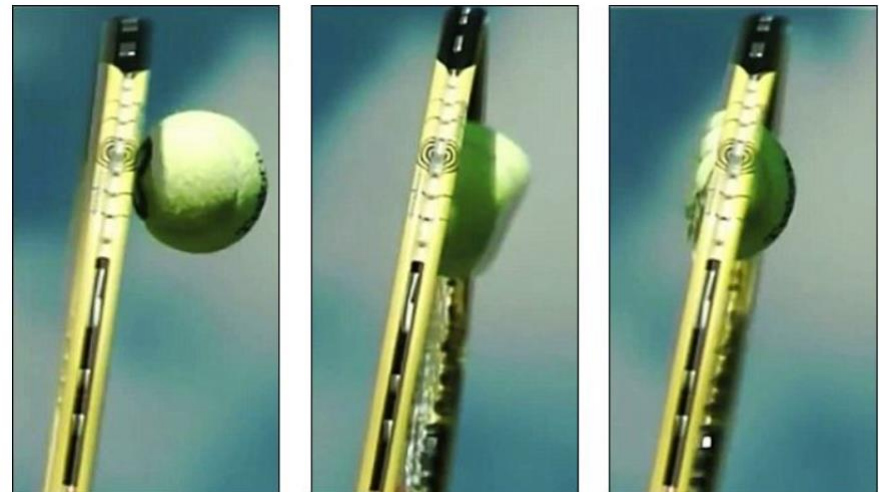
Softer material can be compressed to higher density



- **Compression of a baseball**



- **Compression of a tennis ball**



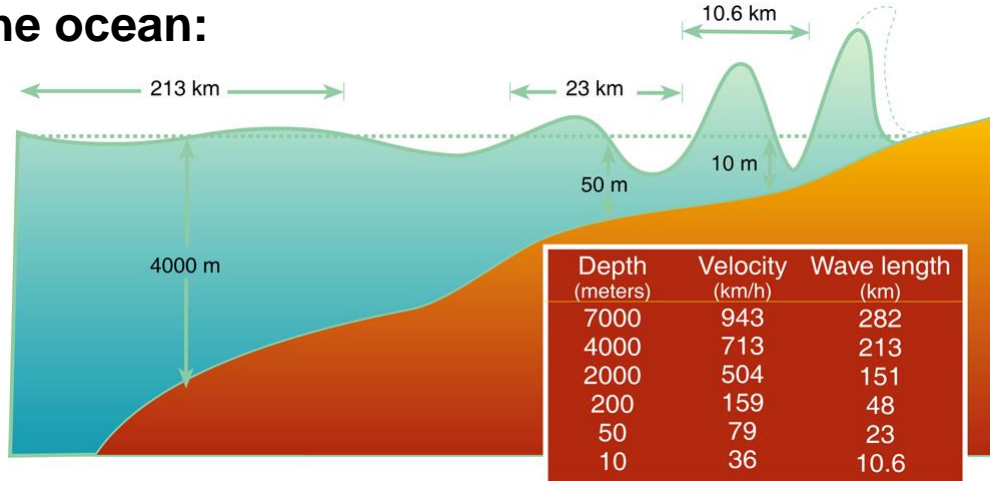
<https://www.youtube.com/watch?v=uxlldMoAwbY>

<https://newsghana.com.gh/wimbledon-slow-motion-video-of-how-a-tennis-ball-turns-to-goo-after-serve/>

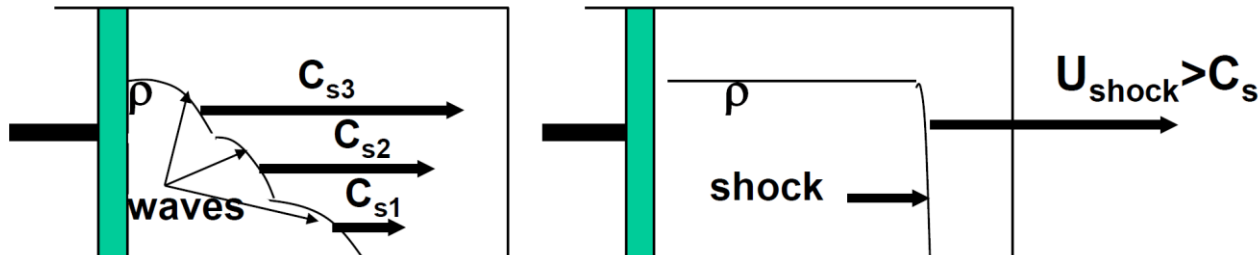
A shock is formed due to the increasing sound speed of a compressed gas/plasma



- Wave in the ocean:

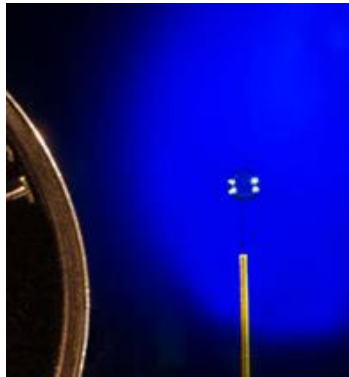


- Acoustic/compression wave driven by a piston:

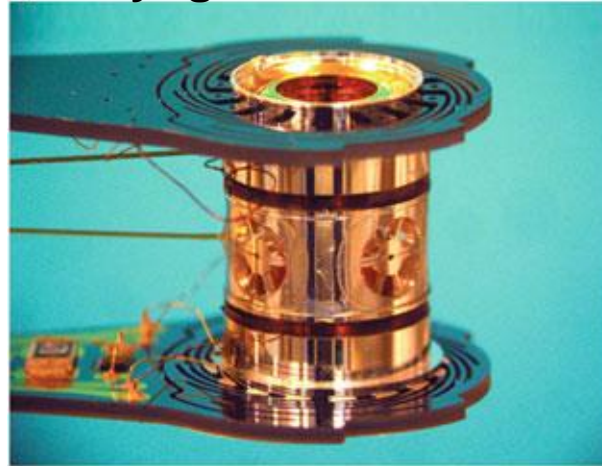


$$C_s \sim \sqrt{\frac{p}{\rho}} \sim \sqrt{\frac{\alpha \rho^{5/3}}{\rho}} \sim \sqrt{\alpha} \rho^{1/3}$$

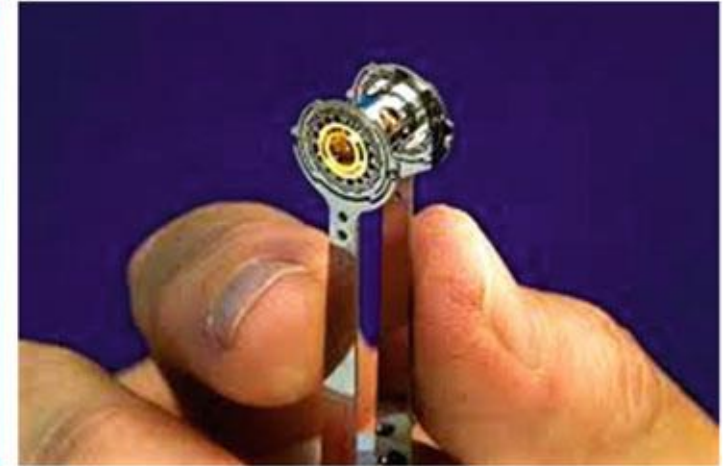
Targets used in ICF



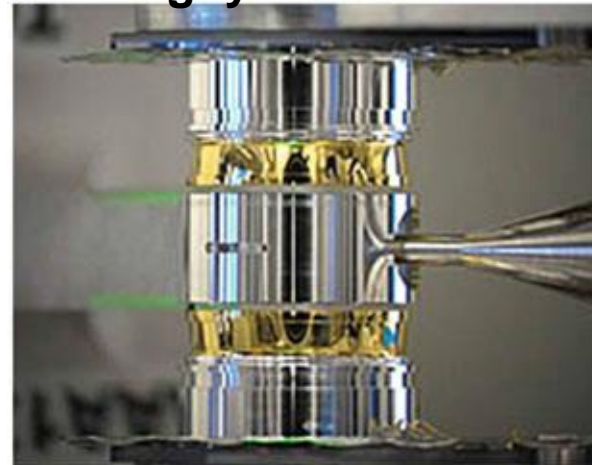
a Cryogenic hohlraum



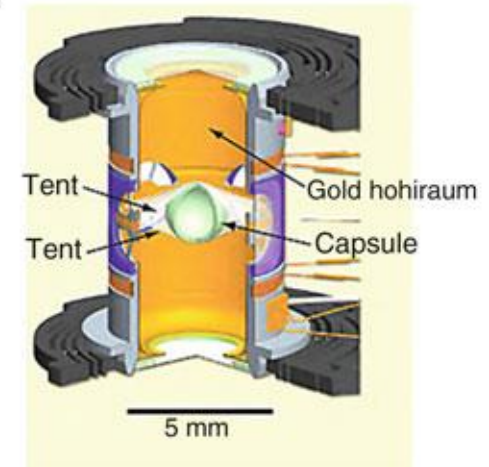
b



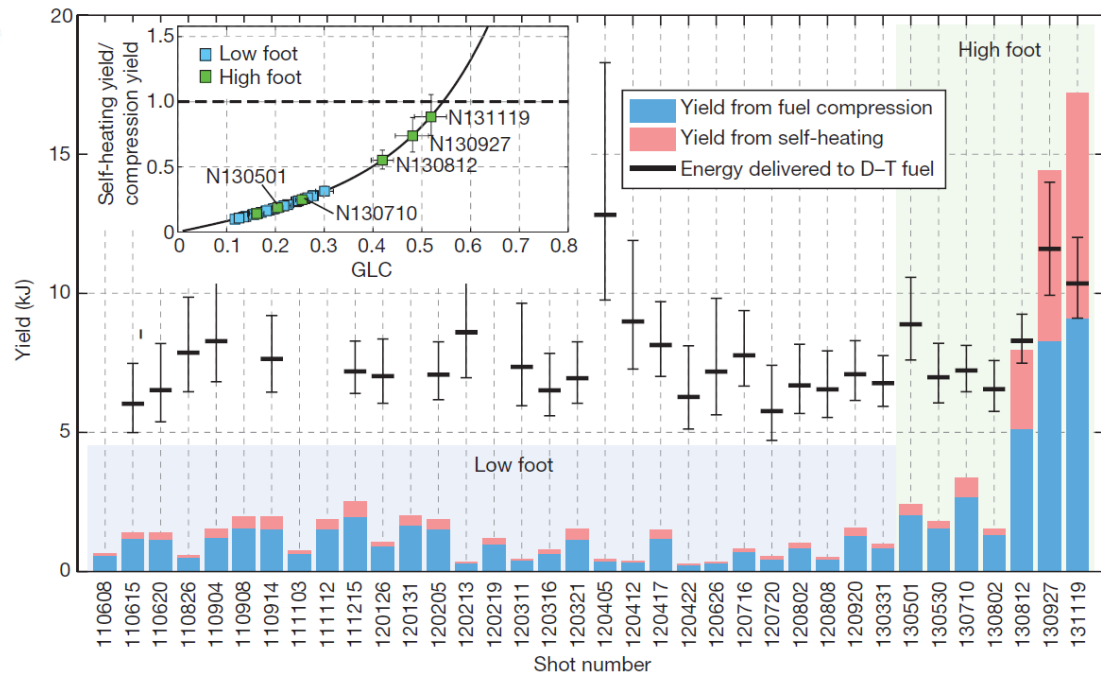
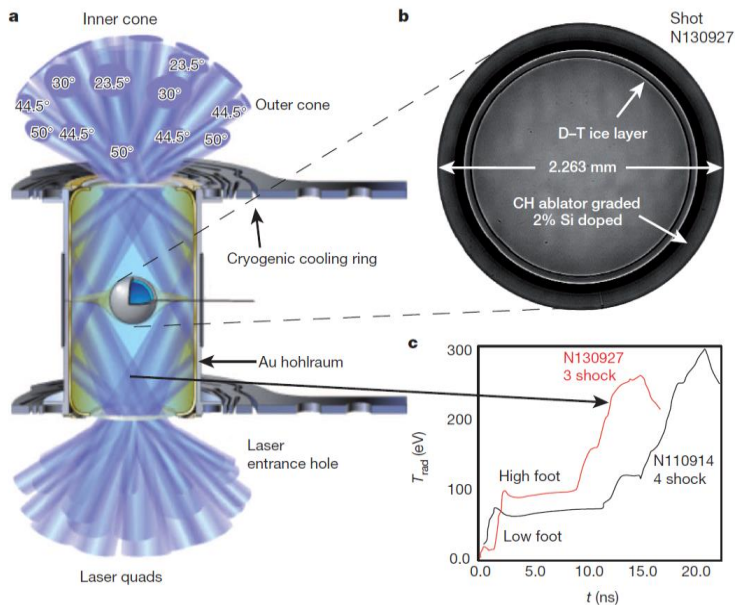
c Rugby hohlraum



d Tent holder

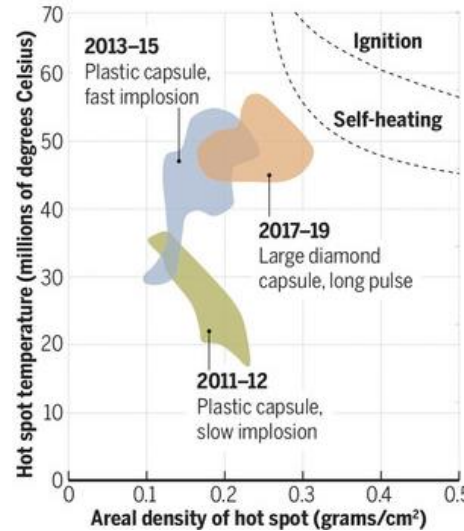
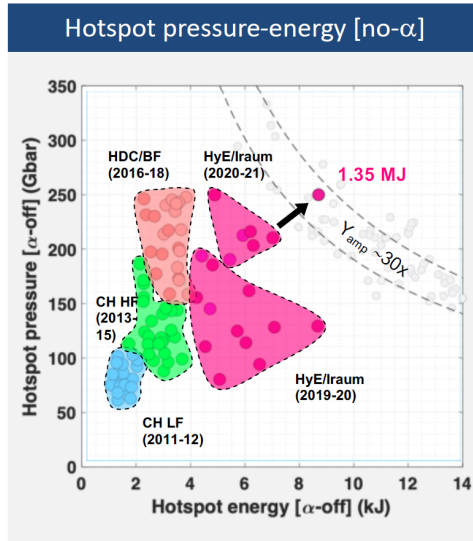


Nature letter “Fuel gain exceeding unity in an inertially confined fusion implosion”

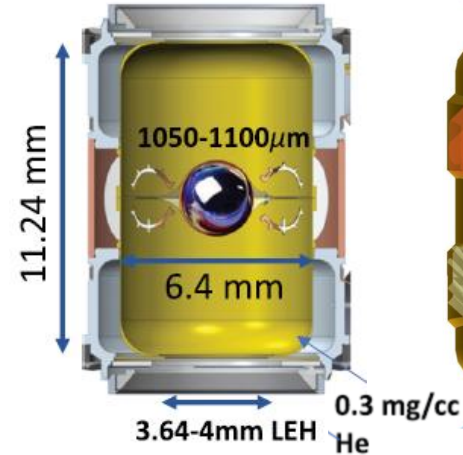


• Fuel gain exceeding unity was demonstrated for the first time.

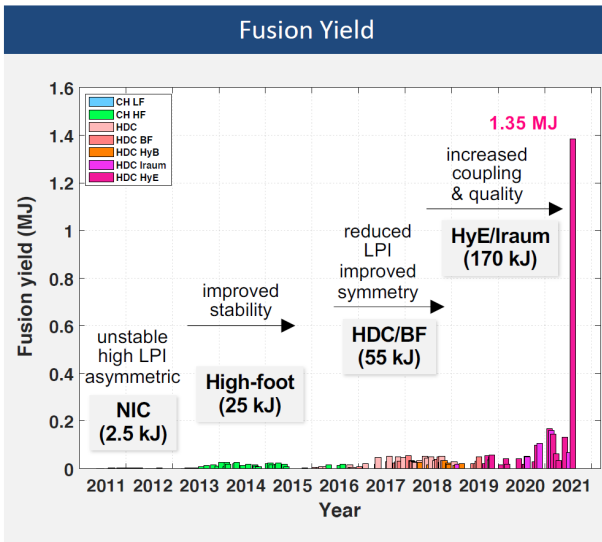
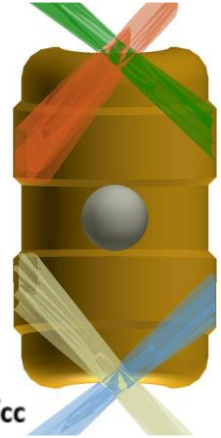
The hot spot has entered the burning plasma regime



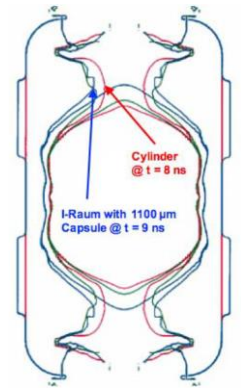
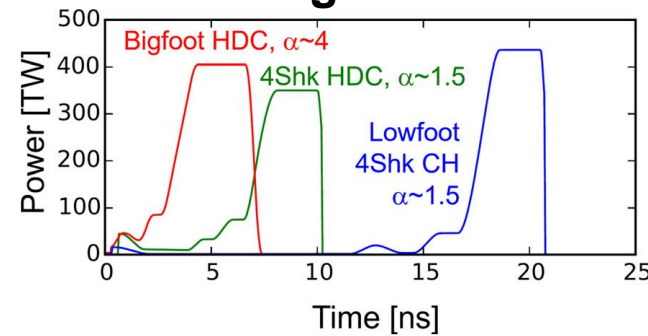
• Hybrid-E



• I-raum



• Big foot



T. Ma, ARPA-E workshop, April 26, 2022

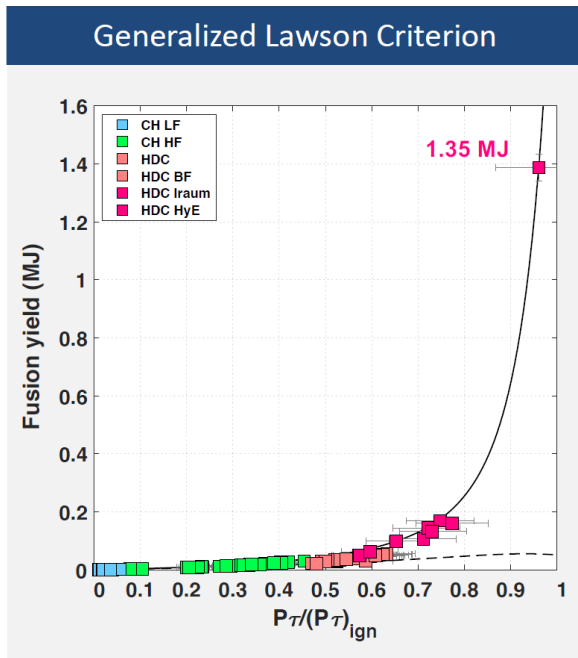
Science 370, p1019, 2020

D. T. Casey, etc., Phys. Plasmas, 25, 056308 (2018)

A. L. Kritcher, etc., Phys. Plasmas, 28, 072706 (2021)

H. F. Robey, etc., Phys. Plasmas, 25, 012711 (2018)

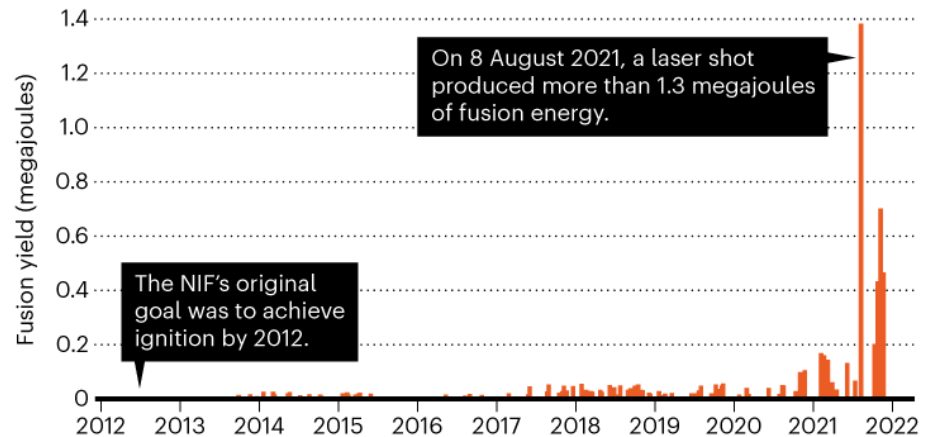
National Ignition Facility (NIF) achieved a yield of more than 1.3 MJ from ~1.9 MJ of laser energy in 2021 (Q~0.7)



- National Ignition Facility (NIF) achieved a yield of more than 1.3 MJ (Q~0.7). This advancement puts researchers at the threshold of fusion ignition.

THE ROAD TO IGNITION

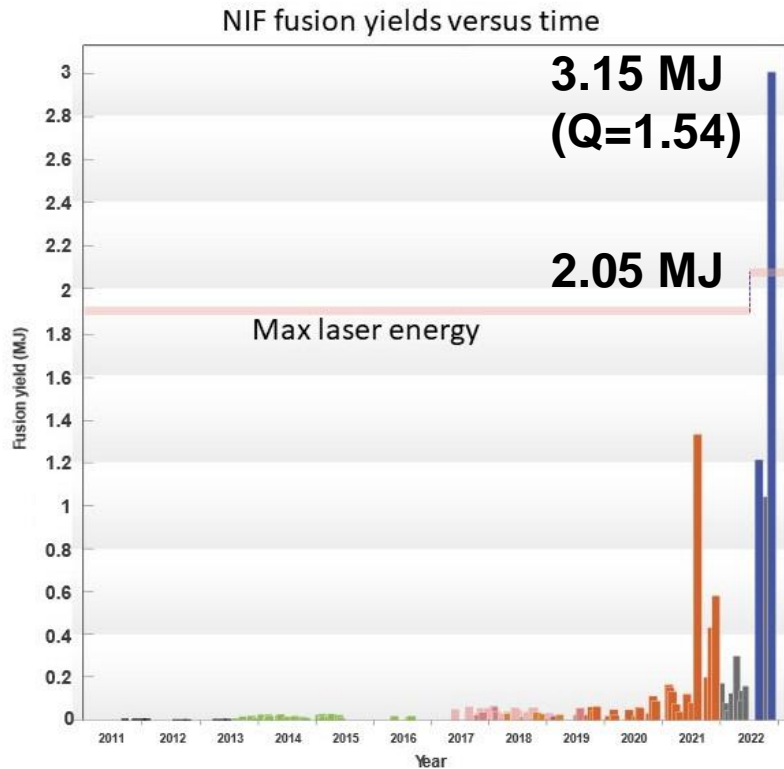
The National Ignition Facility (NIF) struggled for years before achieving a high-yield fusion reaction (considered ignition, by some measures) in 2021. Repeat experiments, however, produced less than half the energy of that result.



©nature

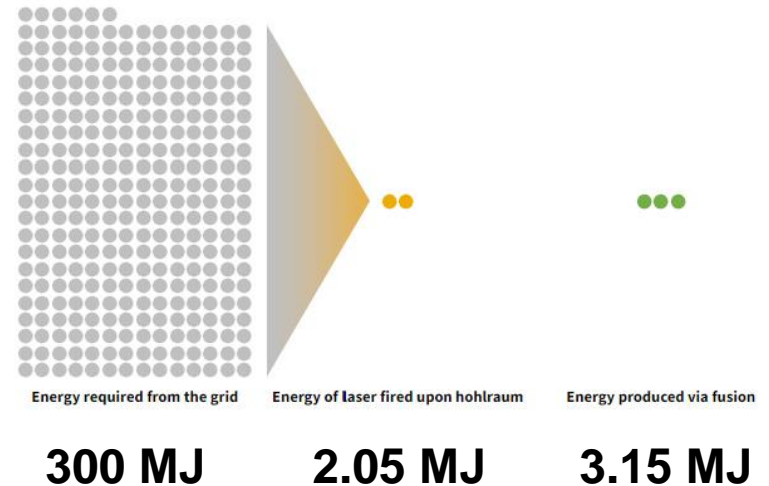
- Laser-fusion facility heads back to the drawing board.

“Ignition” (target yield larger than one) was achieved in NIF on 2022/12/5



NIF's ignition achievement in perspective

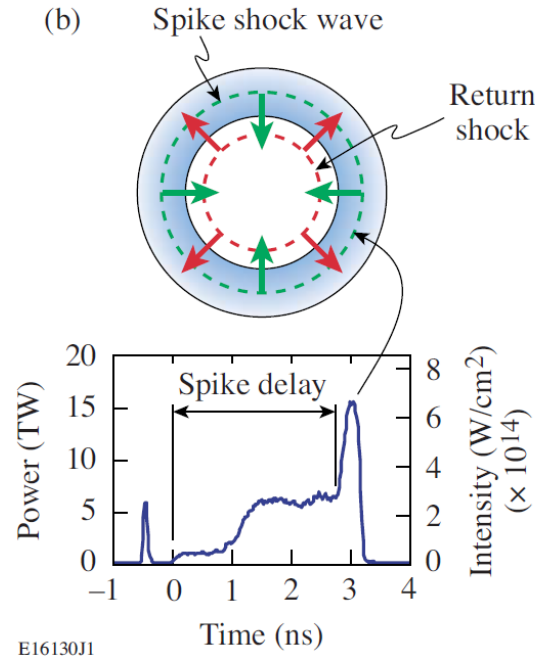
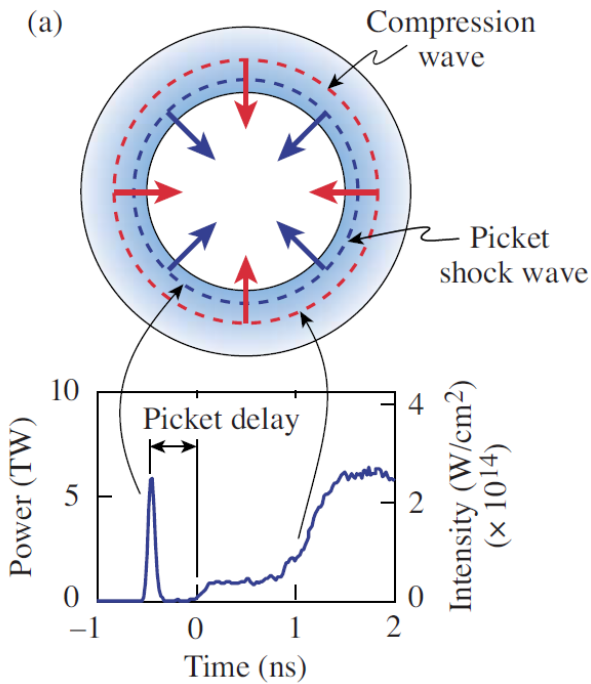
Energy in megajoules ● = 1



External “spark” can be used for ignition

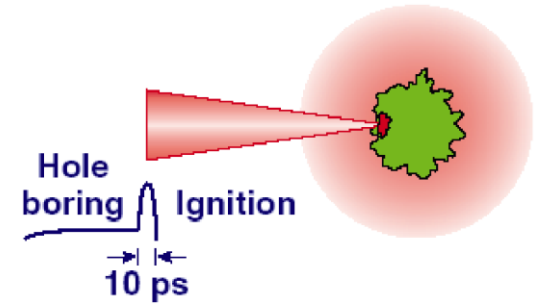


- **Shock ignition**

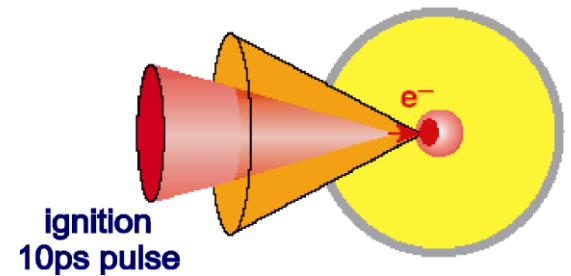


- **Fast ignition**

- a) channeling FI concept



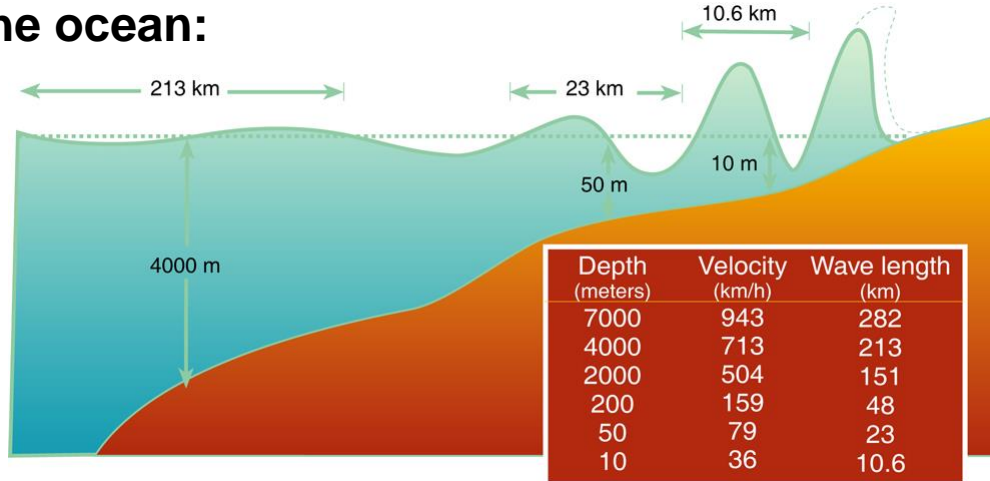
- b) cone-in-shell FI concept



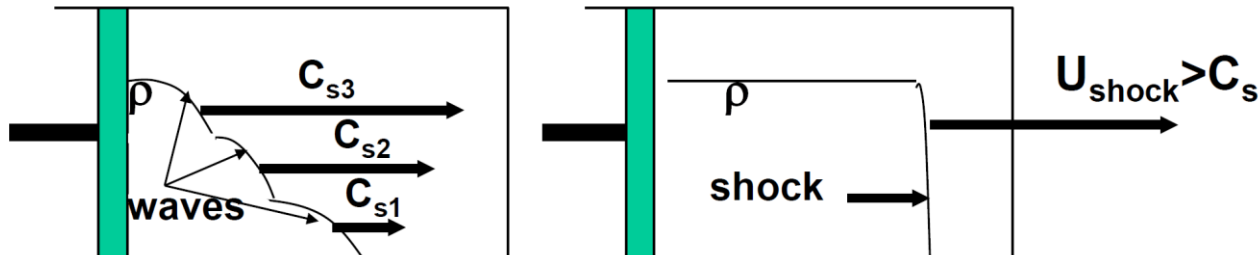
A shock is formed due to the increasing sound speed of a compressed gas/plasma



- Wave in the ocean:



- Acoustic/compression wave driven by a piston:



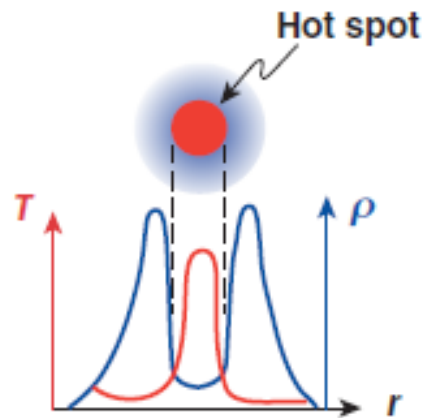
$$C_s \sim \sqrt{\frac{p}{\rho}} \sim \sqrt{\frac{\alpha \rho^{5/3}}{\rho}} \sim \sqrt{\alpha} \rho^{1/3}$$

Ignition can happen by itself or being triggered externally



Self-ignition

Conventional ICF

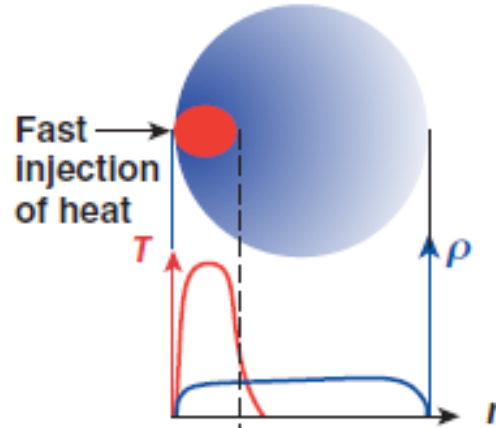


Low-density central spot ignites a high-density cold shell

$$\rho T_{\text{hot}} \approx \rho T_{\text{cold}} \text{ (isobaric)}$$

External “spark” for fast ignition

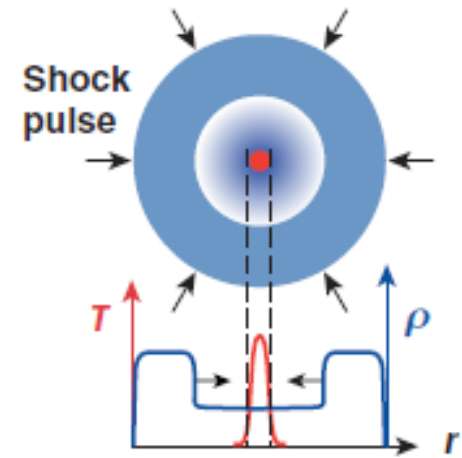
Fast Ignition



Fast-heated side spot ignites a high-density fuel ball

$$\rho_{\text{hot}} \approx \rho_{\text{cold}} \text{ (isochoric)}$$

Shock Ignition



Spherical shock wave ignites a high-density fuel ball

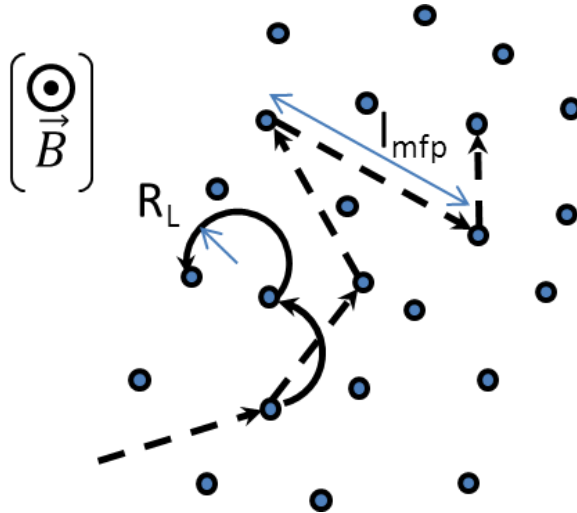
$$\rho T_{\text{hot}} \gg \rho T_{\text{cold}}$$

Outline



- Introduction to nuclear fusion
- Magnetic confinement fusion (MCF)
 - Tokamak
 - Stellarator
- Inertial confinement fusion (ICF)
 - Indirection drive ICF
 - Direct drive ICF
- Innovation idea – MCF + ICF
- Pulsed-power system at NCKU

A strong magnetic field reduces the heat flux



$$\mathbf{q}_T = -\kappa_{\parallel} \nabla_{\parallel} T - \kappa_{\perp} \nabla_{\perp} T$$

$$\kappa_{\parallel} = \kappa_0 T^{5/2}$$

$$\kappa_{\perp} = \frac{\kappa_{\parallel}}{\chi^2} \quad \text{for large Hall parameter } \chi \propto \frac{l_{\text{mfp}}}{R_L} \gg 1$$

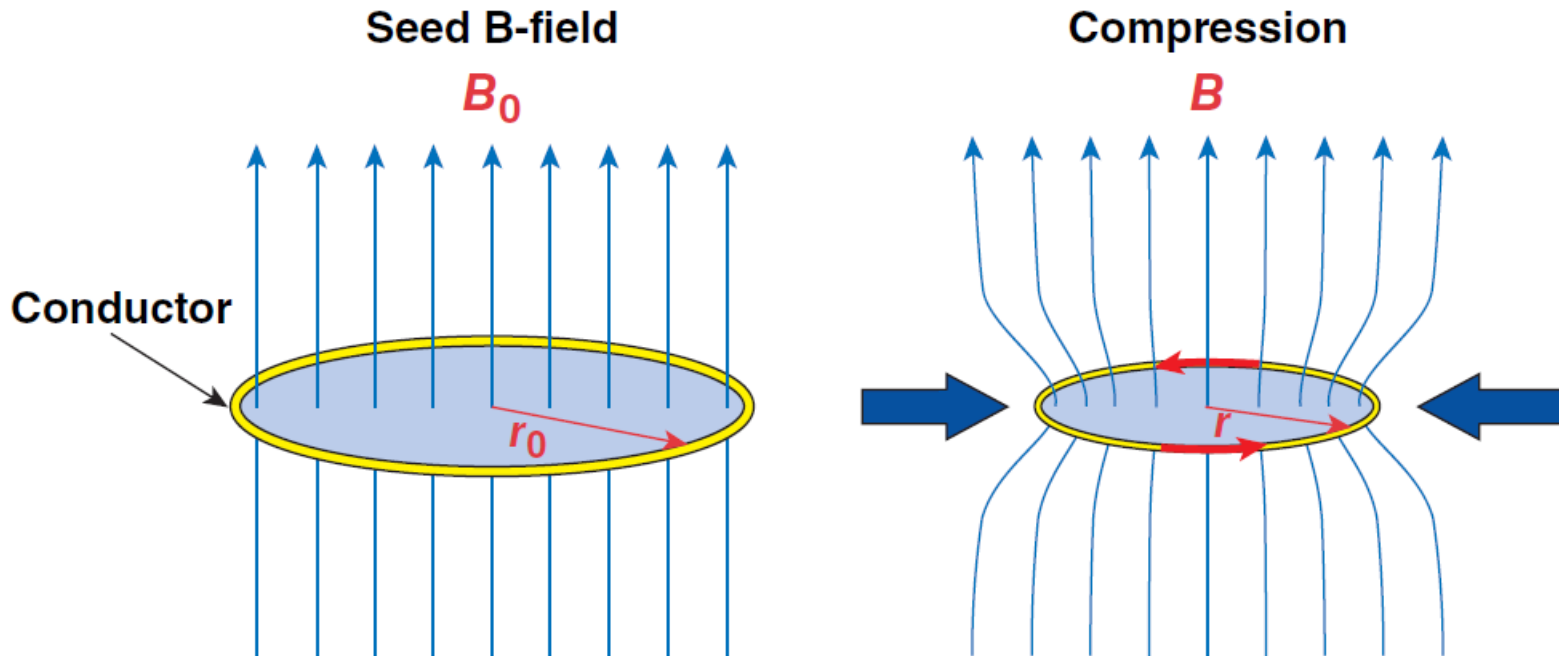
- Typical hot spot conditions:

$R_{\text{hs}} \sim 40 \mu\text{m}$, $\rho \sim 20 \text{ g/cm}^3$, $T \sim 5 \text{ keV}$:

$B > 10 \text{ MG}$ is needed for $\chi > 1$

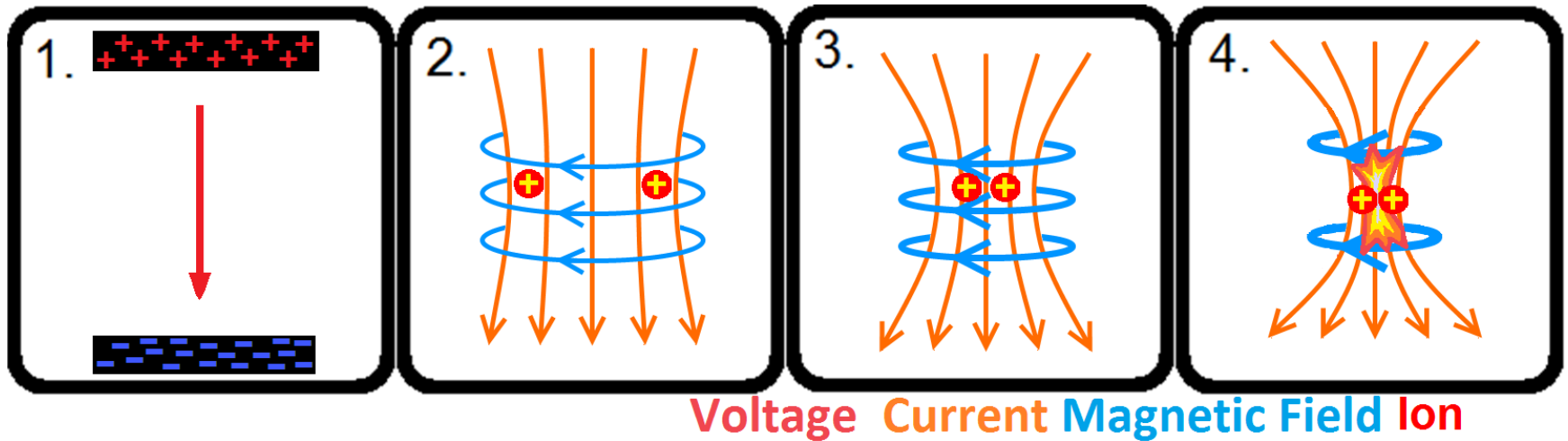
Magnetic-flux compression can be used to provide the needed magnetic field.

Principle of frozen magnetic flux in a good conductor is used to compress fields

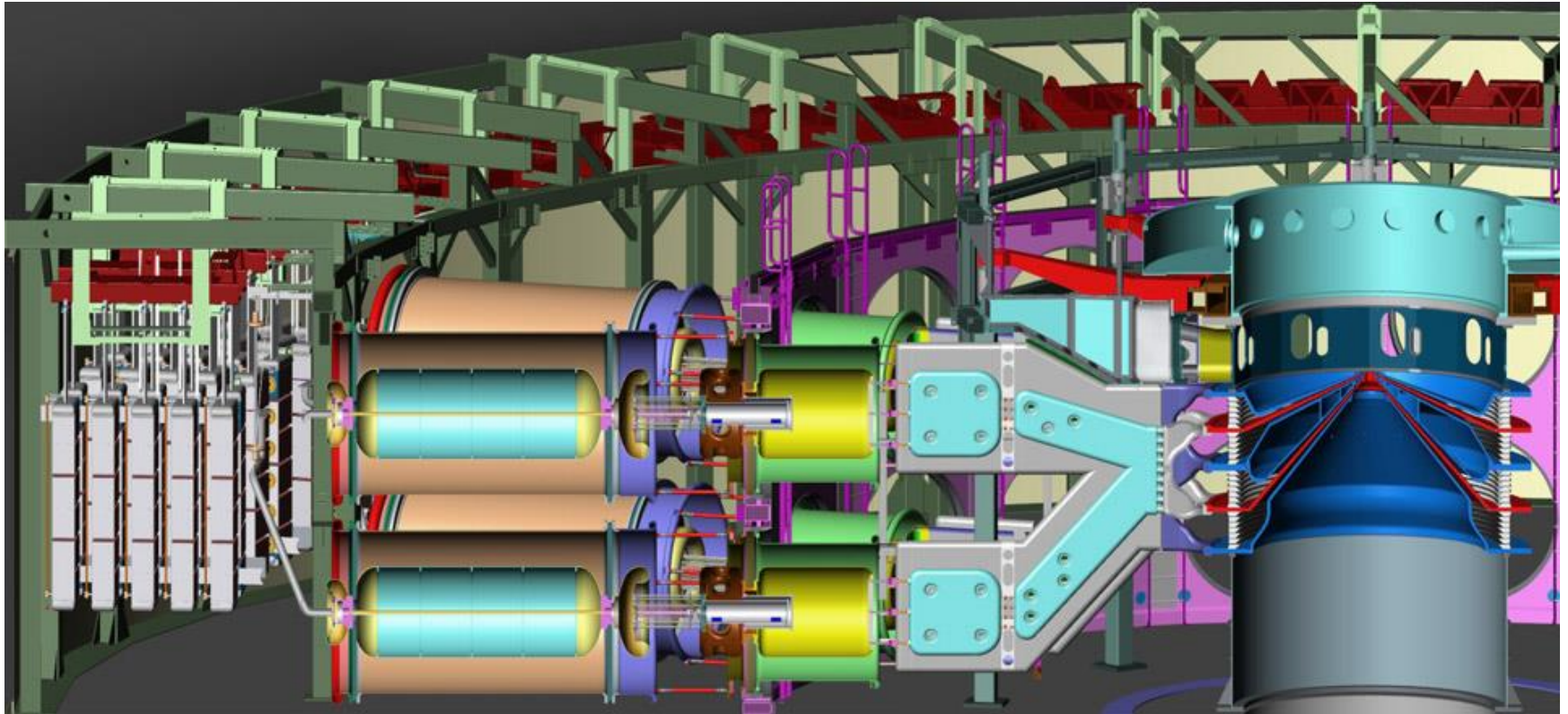


$$\Phi = \pi r_0^2 B_0 = \pi r^2 B$$

Plasma can be pinched by parallel propagating plasmas

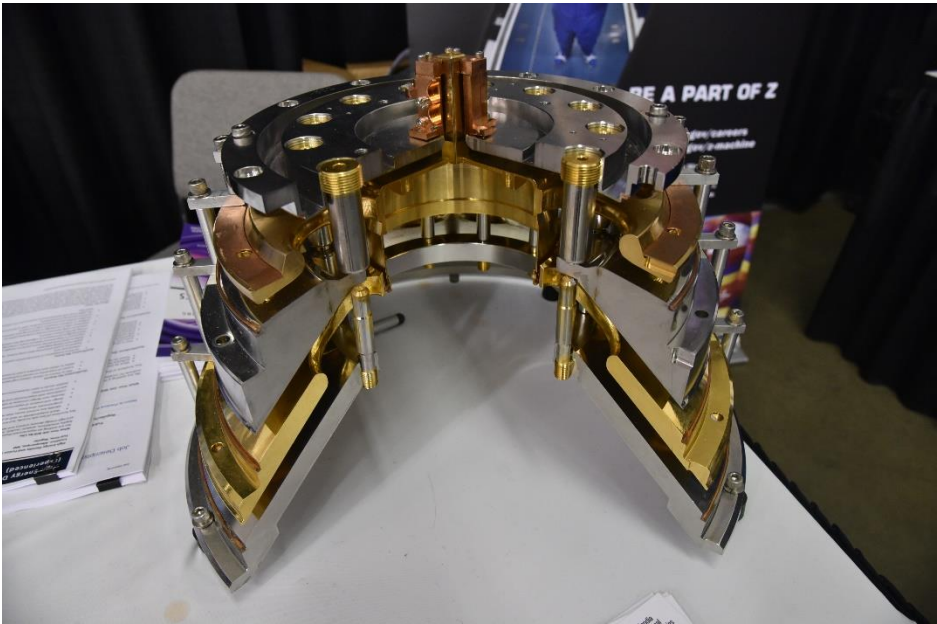


Sandia's Z machine is the world's most powerful and efficient laboratory radiation source

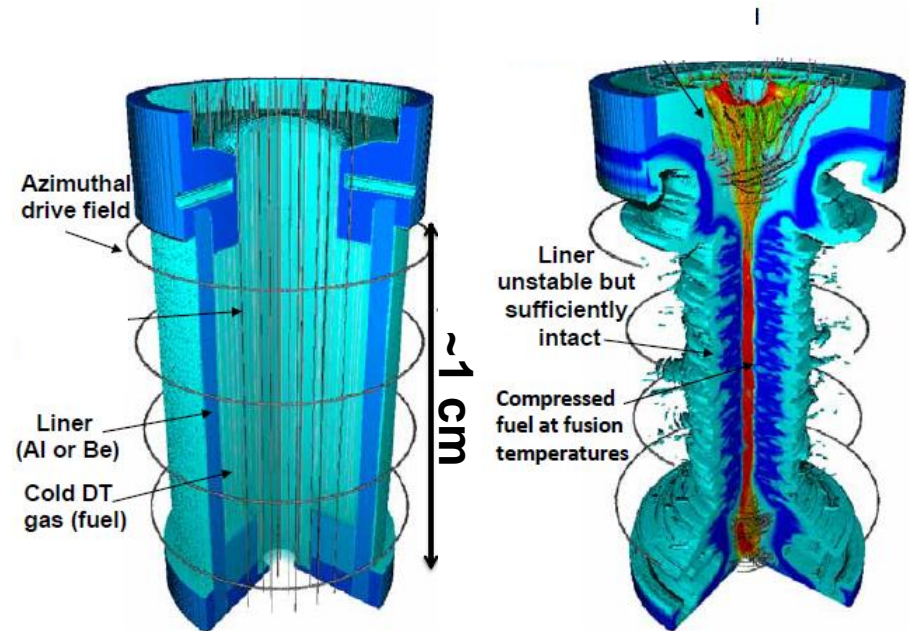


- **Stored energy: 20 MJ**
- **Marx charge voltage: 85 kV**
- **Peak electrical power: 85 TW**
- **Peak current: 26 MA**
- **Rise time: 100 ns**
- **Peak X-ray emissions: 350 TW**
- **Peak X-ray output: 2.7 MJ**

Z machine



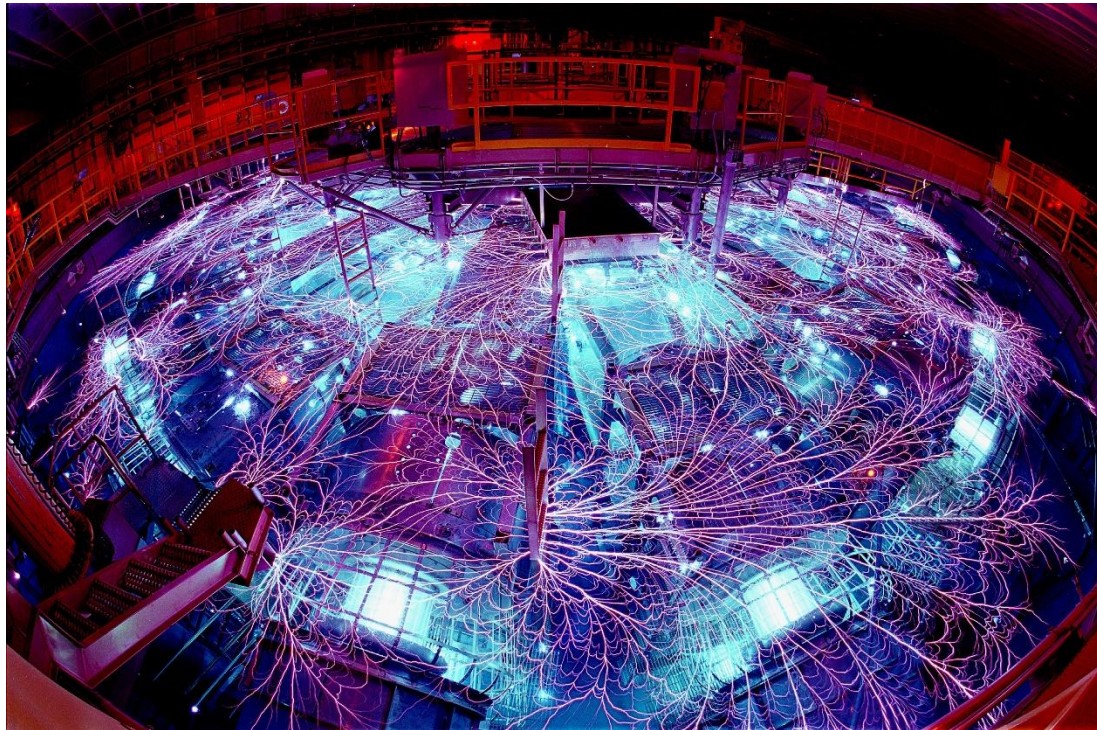
Z machine



- **Stored energy: 20 MJ**
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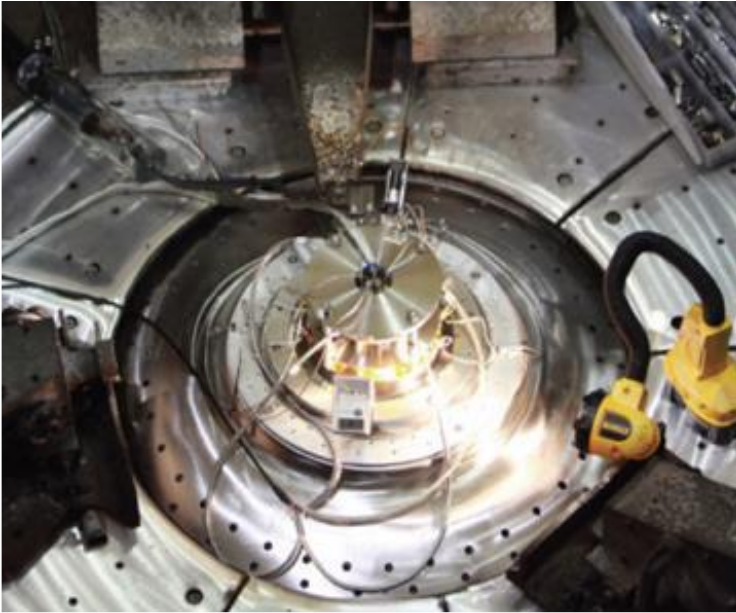
Z machine discharge



Before and after shots



- Before shots

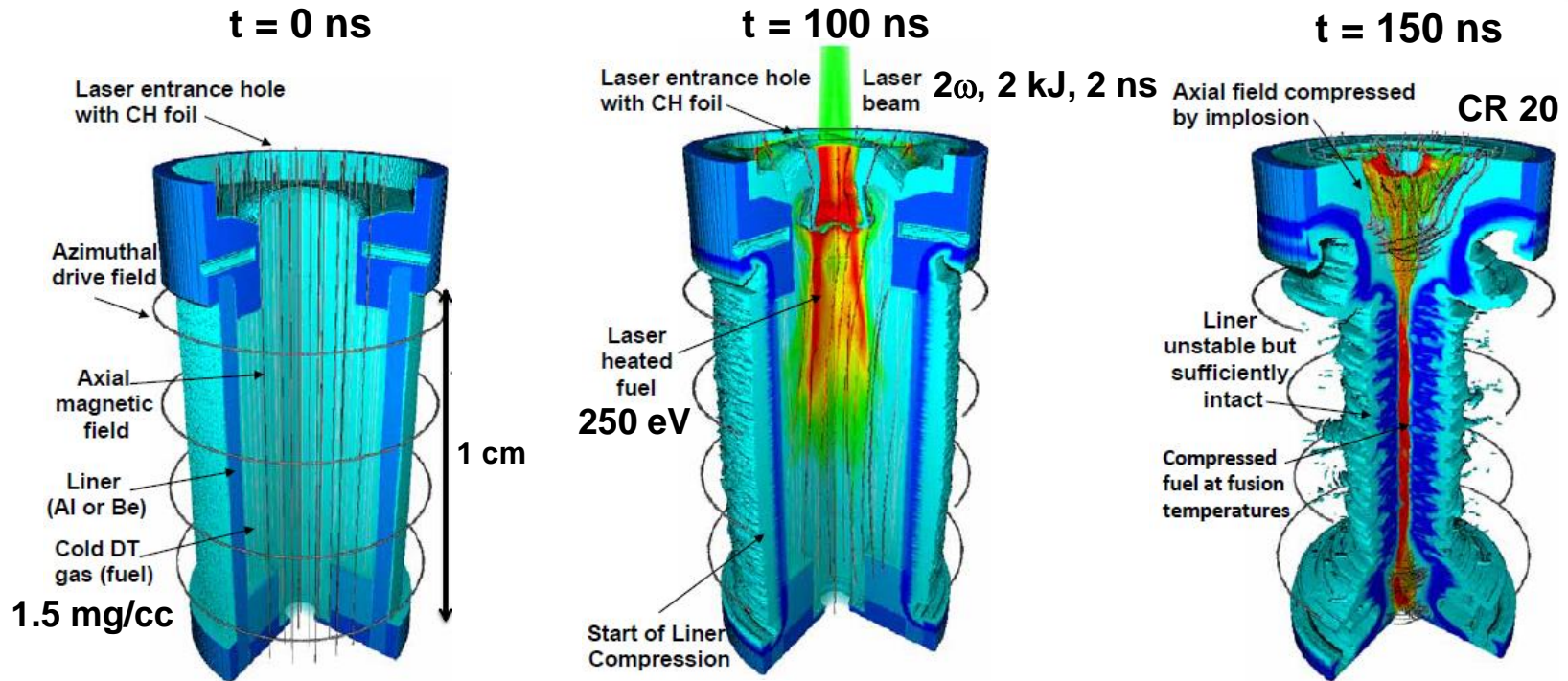


- After shots



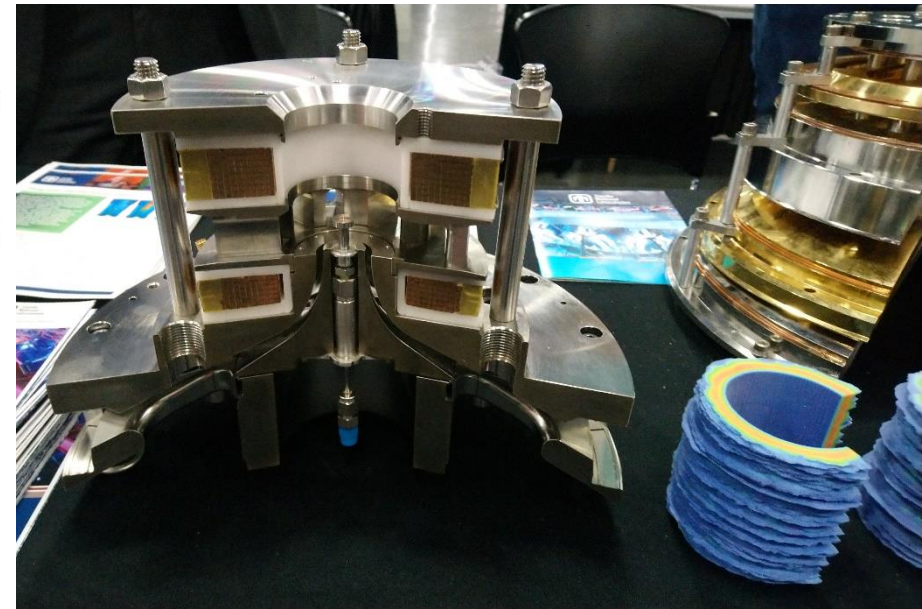
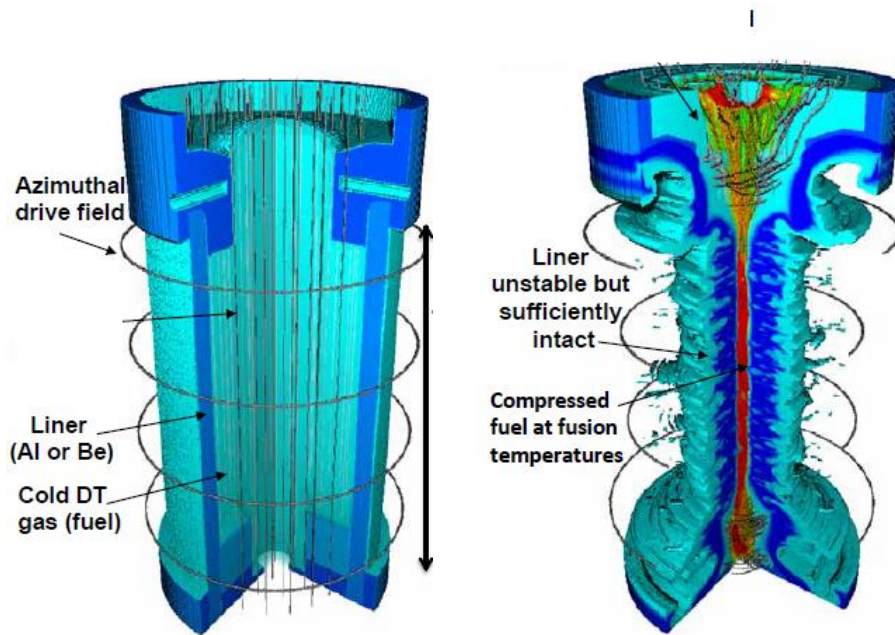
SAND2017-0900PE_The sandia z machine - an overview of the world's most powerful pulsed power facility.pdf

Promising results were shown in MagLIF concept conducted at the Sandia National Laboratories

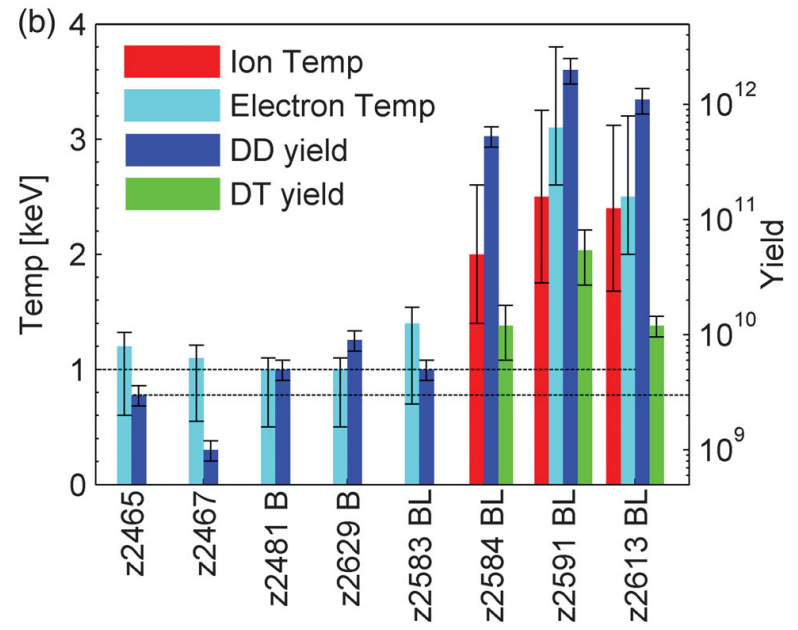
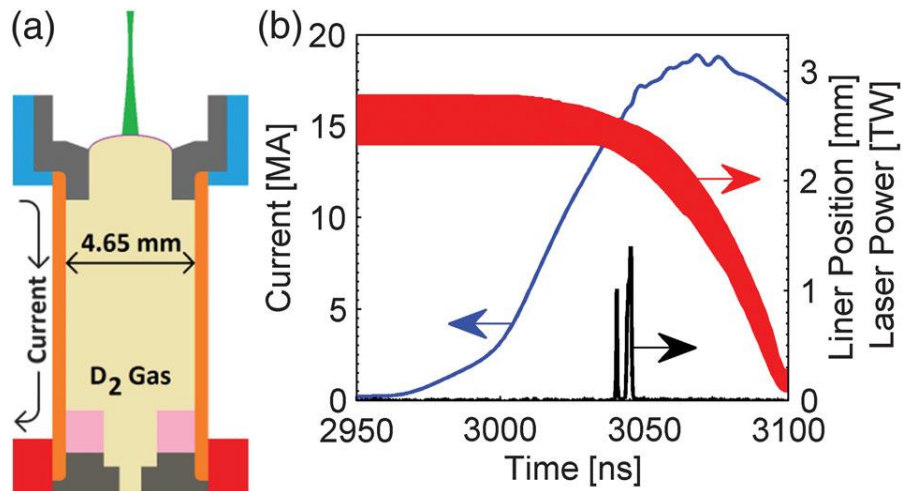


The stagnation plasma reached fusion-relevant temperatures with a 70 km/s implosion velocity

MagLIF target



Neutron yield increased by 100x with preheat and external magnetic field.

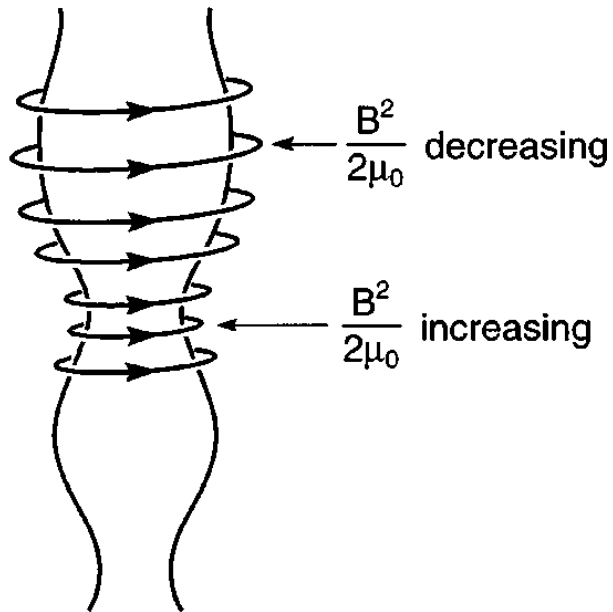


Sheared flow stabilizes MHD instabilities

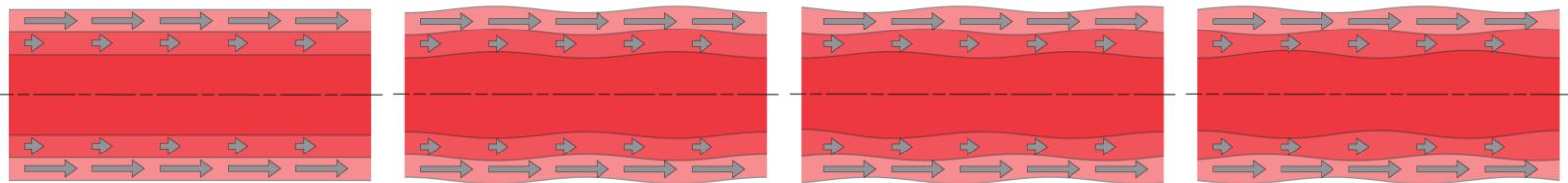
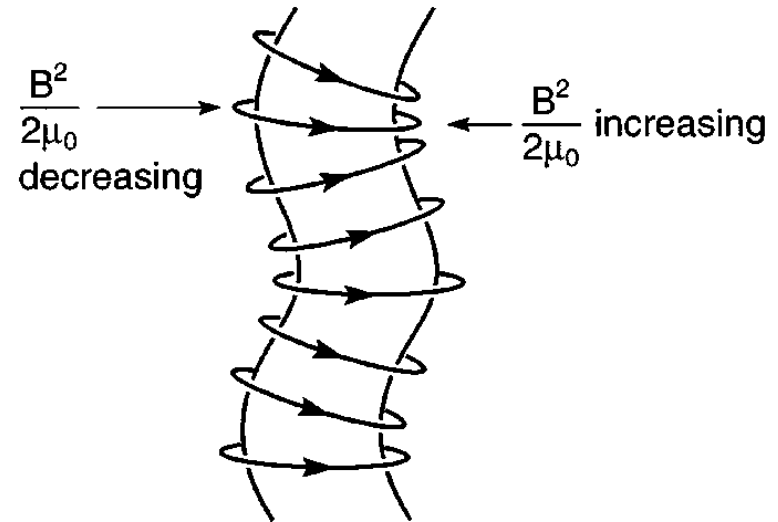


$m = 0$ (sausage)

Perturbation $\propto e^{(im\theta + ikz + \gamma t)}$



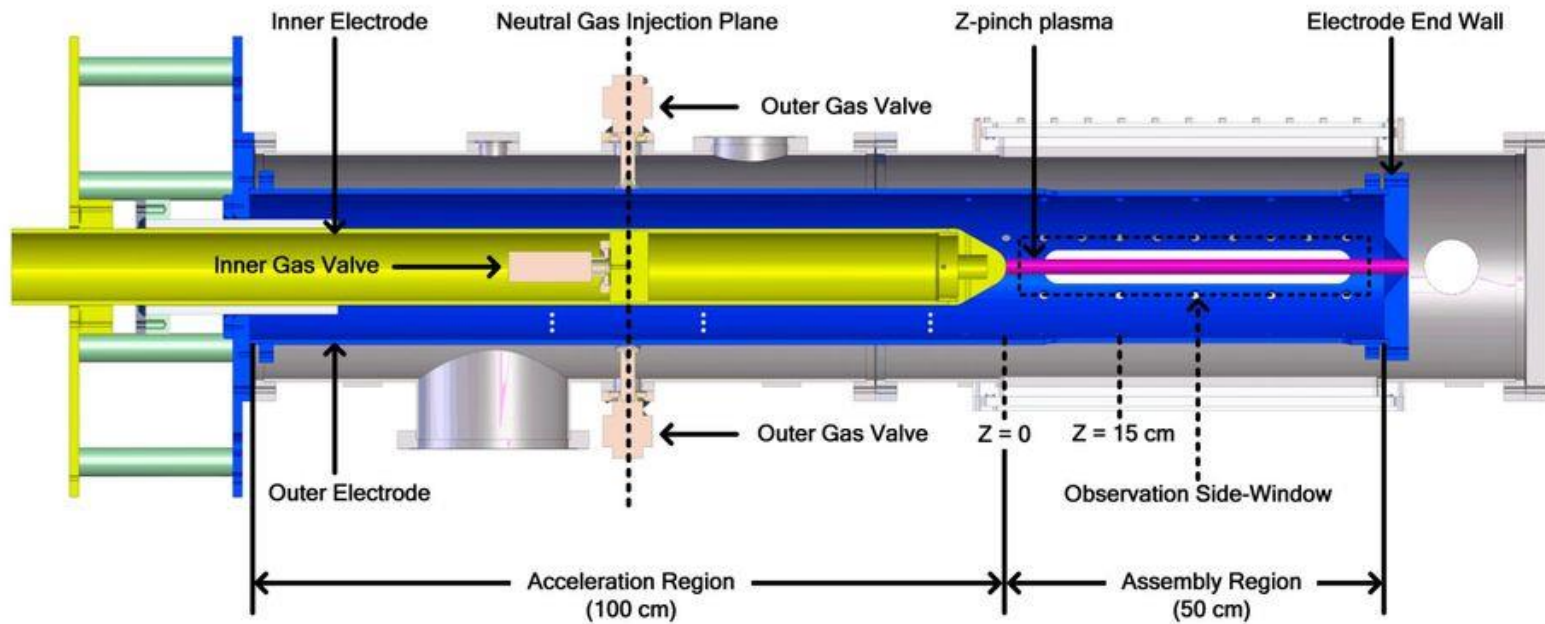
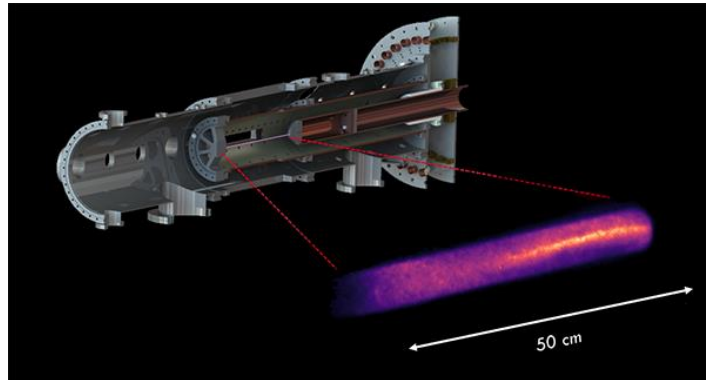
$m = 1$ (kink)



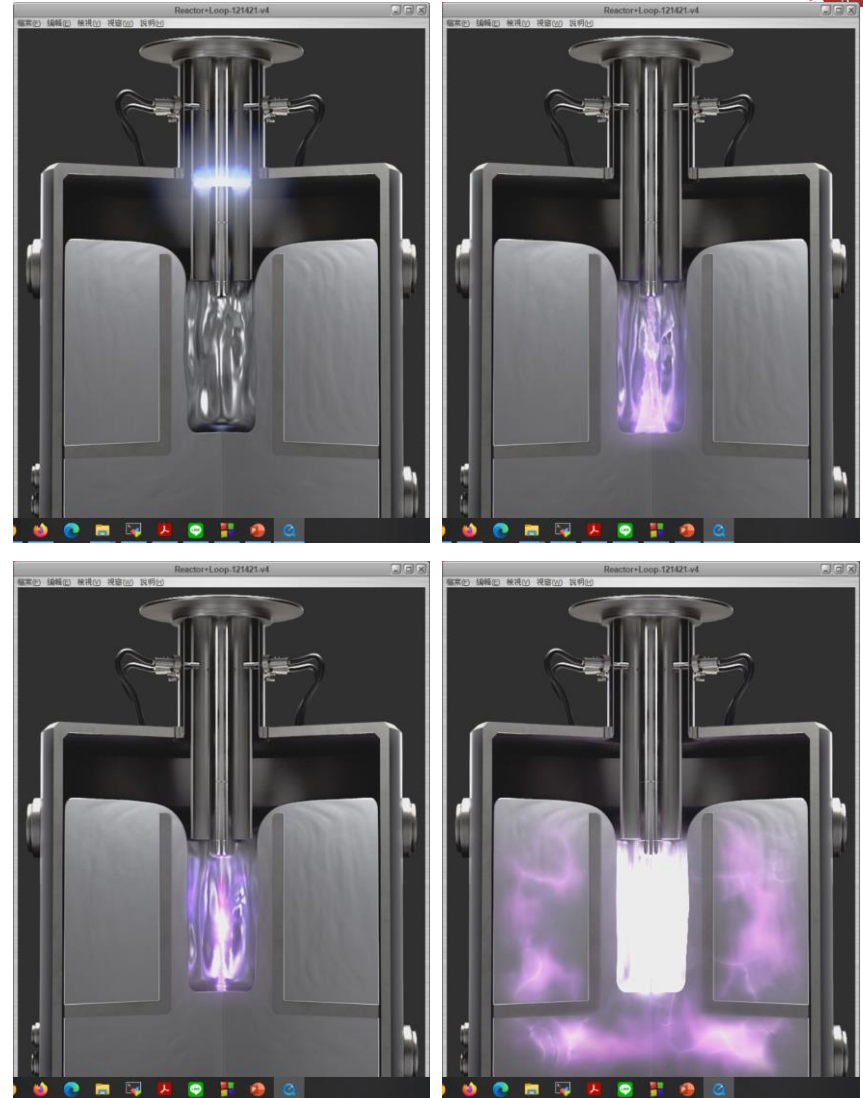
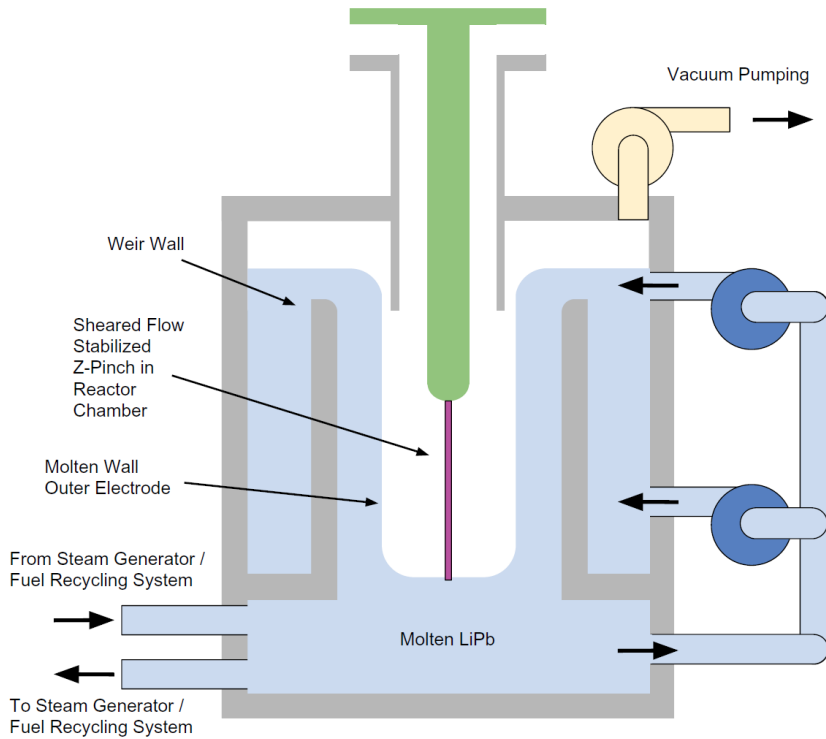
$$\frac{dV_z}{dr} \neq 0$$

M. G. Haines, etc., Phys. Plasmas 7, 1672 (2000)
 U. Shumlak, etc., Physical Rev. Lett. 75, 3285 (1995)
 U. Shumlak, etc., ALPHA Annual Review Meeting 2017

A z-pinch plasma can be stabilized by sheared flows



Fusion reactor concept by ZAP energy



There are alternative

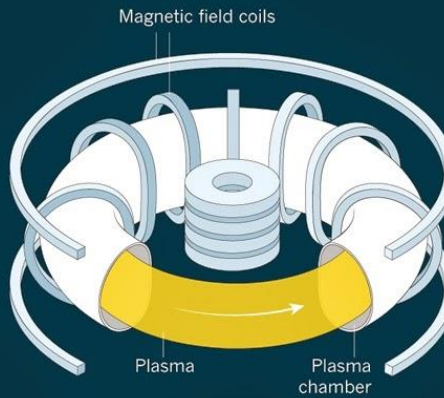


TRAPPING FUSION FIRE

When a superhot, ionized plasma is trapped in a magnetic field, it will fight to escape. Reactors are designed to keep it confined for long enough for the nuclei to fuse and produce energy.

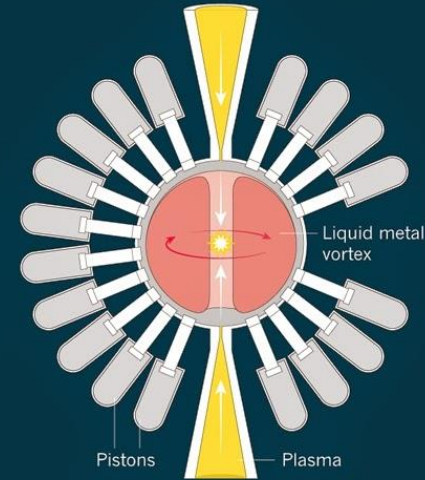
A CHOICE OF FUELS

Many light isotopes will fuse to release energy. A deuterium–tritium mix ignites at the lowest temperature, roughly 100 million kelvin, but produces neutrons that make the reactor radioactive. Other fuels avoid that, but ignite at much higher temperatures.



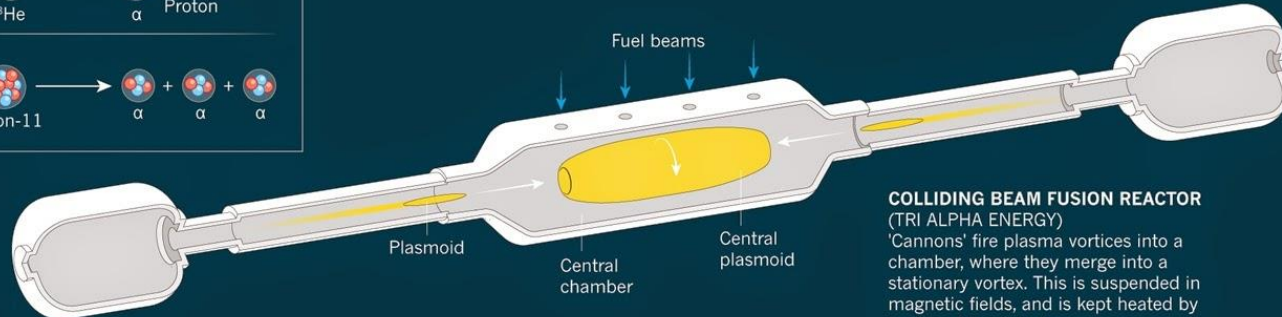
TOKAMAK

(ITER AND MANY OTHERS)
 Multiple coils produce magnetic fields that hold the plasma in the chamber. A coil through the centre drives a current through the plasma to keep it hot.



MAGNETIZED TARGET REACTOR (GENERAL FUSION)

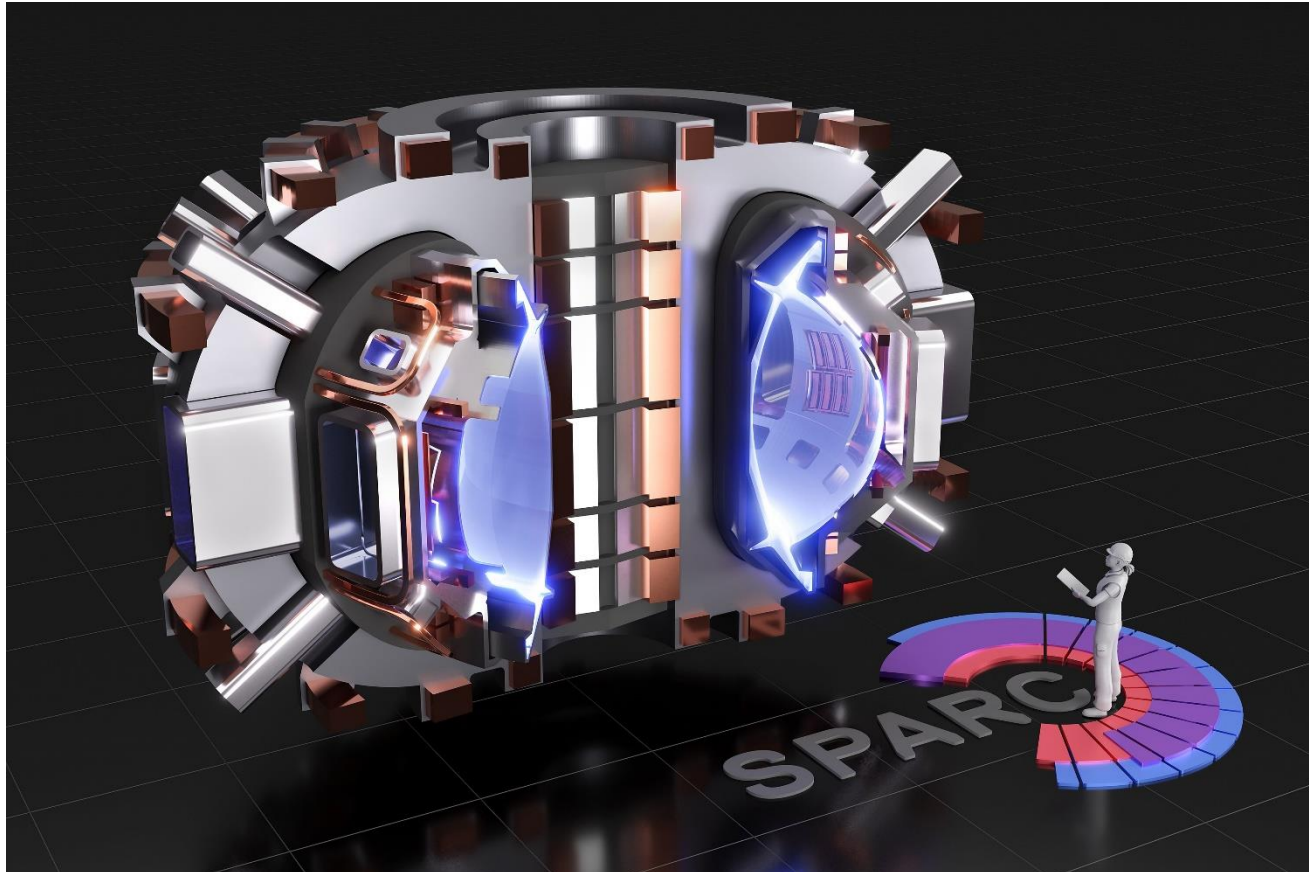
Magnetized rings of plasma are injected into a vortex of liquid metal. Pistons punch the metal inwards, compressing the plasma to ignite fusion.



COLLIDING BEAM FUSION REACTOR (TRI ALPHA ENERGY)

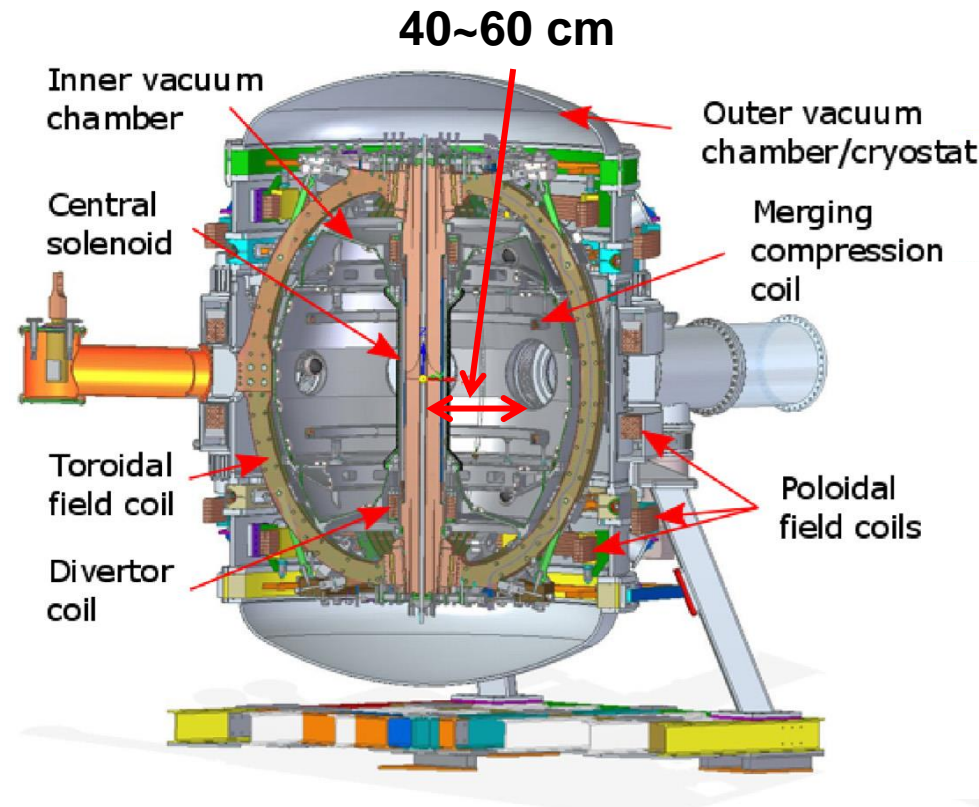
'Cannons' fire plasma vortices into a chamber, where they merge into a stationary vortex. This is suspended in magnetic fields, and is kept heated by beams of fresh fuel.

Commonwealth Fusion Systems, a MIT spin-out company, is building a high-magnetic field tokamak



- Fusion power $\propto B^4$.
- The fusion gain $Q > 2$ is expected for SPARC tokamak.

Merging compression is used to heat the tokamak at the start-up process in ST40 Tokamak at Tokamak Energy Ltd



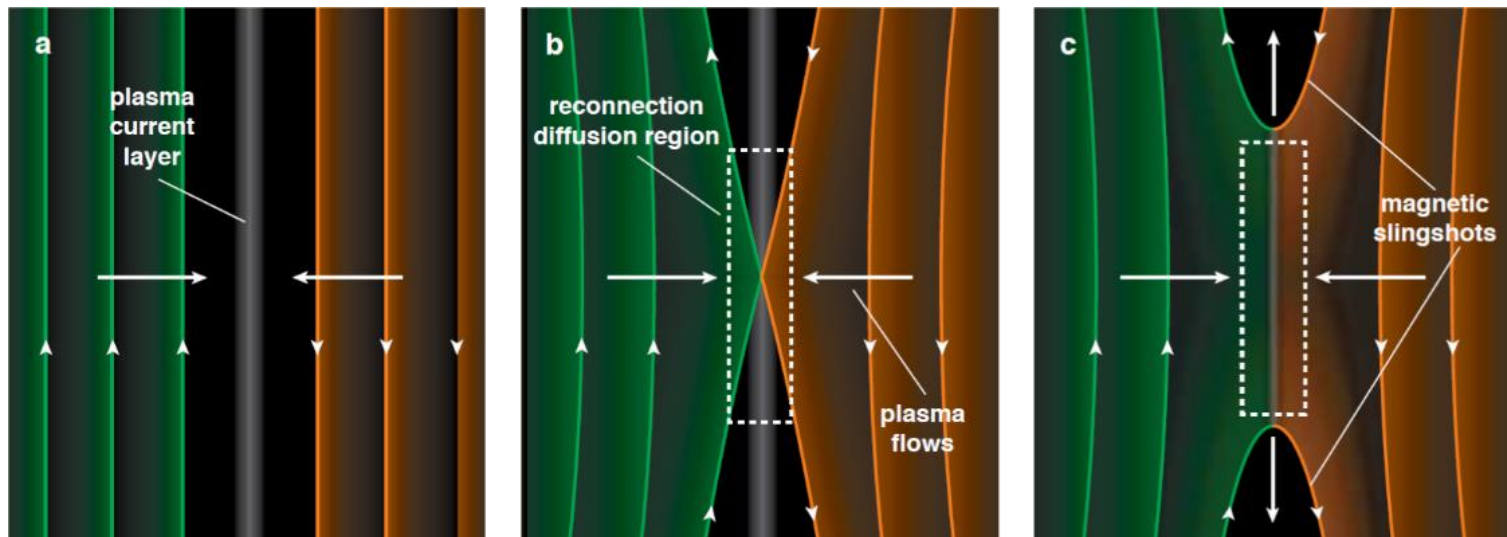
- High temperature superconductors are used.
- $B_T \sim 3\text{ T}$



M. Gryaznevich, et al., Fusion Eng. Design, **123**, 177 (2017)
<https://www.tokamakenergy.co.uk/>

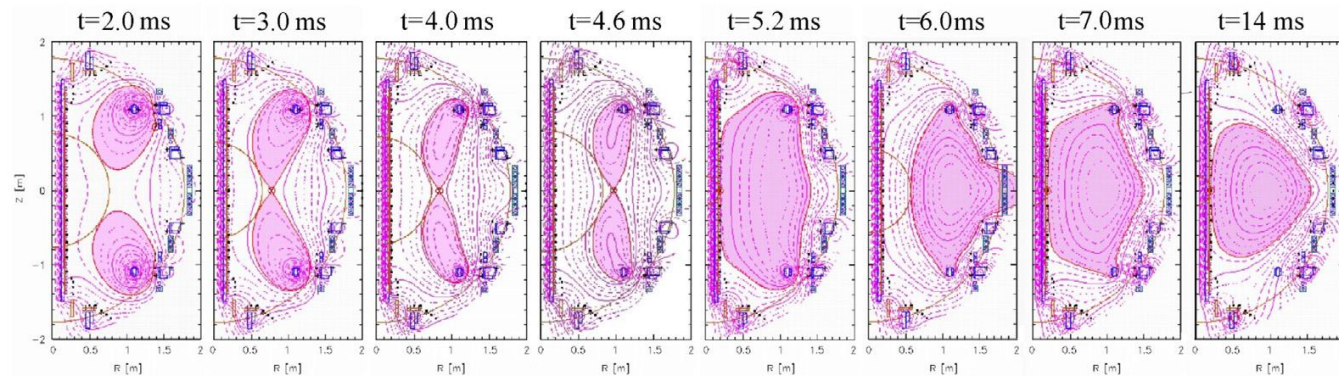
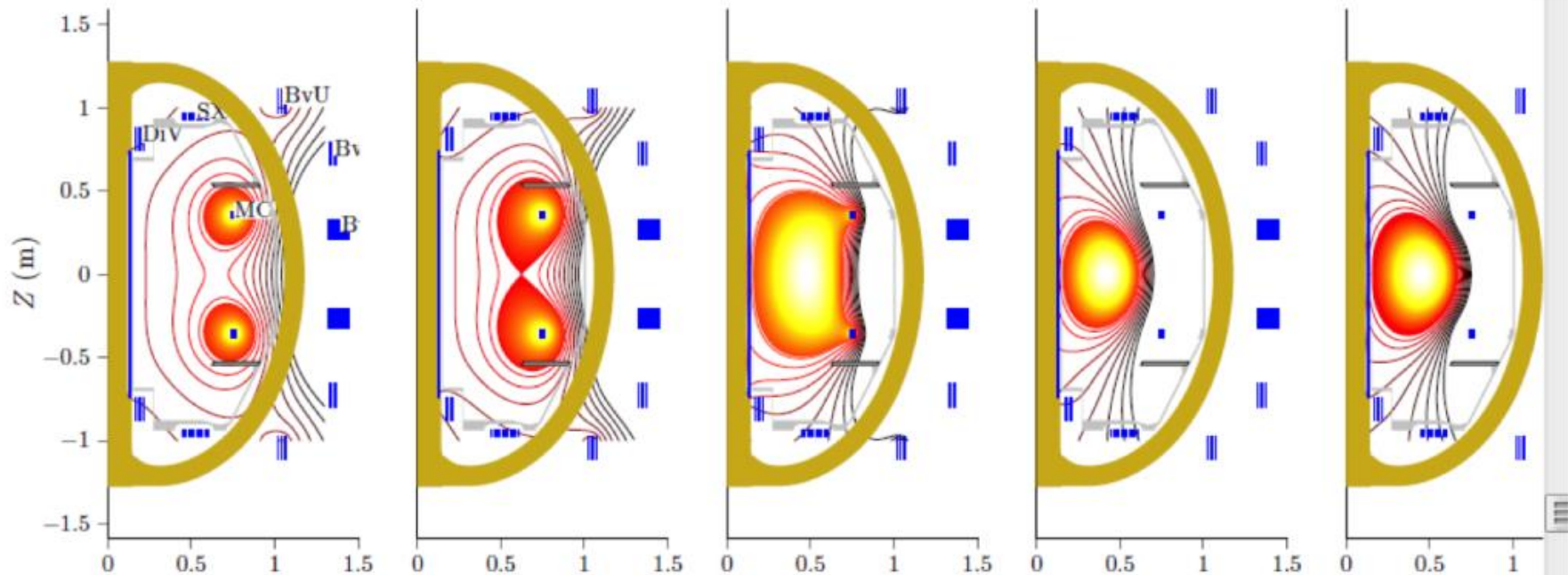
P. F. Buxton, et al., Fusion Eng. Design, **123**, 551 (2017)

Reconnection



<https://www.youtube.com/watch?v=7sS3Lpzh0Zw>

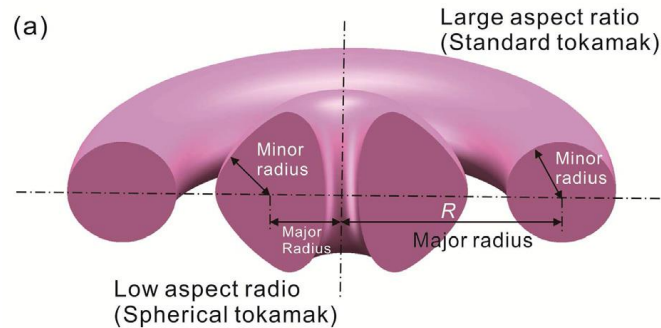
Merging compression is used to heat the plasma



Spherical torus (ST) and compact torus (CT)

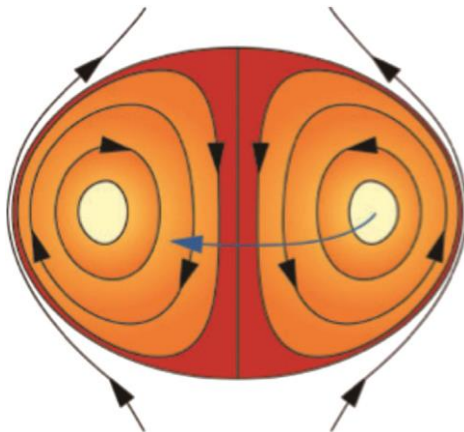


- Spherical torus (ST)

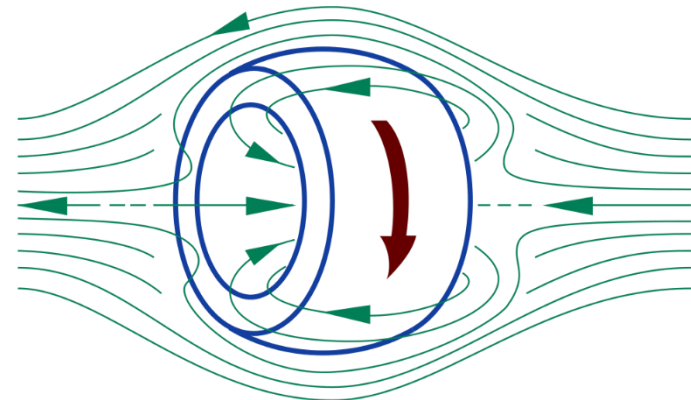


- Compact torus (CT)

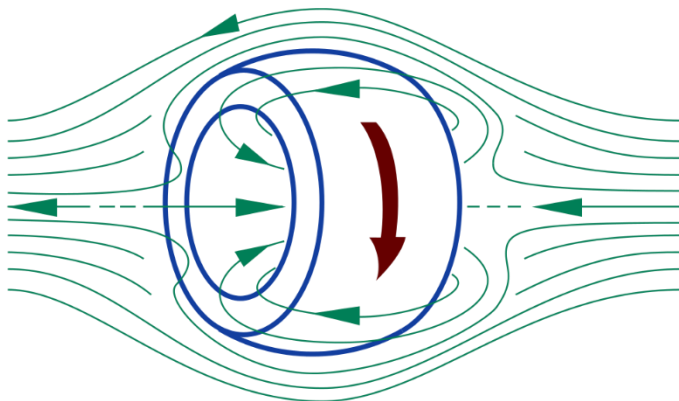
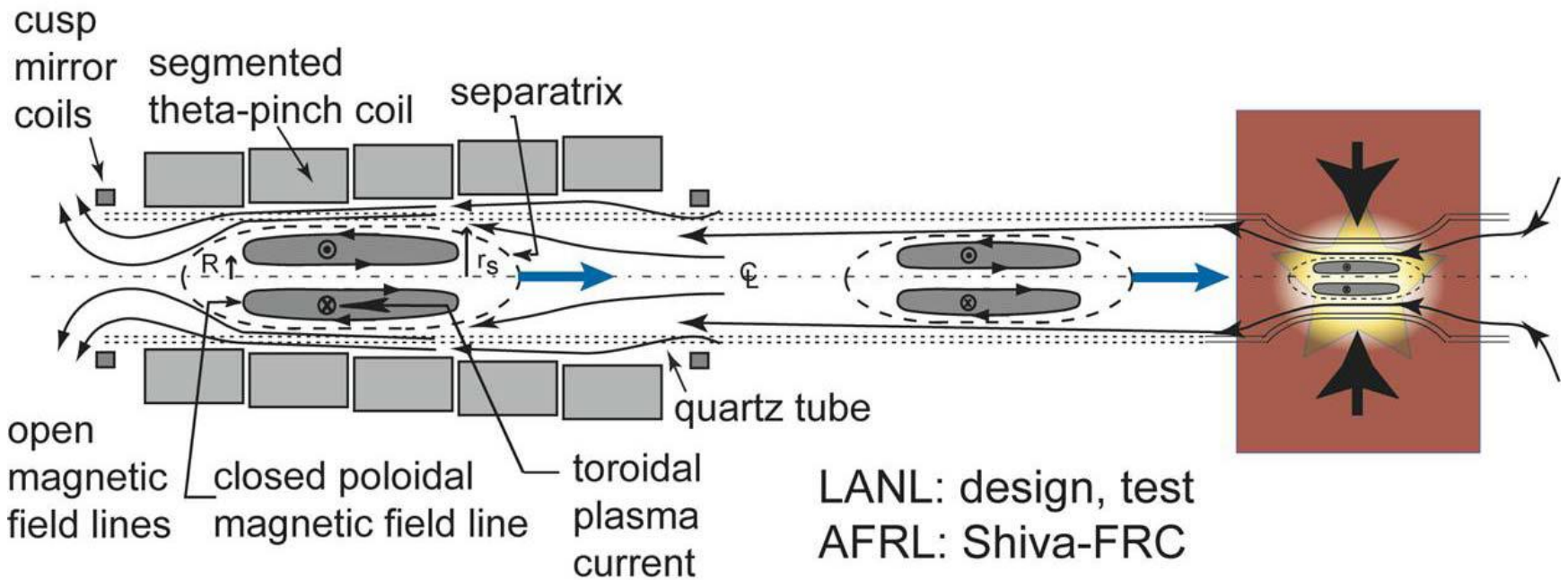
- Spheromak



- Field reversed configuration (FRC)



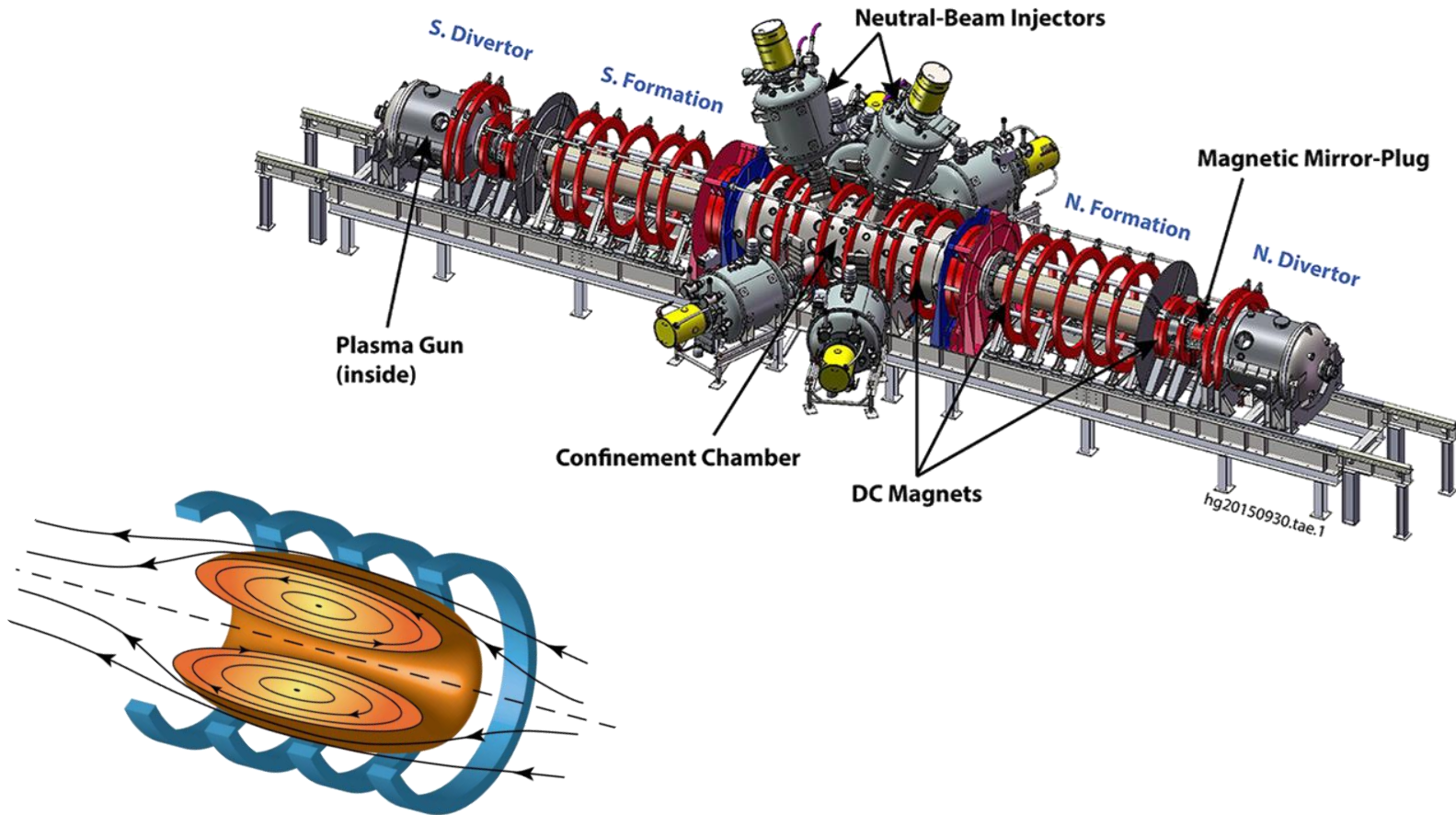
Field reverse configuration is used in Tri-alpha energy



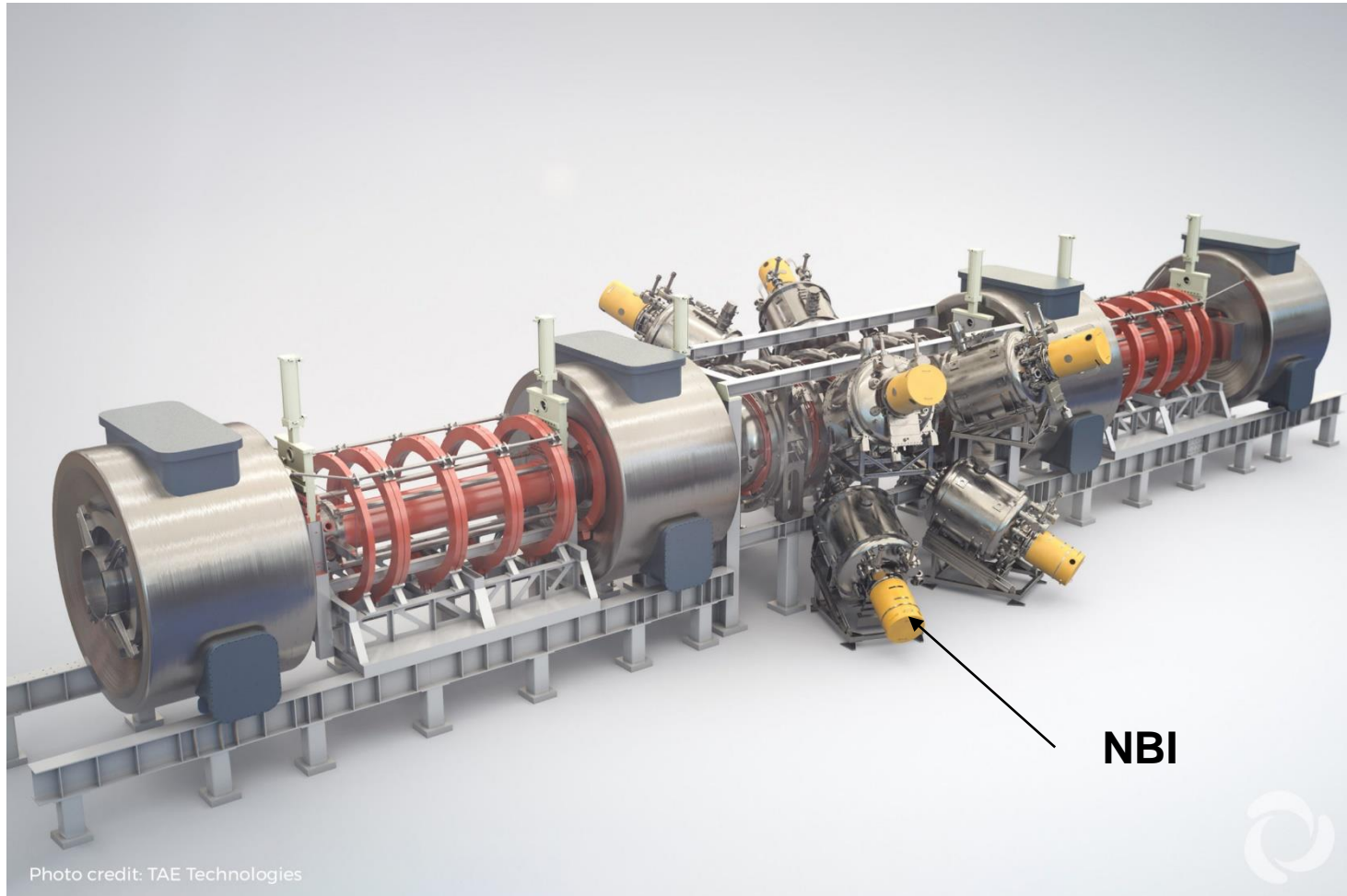
*Magneto-Inertial Fusion & Magnetized HED Physics by Bruno S. Bauer, UNR & Magneto-Inertial Fusion Community

**https://en.wikipedia.org/wiki/Field-reversed_configuration

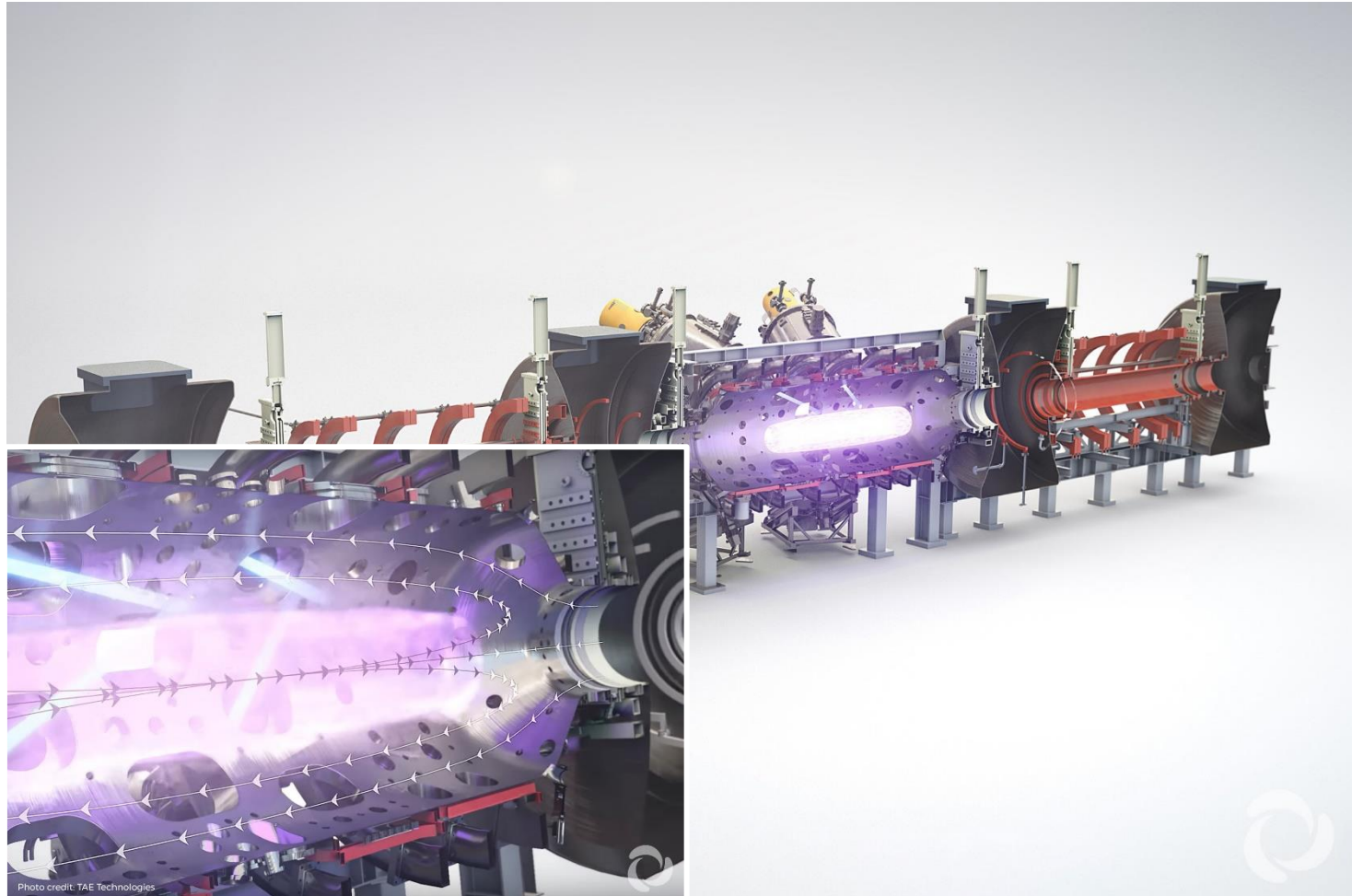
Field reverse configuration is used in Tri-alpha energy



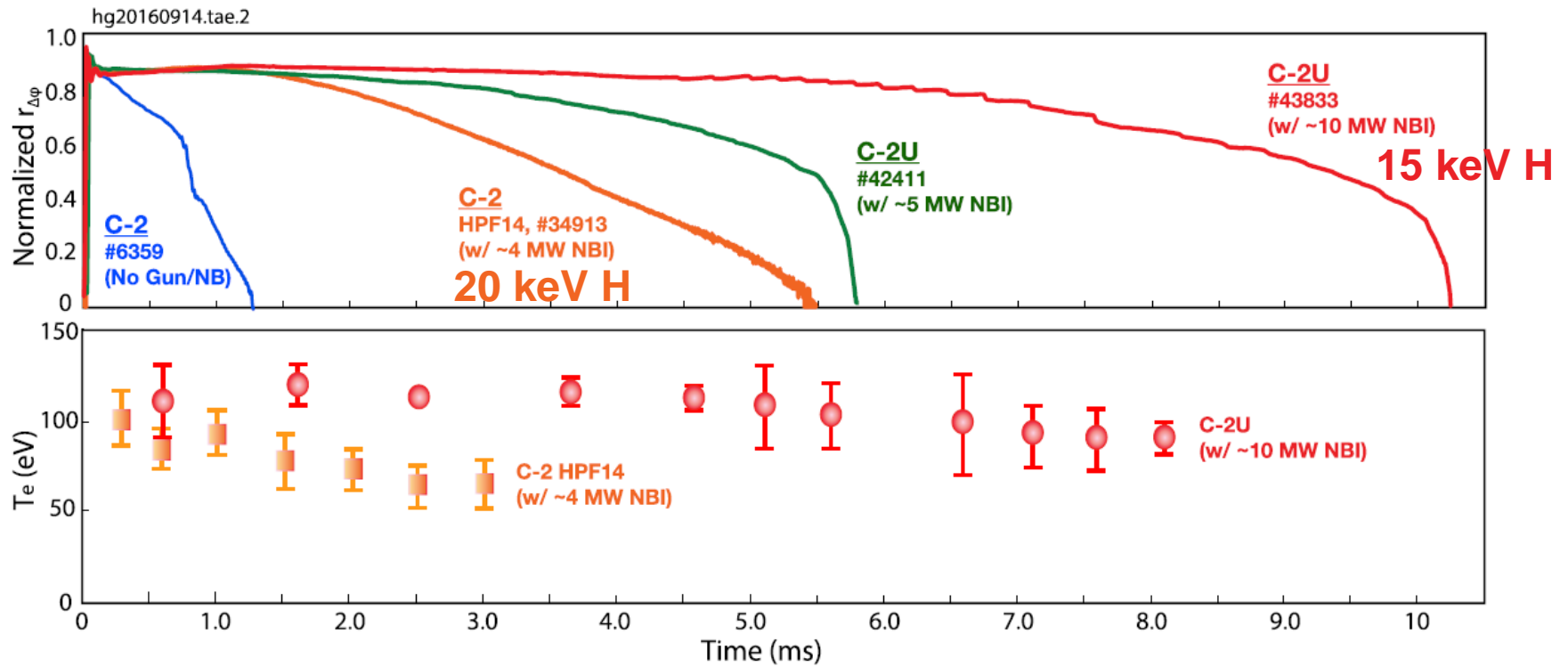
NBI for Tri-Alpha Energy Technologies



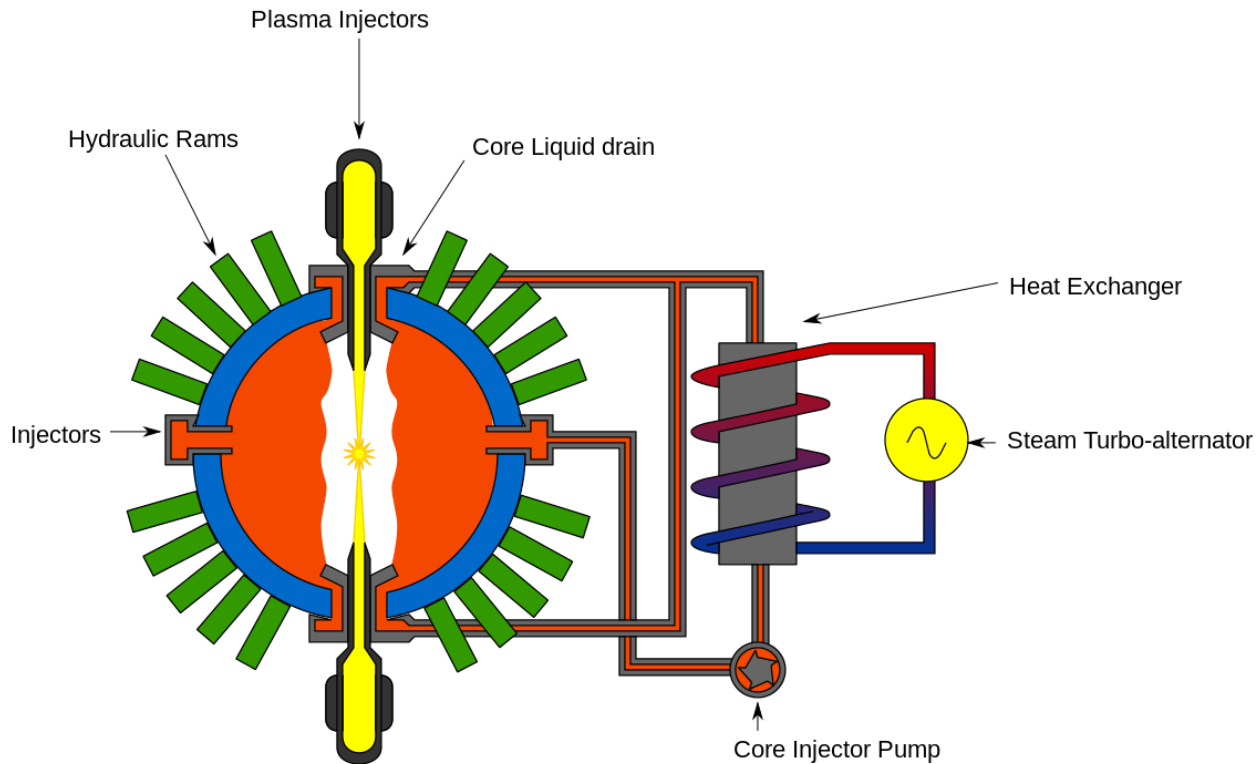
Neutral beams are injected in to the chamber for spinning the FRC



FRC sustain longer with neutral beam injection



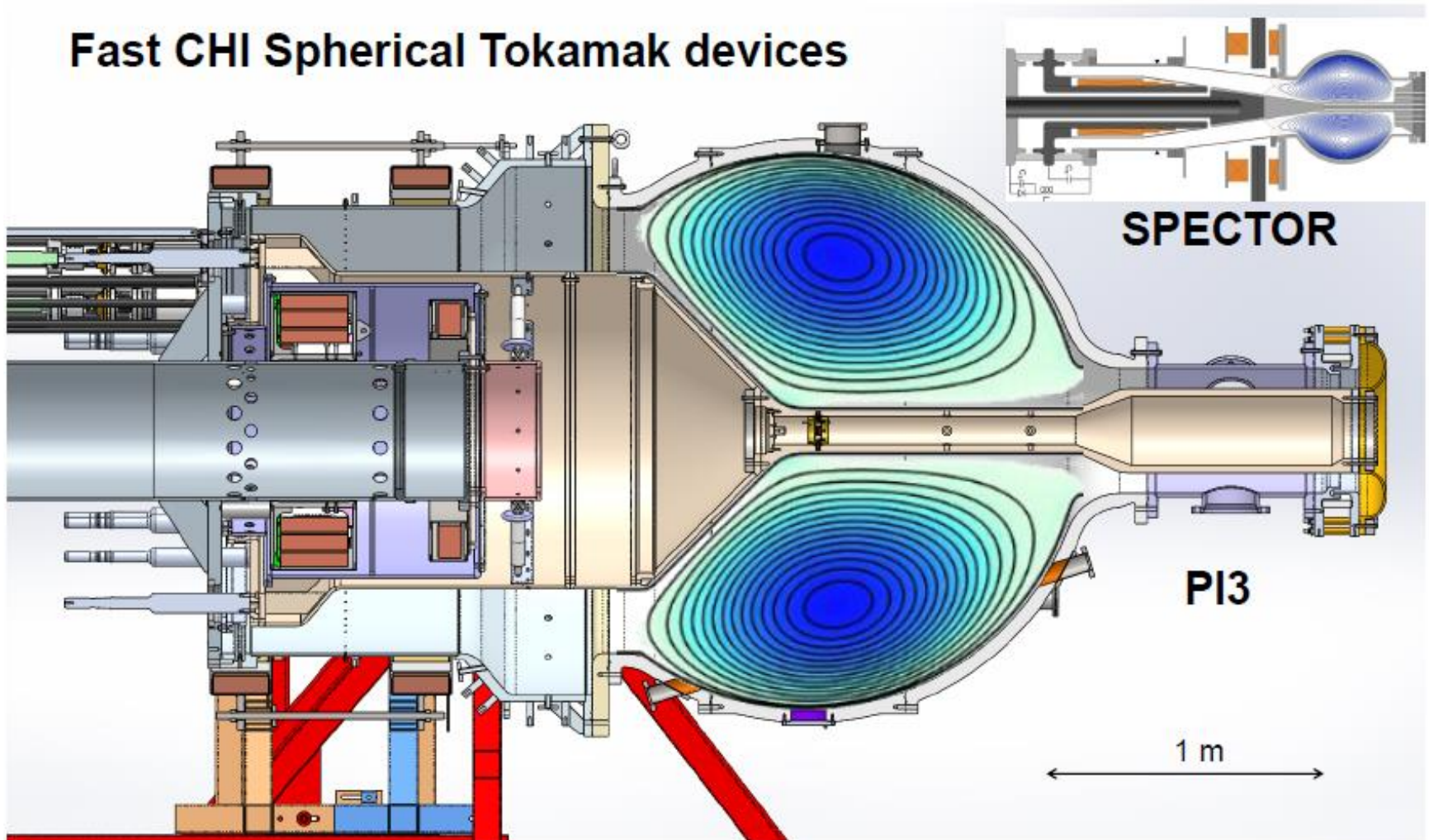
General fusion is a design ready to be migrated to a power plant



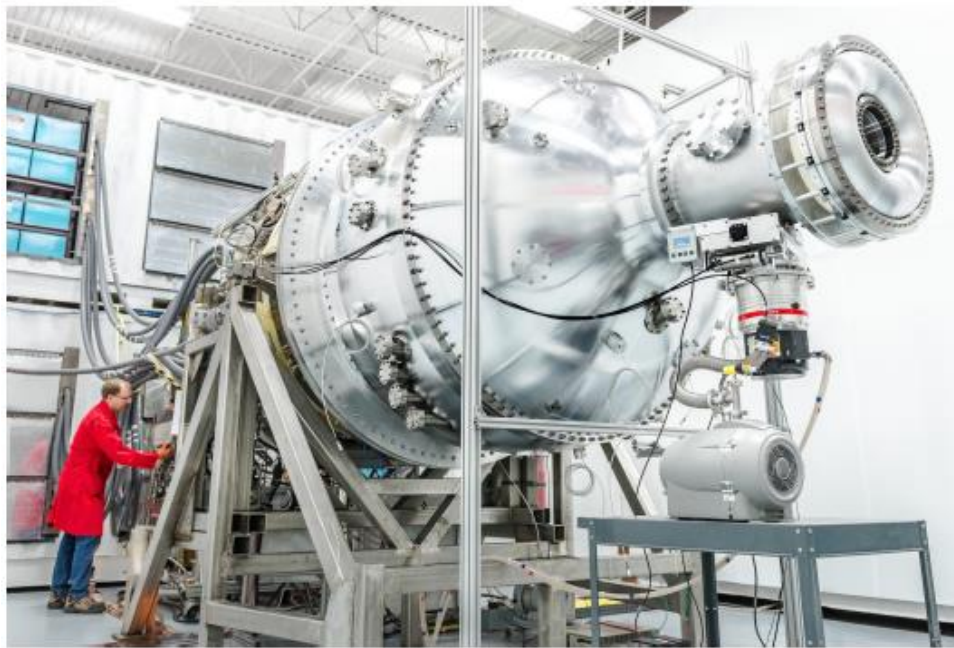
A spherical tokamak is first generated



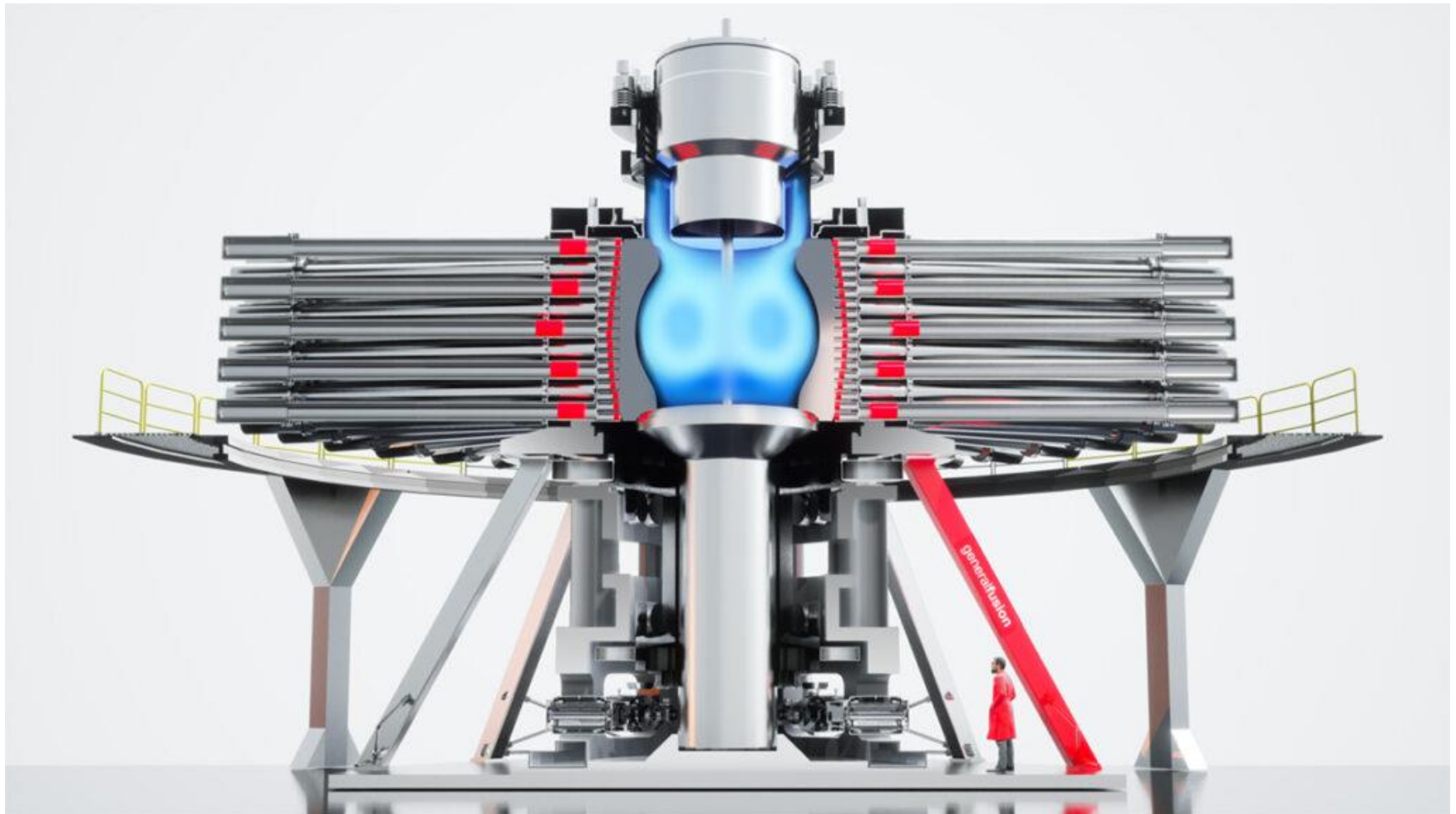
Fast CHI Spherical Tokamak devices



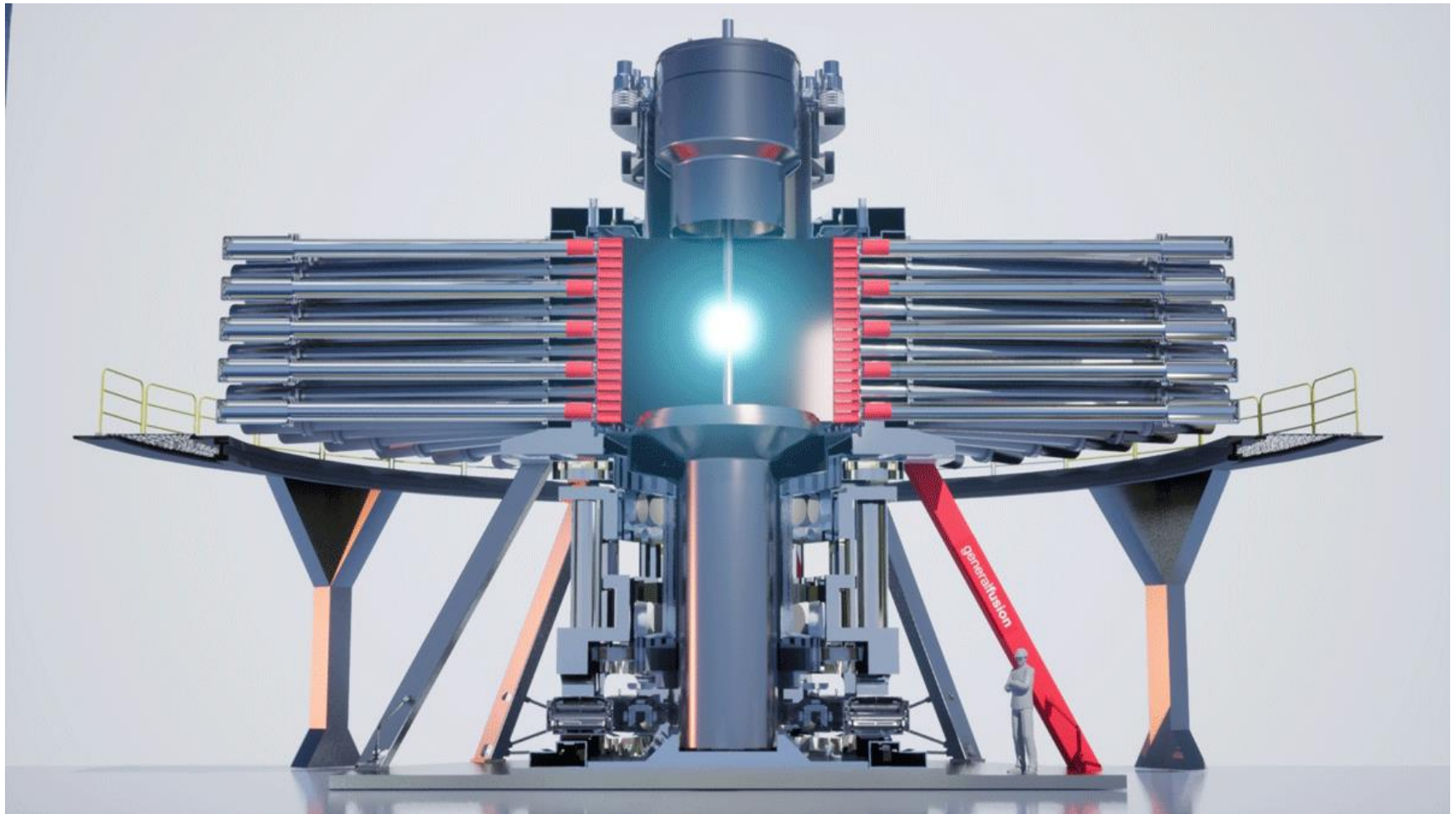
Plasma injector for the spherical tokamak



A spherical tokamak is generated in a liquid metal vortex



The spherical tokamak is compressed by the pressure provided by the surrounding hydraulic pistons



BBC: General Fusion to build its Fusion Demonstration Plant in the UK, at the UKAEA Culham Campus



Nuclear energy: Fusion plant backed by Jeff Bezos to be built in UK

By Matt McGrath
Environment correspondent

17 June

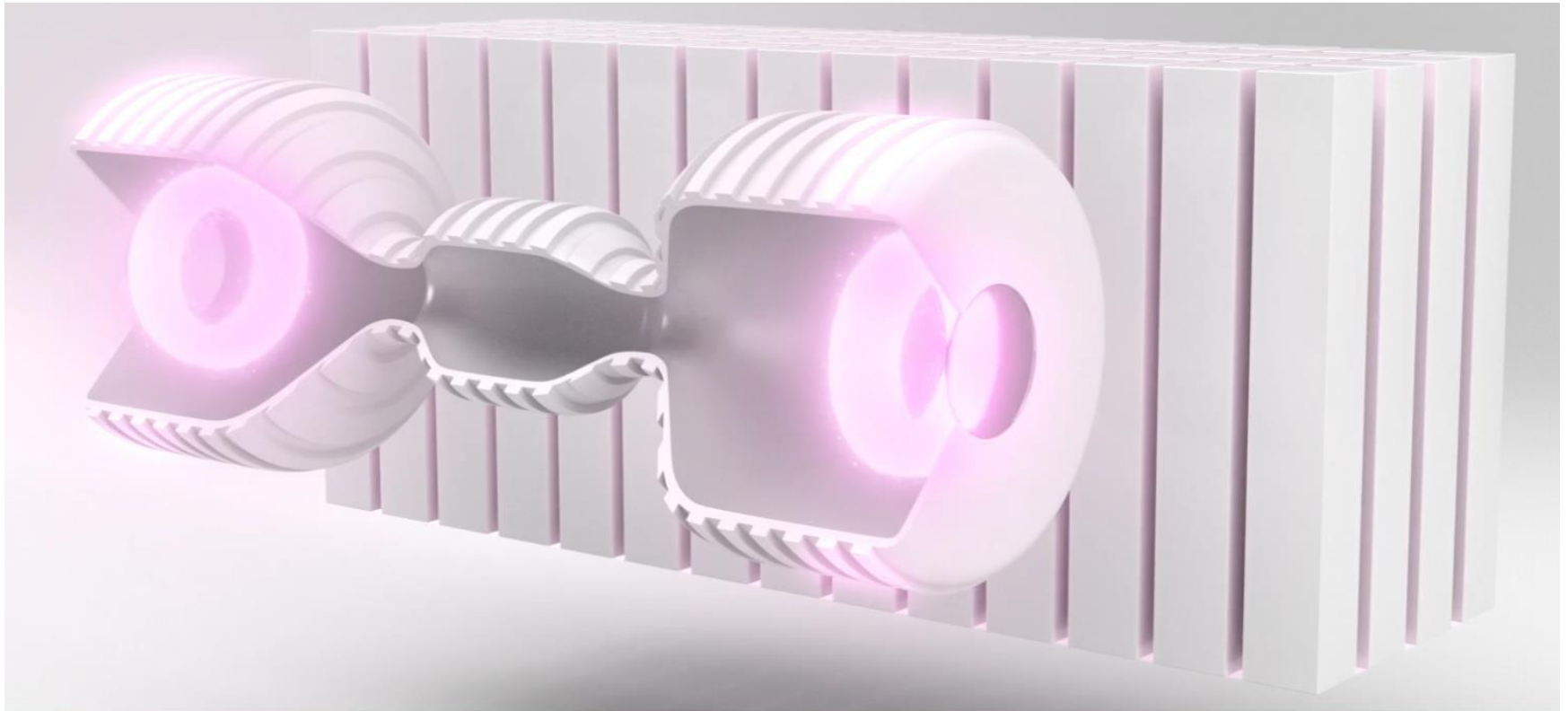


An artist's impression of what the new demonstration plant might look like

A company backed by Amazon's Jeff Bezos is set to build a large-scale nuclear fusion demonstration plant in Oxfordshire.

Canada's General Fusion is one of the leading private firms aiming to turn the

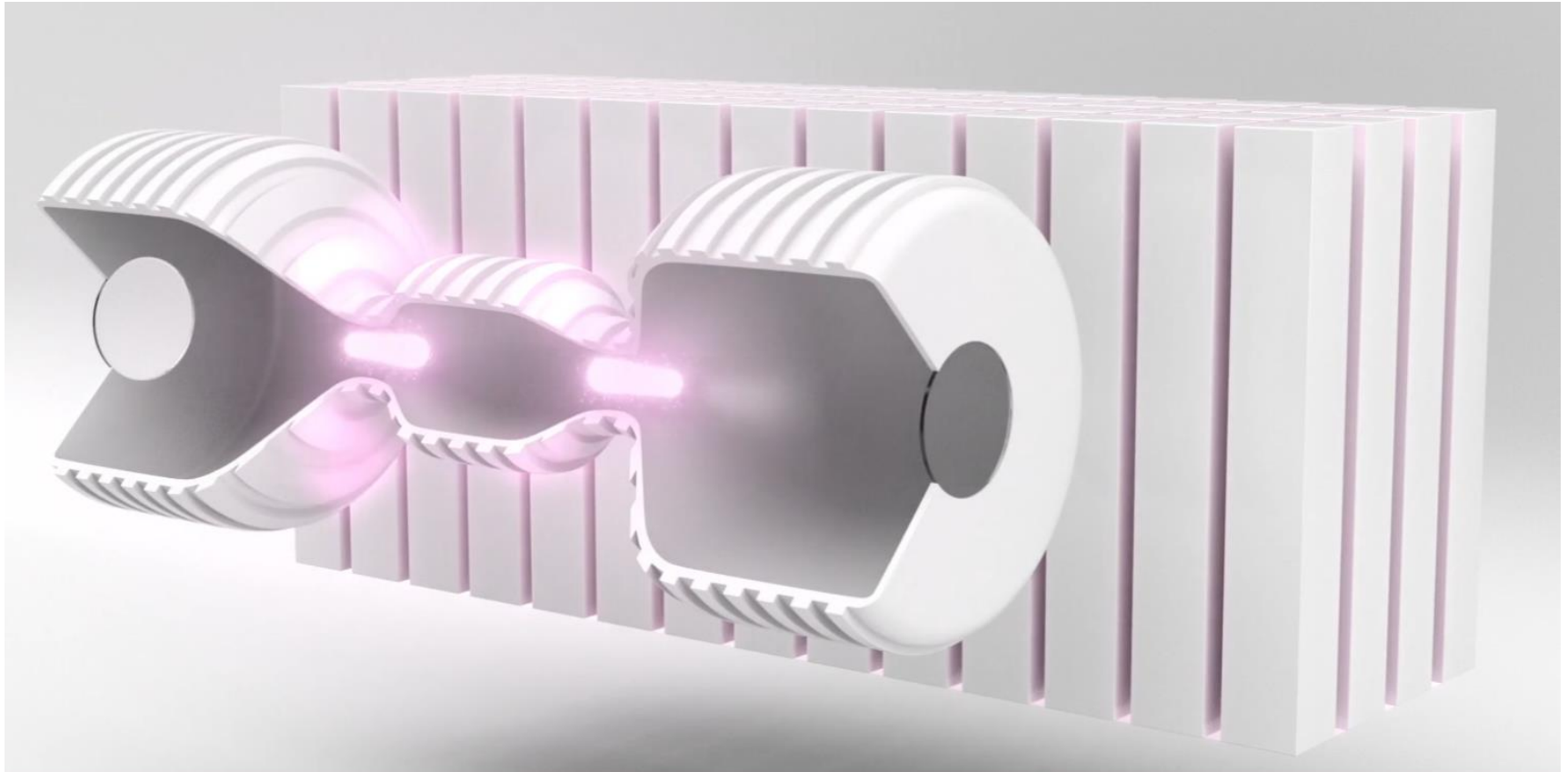
Helion energy is compressing the two merging FRCs



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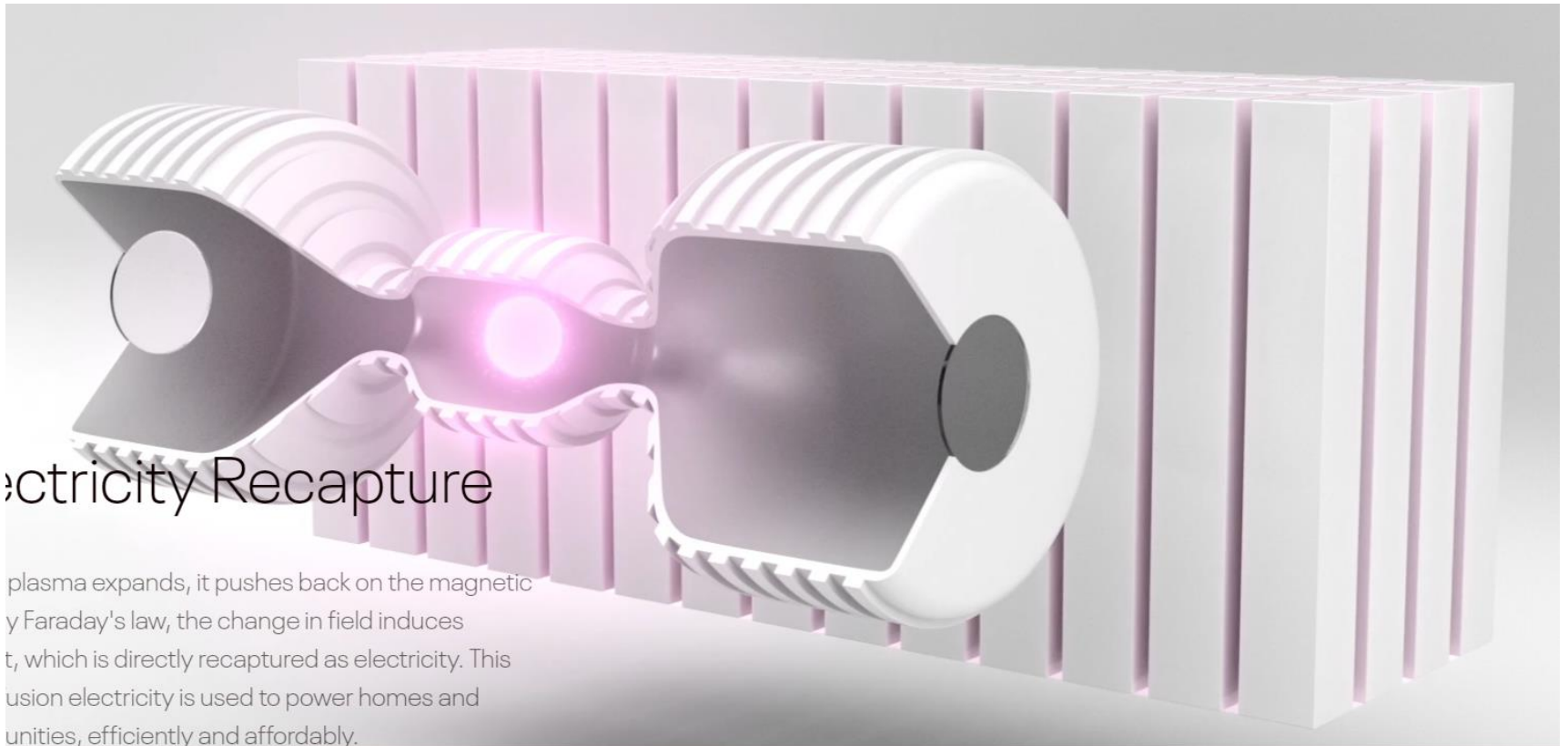
Two FRCs are accelerated toward each other



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Two FRCs merge with each other



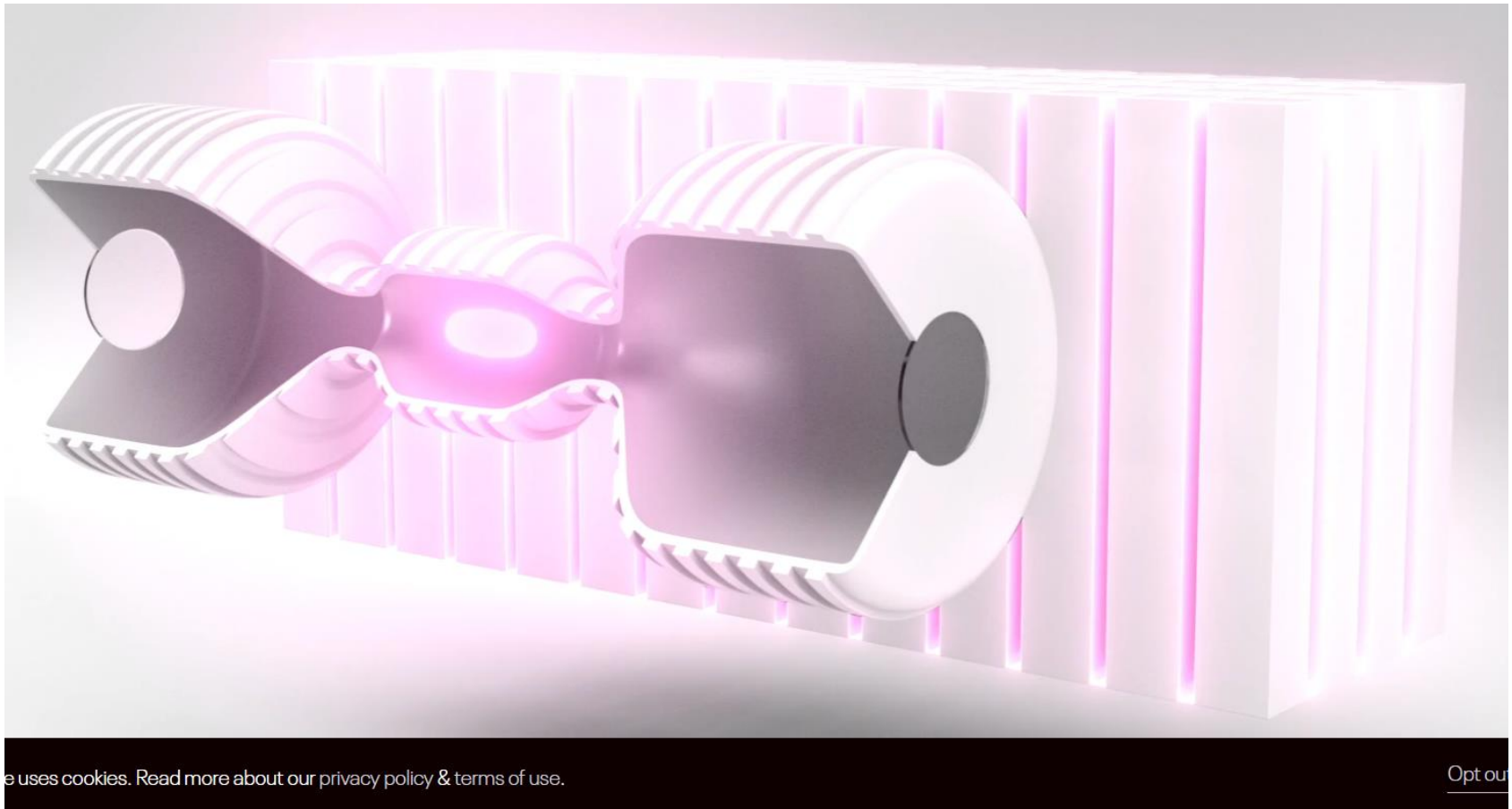
Electricity Recapture

When the plasma expands, it pushes back on the magnetic field. By Faraday's law, the change in field induces an electric current, which is directly recaptured as electricity. This recaptured electricity is used to power homes and businesses, efficiently and affordably.

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The merged FRC is compressed electrically to high temperature



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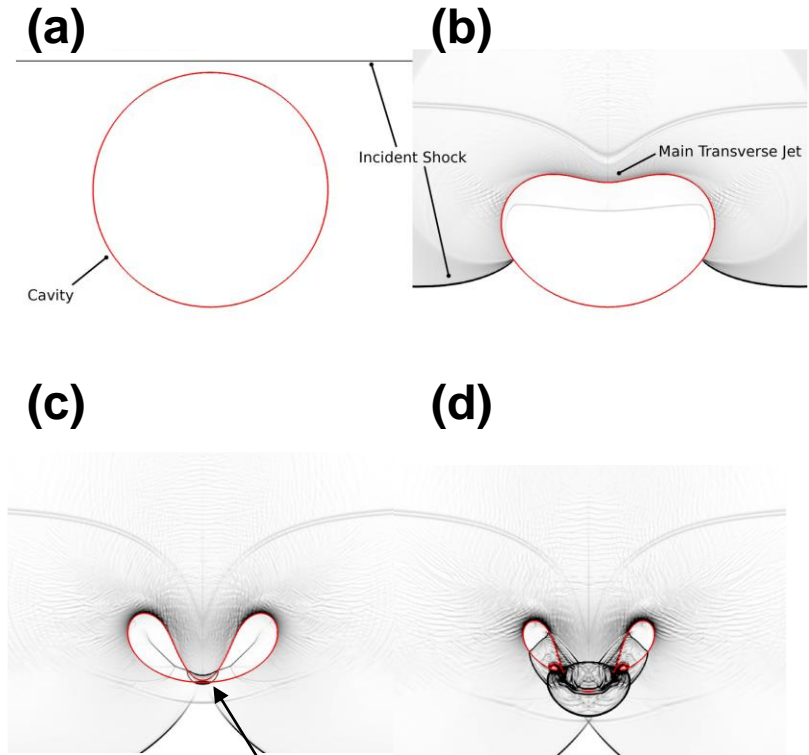
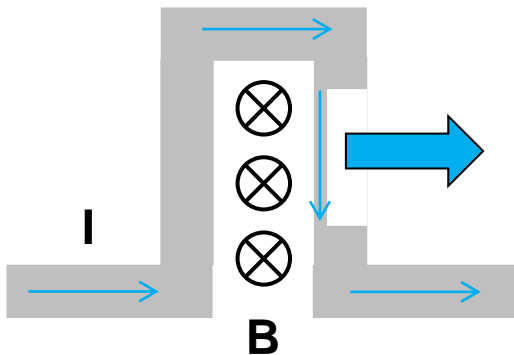
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- **Similar concept will be studied in our laboratory.**

Projectile Fusion is being established at First Light Fusion Ltd, UK



- **Stored energy: 2.5 MJ @ 200 kV**
($C_{\text{tot}}=125 \text{ uF}$)
- $I_{\text{peak}}=14 \text{ MA}$ w/ $T_{\text{rise}} \sim 2 \mu\text{s}$.



- **High pressure is generated by the colliding shock.**
<https://www.youtube.com/watch?v=aTMPigL7FB8>

<https://firstlightfusion.com/>

B. Tully and N. Hawker, Phys. Rev. **E93**, 053105 (2016)

A gas gun is used to eject the projectile



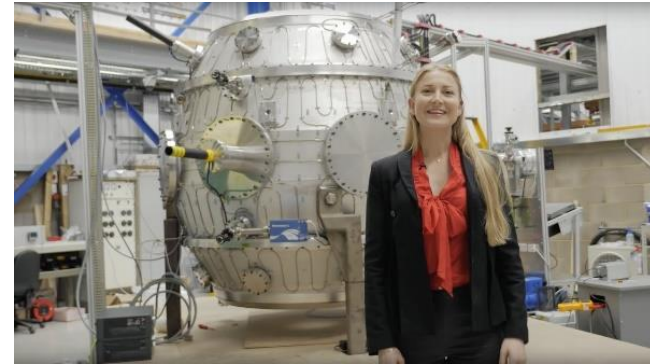
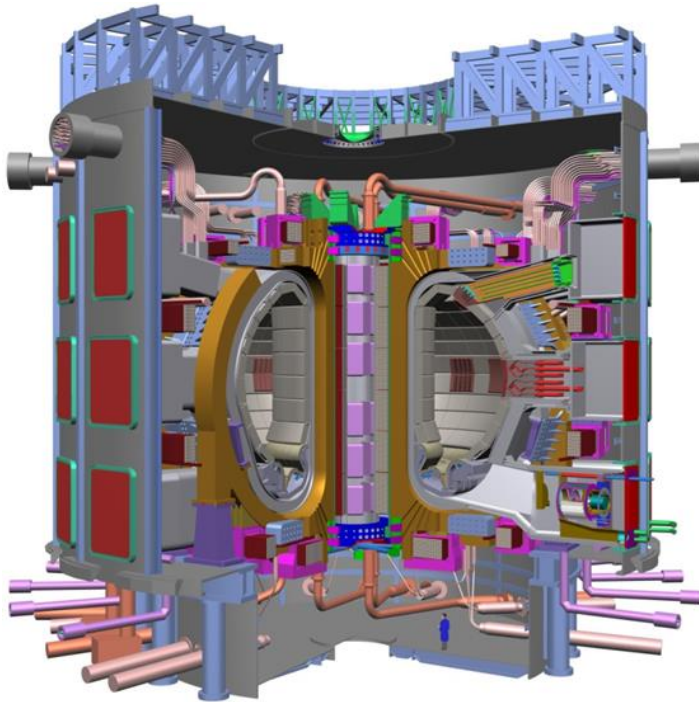
<https://www.youtube.com/watch?v=JN7lyxC11n0>

<https://www.youtube.com/watch?v=aW4eufac-f8>

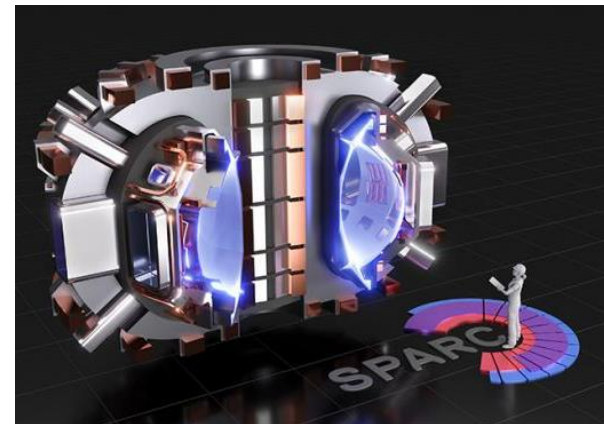
Many groups aim to achieve ignition in the MCF regime in the near future



- **ITER – 2025 First Plasma**
2035 D-T Exps
2050 DEMO
- **Tokamak energy, UK**
 - **2025 Gain**
 - **2030 to power grid**



- **Commonwealth Fusion Systems, USA**
– 2025 Gain



<https://www.iter.org>
<https://www.tokamakenergy.co.uk/>
<https://www.psfc.mit.edu/sparc>

Fusion is blooming!



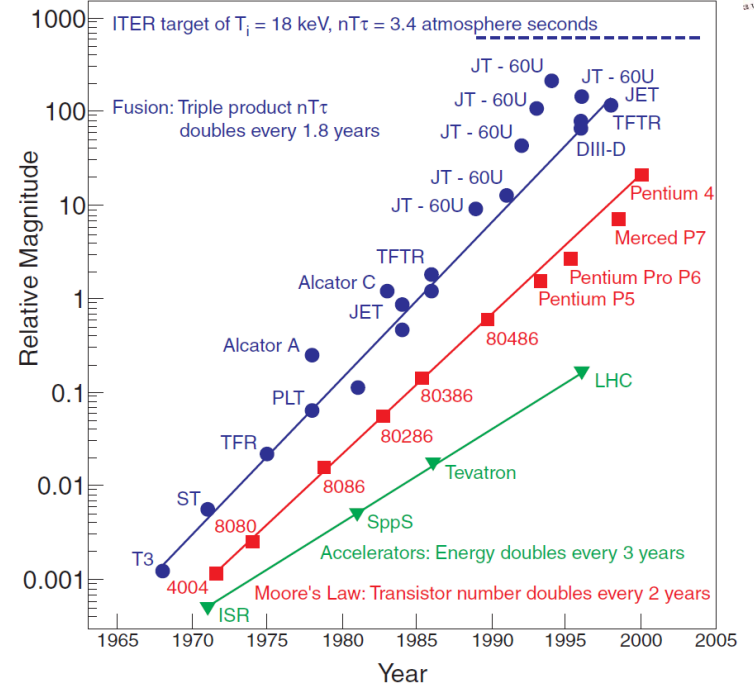
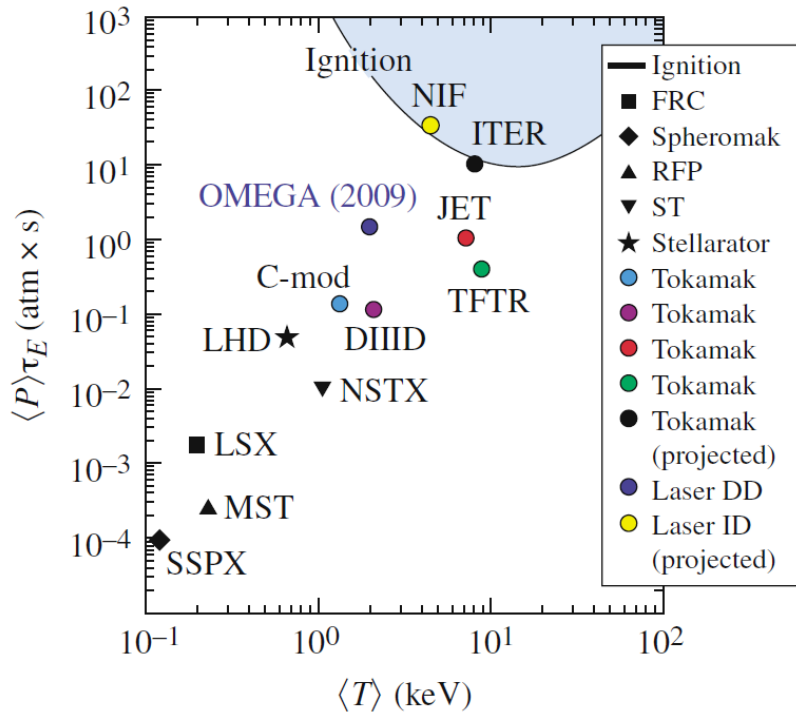
FIA Members

FUSION
INDUSTRY
ASSOCIATION

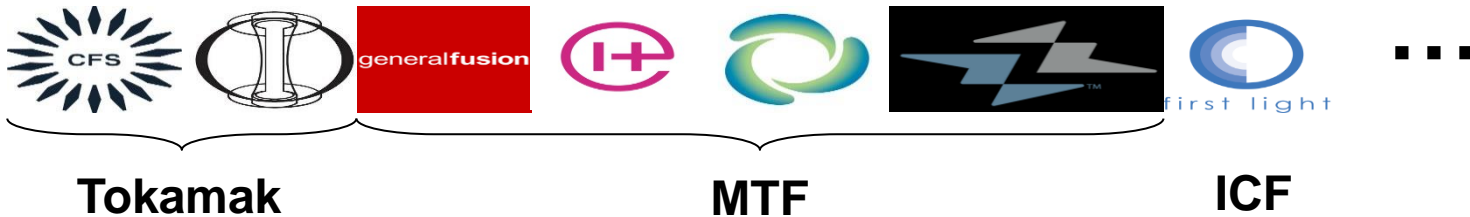


⋮

We are closed to ignition!



• **Other private companies:**

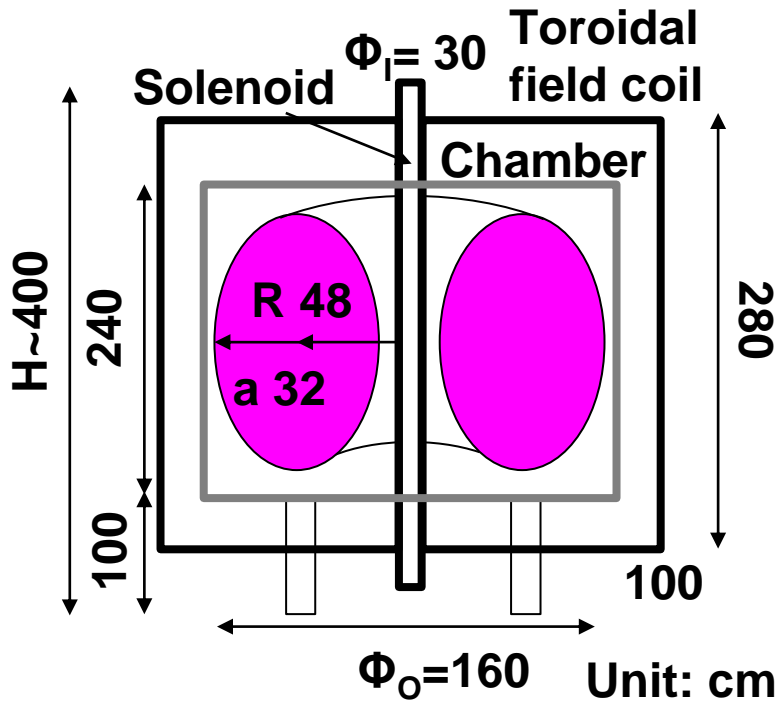


Fusion projects in Inst. Space and Plasma Sciences, National Cheng Kung University

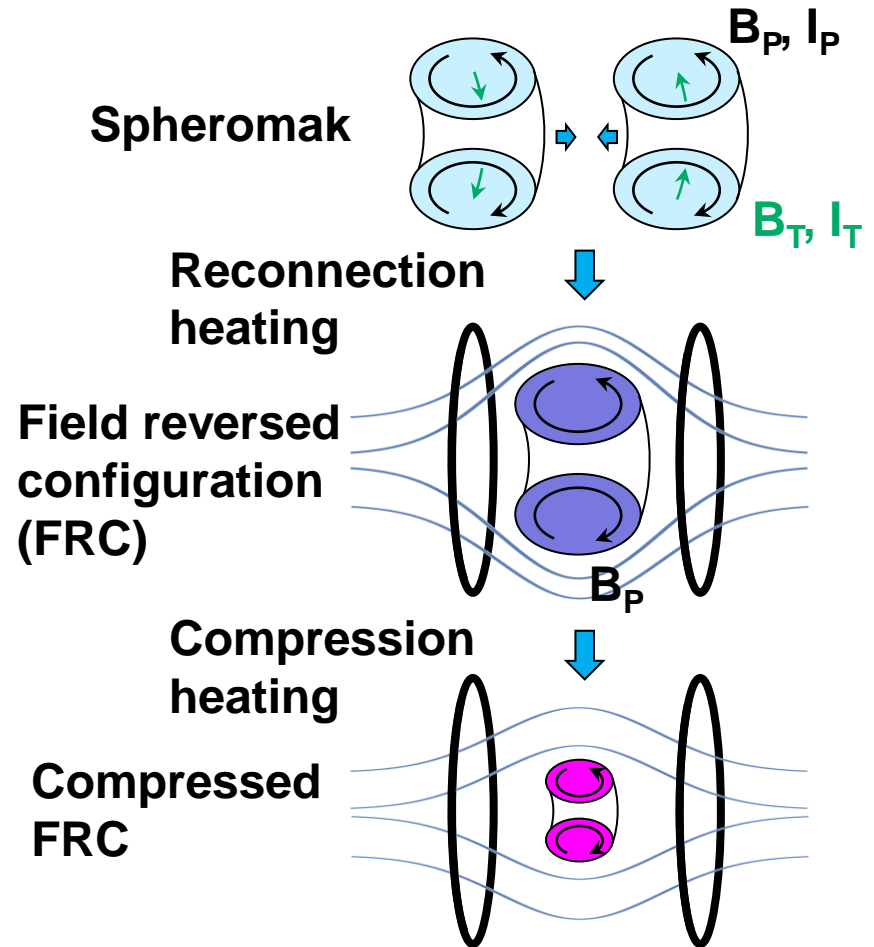


- 國科會計畫 - 磁約束高溫電漿研究

Formosa Integrated Research Spherical Tokamak (FIRST)



- Magneto-inertial fusion (MIF)



• We welcome anyone interested in fusion research to join our team!